

To our customers,

---

## Old Company Name in Catalogs and Other Documents

---

On April 1<sup>st</sup>, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

Send any inquiries to <http://www.renesas.com/inquiry>.

## Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

"Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.

8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

# H8/3694 Group

Hardware Manual

Renesas 16-Bit Single-Chip  
Microcomputer

H8 Family/H8/300H Tiny Series

H8/3694N	HD64N3694G, HD6483694G,
H8/3694F	HD64F3694, HD64F3694G,
H8/3694	HD6433694, HD6433694G,
H8/3693	HD6433693, HD6433693G,
H8/3692	HD6433692, HD6433692G,
H8/3691	HD6433691, HD6433691G,
H8/3690	HD6433690, HD6433690G



- a third party.
2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms or circuit application examples contained in these materials.
  3. All information contained in these materials, including product data, diagrams, charts, programs, algorithms represents information on products at the time of publication of these materials, and is subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.  
The information described here may contain technical inaccuracies or typographical errors. Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss resulting from these inaccuracies or errors.  
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
  4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a test system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
  5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for information considering the use of a product contained herein for any specific purposes, such as apparatuses or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
  6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce these materials in whole or in part these materials.
  7. If these products or technologies are subject to the Japanese export control restrictions, they may not be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.  
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
  8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.

Generally, the input pins of CMOS products are high-impedance input pins. If un... are in their open states, intermediate levels are induced by noise in the vicinity, a... through current flows internally, and a malfunction may occur.

### 3. Processing before Initialization

Note: When power is first supplied, the product's state is undefined.

The states of internal circuits are undefined until full power is supplied throughout the chip and a low level is input on the reset pin. During the period where the states are undefined, the register settings and the output state of each pin are also undefined. Be careful of your system so that it does not malfunction because of processing while it is in this undefined state. For those products which have a reset function, reset the LSI immediately after the power supply has been turned on.

### 4. Prohibition of Access to Undefined or Reserved Addresses

Note: Access to undefined or reserved addresses is prohibited.

The undefined or reserved addresses may be used to expand functions, or test registers may have been allocated to these addresses. Do not access these registers; the operation is not guaranteed if they are accessed.

- CPU and System-Control Modules
- On-Chip Peripheral Modules

The configuration of the functional description of each module differs according to the module. However, the generic style includes the following items:

- i) Feature
- ii) Input/Output Pin
- iii) Register Description
- iv) Operation
- v) Usage Note

When designing an application system that includes this LSI, take notes into account. Each section includes notes in relation to the descriptions given, and usage notes are given, as required, in the final part of each section.

7. List of Registers
8. Electrical Characteristics
9. Appendix
10. Main Revisions and Additions in this Edition (only for revised versions)

The list of revisions is a summary of points that have been revised or added to earlier versions. This does not include all of the revised contents. For details, see the actual locations in the manual.

11. Index

Objective: This manual was written to explain the hardware functions and electrical characteristics of the H8/3694 Group to the target users.  
Refer to the H8/300H Series Software Manual for a detailed description of the instruction set.

Notes on reading this manual:

- In order to understand the overall functions of the chip  
Read the manual according to the contents. This manual can be roughly categorized into sections on the CPU, system control functions, peripheral functions and electrical characteristics.
- In order to understand the details of the CPU's functions  
Read the H8/300H Series Software Manual.
- In order to understand the details of a register when its name is known  
Read the index that is the final part of the manual to find the page number of the entry for the register. The addresses, bits, and initial values of the registers are summarized in section 1.2, List of Registers.  
Example: Bit order: The MSB is on the left and the LSB is on the right.

Notes:

When using the on-chip emulator (E7, E8) for H8/3694 program development and debugging, the following restrictions must be noted.

1. The  $\overline{\text{NMI}}$  pin is reserved for the E7 or E8, and cannot be used.
2. Pins P85, P86, and P87 cannot be used. In order to use these pins, additional hardware must be provided on the user board.
3. Area H'7000 to H'7FFF is used by the E7 or E8, and is not available to the user.
4. Area H'F780 to H'FB7F must on no account be accessed.



<b>Document Title</b>	<b>Docume</b>
H8/3694 Group Hardware Manual	This mar
H8/300H Series Software Manual	REJ09B

User's manuals for development tools:

<b>Document Title</b>	<b>Docume</b>
H8S, H8/300 Series C/C++ Compiler, Assembler, Optimizing Linkage Editor User's Manual	REJ10B
Microcomputer Development Environment System H8S, H8/300 Series Simulator/Debugger User's Manual	ADE-702
H8S, H8/300 Series High-Performance Embedded Workshop 3, Tutorial	REJ10B
H8S, H8/300 Series High-Performance Embedded Workshop 3, User's Manual	REJ10B

Application notes:

<b>Document Title</b>	<b>Docume</b>
H8S, H8/300 Series C/C++ Compiler Package Application Note	REJ05B
Single Power Supply F-ZTAT™ On-Board Programming	ADE-502



2.2	Register Configuration .....
2.2.1	General Registers .....
2.2.2	Program Counter (PC) .....
2.2.3	Condition-Code Register (CCR) .....
2.3	Data Formats .....
2.3.1	General Register Data Formats .....
2.3.2	Memory Data Formats .....
2.4	Instruction Set .....
2.4.1	Table of Instructions Classified by Function .....
2.4.2	Basic Instruction Formats .....
2.5	Addressing Modes and Effective Address Calculation .....
2.5.1	Addressing Modes .....
2.5.2	Effective Address Calculation .....
2.6	Basic Bus Cycle .....
2.6.1	Access to On-Chip Memory (RAM, ROM) .....
2.6.2	On-Chip Peripheral Modules .....
2.7	CPU States .....
2.8	Usage Notes .....
2.8.1	Notes on Data Access to Empty Areas .....
2.8.2	EPMOV Instruction .....
2.8.3	Bit Manipulation Instruction .....
Section 3 Exception Handling .....	
3.1	Exception Sources and Vector Address .....
3.2	Register Descriptions .....
3.2.1	Interrupt Edge Select Register 1 (IEGR1) .....
3.2.2	Interrupt Edge Select Register 2 (IEGR2) .....
3.2.3	Interrupt Enable Register 1 (IENR1) .....
3.2.4	Interrupt Flag Register 1 (IRR1) .....

Section 4	Address Break .....	
4.1	Register Descriptions .....	
4.1.1	Address Break Control Register (ABRKCR) .....	
4.1.2	Address Break Status Register (ABRKSR) .....	
4.1.3	Break Address Registers (BARH, BARL).....	
4.1.4	Break Data Registers (BDRH, BDRL) .....	
4.2	Operation .....	
Section 5	Clock Pulse Generators .....	
5.1	System Clock Generator .....	
5.1.1	Connecting Crystal Resonator .....	
5.1.2	Connecting Ceramic Resonator .....	
5.1.3	External Clock Input Method .....	
5.2	Subclock Generator.....	
5.2.1	Connecting 32.768-kHz Crystal Resonator .....	
5.2.2	Pin Connection when Not Using Subclock.....	
5.3	Prescalers .....	
5.3.1	Prescaler S .....	
5.3.2	Prescaler W.....	
5.4	Usage Notes .....	
5.4.1	Note on Resonators.....	
5.4.2	Notes on Board Design.....	
Section 6	Power-Down Modes.....	
6.1	Register Descriptions .....	
6.1.1	System Control Register 1 (SYSCR1).....	
6.1.2	System Control Register 2 (SYSCR2).....	
6.1.3	Module Standby Control Register 1 (MSTCR1) .....	

Section 7	ROM .....
7.1	Block Configuration.....
7.2	Register Descriptions .....
7.2.1	Flash Memory Control Register 1 (FLMCR1).....
7.2.2	Flash Memory Control Register 2 (FLMCR2).....
7.2.3	Erase Block Register 1 (EBR1) .....
7.2.4	Flash Memory Power Control Register (FLPWCR).....
7.2.5	Flash Memory Enable Register (FENR).....
7.3	On-Board Programming Modes.....
7.3.1	Boot Mode .....
7.3.2	Programming/Erasing in User Program Mode.....
7.4	Flash Memory Programming/Erasing .....
7.4.1	Program/Program-Verify .....
7.4.2	Erase/Erase-Verify .....
7.4.3	Interrupt Handling when Programming/Erasing Flash Memory.....
7.5	Program/Erase Protection .....
7.5.1	Hardware Protection .....
7.5.2	Software Protection.....
7.5.3	Error Protection.....
7.6	Programmer Mode .....
7.7	Power-Down States for Flash Memory.....
Section 8	RAM .....
Section 9	I/O Ports.....
9.1	Port 1.....
9.1.1	Port Mode Register 1 (PMR1).....
9.1.2	Port Control Register 1 (PCR1).....
9.1.3	Port Data Register 1 (PDR1).....

	9.3.5	Pin Functions .....
9.4	Port 7.....	
	9.4.1	Port Control Register 7 (PCR7) .....
	9.4.2	Port Data Register 7 (PDR7) .....
	9.4.3	Pin Functions .....
9.5	Port 8.....	
	9.5.1	Port Control Register 8 (PCR8).....
	9.5.2	Port Data Register 8 (PDR8) .....
	9.5.3	Pin Functions .....
9.6	Port B.....	
	9.6.1	Port Data Register B (PDRB) .....
	Section 10	Timer A .....
	10.1	Features.....
	10.2	Input/Output Pins.....
	10.3	Register Descriptions.....
		10.3.1 Timer Mode Register A (TMA).....
		10.3.2 Timer Counter A (TCA) .....
	10.4	Operation .....
		10.4.1 Interval Timer Operation .....
		10.4.2 Clock Time Base Operation.....
		10.4.3 Clock Output.....
	10.5	Usage Note.....
	Section 11	Timer V .....
	11.1	Features.....
	11.2	Input/Output Pins.....
	11.3	Register Descriptions.....
		11.3.1 Timer Counter V (TCNTV).....

Section 12	Timer W .....
12.1	Features .....
12.2	Input/Output Pins .....
12.3	Register Descriptions .....
12.3.1	Timer Mode Register W (TMRW) .....
12.3.2	Timer Control Register W (TCRW) .....
12.3.3	Timer Interrupt Enable Register W (TIERW) .....
12.3.4	Timer Status Register W (TSRW) .....
12.3.5	Timer I/O Control Register 0 (TIOR0) .....
12.3.6	Timer I/O Control Register 1 (TIOR1) .....
12.3.7	Timer Counter (TCNT).....
12.3.8	General Registers A to D (GRA to GRD).....
12.4	Operation .....
12.4.1	Normal Operation .....
12.4.2	PWM Operation .....
12.5	Operation Timing .....
12.5.1	TCNT Count Timing .....
12.5.2	Output Compare Output Timing .....
12.5.3	Input Capture Timing.....
12.5.4	Timing of Counter Clearing by Compare Match .....
12.5.5	Buffer Operation Timing .....
12.5.6	Timing of IMFA to IMFD Flag Setting at Compare Match.....
12.5.7	Timing of IMFA to IMFD Setting at Input Capture .....
12.5.8	Timing of Status Flag Clearing.....
12.6	Usage Notes .....
Section 13	Watchdog Timer .....
13.1	Features .....
13.2	Register Descriptions .....

14.3.3	Transmit Shift Register (TSR) .....
14.3.4	Transmit Data Register (TDR) .....
14.3.5	Serial Mode Register (SMR) .....
14.3.6	Serial Control Register 3 (SCR3) .....
14.3.7	Serial Status Register (SSR) .....
14.3.8	Bit Rate Register (BRR) .....
14.4	Operation in Asynchronous Mode .....
14.4.1	Clock .....
14.4.2	SCI3 Initialization .....
14.4.3	Data Transmission .....
14.4.4	Serial Data Reception .....
14.5	Operation in Clocked Synchronous Mode .....
14.5.1	Clock .....
14.5.2	SCI3 Initialization .....
14.5.3	Serial Data Transmission .....
14.5.4	Serial Data Reception (Clocked Synchronous Mode) .....
14.5.5	Simultaneous Serial Data Transmission and Reception .....
14.6	Multiprocessor Communication Function .....
14.6.1	Multiprocessor Serial Data Transmission .....
14.6.2	Multiprocessor Serial Data Reception .....
14.7	Interrupts .....
14.8	Usage Notes .....
14.8.1	Break Detection and Processing .....
14.8.2	Mark State and Break Sending .....
14.8.3	Receive Error Flags and Transmit Operations (Clocked Synchronous Mode Only) .....
14.8.4	Receive Data Sampling Timing and Reception Margin in Asynchronous Mode .....



15.3.8	I <sup>2</sup> C Bus Receive Data Register (ICDRR).....	
15.3.9	I <sup>2</sup> C Bus Shift Register (ICDRS).....	
15.4	Operation .....	
15.4.1	I <sup>2</sup> C Bus Format.....	
15.4.2	Master Transmit Operation .....	
15.4.3	Master Receive Operation.....	
15.4.4	Slave Transmit Operation .....	
15.4.5	Slave Receive Operation.....	
15.4.6	Clocked Synchronous Serial Format.....	
15.4.7	Noise Canceler.....	
15.4.8	Example of Use.....	
15.5	Interrupt Request.....	
15.6	Bit Synchronous Circuit.....	
15.7	Usage Notes .....	
15.7.1	Issue (Retransmission) of Start/Stop Conditions .....	
15.7.2	WAIT Setting in I <sup>2</sup> C Bus Mode Register (ICMR) .....	
Section 16 A/D Converter.....		
16.1	Features.....	
16.2	Input/Output Pins .....	
16.3	Register Descriptions .....	
16.3.1	A/D Data Registers A to D (ADDRA to ADDR D) .....	
16.3.2	A/D Control/Status Register (ADCSR) .....	
16.3.3	A/D Control Register (ADCR) .....	
16.4	Operation .....	
16.4.1	Single Mode.....	
16.4.2	Scan Mode .....	
16.4.3	Input Sampling and A/D Conversion Time .....	
16.4.4	External Trigger Input Timing.....	

17.4.1	EEPROM Interface.....
17.4.2	Bus Format and Timing.....
17.4.3	Start Condition.....
17.4.4	Stop Condition.....
17.4.5	Acknowledge.....
17.4.6	Slave Addressing.....
17.4.7	Write Operations.....
17.4.8	Acknowledge Polling.....
17.4.9	Read Operation.....
17.5	Usage Notes.....
17.5.1	Data Protection at $V_{cc}$ On/Off.....
17.5.2	Write/Erase Endurance.....
17.5.3	Noise Suppression Time.....
Section 18	Power-On Reset and Low-Voltage Detection Circuits (Option.....)
18.1	Features.....
18.2	Register Descriptions.....
18.2.1	Low-Voltage-Detection Control Register (LVDCR).....
18.2.2	Low-Voltage-Detection Status Register (LVDSR).....
18.3	Operation.....
18.3.1	Power-On Reset Circuit.....
18.3.2	Low-Voltage Detection Circuit.....
Section 19	Power Supply Circuit.....
19.1	When Using Internal Power Supply Step-Down Circuit.....
19.2	When Not Using Internal Power Supply Step-Down Circuit.....
Section 20	List of Registers.....
20.1	Register Addresses (Address Order).....

21.2.5	Watchdog Timer Characteristics.....
21.2.6	Flash Memory Characteristics .....
21.2.7	EEPROM Characteristics.....
21.2.8	Power-Supply-Voltage Detection Circuit Characteristics (Optional) .....
21.2.9	Power-On Reset Circuit Characteristics (Optional).....
21.3	Electrical Characteristics (Mask-ROM Version, EEPROM Stacked Mask-ROM Version).....
21.3.1	Power Supply Voltage and Operating Ranges .....
21.3.2	DC Characteristics .....
21.3.3	AC Characteristics .....
21.3.4	A/D Converter Characteristics .....
21.3.5	Watchdog Timer Characteristics.....
21.3.6	EEPROM Characteristics.....
21.3.7	Power-Supply-Voltage Detection Circuit Characteristics (Optional) .....
21.3.8	Power-On Reset Circuit Characteristics (Optional).....
21.4	Operation Timing.....
21.5	Output Load Condition .....

Appendix A	Instruction Set .....
A.1	Instruction List.....
A.2	Operation Code Map.....
A.3	Number of Execution States .....
A.4	Combinations of Instructions and Addressing Modes .....

Appendix B	I/O Port Block Diagrams.....
B.1	I/O Port Block Diagrams.....
B.2	Port States in Each Operating State .....

Appendix C	Product Code Lineup.....
------------	--------------------------



## **Section 2 CPU**

Figure 2.1	Memory Map (1)	.....
Figure 2.1	Memory Map (2)	.....
Figure 2.1	Memory Map (3)	.....
Figure 2.2	CPU Registers	.....
Figure 2.3	Usage of General Registers	.....
Figure 2.4	Relationship between Stack Pointer and Stack Area	.....
Figure 2.5	General Register Data Formats (1)	.....
Figure 2.5	General Register Data Formats (2)	.....
Figure 2.6	Memory Data Formats	.....
Figure 2.7	Instruction Formats	.....
Figure 2.8	Branch Address Specification in Memory Indirect Mode	.....
Figure 2.9	On-Chip Memory Access Cycle	.....
Figure 2.10	On-Chip Peripheral Module Access Cycle (3-State Access)	.....
Figure 2.11	CPU Operation States	.....
Figure 2.12	State Transitions	.....
Figure 2.13	Example of Timer Configuration with Two Registers Allocated to Same A	.....

## **Section 3 Exception Handling**

Figure 3.1	Reset Sequence	.....
Figure 3.2	Stack Status after Exception Handling	.....
Figure 3.3	Interrupt Sequence	.....
Figure 3.4	Port Mode Register Setting and Interrupt Request Flag Clearing Procedure	.....

## **Section 4 Address Break**

Figure 4.1	Block Diagram of Address Break	.....
Figure 4.2	Address Break Interrupt Operation Example (1)	.....
Figure 4.2	Address Break Interrupt Operation Example (2)	.....

Figure 5.10	Pin Connection when not Using Subclock .....
Figure 5.11	Example of Incorrect Board Design .....
<b>Section 6 Power-Down Modes</b>	
Figure 6.1	Mode Transition Diagram .....
<b>Section 7 ROM</b>	
Figure 7.1	Flash Memory Block Configuration.....
Figure 7.2	Programming/Erasing Flowchart Example in User Program Mode.....
Figure 7.3	Program/Program-Verify Flowchart .....
Figure 7.4	Erase/Erase-Verify Flowchart .....
<b>Section 9 I/O Ports</b>	
Figure 9.1	Port 1 Pin Configuration.....
Figure 9.2	Port 2 Pin Configuration.....
Figure 9.3	Port 5 Pin Configuration.....
Figure 9.4	Port 7 Pin Configuration.....
Figure 9.5	Port 8 Pin Configuration.....
Figure 9.6	Port B Pin Configuration.....
<b>Section 10 Timer A</b>	
Figure 10.1	Block Diagram of Timer A .....
<b>Section 11 Timer V</b>	
Figure 11.1	Block Diagram of Timer V .....
Figure 11.2	Increment Timing with Internal Clock.....
Figure 11.3	Increment Timing with External Clock.....
Figure 11.4	OVF Set Timing .....
Figure 11.5	CMFA and CMFB Set Timing.....
Figure 11.6	TMOV Output Timing .....
Figure 11.7	Clear Timing by Compare Match.....
Figure 11.8	Clear Timing by TMRIV Input .....

Figure 12.5	Toggle Output Example (TOA = 0, TOB = 1)	.....
Figure 12.6	Toggle Output Example (TOA = 0, TOB = 1)	.....
Figure 12.7	Input Capture Operating Example	.....
Figure 12.8	Buffer Operation Example (Input Capture)	.....
Figure 12.9	PWM Mode Example (1)	.....
Figure 12.10	PWM Mode Example (2)	.....
Figure 12.11	Buffer Operation Example (Output Compare)	.....
Figure 12.12	PWM Mode Example (TOB, TOC, and TOD = 0: initial output values are set to 0)	.....
Figure 12.13	PWM Mode Example (TOB, TOC, and TOD = 1: initial output values are set to 1)	.....
Figure 12.14	Count Timing for Internal Clock Source	.....
Figure 12.15	Count Timing for External Clock Source	.....
Figure 12.16	Output Compare Output Timing	.....
Figure 12.17	Input Capture Input Signal Timing	.....
Figure 12.18	Timing of Counter Clearing by Compare Match	.....
Figure 12.19	Buffer Operation Timing (Compare Match)	.....
Figure 12.20	Buffer Operation Timing (Input Capture)	.....
Figure 12.21	Timing of IMFA to IMFD Flag Setting at Compare Match	.....
Figure 12.22	Timing of IMFA to IMFD Flag Setting at Input Capture	.....
Figure 12.23	Timing of Status Flag Clearing by CPU	.....
Figure 12.24	Contention between TCNT Write and Clear	.....
Figure 12.25	Internal Clock Switching and TCNT Operation	.....
Figure 12.26	When Compare Match and Bit Manipulation Instruction to TCRW Occur at the Same Timing	.....

### **Section 13 Watchdog Timer**

Figure 13.1	Block Diagram of Watchdog Timer	.....
Figure 13.2	Watchdog Timer Operation Example	.....

Figure 14.8	Sample Serial Data Reception Flowchart (Asynchronous mode) (1).....	(8-Bit Data, Parity, One Stop Bit)
Figure 14.8	Sample Serial Reception Data Flowchart (2) .....	
Figure 14.9	Data Format in Clocked Synchronous Communication .....	
Figure 14.10	Example of SCI3 Operation in Transmission in Clocked Synchronous Mode .....	
Figure 14.11	Sample Serial Transmission Flowchart (Clocked Synchronous Mode) .....	
Figure 14.12	Example of SCI3 Reception Operation in Clocked Synchronous Mode .....	
Figure 14.13	Sample Serial Reception Flowchart (Clocked Synchronous Mode).....	
Figure 14.14	Sample Flowchart of Simultaneous Serial Transmit and Receive Operations (Clocked Synchronous Mode) .....	
Figure 14.15	Example of Communication Using Multiprocessor Format (Transmission of Data H'AA to Receiving Station A) .....	
Figure 14.16	Sample Multiprocessor Serial Transmission Flowchart .....	
Figure 14.17	Sample Multiprocessor Serial Reception Flowchart (1).....	
Figure 14.17	Sample Multiprocessor Serial Reception Flowchart (2).....	
Figure 14.18	Example of SCI3 Operation in Reception Using Multiprocessor Format (Example with 8-Bit Data, Multiprocessor Bit, One Stop Bit) .....	
Figure 14.19	Receive Data Sampling Timing in Asynchronous Mode .....	

## **Section 15 I<sup>2</sup>C Bus Interface 2 (IIC2)**

Figure 15.1	Block Diagram of I <sup>2</sup> C Bus Interface 2.....
Figure 15.2	External Circuit Connections of I/O Pins .....
Figure 15.3	I <sup>2</sup> C Bus Formats .....
Figure 15.4	I <sup>2</sup> C Bus Timing.....
Figure 15.5	Master Transmit Mode Operation Timing (1).....
Figure 15.6	Master Transmit Mode Operation Timing (2).....
Figure 15.7	Master Receive Mode Operation Timing (1) .....
Figure 15.8	Master Receive Mode Operation Timing (2) .....
Figure 15.9	Slave Transmit Mode Operation Timing (1).....
Figure 15.10	Slave Transmit Mode Operation Timing (2).....



## **Section 16 A/D Converter**

Figure 16.1	Block Diagram of A/D Converter .....
Figure 16.2	A/D Conversion Timing .....
Figure 16.3	External Trigger Input Timing .....
Figure 16.4	A/D Conversion Accuracy Definitions (1) .....
Figure 16.5	A/D Conversion Accuracy Definitions (2) .....
Figure 16.6	Analog Input Circuit Example .....

## **Section 17 EEPROM**

Figure 17.1	Block Diagram of EEPROM .....
Figure 17.2	EEPROM Bus Format and Bus Timing .....
Figure 17.3	Byte Write Operation .....
Figure 17.4	Page Write Operation .....
Figure 17.5	Current Address Read Operation .....
Figure 17.6	Random Address Read Operation .....
Figure 17.7	Sequential Read Operation (when current address read is used) .....

## **Section 18 Power-On Reset and Low-Voltage Detection Circuits (Optional)**

Figure 18.1	Block Diagram of Power-On Reset Circuit and Low-Voltage Detection Circuit .....
Figure 18.2	Operational Timing of Power-On Reset Circuit .....
Figure 18.3	Operational Timing of LVDR Circuit .....
Figure 18.4	Operational Timing of LVDI Circuit .....
Figure 18.5	Timing for Operation/Release of Low-Voltage Detection Circuit .....

## **Section 19 Power Supply Circuit**

Figure 19.1	Power Supply Connection when Internal Step-Down Circuit is Used .....
Figure 19.2	Power Supply Connection when Internal Step-Down Circuit is Not Used .....

## **Section 21 Electrical Characteristics**

Figure 21.1	System Clock Input Timing .....
Figure 21.2	$\overline{\text{RES}}$ Low Width Timing .....

Figure B.4	Port 1 Block Diagram (P10)	.....
Figure B.5	Port 2 Block Diagram (P22)	.....
Figure B.6	Port 2 Block Diagram (P21)	.....
Figure B.7	Port 2 Block Diagram (P20)	.....
Figure B.8	Port 5 Block Diagram (P57, P56)	.....
Figure B.9	Port 5 Block Diagram (P55)	.....
Figure B.10	Port 5 Block Diagram (P54 to P50)	.....
Figure B.11	Port 7 Block Diagram (P76)	.....
Figure B.12	Port 7 Block Diagram (P75)	.....
Figure B.13	Port 7 Block Diagram (P74)	.....
Figure B.14	Port 8 Block Diagram (P87 to P85)	.....
Figure B.15	Port 8 Block Diagram (P84 to P81)	.....
Figure B.16	Port 8 Block Diagram (P80)	.....
Figure B.17	Port B Block Diagram (PB7 to PB0)	.....

**Appendix D Package Dimensions**

Figure D.1	FP-64E Package Dimensions	.....
Figure D.2	FP-64A Package Dimensions	.....
Figure D.3	FP-48F Package Dimensions	.....
Figure D.4	FP-48B Package Dimensions	.....
Figure D.5	TNP-48 Package Dimensions	.....

**Appendix E EEPROM Stacked-Structure Cross-Sectional View**

Figure E.1	EEPROM Stacked-Structure Cross-Sectional View	.....
------------	---	-------

Table 2.5	Shift Instructions.....
Table 2.6	Bit Manipulation Instructions (1).....
Table 2.6	Bit Manipulation Instructions (2).....
Table 2.7	Branch Instructions.....
Table 2.8	System Control Instructions.....
Table 2.9	Block Data Transfer Instructions.....
Table 2.10	Addressing Modes.....
Table 2.11	Absolute Address Access Ranges.....
Table 2.12	Effective Address Calculation (1).....
Table 2.12	Effective Address Calculation (2).....
<b>Section 3 Exception Handling</b>	
Table 3.1	Exception Sources and Vector Address.....
Table 3.2	Interrupt Wait States.....
<b>Section 4 Address Break</b>	
Table 4.1	Access and Data Bus Used.....
<b>Section 5 Clock Pulse Generators</b>	
Table 5.1	Crystal Resonator Parameters.....
<b>Section 6 Power-Down Modes</b>	
Table 6.1	Operating Frequency and Waiting Time.....
Table 6.2	Transition Mode after SLEEP Instruction Execution and Interrupt Handl.....
Table 6.3	Internal State in Each Operating Mode.....
<b>Section 7 ROM</b>	
Table 7.1	Setting Programming Modes.....
Table 7.2	Boot Mode Operation.....
Table 7.3	System Clock Frequencies for which Automatic Adjustment of LSI Bit Rate is Possible.....
Table 7.4	Reprogram Data Computation Table.....

Table 12.1	Timer W Functions.....
Table 12.2	Pin Configuration.....

**Section 14 Serial Communication Interface 3 (SCI3)**

Table 14.1	Pin Configuration.....
Table 14.2	Examples of BRR Settings for Various Bit Rates (Asynchronous Mode) (1)
Table 14.2	Examples of BRR Settings for Various Bit Rates (Asynchronous Mode) (2)
Table 14.2	Examples of BRR Settings for Various Bit Rates (Asynchronous Mode) (3)
Table 14.3	Maximum Bit Rate for Each Frequency (Asynchronous Mode) .....
Table 14.4	Examples of BBR Setting for Various Bit Rates (Clocked Synchronous Mode) (1).....
Table 14.4	Examples of BRR Settings for Various Bit Rates (Clocked Synchronous Mode) (2).....
Table 14.5	SSR Status Flags and Receive Data Handling .....
Table 14.6	SCI3 Interrupt Requests.....

**Section 15 I<sup>2</sup>C Bus Interface 2 (IIC2)**

Table 15.1	I <sup>2</sup> C Bus Interface Pins.....
Table 15.2	Transfer Rate .....
Table 15.3	Interrupt Requests.....
Table 15.4	Time for Monitoring SCL.....

**Section 16 A/D Converter**

Table 16.1	Pin Configuration.....
Table 16.2	Analog Input Channels and Corresponding ADDR Registers.....
Table 16.3	A/D Conversion Time (Single Mode).....

**Section 17 EEPROM**

Table 17.1	Pin Configuration.....
Table 17.2	Slave Addresses.....

Table 21.6	A/D Converter Characteristics .....
Table 21.7	Watchdog Timer Characteristics .....
Table 21.8	Flash Memory Characteristics .....
Table 21.9	EEPROM Characteristics .....
Table 21.10	Power-Supply-Voltage Detection Circuit Characteristics .....
Table 21.11	Power-On Reset Circuit Characteristics .....
Table 21.12	DC Characteristics (1) .....
Table 21.12	DC Characteristics (2) .....
Table 21.12	DC Characteristics (3) .....
Table 21.13	AC Characteristics .....
Table 21.14	I <sup>2</sup> C Bus Interface Timing .....
Table 21.15	Serial Communication Interface (SCI) Timing .....
Table 21.16	A/D Converter Characteristics .....
Table 21.17	Watchdog Timer Characteristics .....
Table 21.18	EEPROM Characteristics .....
Table 21.19	Power-Supply-Voltage Detection Circuit Characteristics .....
Table 21.20	Power-On Reset Circuit Characteristics .....

## **Appendix A Instruction Set**

Table A.1	Instruction Set .....
Table A.2	Operation Code Map (1) .....
Table A.2	Operation Code Map (2) .....
Table A.2	Operation Code Map (3) .....
Table A.3	Number of Cycles in Each Instruction .....
Table A.4	Number of Cycles in Each Instruction .....
Table A.5	Combinations of Instructions and Addressing Modes .....



- Timer A (can be used as a time base for a clock)
- Timer V (8-bit timer)
- Timer W (16-bit timer)
- Watchdog timer
- SCI (Asynchronous or clocked synchronous serial communication interface)
- I<sup>2</sup>C Bus Interface (conforms to the I<sup>2</sup>C bus interface format that is advocated by Philips Electronics)
- 10-bit A/D converter

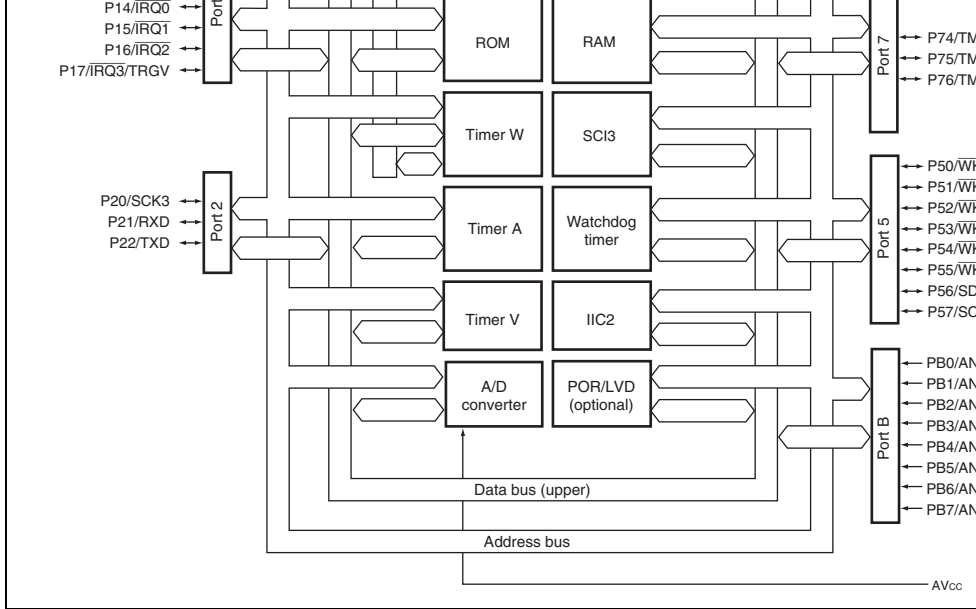
		H8/3694	HD6433694	HD6433694G	32 kbytes	1,024 bytes
		H8/3693	HD6433693	HD6433693G	24 kbytes	1,024 bytes
		H8/3692	HD6433692	HD6433692G	16 kbytes	512 bytes
		H8/3691	HD6433691	HD6433691G	12 kbytes	512 bytes
		H8/3690	HD6433690	HD6433690G	8 kbytes	512 bytes
EEPROM stacked version (512 bytes)	Flash memory version	H8/3694N	—	HD64N3694G	32 kbytes	2,048 bytes
	Mask-ROM version		—	HD6483694G	32 kbytes	1,024 bytes

- General I/O ports
  - I/O pins: 29 I/O pins (27 I/O pins for H8/3694N), including 8 large current ports (100 mA, @V<sub>OL</sub> = 1.5 V)
  - Input-only pins: 8 input pins (also used for analog input)
- EEPROM interface (only for H8/3694N)
  - I<sup>2</sup>C bus interface (conforms to the I<sup>2</sup>C bus interface format that is advocated by Philips Electronics)
- Supports various power-down modes

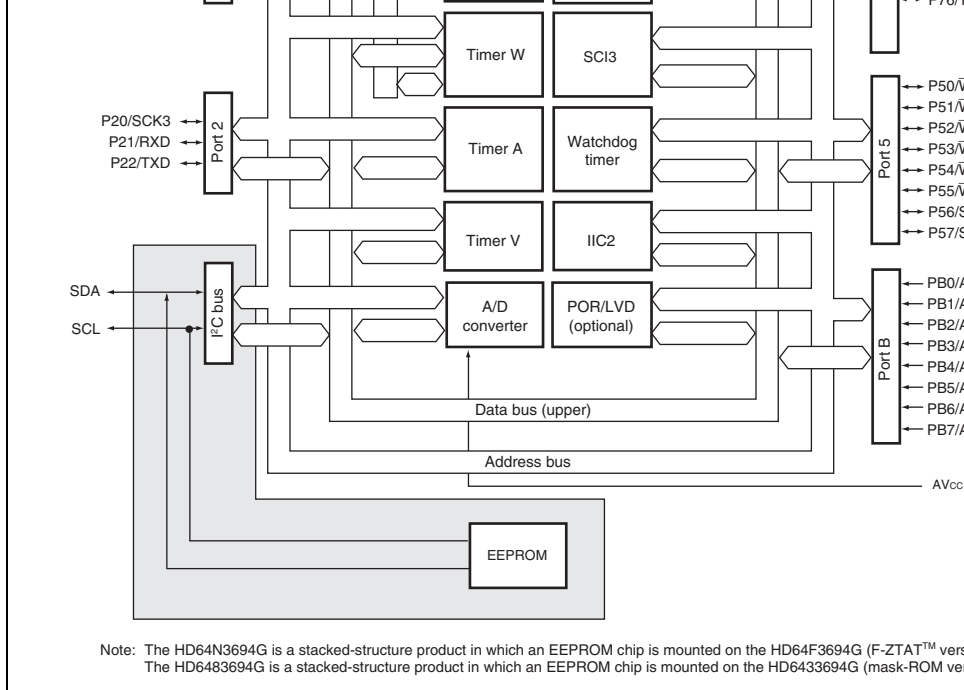
Note: F-ZTAT™ is a trademark of Renesas Technology Corp.



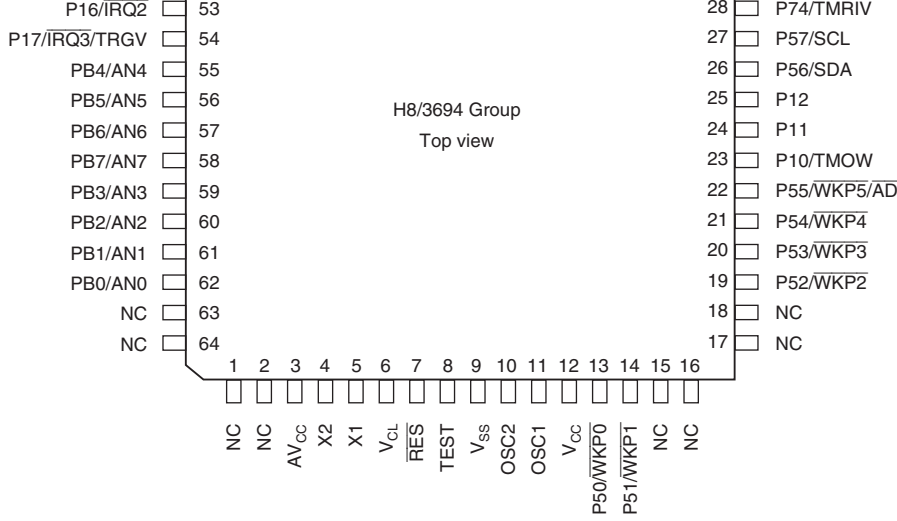




**Figure 1.1 Internal Block Diagram of H8/3694 Group of F-ZTAT™ and Mask-ROM Versions**

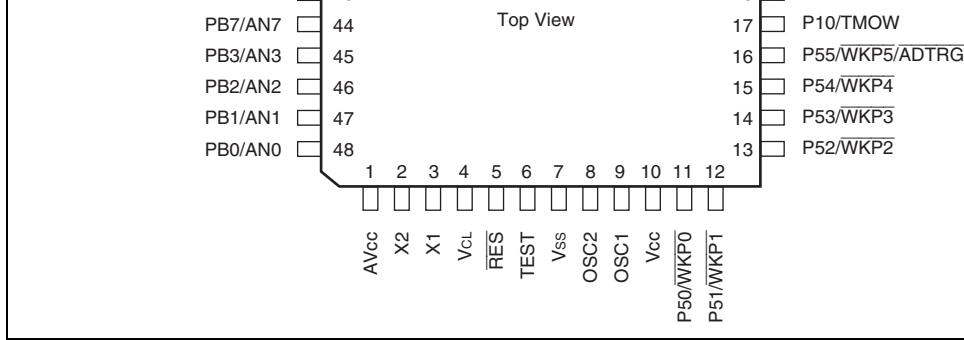


**Figure 1.2 Internal Block Diagram of H8/3694N (EEPROM Stacked Version)**

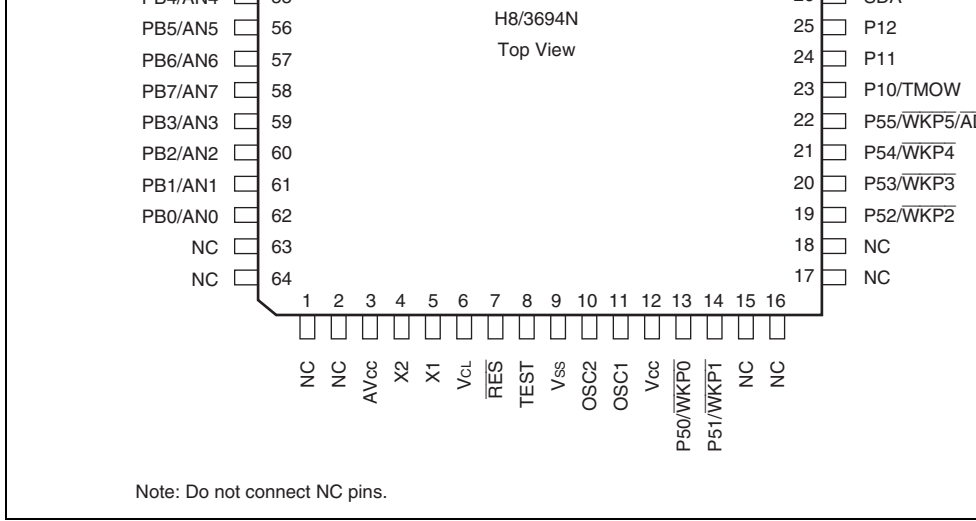


Note: Do not connect NC pins (these pins are not connected to the internal circuitry).

**Figure 1.3 Pin Arrangement of H8/3694 Group of F-ZTAT™ and Mask-ROM V (FP-64E, FP-64A)**



**Figure 1.4 Pin Arrangement of H8/3694 Group of F-ZTAT™ and Mask-ROM V (FP-48F, FP-48B, TNP-48)**



**Figure 1.5 Pin Arrangement of H8/3694N (EEPROM Stacked Version)  
(FP-64E)**

	$AV_{CC}$	3	1	Input	power supply (UV). Analog power supply pin for the A/D converter. When the A/D converter is not used, connect this pin to the system power supply.
	$V_{CL}$	6	4	Input	Internal step-down power supply pin. Connect a capacitor of around 0.1 $\mu$ F between this pin and the Vss pin for stabilization.
Clock pins	OSC1	11	9	Input	These pins connect with crystal or ceramic resonator for the system clock, or can be used to input an external clock.  See section 5, Clock Pulse Generator for a typical connection.
	OSC2	10	8	Output	
	X1	5	3	Input	These pins connect with a 32.768 kHz resonator for the subclock. See section 5, Clock Pulse Generators, for a typical connection.
X2	4	2	Output		
System control	$\overline{RES}$	7	5	Input	Reset pin. The pull-up resistor (typ. 10 k $\Omega$ ) is incorporated. When driven low, the chip resets.
	TEST	8	6	Input	Test pin. Connect this pin to Vss.
Interrupt pins	$\overline{NMI}$	35	25	Input	Non-maskable interrupt request input pin. Be sure to pull-up by a pull-up resistor.
	$\overline{IRQ0}$ to $\overline{IRQ3}$	51 to 54	37 to 40	Input	External interrupt request input pins. Connect to the rising or falling edge.
	$\overline{WKP0}$ to $\overline{WKP5}$	13, 14, 19 to 22	11 to 16	Input	External interrupt request input pins. Connect to the rising or falling edge.

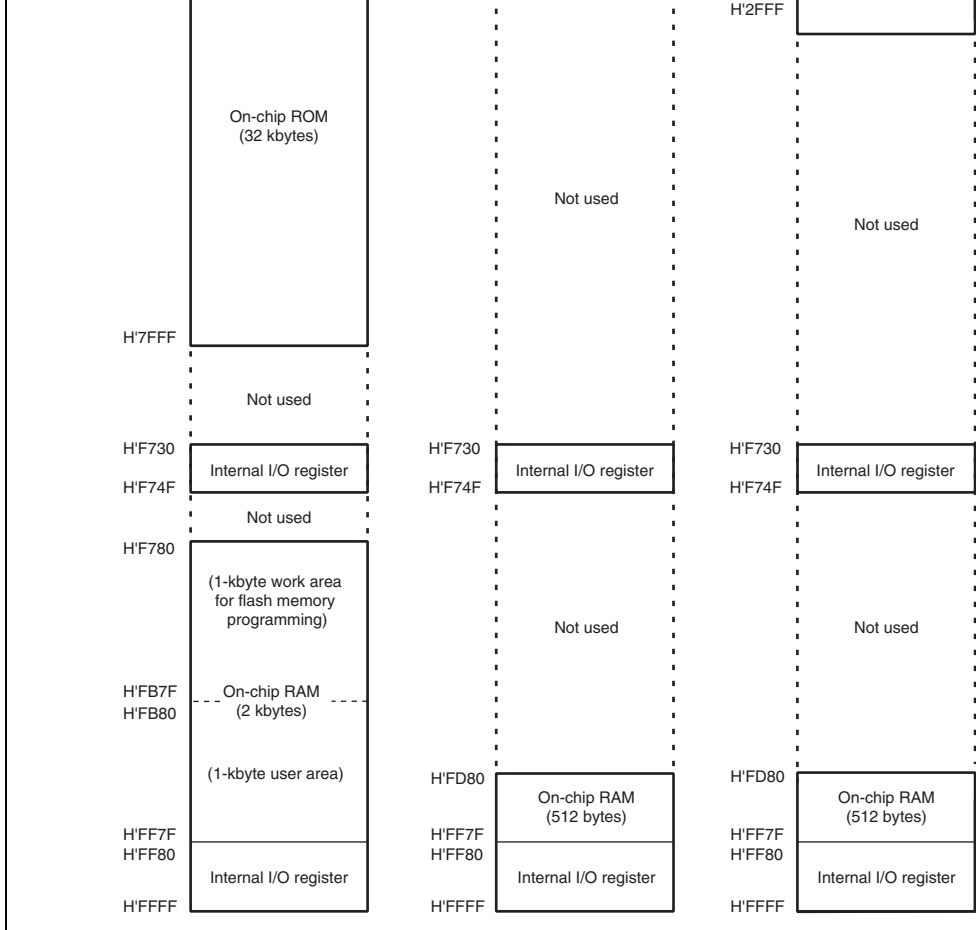
Timer W	FTCI	36	26	Input	External event input pin.
	FTIOA to FTIOD	37 to 40	27 to 30	I/O	Output compare output/input capture PWM output pin
I <sup>2</sup> C bus interface (IIC)	SDA	26* <sup>1</sup>	20	I/O	IIC data I/O pin. Can directly drive NMOS open-drain output.
	SCL	27* <sup>1</sup>	21	I/O (EEPROM: Input)	IIC clock I/O pin. Can directly drive by NMOS open-drain output.
Serial communication interface (SCI)	TXD	46	36	Output	Transmit data output pin
	RXD	45	35	Input	Receive data input pin
	SCK3	44	34	I/O	Clock I/O pin
A/D converter	AN7 to AN0	55 to 62	41 to 48	Input	Analog input pin
	ADTRG	22	16	Input	A/D converter trigger input pin.
I/O ports	PB7 to PB0	55 to 62	41 to 48	Input	8-bit input port.
	P17 to P14, P12 to P10	51 to 54, 23 to 25	37 to 40, 17 to 19	I/O	7-bit I/O port.
	P22 to P20	44 to 46	34 to 36	I/O	3-bit I/O port.
	P57 to P50	13, 14, 19 to 22, 26* <sup>2</sup> , 27* <sup>2</sup>	20, 21, 13 to 16, 11, 12	I/O	8-bit I/O port



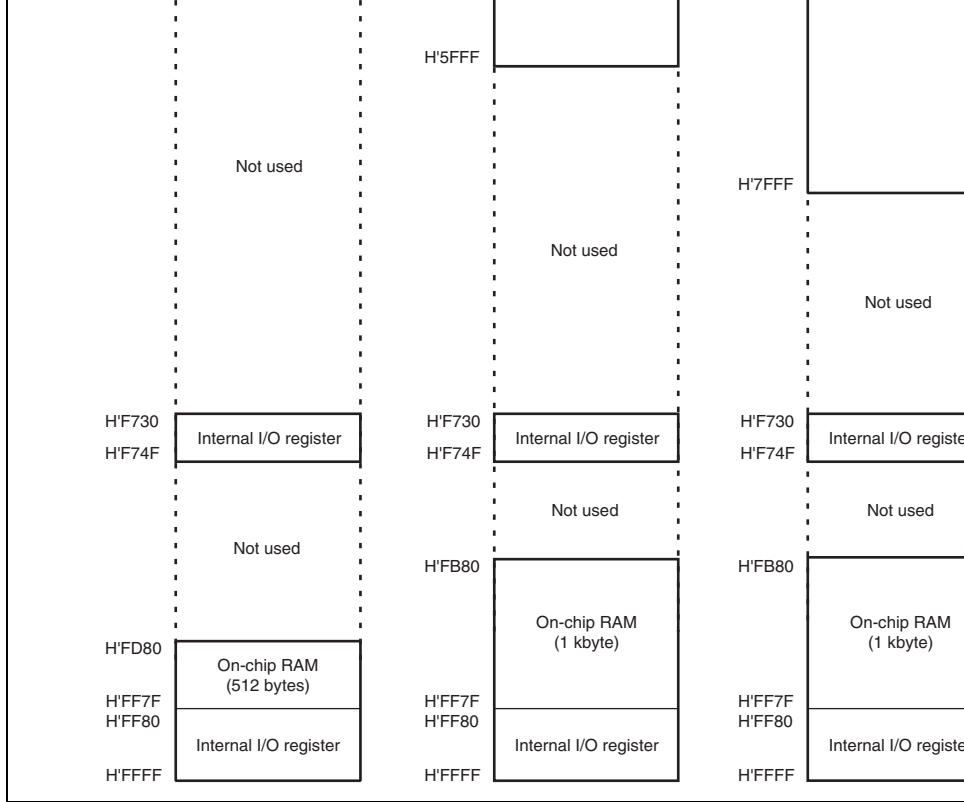
2. The P57 and P56 pins are not available in the H8/3694N.



- General-register architecture
  - Sixteen 16-bit general registers also usable as sixteen 8-bit registers and eight 16-bit registers, or eight 32-bit registers
- Sixty-two basic instructions
  - 8/16/32-bit data transfer and arithmetic and logic instructions
  - Multiply and divide instructions
  - Powerful bit-manipulation instructions
- Eight addressing modes
  - Register direct [Rn]
  - Register indirect [@ERn]
  - Register indirect with displacement [@(d:16,ERn) or @(d:24,ERn)]
  - Register indirect with post-increment or pre-decrement [@ERn+ or @-ERn]
  - Absolute address [@aa:8, @aa:16, @aa:24]
  - Immediate [#xx:8, #xx:16, or #xx:32]
  - Program-counter relative [@(d:8,PC) or @(d:16,PC)]
  - Memory indirect [@@aa:8]
- 64-kbyte address space
- High-speed operation
  - All frequently-used instructions execute in one or two states
  - 8/16/32-bit register-register add/subtract : 2 state
  - $8 \times 8$ -bit register-register multiply : 14 states
  - $16 \div 8$ -bit register-register divide : 14 states
  - $16 \times 16$ -bit register-register multiply : 22 states
  - $32 \div 16$ -bit register-register divide : 22 states
- Power-down state
  - Transition to power-down state by SLEEP instruction



**Figure 2.1 Memory Map (1)**



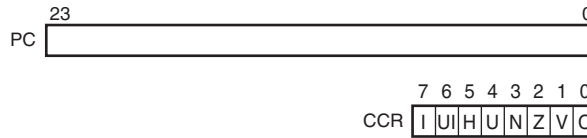
**Figure 2.1 Memory Map (2)**



**Figure 2.1 Memory Map (3)**

ER3	E3	R3H	R3L
ER4	E4	R4H	R4L
ER5	E5	R5H	R5L
ER6	E6	R6H	R6L
ER7	E7	(SP) R7H	R7L

Control Registers (CR)



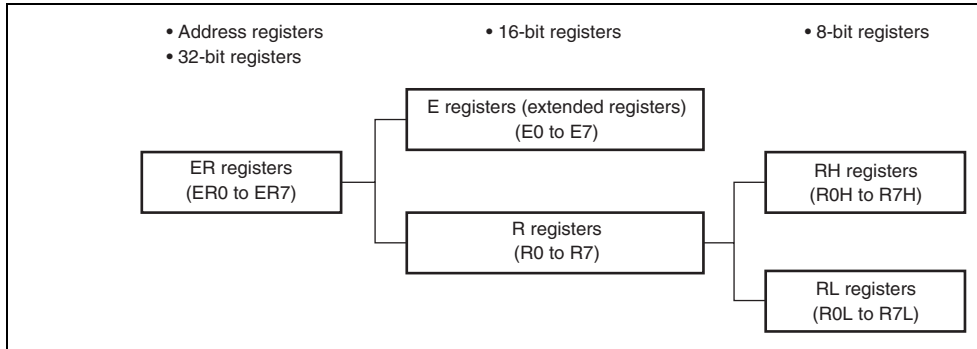
[Legend]

- |                              |                    |
|------------------------------|--------------------|
| SP: Stack pointer            | H: Half-carry flag |
| PC: Program counter          | U: User bit        |
| CCR: Condition-code register | N: Negative flag   |
| I: Interrupt mask bit        | Z: Zero flag       |
| UI: User bit                 | V: Overflow flag   |
|                              | C: Carry flag      |

**Figure 2.2 CPU Registers**

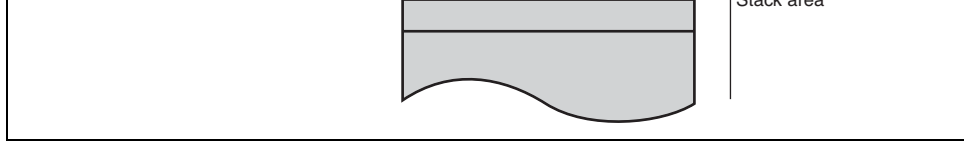
The R registers divide into 8-bit registers designated by the letters RH (R0H to R7H) and to R7L). These registers are functionally equivalent, providing a maximum of sixteen 8-bit registers.

The usage of each register can be selected independently.



**Figure 2.3 Usage of General Registers**





**Figure 2.4 Relationship between Stack Pointer and Stack Area**

### 2.2.2 Program Counter (PC)

This 24-bit counter indicates the address of the next instruction the CPU will execute. The least significant bit of all CPU instructions is 2 bytes (one word), so the least significant PC bit is ignored. (When an instruction is fetched, the least significant PC bit is regarded as 0). The PC is initialized to the start address is loaded by the vector address generated during reset exception-handling sequence.

### 2.2.3 Condition-Code Register (CCR)

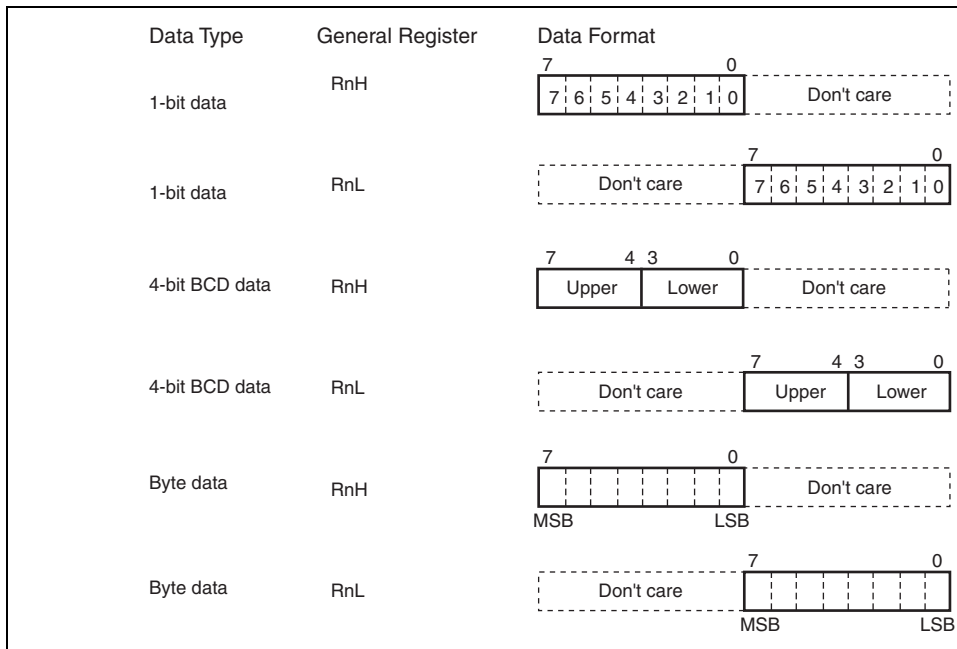
This 8-bit register contains internal CPU status information, including an interrupt mask (I), half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags. The I bit is initialized by reset exception-handling sequence, but other bits are not initialized.

Some instructions leave flag bits unchanged. Operations can be performed on the CCR by LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used as conditions for conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see appendix A.1, Instruction List.

When the ADD.B, ADDX.B, SUB.B, SUBX.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise. When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

4	U	Undefined	R/W	User Bit  Can be written and read by software using the STC, ANDC, ORC, and XORC instructions.
3	N	Undefined	R/W	Negative Flag  Stores the value of the most significant bit of data. Set to 1 if the sign bit is 1, and cleared to 0 otherwise.
2	Z	Undefined	R/W	Zero Flag  Set to 1 to indicate zero data, and cleared to 0 otherwise. Set to 1 to indicate non-zero data.
1	V	Undefined	R/W	Overflow Flag  Set to 1 when an arithmetic overflow occurs, and cleared to 0 at other times.
0	C	Undefined	R/W	Carry Flag  Set to 1 when a carry occurs, and cleared to 0 otherwise. Used by: <ul style="list-style-type: none"> <li>• Add instructions, to indicate a carry</li> <li>• Subtract instructions, to indicate a borrow</li> <li>• Shift and rotate instructions, to indicate a carry</li> </ul> The carry flag is also used as a bit accumulator for shift and rotate manipulation instructions.



**Figure 2.5 General Register Data Formats (1)**

MSB

[Legend]

ERn: General register ER

En: General register E

Rn: General register R

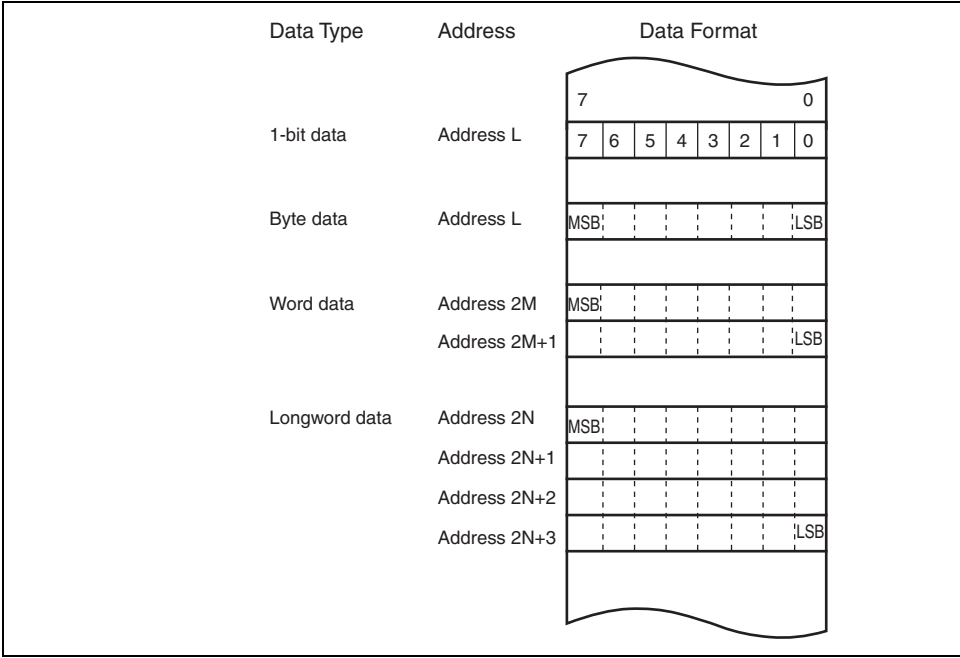
RnH: General register RH

RnL: General register RL

MSB: Most significant bit

LSB: Least significant bit

**Figure 2.5 General Register Data Formats (2)**



**Figure 2.6 Memory Data Formats**

Rs	General register (source)*
Rn	General register*
ERn	General register (32-bit register or address register)
(EAd)	Destination operand
(EAs)	Source operand
CCR	Condition-code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
C	C (carry) flag in CCR
PC	Program counter
SP	Stack pointer
#IMM	Immediate data
disp	Displacement
+	Addition
-	Subtraction
×	Multiplication
÷	Division
^	Logical AND
∨	Logical OR
⊕	Logical XOR
→	Move
¬	NOT (logical complement)
:3/:8/:16/:24	3-, 8-, 16-, or 24-bit length

Note: \* General registers include 8-bit registers (R0H to R7H, R0L to R7L), 16-bit registers (R8 to R7, E0 to E7), and 32-bit registers/address register (ER0 to ER7).

PUSH	W/L	Rn → @-SP Pushes a general register onto the stack. PUSH.W Rn is identical to MOV.W Rn, @-SP. PUSH.L ERn is identical to MOV.L ERn, @-SP.
------	-----	--

---

Note: \* Refers to the operand size.

B: Byte

W: Word

L: Longword

DEC		Increments or decrements a general register by 1 or 2. (Byte operations can be incremented or decremented by 1 only.)
ADDS SUBS	L	$Rd \pm 1 \rightarrow Rd$ , $Rd \pm 2 \rightarrow Rd$ , $Rd \pm 4 \rightarrow Rd$ Adds or subtracts the value 1, 2, or 4 to or from data in a 32-bit register.
DAA DAS	B	$Rd$ decimal adjust $\rightarrow Rd$ Decimal-adjusts an addition or subtraction result in a general register referring to the CCR to produce 4-bit BCD data.
MULXU	B/W	$Rd \times Rs \rightarrow Rd$ Performs unsigned multiplication on data in two general registers: 8 bits $\times$ 8 bits $\rightarrow$ 16 bits or 16 bits $\times$ 16 bits $\rightarrow$ 32 bits.
MULXS	B/W	$Rd \times Rs \rightarrow Rd$ Performs signed multiplication on data in two general registers: 8 bits $\times$ 8 bits $\rightarrow$ 16 bits or 16 bits $\times$ 16 bits $\rightarrow$ 32 bits.
DIVXU	B/W	$Rd \div Rs \rightarrow Rd$ Performs unsigned division on data in two general registers: either 8 bits $\div$ 8 bits $\rightarrow$ 8-bit quotient and 8-bit remainder or 32 bits $\div$ 16 bits $\rightarrow$ 16-bit quotient and 16-bit remainder.

Note: \* Refers to the operand size.

B: Byte

W: Word

L: Longword



		Takes the two's complement (arithmetic complement) of data in the general register.
EXTU	W/L	Rd (zero extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the lower 16 bits of a 32-bit register to longword size, by padding with zeros on the left.
EXTS	W/L	Rd (sign extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the lower 16 bits of a 32-bit register to longword size, by extending the sign bit.

Note: \* Refers to the operand size.

B: Byte

W: Word

L: Longword

NOT	B/W/L	$\neg$ (Rd) $\rightarrow$ (Rd) Takes the one's complement (logical complement) of general register contents.
-----	-------	---

Note: \* Refers to the operand size.  
 B: Byte  
 W: Word  
 L: Longword

**Table 2.5 Shift Instructions**

Instruction	Size*	Function
SHAL SHAR	B/W/L	Rd (shift) $\rightarrow$ Rd Performs an arithmetic shift on general register contents.
SHLL SHLR	B/W/L	Rd (shift) $\rightarrow$ Rd Performs a logical shift on general register contents.
ROTL ROTR	B/W/L	Rd (rotate) $\rightarrow$ Rd Rotates general register contents.
ROTXL ROTXR	B/W/L	Rd (rotate) $\rightarrow$ Rd Rotates general register contents through the carry flag.

Note: \* Refers to the operand size.  
 B: Byte  
 W: Word  
 L: Longword

Inverts a specified bit in a general register or memory operand. The bit number is specified by 3-bit immediate data or the lower three bits of a general register.

BTST	B	$\neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow Z$ Tests a specified bit in a general register or memory operand and sets the Z flag if the bit is 0 or clears the Z flag accordingly. The bit number is specified by 3-bit immediate data or the lower three bits of a general register.
BAND	B	$C \wedge (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ANDs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIAND	B	$C \wedge \neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ANDs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag. The bit number is specified by 3-bit immediate data.
BOR	B	$C \vee (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIOR	B	$C \vee \neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag. The bit number is specified by 3-bit immediate data.

Note: \* Refers to the operand size.  
B: Byte

		carry flag.
BILD	B	$\neg$ (<bit-No.> of <EAd>) $\rightarrow$ C Transfers the inverse of a specified bit in a general register or memory operand to the carry flag. The bit number is specified by 3-bit immediate data.
BST	B	C $\rightarrow$ (<bit-No.> of <EAd>) Transfers the carry flag value to a specified bit in a general register or memory operand.
BIST	B	$\neg$ C $\rightarrow$ (<bit-No.> of <EAd>) Transfers the inverse of the carry flag value to a specified bit in a general register or memory operand. The bit number is specified by 3-bit immediate data.

Note: \* Refers to the operand size.

B: Byte

BCC(BHS)		Carry clear (high or same)	$C = 0$
BCS(BLO)		Carry set (low)	$C = 1$
BNE		Not equal	$Z = 0$
BEQ		Equal	$Z = 1$
BVC		Overflow clear	$V = 0$
BVS		Overflow set	$V = 1$
BPL		Plus	$N = 0$
BMI		Minus	$N = 1$
BGE		Greater or equal	$N \oplus V = 0$
BLT		Less than	$N \oplus V = 1$
BGT		Greater than	$Z \vee (N \oplus V) = 0$
BLE		Less or equal	$Z \vee (N \oplus V) = 1$
JMP	—	Branches unconditionally to a specified address.	
BSR	—	Branches to a subroutine at a specified address.	
JSR	—	Branches to a subroutine at a specified address.	
RTS	—	Returns from a subroutine	

Note : \* Bcc is the general name for conditional branch instructions.

code register size is one byte, but in transfer to memory, data is transferred by word access.

---

ANDC	B	$CCR \wedge \#IMM \rightarrow CCR$ Logically ANDs the CCR with immediate data.
ORC	B	$CCR \vee \#IMM \rightarrow CCR$ Logically ORs the CCR with immediate data.
XORC	B	$CCR \oplus \#IMM \rightarrow CCR$ Logically XORs the CCR with immediate data.
NOP	—	$PC + 2 \rightarrow PC$ Only increments the program counter.

---

Note: \* Refers to the operand size.

B: Byte

W: Word

else next;

Transfers a data block. Starting from the address set in ER5, the processor transfers data for the number of bytes set in R4L or R4 to the address location set in ER6.

Execution of the next instruction begins as soon as the transfer is completed.

---

## 2.4.2 Basic Instruction Formats

H8/300H CPU instructions consist of 2-byte (1-word) units. An instruction consists of an operation field (op), a register field (r), an effective address extension (EA), and a condition code field (cc).

Figure 2.7 shows examples of instruction formats.

- **Operation Field**  
Indicates the function of the instruction, the addressing mode, and the operation to be performed on the operand. The operation field always includes the first four bits of the instruction. Some instructions have two operation fields.
- **Register Field**  
Specifies a general register. Address registers are specified by 3 bits, and data registers by 4 bits. Some instructions have two register fields. Some have no register field.
- **Effective Address Extension**  
8, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. An address or displacement is treated as a 32-bit data in which the first 8 bits are 0 (H'00).
- **Condition Field**  
Specifies the branching condition of Bcc instructions.

(4) Operation field, effective address extension, and condition field



**Figure 2.7 Instruction Formats**

## 2.5 Addressing Modes and Effective Address Calculation

The following describes the H8/300H CPU. In this LSI, the upper eight bits are ignored in the generated 24-bit address, so the effective address is 16 bits.

### 2.5.1 Addressing Modes

The H8/300H CPU supports the eight addressing modes listed in table 2.10. Each instruction uses a subset of these addressing modes. Addressing modes that can be used differ depending on the instruction. For details, refer to appendix A.4, Combinations of Instructions and Addressing Modes.

Arithmetic and logic instructions can use the register direct and immediate modes. Data transfer instructions can use all addressing modes except program-counter relative and memory indirect. Bit manipulation instructions use register direct, register indirect, or the absolute addressing mode (@aa:8) to specify an operand, and register direct (BSET, BCLR, BNOT, and BTST instructions) or immediate (3-bit) addressing mode to specify a bit number in the operand.



7	Program-counter relative	@(d:8,PC)/@(d:16,PC)
8	Memory indirect	@aa:8

### Register Direct—Rn

The register field of the instruction specifies an 8-, 16-, or 32-bit general register containing the operand. R0H to R7H and R0L to R7L can be specified as 8-bit registers. R0 to R7 and ER0 to ER7 can be specified as 16-bit registers. ER0 to ER7 can be specified as 32-bit registers.

### Register Indirect—@ERn

The register field of the instruction code specifies an address register (ERn), the lower 24 bits of which contain the address of the operand on memory.

### Register Indirect with Displacement—@(d:16, ERn) or @(d:24, ERn)

A 16-bit or 24-bit displacement contained in the instruction is added to an address register specified by the register field of the instruction, and the lower 24 bits of the sum the address of the memory operand. A 16-bit displacement is sign-extended when added.

### Register Indirect with Post-Increment or Pre-Decrement—@ERn+ or @-ERn

- Register indirect with post-increment—@ERn+

The register field of the instruction code specifies an address register (ERn) the lower 24 bits of which contains the address of a memory operand. After the operand is accessed, 1, 2, or 4 is added to the address register contents (32 bits) and the sum is stored in the address register. The value added is 1 for byte access, 2 for word access, or 4 for longword access. For byte or longword access, the register value should be even.

For an 8-bit absolute address, the upper 16 bits are all assumed to be 1 (H'FFFF). For a 16-bit absolute address the upper 8 bits are a sign extension. A 24-bit absolute address can access the entire address space.

The access ranges of absolute addresses for the group of this LSI are those shown in table 2.11 because the upper 8 bits are ignored.

**Table 2.11 Absolute Address Access Ranges**

<b>Absolute Address</b>	<b>Access Range</b>
8 bits (@aa:8)	H'FF00 to H'FFFF
16 bits (@aa:16)	H'0000 to H'FFFF
24 bits (@aa:24)	H'0000 to H'FFFF

**Immediate—#xx:8, #xx:16, or #xx:32**

The instruction contains 8-bit (#xx:8), 16-bit (#xx:16), or 32-bit (#xx:32) immediate data as an operand.

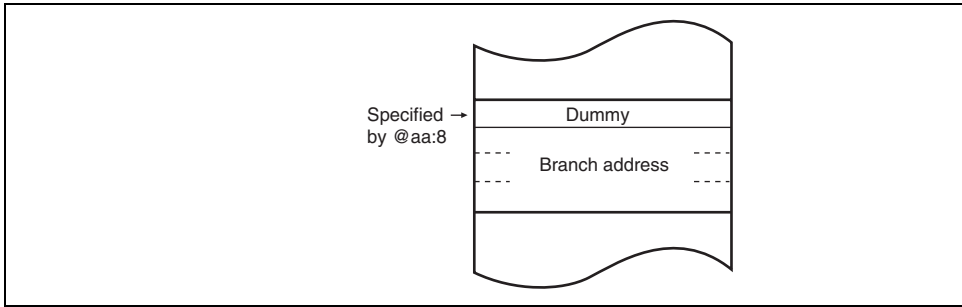
The ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. Some manipulation instructions contain 3-bit immediate data in the instruction code, specifying a constant number. The TRAPA instruction contains 2-bit immediate data in its instruction code, specifying a vector address.

**Program-Counter Relative—@(d:8, PC) or @(d:16, PC)**

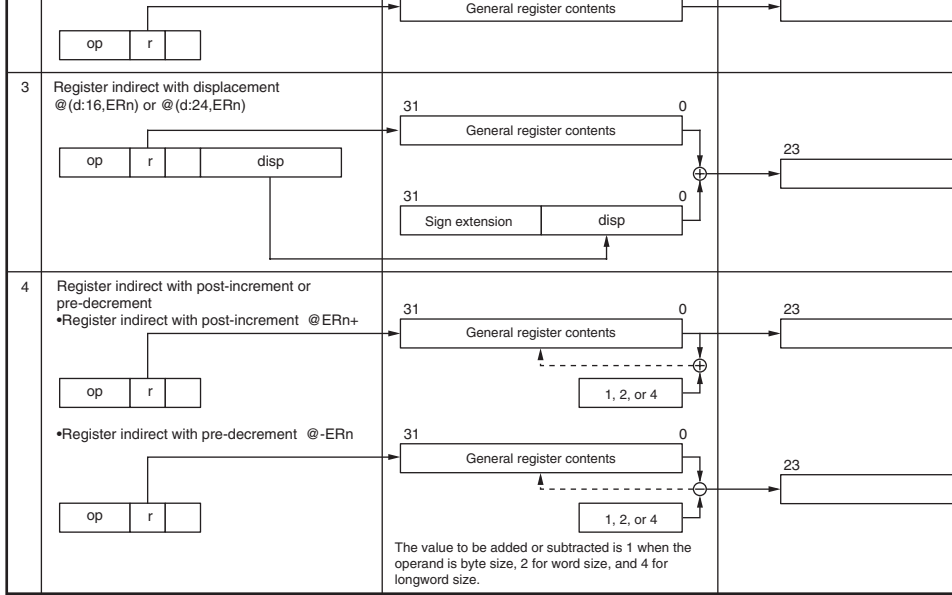
This mode is used in the BSR instruction. An 8-bit or 16-bit displacement contained in the instruction is sign-extended and added to the 24-bit PC contents to generate a branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction.

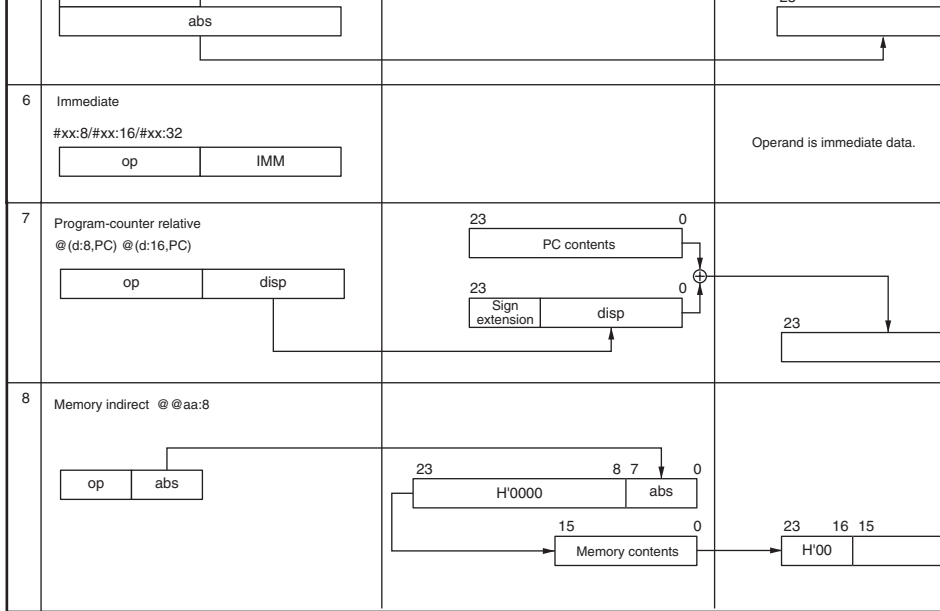
address range is 0 to 255 (H 0000 to H 00FF).

Note that the first part of the address range is also the exception vector area.



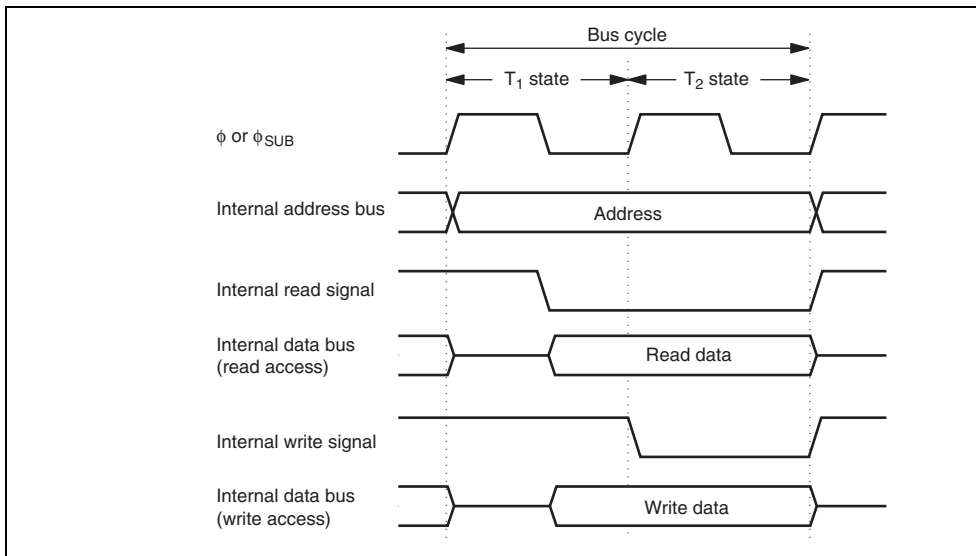
**Figure 2.8 Branch Address Specification in Memory Indirect Mode**





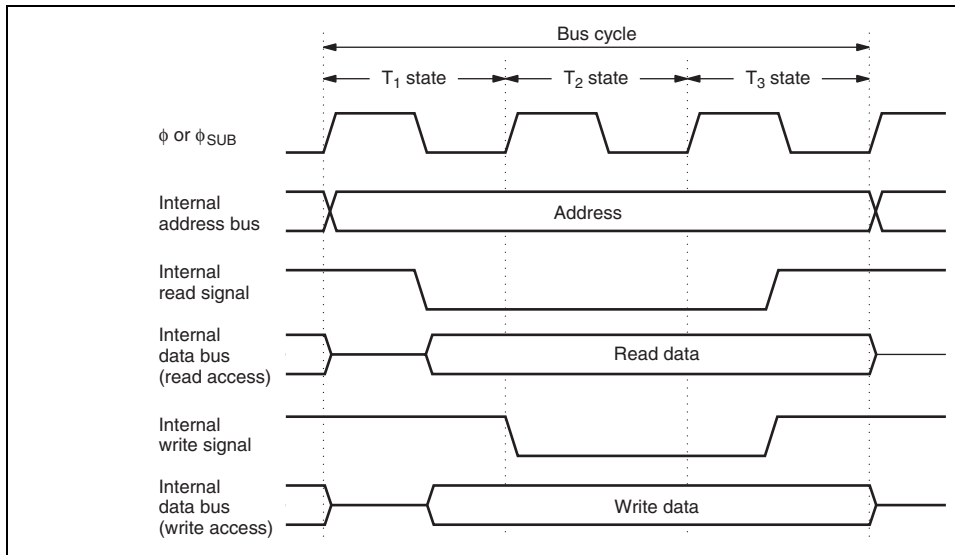
[Legend]

r, rm, rn: Register field  
 op: Operation field  
 disp: Displacement  
 IMM: Immediate data  
 abs: Absolute address

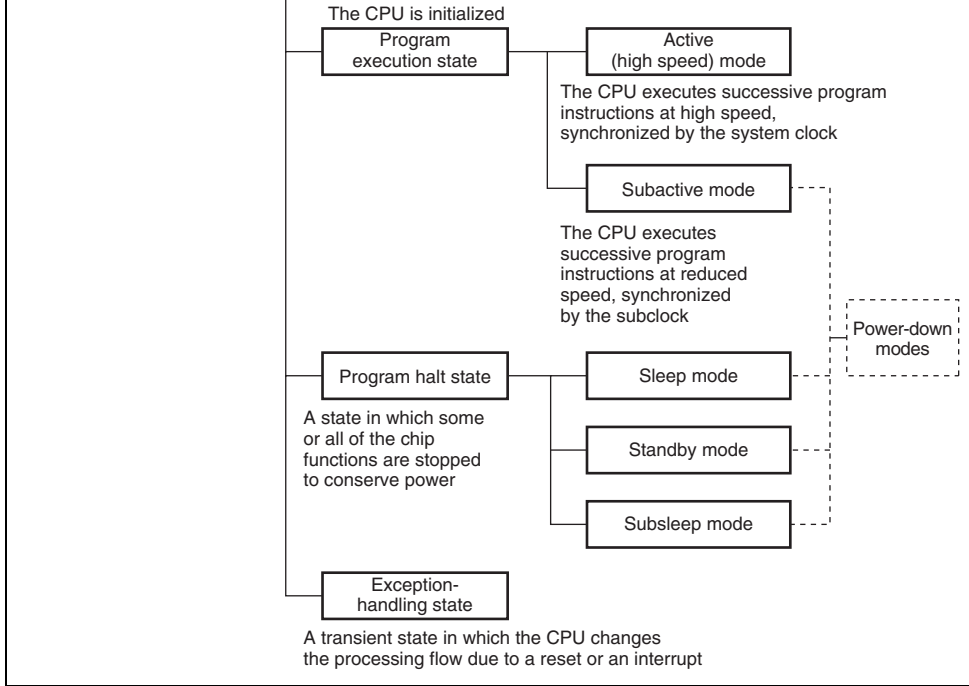


**Figure 2.9 On-Chip Memory Access Cycle**

module.



**Figure 2.10 On-Chip Peripheral Module Access Cycle (3-State Access)**



**Figure 2.11 CPU Operation States**



## 2.8 Usage Notes

### 2.8.1 Notes on Data Access to Empty Areas

The address space of this LSI includes empty areas in addition to the ROM, RAM, and I/O registers areas available to the user. When data is transferred from CPU to empty areas, the transferred data will be lost. This action may also cause the CPU to malfunction. When data is transferred from an empty area to CPU, the contents of the data cannot be guaranteed.

### 2.8.2 EEPMOV Instruction

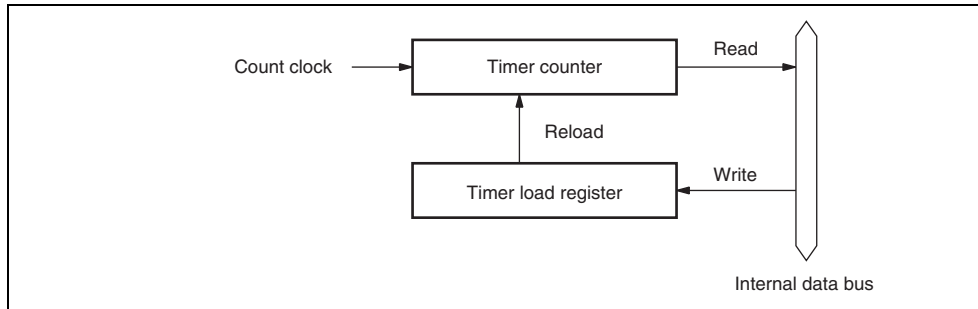
EEPMOV is a block-transfer instruction and transfers the byte size of data indicated by R4L, which starts from the address indicated by R5, to the address indicated by R6. Set R4L so that the end address of the destination address (value of R6 + R4L) does not exceed H'FFFF. The value of R6 must not change from H'FFFF to H'0000 during execution).

### 2.8.3 Bit Manipulation Instruction

The BSET, BCLR, BNOT, BST, and BIST instructions read data from the specified address in byte units, manipulate the data of the target bit, and write data to the same address again in byte units. Special care is required when using these instructions in cases where two registers are assigned to the same address or when a bit is directly manipulated for a port or a register containing a write-only bit, because this may rewrite data of a bit other than the bit to be manipulated.

2. The CPU sets or resets the bit to be manipulated with the bit manipulation instruction.
3. The written data is written again in byte units to the timer load register.

The timer is counting, so the value read is not necessarily the same as the value in the timer load register. As a result, bits other than the intended bit in the timer counter may be modified. The modified value may be written to the timer load register.



**Figure 2.13 Example of Timer Configuration with Two Registers Allocated to Same Address**

**Example 2: The BSET instruction is executed for port 5.**

P57 and P56 are input pins, with a low-level signal input at P57 and a high-level signal input at P56. P55 to P50 are output pins and output low-level signals. An example to output a high-level signal at P50 with a BSET instruction is shown below.

- After executing BSET instruction

	<b>P57</b>	<b>P56</b>	<b>P55</b>	<b>P54</b>	<b>P53</b>	<b>P52</b>	<b>P51</b>
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	0	1	0	0	0	0	0

- Description on operation

1. When the BSET instruction is executed, first the CPU reads port 5.

Since P57 and P56 are input pins, the CPU reads the pin states (low-level and high-level input).

P55 to P50 are output pins, so the CPU reads the value in PDR5. In this example PDR5 value is H'80, but the value read by the CPU is H'40.

2. Next, the CPU sets bit 0 of the read data to 1, changing the PDR5 data to H'41.
3. Finally, the CPU writes H'41 to PDR5, completing execution of BSET instruction.

As a result of the BSET instruction, bit 0 in PDR5 becomes 1, and P50 outputs a high signal. However, bits 7 and 6 of PDR5 end up with different values. To prevent this, store a copy of the PDR5 data in a work area in memory. Perform the bit manipulation on the data in the work area, then write this data to PDR5.

PDR5	1	0	0	0	0	0	0
RAM0	1	0	0	0	0	0	0

- BSET instruction executed

```
BSET    #0,    @RAM0
```

The BSET instruction is executed designating the work area (RAM0).

- After executing BSET instruction

```
MOV.B   @RAM0, R0L
MOV.B   R0L,   @PDR5
```

The work area (RAM0) value is written to PDR5.

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0
RAM0	1	0	0	0	0	0	0

### Bit Manipulation in a Register Containing a Write-Only Bit

#### Example 3: BCLR instruction executed designating port 5 control register PCR5

P57 and P56 are input pins, with a low-level signal input at P57 and a high-level signal input at P56. P55 to P50 are output pins that output low-level signals. An example of setting the P57 and P56 pins is shown below.

- BCLR instruction executed

```
BCLR    #0,    @PCR5
```

The BCLR instruction is executed for PCR5.

- After executing BCLR instruction

	P57	P56	P55	P54	P53	P52	P51
Input/output	Output	Output	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	1	1	1	1	1	1	1
PDR5	1	0	0	0	0	0	0

- Description on operation

1. When the BCLR instruction is executed, first the CPU reads PCR5. Since PCR5 is a register, the CPU reads a value of H'FF, even though the PCR5 value is actually H'3F.
2. Next, the CPU clears bit 0 in the read data to 0, changing the data to H'FE.
3. Finally, H'FE is written to PCR5 and BCLR instruction execution ends.

As a result of this operation, bit 0 in PCR5 becomes 0, making P50 an input port. However, bits 7 and 6 in PCR5 change to 1, so that P57 and P56 change from input pins to output pins. To prevent this problem, store a copy of the PDR5 data in a work area in memory and manipulate data of the bit in the work area, then write this data to PDR5.

PDR5	1	0	0	0	0	0	0
RAM0	0	0	1	1	1	1	1

- BCLR instruction executed

```
BCLR #0, @RAM0
```

The BCLR instructions executed for the PCR5 work area (RAM0).

- After executing BCLR instruction

```
MOV.B @RAM0, R0L
MOV.B R0L, @PCR5
```

The work area (RAM0) value is written to PCR5.

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0
RAM0	0	0	1	1	1	1	1

Exception handling starts when a trap instruction (TRAP) is executed. The TRAP instruction generates a vector address corresponding to a vector number from 0 to 3, as specified in the instruction code. Exception handling can be executed at all times in the program execution regardless of the setting of the I bit in CCR.

- Interrupts

External interrupts other than NMI and internal interrupts other than address break are masked by the I bit in CCR, and kept masked while the I bit is set to 1. Exception handling starts when the current instruction or exception handling ends, if an interrupt request has been issued.

### 3.1 Exception Sources and Vector Address

Table 3.1 shows the vector addresses and priority of each exception handling. When more than one interrupt is requested, handling is performed from the interrupt with the highest priority.

**Table 3.1 Exception Sources and Vector Address**

Relative Module	Exception Sources	Vector Number	Vector Address
RES pin Watchdog timer	Reset	0	H'0000 to H'0001
—	Reserved for system use	1 to 6	H'0002 to H'000D
External interrupt pin	NMI	7	H'000E to H'000F
CPU	Trap instruction (#0)	8	H'0010 to H'0011
		9	H'0012 to H'0013
		10	H'0014 to H'0015
		11	H'0016 to H'0017
Address break	Break conditions satisfied	12	H'0018 to H'0019

	WKP	18	H'0024 to H'0025
Timer A	Overflow	19	H'0026 to H'0027
—	Reserved for system use	20	H'0028 to H'0029
Timer W	Timer W input capture A /compare match A Timer W input capture B /compare match B Timer W input capture C /compare match C Timer W input capture D /compare match D Timer W overflow	21	H'002A to H'002B
Timer V	Timer V compare match A Timer V compare match B Timer V overflow	22	H'002C to H'002D
SCI3	SCI3 receive data full SCI3 transmit data empty SCI3 transmit end SCI3 receive error	23	H'002E to H'002F
IIC2	Transmit data empty Transmit end Receive data full Arbitration lost/Overrun error NACK detection Stop conditions detected	24	H'0030 to H'0031
A/D converter	A/D conversion end	25	H'0032 to H'0033

Note \* A low-voltage detection interrupt is enabled only in the product with an on-chip on reset and low-voltage detection circuit.



IEGR1 selects the direction of an edge that generates interrupt requests of pins  $\overline{\text{NMI}}$  and  $\overline{\text{IRQ0}}$ .

Bit	Bit Name	Initial Value	R/W	Description
7	NMIEG	0	R/W	NMI Edge Select 0: Falling edge of $\overline{\text{NMI}}$ pin input is detected 1: Rising edge of $\overline{\text{NMI}}$ pin input is detected
6 to 4	—	All 1	—	Reserved These bits are always read as 1.
3	IEG3	0	R/W	IRQ3 Edge Select 0: Falling edge of $\overline{\text{IRQ3}}$ pin input is detected 1: Rising edge of $\overline{\text{IRQ3}}$ pin input is detected
2	IEG2	0	R/W	IRQ2 Edge Select 0: Falling edge of $\overline{\text{IRQ2}}$ pin input is detected 1: Rising edge of $\overline{\text{IRQ2}}$ pin input is detected
1	IEG1	0	R/W	IRQ1 Edge Select 0: Falling edge of $\overline{\text{IRQ1}}$ pin input is detected 1: Rising edge of $\overline{\text{IRQ1}}$ pin input is detected
0	IEG0	0	R/W	IRQ0 Edge Select 0: Falling edge of $\overline{\text{IRQ0}}$ pin input is detected 1: Rising edge of $\overline{\text{IRQ0}}$ pin input is detected

				0: Falling edge of $\overline{WKP5(ADTRG)}$ pin input is detected
				1: Rising edge of $\overline{WKP5(ADTRG)}$ pin input is detected
4	WPEG4	0	R/W	WKP4 Edge Select 0: Falling edge of $\overline{WKP4}$ pin input is detected 1: Rising edge of $\overline{WKP4}$ pin input is detected
3	WPEG3	0	R/W	WKP3 Edge Select 0: Falling edge of $\overline{WKP3}$ pin input is detected 1: Rising edge of $\overline{WKP3}$ pin input is detected
2	WPEG2	0	R/W	WKP2 Edge Select 0: Falling edge of $\overline{WKP2}$ pin input is detected 1: Rising edge of $\overline{WKP2}$ pin input is detected
1	WPEG1	0	R/W	WKP1 Edge Select 0: Falling edge of $\overline{WKP1}$ pin input is detected 1: Rising edge of $\overline{WKP1}$ pin input is detected
0	WPEG0	0	R/W	WKP0 Edge Select 0: Falling edge of $\overline{WKP0}$ pin input is detected 1: Rising edge of $\overline{WKP0}$ pin input is detected

				requests are enabled.
5	IENWP	0	R/W	Wakeup Interrupt Enable This bit is an enable bit, which is common to the WKP5 to WKP0. When the bit is set to 1, interrupt requests are enabled.
4	—	1	—	Reserved This bit is always read as 1.
3	IEN3	0	R/W	IRQ3 Interrupt Enable When this bit is set to 1, interrupt requests of the pin are enabled.
2	IEN2	0	R/W	IRQ2 Interrupt Enable When this bit is set to 1, interrupt requests of the pin are enabled.
1	IEN1	0	R/W	IRQ1 Interrupt Enable When this bit is set to 1, interrupt requests of the pin are enabled.
0	IEN0	0	R/W	IRQ0 Interrupt Enable When this bit is set to 1, interrupt requests of the pin are enabled.

When disabling interrupts by clearing bits in an interrupt enable register, or when clearing an interrupt flag register, always do so while interrupts are masked ( $I = 1$ ). If the above operations are performed while  $I = 0$ , and as a result a conflict arises between the clear instruction and an interrupt request, exception handling for the interrupt will be executed after the clear instruction has been executed.

				[Clearing condition] When IRRDT is cleared by writing 0
6	IRRTA	0	R/W	Timer A Interrupt Request Flag [Setting condition] When the timer A counter value overflows [Clearing condition] When IRRTA is cleared by writing 0
5, 4	—	All 1	—	Reserved These bits are always read as 1.
3	IRRI3	0	R/W	IRQ3 Interrupt Request Flag [Setting condition] When $\overline{\text{IRQ3}}$ pin is designated for interrupt input and designated signal edge is detected. [Clearing condition] When IRRI3 is cleared by writing 0
2	IRRI2	0	R/W	IRQ2 Interrupt Request Flag [Setting condition] When $\overline{\text{IRQ2}}$ pin is designated for interrupt input and designated signal edge is detected. [Clearing condition] When IRRI2 is cleared by writing 0
1	IRRI1	0	R/W	IRQ1 Interrupt Request Flag [Setting condition] When $\overline{\text{IRQ1}}$ pin is designated for interrupt input and designated signal edge is detected. [Clearing condition] When IRRI1 is cleared by writing 0

IWPR is a status flag register for  $\overline{\text{WKP5}}$  to  $\overline{\text{WKP0}}$  interrupt requests.

Bit	Bit Name	Initial Value	R/W	Description
7, 6	—	All 1	—	Reserved These bits are always read as 1.
5	IWPF5	0	R/W	WKP5 Interrupt Request Flag [Setting condition] When $\overline{\text{WKP5}}$ pin is designated for interrupt input, designated signal edge is detected. [Clearing condition] When IWPF5 is cleared by writing 0.
4	IWPF4	0	R/W	WKP4 Interrupt Request Flag [Setting condition] When $\overline{\text{WKP4}}$ pin is designated for interrupt input, designated signal edge is detected. [Clearing condition] When IWPF4 is cleared by writing 0.
3	IWPF3	0	R/W	WKP3 Interrupt Request Flag [Setting condition] When $\overline{\text{WKP3}}$ pin is designated for interrupt input, designated signal edge is detected. [Clearing condition] When IWPF3 is cleared by writing 0.

When WKP1 pin is designated for interrupt input, designated signal edge is detected.

[Clearing condition]

When IWPF1 is cleared by writing 0.

---

0	IWPF0	0	R/W	WKP0 Interrupt Request Flag
---	-------	---	-----	-----------------------------

[Setting condition]  
When  $\overline{WKP0}$  pin is designated for interrupt input, designated signal edge is detected.  
[Clearing condition]  
When IWPF0 is cleared by writing 0.

---

### 3.3 Reset Exception Handling

When the  $\overline{RES}$  pin goes low, all processing halts and this LSI enters the reset. The internal CPU and the registers of the on-chip peripheral modules are initialized by the reset. To ensure that this LSI is reset at power-up, hold the  $\overline{RES}$  pin low until the clock pulse generator output stabilizes. To reset the chip during operation, hold the  $\overline{RES}$  pin low for at least 10 system clock cycles. When the  $\overline{RES}$  pin goes high after being held low for the necessary time, this LSI starts reset exception handling. The reset exception handling sequence is shown in figure 3.1.

The reset exception handling sequence is as follows. However, for the reset exception handling sequence of the product with on-chip power-on reset circuit, refer to section 18, Power-On Reset and Low-Voltage Detection Circuits (Optional).

1. Set the I bit in the condition code register (CCR) to 1.
2. The CPU generates a reset exception handling vector address (from H'0000 to H'000F). The data in that address is sent to the program counter (PC) as the start address, and program execution starts from that address.

bit value in CCR.

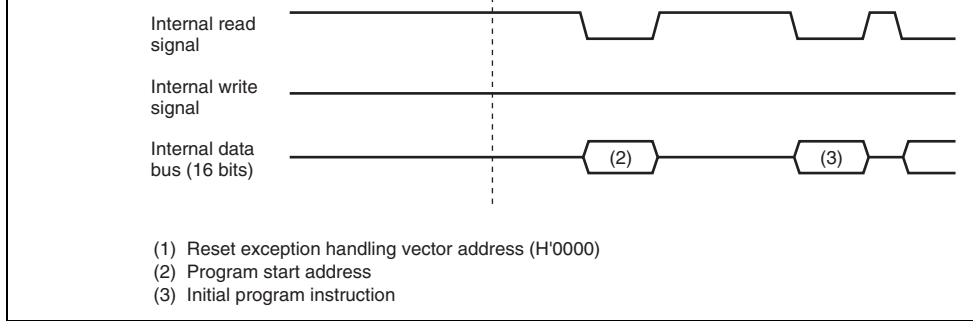
### **IRQ3 to IRQ0 Interrupts**

IRQ3 to IRQ0 interrupts are requested by input signals to pins  $\overline{\text{IRQ3}}$  to  $\overline{\text{IRQ0}}$ . These interrupts are given different vector addresses, and are detected individually by either edge sensing or falling edge sensing, depending on the settings of bits IEG3 to IEG0. When pins  $\overline{\text{IRQ3}}$  to  $\overline{\text{IRQ0}}$  are designated for interrupt input in PMR1 and the designated edge is input, the corresponding bit in IRR1 is set to 1, requesting the CPU of an interrupt. These interrupts can be masked by setting bits IEN3 to IEN0 in IENR1.

### **WKP5 to WKP0 Interrupts**

WKP5 to WKP0 interrupts are requested by input signals to pins  $\overline{\text{WKP5}}$  to  $\overline{\text{WKP0}}$ . These interrupts have the same vector addresses, and are detected individually by either rising edge sensing or falling edge sensing, depending on the settings of bits WPEG5 to WPEG0 in IEGR2.

When pins  $\overline{\text{WKP5}}$  to  $\overline{\text{WKP0}}$  are designated for interrupt input in PMR5 and the designated signal edge is input, the corresponding bit in IWPR is set to 1, requesting the CPU of an interrupt. These interrupts can be masked by setting bit IENWP in IENR1.



**Figure 3.1 Reset Sequence**

### 3.4.2 Internal Interrupts

Each on-chip peripheral module has a flag to show the interrupt request status and the enable or disable the interrupt. For timer A interrupt requests and direct transfer interrupt generated by execution of a SLEEP instruction, this function is included in IRR1 and IEN.

When an on-chip peripheral module requests an interrupt, the corresponding interrupt request status flag is set to 1, requesting the CPU of an interrupt. These interrupts can be masked by writing 0 to clear the corresponding enable bit.

### 3.4.3 Interrupt Handling Sequence

Interrupts are controlled by an interrupt controller.

Interrupt operation is described as follows.

1. If an interrupt occurs while the NMI or interrupt enable bit is set to 1, an interrupt request signal is sent to the interrupt controller.



5. Then, the I bit of CCR is set to 1, masking further interrupts excluding the NMI and break. Upon return from interrupt handling, the values of I bit and other bits in CCR are restored and returned to the values prior to the start of interrupt exception handling.
6. Next, the CPU generates the vector address corresponding to the accepted interrupt, transfers the address to PC as a start address of the interrupt handling-routine. Then it starts executing from the address indicated in PC.

Figure 3.3 shows a typical interrupt sequence where the program area is in the on-chip Flash ROM and the stack area is in the on-chip RAM.

[Legend]  
PCH: Upper 8 bits of program counter (PC)  
PCL: Lower 8 bits of program counter (PC)  
CCR: Condition code register  
SP: Stack pointer

- Notes: 1. PC shows the address of the first instruction to be executed upon return from the interrupt handling routine.  
2. Register contents must always be saved and restored by word length, starting from an even-numbered address.  
3. Ignored when returning from the interrupt handling routine.

**Figure 3.2 Stack Status after Exception Handling**

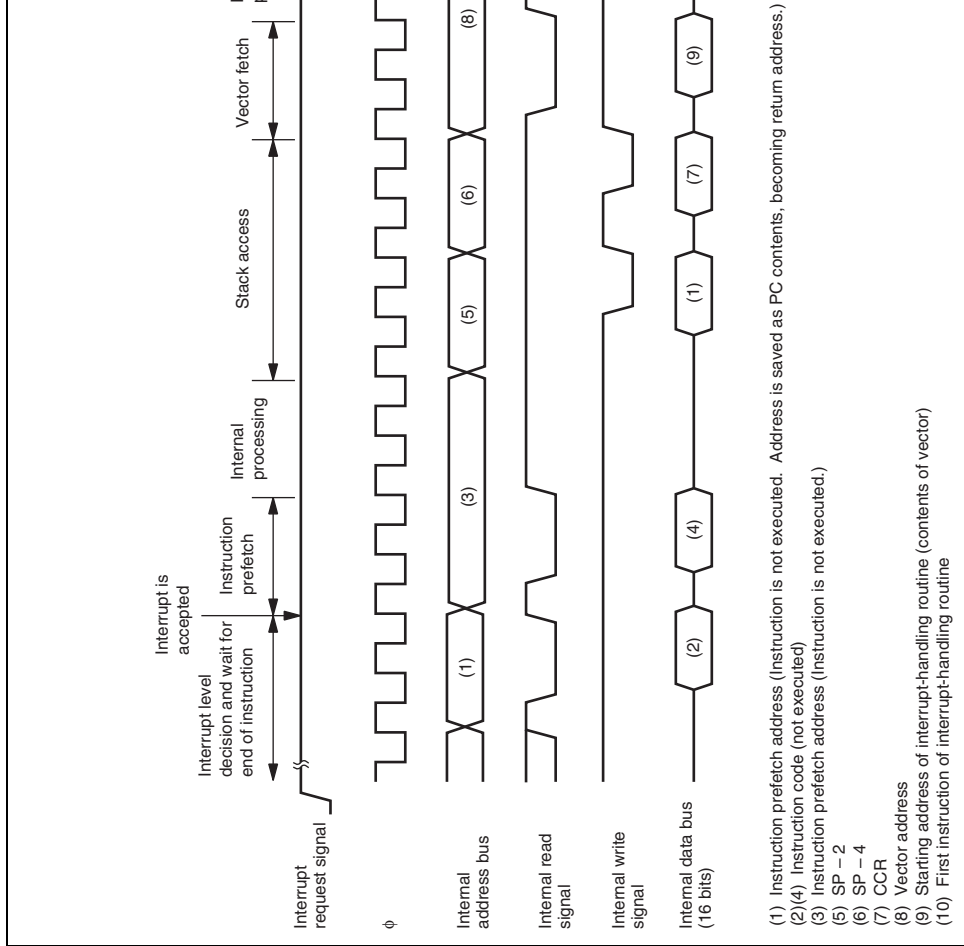
### 3.4.4 Interrupt Response Time

Table 3.2 shows the number of wait states after an interrupt request flag is set until the first instruction of the interrupt handling-routine is executed.

**Table 3.2 Interrupt Wait States**

Item	States	Total
Waiting time for completion of executing instruction*	1 to 23	15 to 37
Saving of PC and CCR to stack	4	
Vector fetch	2	
Instruction fetch	4	
Internal processing	4	

Note: \* Not including EEPMOV instruction.



**Figure 3.3 Interrupt Sequence**

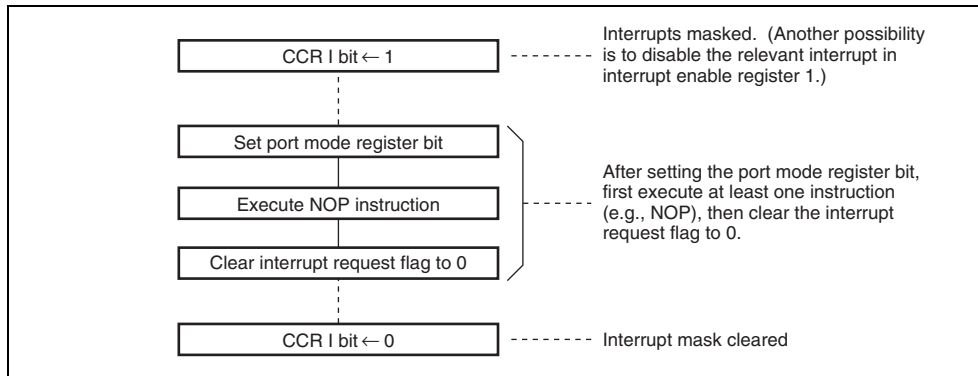
When word data is accessed, the least significant bit of the address is regarded as 0. Access to the stack always takes place in word size, so the stack pointer (SP: R7) should never indicate an odd address. Use PUSH Rn (MOV.W Rn, @-SP) or POP Rn (MOV.W @SP+, Rn) to save or restore register values.

### 3.5.3 Notes on Rewriting Port Mode Registers

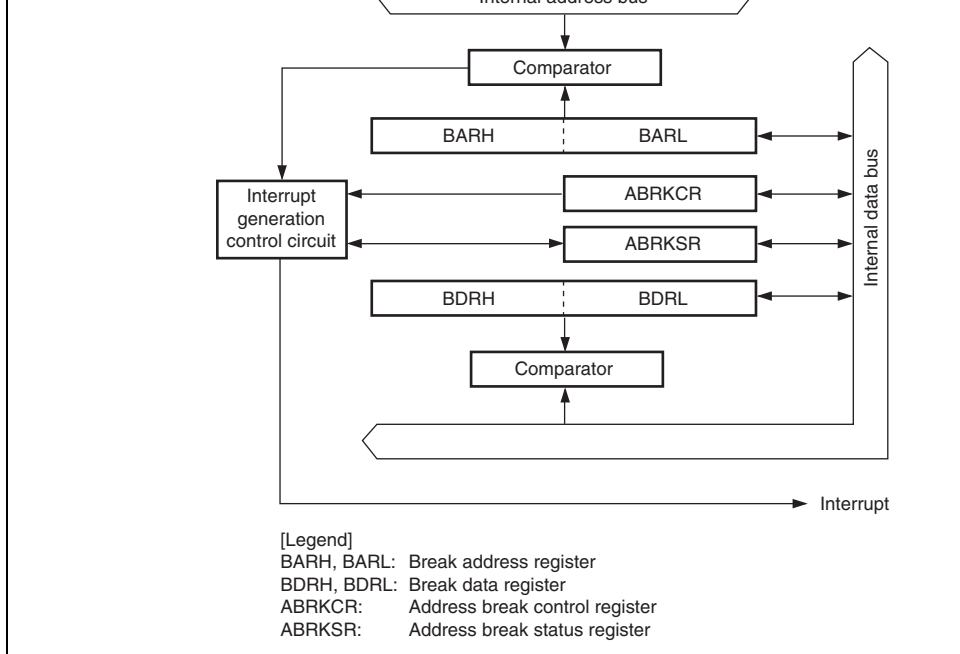
When a port mode register is rewritten to switch the functions of external interrupt pins,  $\bar{I}RQ0$ , and WKP5 to WKP0, the interrupt request flag may be set to 1.

When switching a pin function, mask the interrupt before setting the bit in the port mode register. After accessing the port mode register, execute at least one instruction (e.g., NOP), then clear the interrupt request flag from 1 to 0.

Figure 3.4 shows a port mode register setting and interrupt request flag clearing procedure.



**Figure 3.4 Port Mode Register Setting and Interrupt Request Flag Clearing Procedure**



**Figure 4.1 Block Diagram of Address Break**

## 4.1 Register Descriptions

Address break has the following registers.

- Address break control register (ABRKCR)
- Address break status register (ABRKSR)
- Break address register (BARH, BARL)
- Break data register (BDRH, BDRL)

6	CSEL1	0	R/W	Condition Select 1 and 0
5	CSEL0	0	R/W	These bits set address break conditions. 00: Instruction execution cycle 01: CPU data read cycle 10: CPU data write cycle 11: CPU data read/write cycle
4	ACMP2	0	R/W	Address Compare Condition Select 2 to 0
3	ACMP1	0	R/W	These bits set the comparison condition between
2	ACMP0	0	R/W	address set in BAR and the internal address bus 000: Compares 16-bit addresses 001: Compares upper 12-bit addresses 010: Compares upper 8-bit addresses 011: Compares upper 4-bit addresses 1XX: Reserved (setting prohibited)
1	DCMP1	0	R/W	Data Compare Condition Select 1 and 0
0	DCMP0	0	R/W	These bits set the comparison condition between set in BDR and the internal data bus. 00: No data comparison 01: Compares lower 8-bit data between BDRL and bus 10: Compares upper 8-bit data between BDRH and bus 11: Compares 16-bit data between BDR and data

Legend: X: Don't care.

ROM space	Upper 8 bits	Lower 8 bits	Upper 8 bits	Upper 8 bits
RAM space	Upper 8 bits	Lower 8 bits	Upper 8 bits	Upper 8 bits
I/O register with 8-bit data bus width	Upper 8 bits	Upper 8 bits	Upper 8 bits	Upper 8 bits
I/O register with 16-bit data bus width	Upper 8 bits	Lower 8 bits	—	—

#### 4.1.2 Address Break Status Register (ABRKSR)

ABRKSR consists of the address break interrupt flag and the address break interrupt enable.

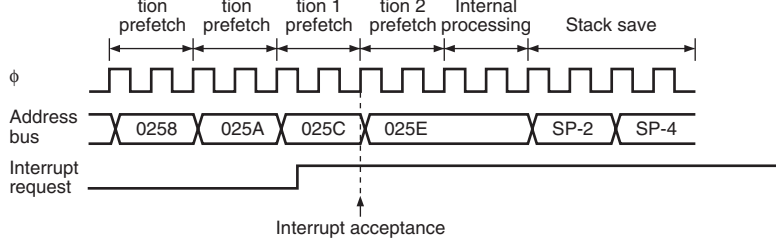
Bit	Bit Name	Initial Value	R/W	Description
7	ABIF	0	R/W	Address Break Interrupt Flag [Setting condition] When the condition set in ABRKCR is satisfied [Clearing condition] When 0 is written after ABIF=1 is read
6	ABIE	0	R/W	Address Break Interrupt Enable When this bit is 1, an address break interrupt request is enabled.
5 to 0	—	All 1	—	Reserved These bits are always read as 1.

even and odd addresses in the data transmission. Therefore, comparison data must be set in BDRH for byte access. For word access, the data bus used depends on the address. See section 4.1.1, Address Break Control Register (ABRKCR), for details. The initial value of this register is undefined.

## 4.2 Operation

When the ABIF and ABIE bits in ABRKSR are set to 1, the address break function generates an interrupt request to the CPU. The ABIF bit in ABRKSR is set to 1 by the combination of the address set in BAR, the data set in BDR, and the conditions set in ABRKCR. When the interrupt request is accepted, interrupt exception handling starts after the instruction being executed. The address break interrupt is not masked by the I bit in CCR of the CPU.





**Figure 4.2 Address Break Interrupt Operation Example (1)**

When the address break is specified in the data read cycle

- Register setting
- ABRKCR = H'A0
  - BAR = H'025A

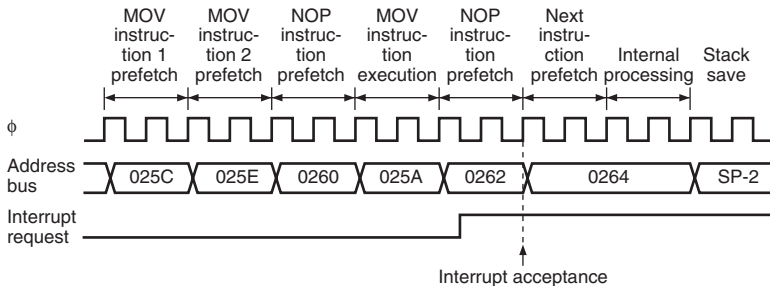
Program

```

0258  NOP
025A  NOP
* 025C  MOV.W @H'025A,R0
0260  NOP
0262  NOP
:      :

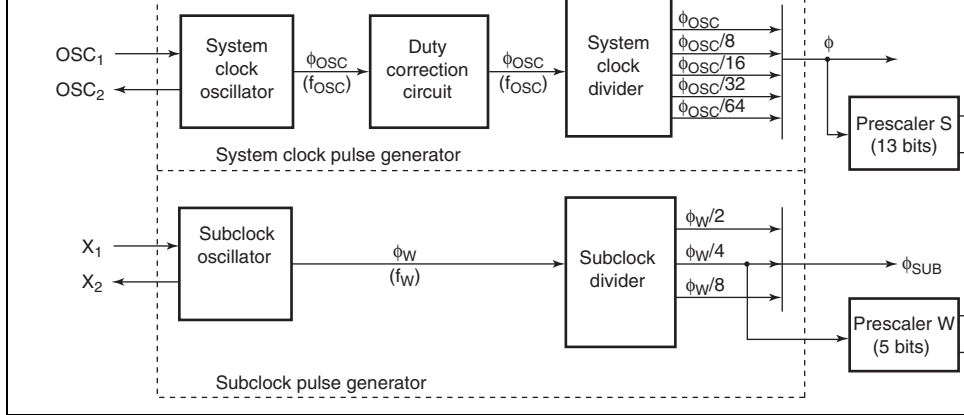
```

Underline indicates the address to be stacked.



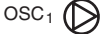
**Figure 4.2 Address Break Interrupt Operation Example (2)**





**Figure 5.1 Block Diagram of Clock Pulse Generators**

The basic clock signals that drive the CPU and on-chip peripheral modules are  $\phi$  and  $\phi_{\text{SUB}}$ . The system clock is divided by prescaler S to become a clock signal from  $\phi/8192$  to  $\phi/2$ , and the subclock is divided by prescaler W to become a clock signal from  $\phi_w/128$  to  $\phi_w/8$ . Both the system clock and subclock signals are provided to the on-chip peripheral modules.

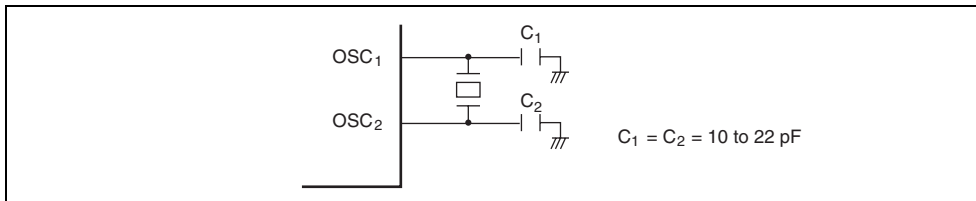


LPM: Low-power mode (standby mode, subactive mode, subsleep mode)

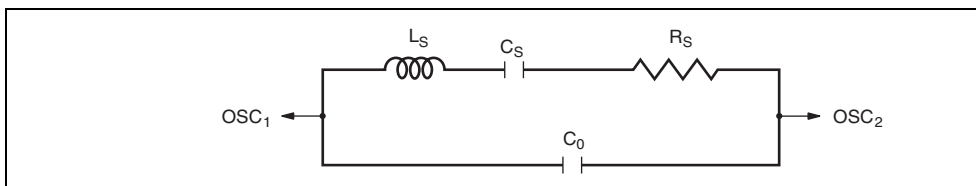
**Figure 5.2 Block Diagram of System Clock Generator**

### 5.1.1 Connecting Crystal Resonator

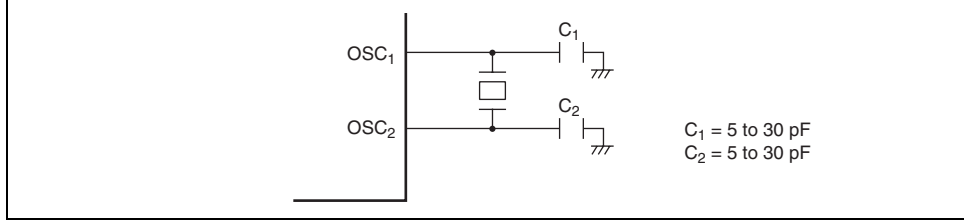
Figure 5.3 shows a typical method of connecting a crystal resonator. An AT-cut parallel-resonant crystal resonator should be used. Figure 5.4 shows the equivalent circuit of a crystal resonator having the characteristics given in table 5.1 should be used.



**Figure 5.3 Typical Connection to Crystal Resonator**



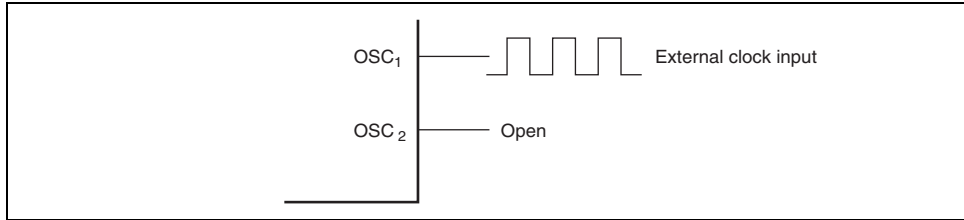
**Figure 5.4 Equivalent Circuit of Crystal Resonator**



**Figure 5.5 Typical Connection to Ceramic Resonator**

### 5.1.3 External Clock Input Method

Connect an external clock signal to pin OSC<sub>1</sub>, and leave pin OSC<sub>2</sub> open. Figure 5.6 shows connection. The duty cycle of the external clock signal must be 45 to 55%.

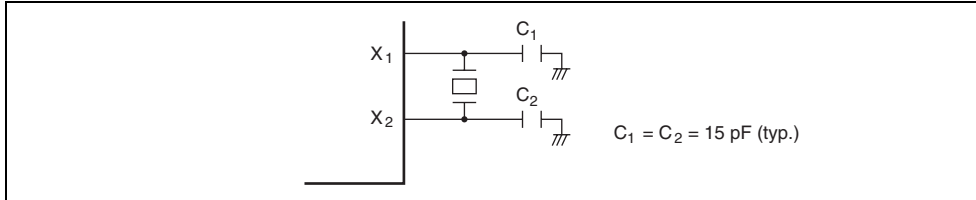


**Figure 5.6 Example of External Clock Input**

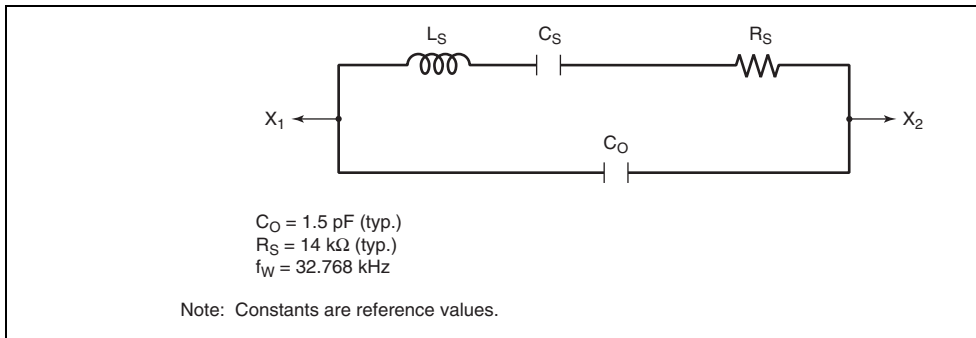
## Figure 5.7 Block Diagram of Subclock Generator

### 5.2.1 Connecting 32.768-kHz Crystal Resonator

Clock pulses can be supplied to the subclock divider by connecting a 32.768-kHz crystal resonator, as shown in figure 5.8. Figure 5.9 shows the equivalent circuit of the 32.768-kHz resonator.



**Figure 5.8 Typical Connection to 32.768-kHz Crystal Resonator**



**Figure 5.9 Equivalent Circuit of 32.768-kHz Crystal Resonator**

## 5.3 Prescalers

### 5.3.1 Prescaler S

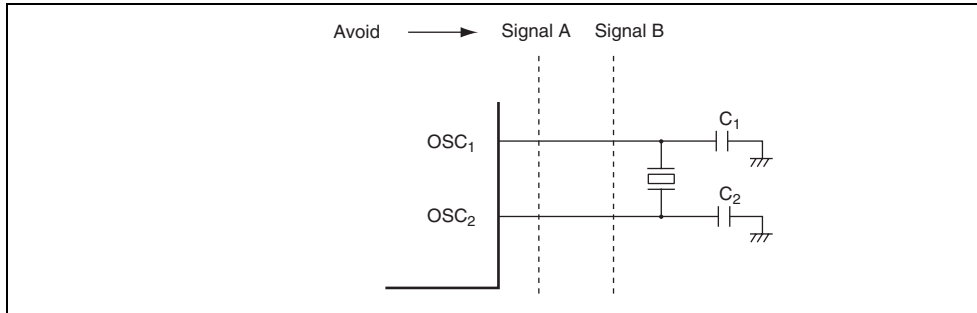
Prescaler S is a 13-bit counter using the system clock ( $\phi$ ) as its input clock. It is incremented per clock period. Prescaler S is initialized to H'0000 by a reset, and starts counting on exit from the reset state. In standby mode, subactive mode, and subsleep mode, the system clock prescaler generator stops. Prescaler S also stops and is initialized to H'0000. The CPU cannot read the value of prescaler S. The output from prescaler S is shared by the on-chip peripheral modules. The division ratio can be set separately for each on-chip peripheral function. In active mode and sleep mode, the clock input to prescaler S is determined by the division factor designated by MA2 to MA4 of SYSCR2.

### 5.3.2 Prescaler W

Prescaler W is a 5-bit counter using a 32.768 kHz signal divided by 4 ( $\phi_w/4$ ) as its input clock. The divided output is used for clock time base operation of timer A. Prescaler W is initialized to H'0000 by a reset, and starts counting on exit from the reset state. Even in standby mode, subactive mode, or subsleep mode, prescaler W continues functioning so long as clock signals are supplied to X<sub>1</sub> and X<sub>2</sub>. Prescaler W can be reset by setting 1s in bits TMA3 and TMA2 of timer mode register A (TMA).

## 5.4.2 Notes on Board Design

When using a crystal resonator (ceramic resonator), place the resonator and its load capacitors close as possible to the  $OSC_1$  and  $OSC_2$  pins. Other signal lines should be routed away from resonator circuit to prevent induction from interfering with correct oscillation (see figure



**Figure 5.11 Example of Incorrect Board Design**



The CPU and all on-chip peripheral modules are operable on the subclock. The subclock frequency can be selected from  $\phi w/2$ ,  $\phi w/4$ , and  $\phi w/8$ .

- Sleep mode  
The CPU halts. On-chip peripheral modules are operable on the system clock.
- Subsleep mode  
The CPU halts. On-chip peripheral modules are operable on the subclock.
- Standby mode  
The CPU and all on-chip peripheral modules halt. When the clock time-base function is selected, timer A is operable.
- Module standby mode  
Independent of the above modes, power consumption can be reduced by halting on-chip peripheral modules that are not used in module units.

## 6.1 Register Descriptions

The registers related to power-down modes are listed below.

- System control register 1 (SYSCR1)
- System control register 2 (SYSCR2)
- Module standby control register 1 (MSTCR1)

1. a transition is made to standby mode.

For details, see table 6.2.

6	STS2	0	R/W	Standby Timer Select 2 to 0
5	STS1	0	R/W	These bits designate the time the CPU and peripheral modules wait for stable clock operation after exiting standby mode, subactive mode, or subsleep mode to active mode or sleep mode due to an interrupt. The designation should be made according to the clock frequency so that the waiting time is at least 6.5 $\mu$ s. The relationship between the specified value and the number of wait states is shown in table 6.1. When an external clock is to be used, the minimum value (STS2 = STS0 = 1) is recommended.
4	STS0	0	R/W	
3	NESEL	0	R/W	
2 to 0	—	All 0	—	Reserved  These bits are always read as 0.

1	0	128 states	0.00	0.00	0.01	0.02	0.03	0.06	0.13
	1	16 states	0.00	0.00	0.00	0.00	0.00	0.01	0.02

Note: Time unit is ms.

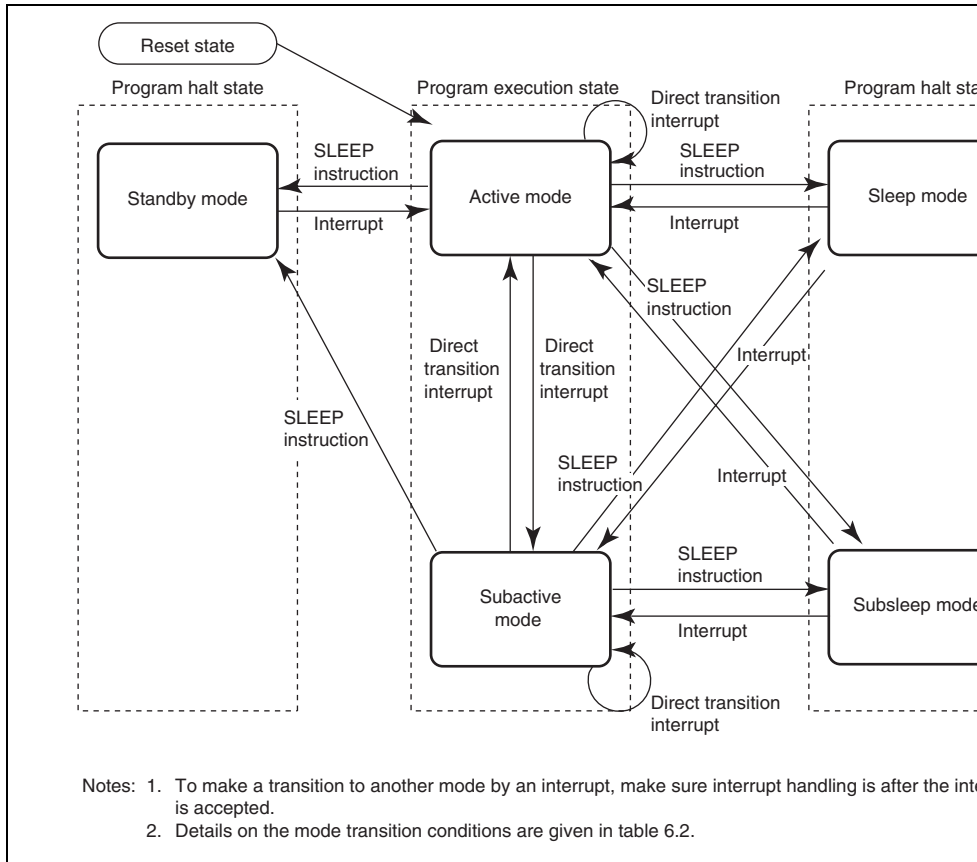
of a SLEEP instruction, as well as bit SSBY of SLEEP instruction.  
For details, see table 6.2.

4	MA2	0	R/W	Active Mode Clock Select 2 to 0	
3	MA1	0	R/W	These bits select the operating clock frequency in active and sleep modes. The operating clock frequency changes to the set frequency after the SLEEP instruction is executed.  0XX: $\phi_{OSC}$ 100: $\phi_{OSC}/8$ 101: $\phi_{OSC}/16$ 110: $\phi_{OSC}/32$ 111: $\phi_{OSC}/64$	
2	MA0	0	R/W		
<hr/>					
1	SA1	0	R/W		Subactive Mode Clock Select 1 and 0
0	SA0	0	R/W		These bits select the operating clock frequency in subactive and subsleep modes. The operating clock frequency changes to the set frequency after the SLEEP instruction is executed.  00: $\phi_W/8$ 01: $\phi_W/4$ 1X: $\phi_W/2$

Legend: X : Don't care.

5	MSTS3	0	R/W	SCI3 Module Standby SCI3 enters standby mode when this bit is set to 1
4	MSTAD	0	R/W	A/D Converter Module Standby A/D converter enters standby mode when this bit is set to 1
3	MSTWD	0	R/W	Watchdog Timer Module Standby Watchdog timer enters standby mode when this bit is set to 1. When the internal oscillator is selected for the watchdog timer clock, the watchdog timer operates regardless of the setting of this bit
2	MSTTW	0	R/W	Timer W Module Standby Timer W enters standby mode when this bit is set to 1
1	MSTTV	0	R/W	Timer V Module Standby Timer V enters standby mode when this bit is set to 1
0	MSTTA	0	R/W	Timer A Module Standby Timer A enters standby mode when this bit is set to 1

is executed and a mode to return by an interrupt. Table 6.5 shows the internal states of the device in each mode.



**Figure 6.1 Mode Transition Diagram**

	X	0	0	Active mode (direct transition)	—
	X	X	1	Subactive mode (direct transition)	—

Legend: X : Don't care.

- \* When a state transition is performed while SMSEL is 1, timer V, SCI3, and the converter are reset, and all registers are set to their initial values. To use these functions after entering active mode, reset the registers.

con  
retai  
outp  
high  
impe  
state

External interrupts	IRQ3 to IRQ0	Functioning	Functioning	Functioning	Functioning	Func
	WKP5 to WKP0	Functioning	Functioning	Functioning	Functioning	Func
Peripheral functions	Timer A	Functioning	Functioning	Functioning if the timekeeping time-base function is selected, and retained if no		
	Timer V	Functioning	Functioning	Reset	Reset	Rese
	Timer W	Functioning	Functioning	Retained (if internal clock $\phi$ is selected as a count clock, the counter is incremented by a subclock*)		Reta
	Watchdog timer	Functioning	Functioning	Retained (functioning if the internal os selected as a count clock*)		
	SCI3	Functioning	Functioning	Reset	Reset	Rese
	IIC	Functioning	Functioning	Retained*	Retained	Reta
	A/D converter	Functioning	Functioning	Reset	Reset	Rese

Note: \* Registers can be read or written in subactive mode.



## 6.2.2 Standby Mode

In standby mode, the clock pulse generator stops, so the CPU and on-chip peripheral modules are not functioning. However, as long as the rated voltage is supplied, the contents of CPU registers, on-chip RAM, and some on-chip peripheral module registers are retained. On-chip RAM contents will be retained as long as the voltage set by the RAM data retention voltage is provided. I/O ports go to the high-impedance state.

Standby mode is cleared by an interrupt. When an interrupt is requested, the system clock pulse generator starts. After the time set in bits STS2–STS0 in SYSCR1 has elapsed, and interrupt exception handling starts. Standby mode is not cleared if the I bit of CCR is set to 1 or the requested interrupt is disabled in the interrupt enable register.

When the  $\overline{\text{RES}}$  pin goes low, the system clock pulse generator starts. Since system clock pulses are supplied to the entire chip as soon as the system clock pulse generator starts functioning, the  $\overline{\text{RES}}$  pin must be kept low until the pulse generator output stabilizes. After the pulse generator output has stabilized, the CPU starts reset exception handling if the  $\overline{\text{RES}}$  pin is driven high.

## 6.2.3 Subsleep Mode

In subsleep mode, operation of the CPU and on-chip peripheral modules other than timer modules is halted. As long as a required voltage is applied, the contents of CPU registers, the on-chip peripheral modules, and some registers of the on-chip peripheral modules are retained. I/O ports keep the same state as before the transition.

Subsleep mode is cleared by an interrupt. When an interrupt is requested, subsleep mode is cleared and interrupt exception handling starts. Subsleep mode is not cleared if the I bit of CCR is set to 1 or the requested interrupt is disabled in the interrupt enable register. After subsleep mode is cleared, the system clock pulse generator starts.

SA0 bits in SYSCR2. After the SLEEP instruction is executed, the operating frequency changes to the frequency which is set before the execution. When the SLEEP instruction is executed, a transition to subactive mode, a transition to sleep mode, subsleep mode, standby mode, active mode, or subactive mode is made, depending on the combination of SYSCR1 and SYSCR2. When the  $\overline{\text{RES}}$  pin goes low, the system clock pulse generator starts. Since system clock signals are supplied to the entire chip as soon as the system clock pulse generator starts functioning, the  $\overline{\text{RES}}$  pin is kept low until the pulse generator output stabilizes. After the pulse generator output has stabilized, the CPU starts reset exception handling if the  $\overline{\text{RES}}$  pin is driven high.

### 6.3 Operating Frequency in Active Mode

Operation in active mode is clocked at the frequency designated by the MA2, MA1, and MA0 bits in SYSCR2. The operating frequency changes to the set frequency after SLEEP instruction execution.

by means of an interrupt.

#### 6.4.1 Direct Transition from Active Mode to Subactive Mode

The time from the start of SLEEP instruction execution to the end of interrupt exception (the direct transition time) is calculated by equation (1).

Direct transition time = {(number of SLEEP instruction execution states) + (number of interrupt processing states)} × (tcyc before transition) + (number of interrupt exception handling states) × (tsubcyc after transition) (1)

##### Example

Direct transition time =  $(2 + 1) \times \text{tosc} + 14 \times 8\text{tw} = 3\text{tosc} + 112\text{tw}$   
(when the CPU operating clock of  $\phi_{\text{osc}} \rightarrow \phi_{\text{w}}/8$  is selected)

##### Legend

tosc: OSC clock cycle time  
tw: watch clock cycle time  
tcyc: system clock ( $\phi$ ) cycle time  
tsubcyc: subclock ( $\phi_{\text{SUB}}$ ) cycle time

#### 6.4.2 Direct Transition from Subactive Mode to Active Mode

The time from the start of SLEEP instruction execution to the end of interrupt exception (the direct transition time) is calculated by equation (2).

Direct transition time = {(number of SLEEP instruction execution states) + (number of interrupt processing states)} × (tsubcyc before transition) + {(waiting time set in bits STS2 to STS4) + (number of interrupt exception handling states)} × (tcyc after transition) (2)

The module-standby function can be set to any peripheral module. In module standby mode, clock supply to modules stops to enter the power-down mode. Module standby mode enables on-chip peripheral module to enter the standby state by setting a bit that corresponds to each module to 1 and cancels the mode by clearing the bit to 0.

- The flash memory can be reprogrammed up to 1,000 times.
- On-board programming
  - On-board programming/erasing can be done in boot mode, in which the boot program into the chip is started to erase or program of the entire flash memory. In normal program mode, individual blocks can be erased or programmed.
- Programmer mode
  - Flash memory can be programmed/erased in programmer mode using a PROM programmer, as well as in on-board programming mode.
- Automatic bit rate adjustment
  - For data transfer in boot mode, this LSI's bit rate can be automatically adjusted to the transfer bit rate of the host.
- Programming/erasing protection
  - Sets software protection against flash memory programming/erasing.
- Power-down mode
  - Operation of the power supply circuit can be partly halted in subactive mode. As flash memory can be read with low power consumption.

## 7.1 Block Configuration

Figure 7.1 shows the block configuration of 32-kbyte flash memory. The thick lines indicate erasing units, the narrow lines indicate programming units, and the values are addresses. The memory is divided into 1 kbyte  $\times$  4 blocks and 28 kbytes  $\times$  1 block. Erasing is performed in 128-byte units. Programming is performed in 128-byte units starting from an address with lower H'00 or H'80.

Erase unit 1kbyte	H'0880	H'0881	H'0882		H'08FF
	H'0B80	H'0B81	H'0B82		H'0BFF
	H'0C00	H'0C01	H'0C02	← Programming unit: 128 bytes →	H'0C7F
Erase unit 1kbyte	H'0C80	H'0C81	H'0C82		H'0CFF
	H'0F80	H'0F81	H'0F82		H'0FFF
	H'1000	H'1001	H'1002	← Programming unit: 128 bytes →	H'107F
Erase unit 28 kbytes	H'1080	H'1081	H'1082		H'10FF
	H'7F80	H'7F81	H'7F82		H'7FFF

**Figure 7.1 Flash Memory Block Configuration**

## 7.2 Register Descriptions

The flash memory has the following registers.

- Flash memory control register 1 (FLMCR1)
- Flash memory control register 2 (FLMCR2)
- Erase block register 1 (EBR1)
- Flash memory power control register (FLPWCR)
- Flash memory enable register (FENR)

	SWE	0	R/W	<p>Control Write Enable</p> <p>When this bit is set to 1, flash memory programming/erasing is enabled. When this bit is cleared to 0, other FLMCR1 register bits and all EBR1 bits cannot be set.</p>
5	ESU	0	R/W	<p>Erase Setup</p> <p>When this bit is set to 1, the flash memory changes to the erase setup state. When it is cleared to 0, the erase setup state is cancelled. Set this bit to 1 before setting the E bit to 1 in FLMCR1.</p>
4	PSU	0	R/W	<p>Program Setup</p> <p>When this bit is set to 1, the flash memory changes to the program setup state. When it is cleared to 0, the program setup state is cancelled. Set this bit to 1 before setting the P bit in FLMCR1.</p>
3	EV	0	R/W	<p>Erase-Verify</p> <p>When this bit is set to 1, the flash memory changes to the erase-verify mode. When it is cleared to 0, the erase-verify mode is cancelled.</p>
2	PV	0	R/W	<p>Program-Verify</p> <p>When this bit is set to 1, the flash memory changes to the program-verify mode. When it is cleared to 0, the program-verify mode is cancelled.</p>
1	E	0	R/W	<p>Erase</p> <p>When this bit is set to 1, and while the SWE=1 and ESU=1 bits are 1, the flash memory changes to the erase mode. When it is cleared to 0, erase mode is cancelled.</p>

FLERR is a register that displays the state of flash memory programming/erasing. FLERR is a read-only register, and should not be written to.

Bit	Bit Name	Initial Value	R/W	Description
7	FLER	0	R	Flash Memory Error Indicates that an error has occurred during an operation on flash memory (programming or erasing). When this bit is set to 1, flash memory goes to the error-protected state. See 7.5.3, Error Protection, for details.
6 to 0	—	All 0	—	Reserved These bits are always read as 0.



4	EB4	0	R/W	When this bit is set to 1, 28 kbytes of H'1000 to H'1027 will be erased.
3	EB3	0	R/W	When this bit is set to 1, 1 kbyte of H'0C00 to H'0CFF will be erased.
2	EB2	0	R/W	When this bit is set to 1, 1 kbyte of H'0800 to H'08FF will be erased.
1	EB1	0	R/W	When this bit is set to 1, 1 kbyte of H'0400 to H'04FF will be erased.
0	EB0	0	R/W	When this bit is set to 1, 1 kbyte of H'0000 to H'00FF will be erased.

When this bit is 0 and a transition is made to sub-  
mode, the flash memory enters the power-down  
When this bit is 1, the flash memory remains in t  
normal mode even after a transition is made to s  
mode.

---

6 to 0	—	All 0	—	Reserved
--------	---	-------	---	----------

These bits are always read as 0.

---

### 7.2.5 Flash Memory Enable Register (FENR)

Bit 7 (FLSHE) in FENR enables or disables the CPU access to the flash memory control  
FLMCR1, FLMCR2, EBR1, and FLPWCR.

Bit	Bit Name	Initial Value	R/W	Description
7	FLSHE	0	R/W	Flash Memory Control Register Enable  Flash memory control registers can be accessed this bit is set to 1. Flash memory control register be accessed when this bit is set to 0.
6 to 0	—	All 0	—	Reserved  These bits are always read as 0.

---

via SCI3. After erasing the entire flash memory, the programming control program is erased. This can be used for programming initial values in the on-board state or for a forcible reprogramming/erasing can no longer be done in user program mode. In user program mode, individual blocks can be erased and programmed by branching to the user program/erasing program prepared by the user.

**Table 7.1 Setting Programming Modes**

TEST	$\overline{\text{NMI}}$	P85	PB0	PB1	PB2	LSI State after Reset End
0	1	X	X	X	X	User Mode
0	0	1	X	X	X	Boot Mode
1	X	X	0	0	0	Programmer Mode

Legend: X : Don't care.

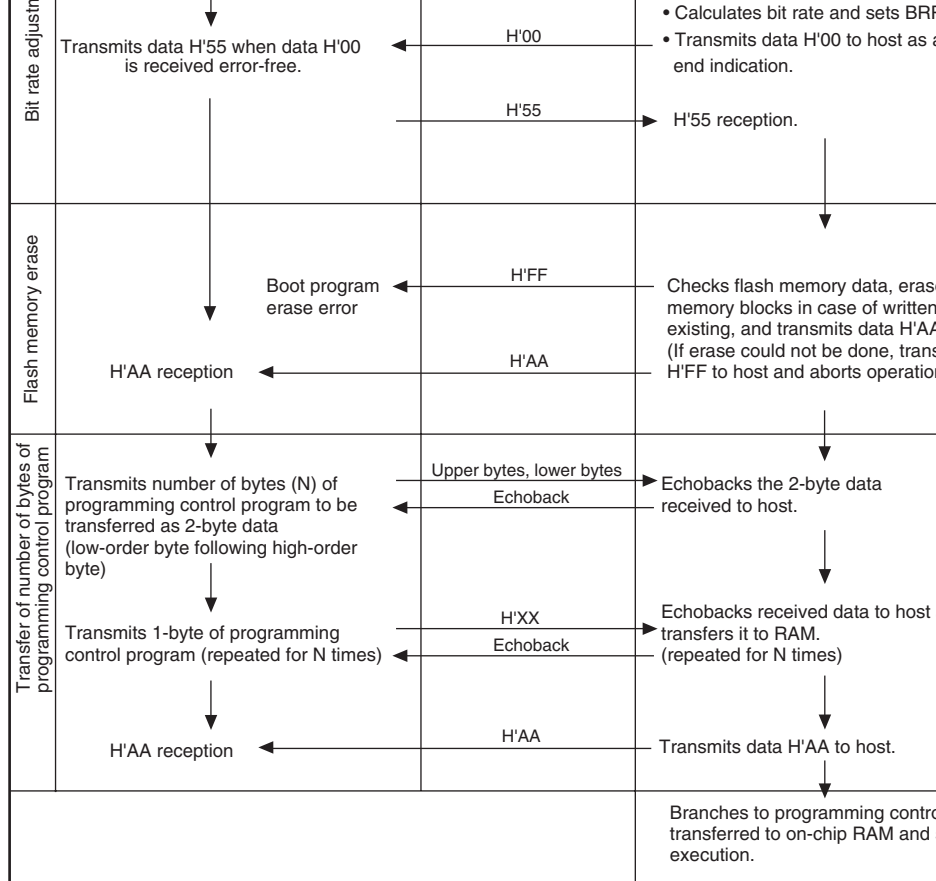
### 7.3.1 Boot Mode

Table 7.2 shows the boot mode operations between reset end and branching to the program control program.

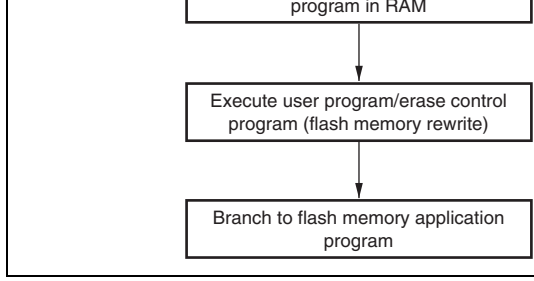
1. When boot mode is used, the flash memory programming control program must be prepared on the host beforehand. Prepare a programming control program in accordance with the description in section 7.4, Flash Memory Programming/Erasing.
2. SCI3 should be set to asynchronous mode, and the transfer format as follows: 8-bit character, 1 stop bit, and no parity.
3. When the boot program is initiated, the chip measures the low-level period of asynchronous SCI communication data (H'00) transmitted continuously from the host. The chip then calculates the bit rate of transmission from the host, and adjusts the SCI3 bit rate to match that of the host. The reset should end with the RxD pin high. The RxD and TxD pins should be set to high-impedance state.

The boot program area cannot be used until the execution state in boot mode switches to programming control program.

6. Before branching to the programming control program, the chip terminates transfer of data by SCI3 (by clearing the RE and TE bits in SCR to 0), however the adjusted bit rate value remains set in BRR. Therefore, the programming control program can still use it for transfer of write data or verify data with the host. The TxD pin is high (PCR22 = 1, P22 = 1). The contents of the CPU general registers are undefined immediately after branching to the programming control program. These registers must be initialized at the beginning of the programming control program, as the stack pointer (SP), in particular, is used implicitly in subroutine calls, etc.
7. Boot mode can be cleared by a reset. End the reset after driving the reset pin low, wait at least 20 states, and then setting the  $\overline{\text{NMI}}$  pin. Boot mode is also cleared when a WDT timeout occurs.
8. Do not change the TEST pin and NMI pin input levels in boot mode.



On-board programming/erasing of an individual flash memory block can also be performed in user program mode by branching to a user program/erase control program. The user must set the appropriate conditions and provide on-board means of supplying programming data. The flash memory must contain the user program/erase control program or a program that provides the user program/erase control program from external memory. As the flash memory itself cannot be read during programming/erasing, transfer the user program/erase control program to on-chip RAM, and execute it in user program mode. Figure 7.2 shows a sample procedure for programming/erasing in user program mode. Prepare a user program/erase control program in accordance with the description in section 7.5.2.2.2.2 Flash Memory Programming/Erasing.



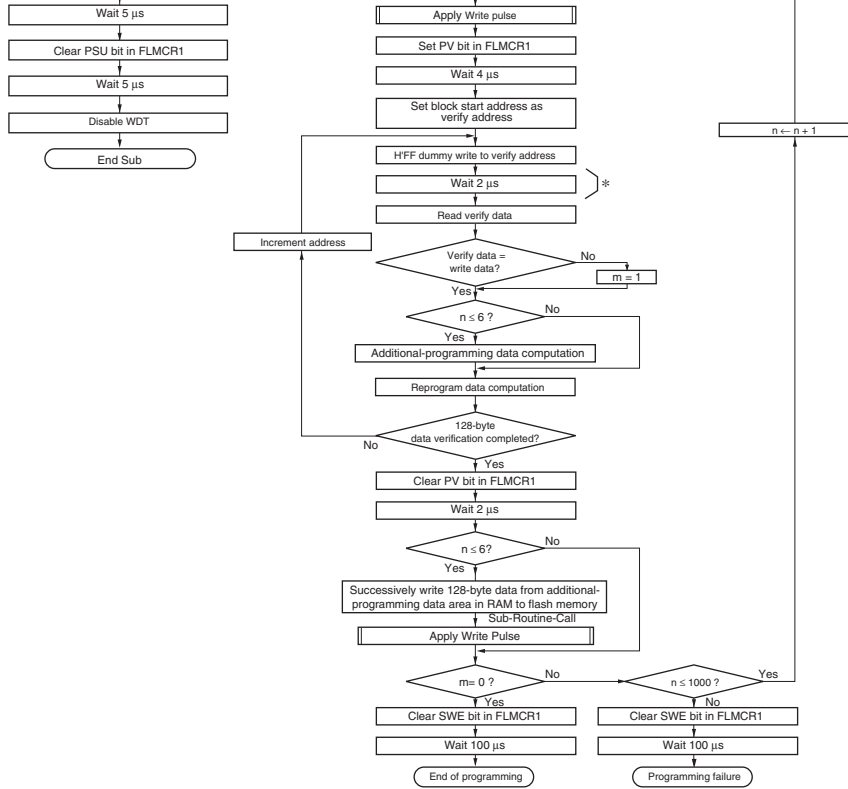
**Figure 7.2 Programming/Erasing Flowchart Example in User Program M**

### 7.4.1 Program/Program-Verify

When writing data or programs to the flash memory, the program/program-verify flowchart in figure 7.3 should be followed. Performing programming operations according to this flowchart will enable data or programs to be written to the flash memory without subjecting the chip to excessive voltage stress or sacrificing program data reliability.

1. Programming must be done to an empty address. Do not reprogram an address to which programming has already been performed.
2. Programming should be carried out 128 bytes at a time. A 128-byte data transfer must be performed even if writing fewer than 128 bytes. In this case, H'FF data must be written to the extra addresses.
3. Prepare the following data storage areas in RAM: A 128-byte programming data area, a 128-byte reprogramming data area, and a 128-byte additional-programming data area. Perform reprogramming data computation according to table 7.4, and additional programming data computation according to table 7.5.
4. Consecutively transfer 128 bytes of data in byte units from the reprogramming data area and the additional-programming data area to the flash memory. The program address and 128 bytes of data are latched in the flash memory. The lower 8 bits of the start address in the flash memory destination area must be H'00 or H'80.
5. The time during which the P bit is set to 1 is the programming time. Table 7.6 shows the allowable programming times.
6. The watchdog timer (WDT) is set to prevent overprogramming due to program runaway. An overflow cycle of approximately 6.6 ms is allowed.
7. For a dummy write to a verify address, write 1-byte data H'FF to an address whose lower 8 bits are B'00. Verify data can be read in words or in longwords from the address to which the dummy write was performed.





Notes: \* The RTS instruction must not be used during the following 1. and 2. periods.  
 1. A period between 128-byte data programming to flash memory and the P bit clearing  
 2. A period between dummy writing of HFF to a verify address and verify data reading

**Figure 7.3 Program/Program-Verify Flowchart**

Reprogram Data	Verify Data	Additional Program Data	Comments
0	0	0	Additional-program
0	1	1	No additional progra
1	0	1	No additional progra
1	1	1	No additional progra

**Table 7.6 Programming Time**

n (Number of Writes)	Programming Time	In Additional Programming	Comments
1 to 6	30	10	
7 to 1,000	200	—	

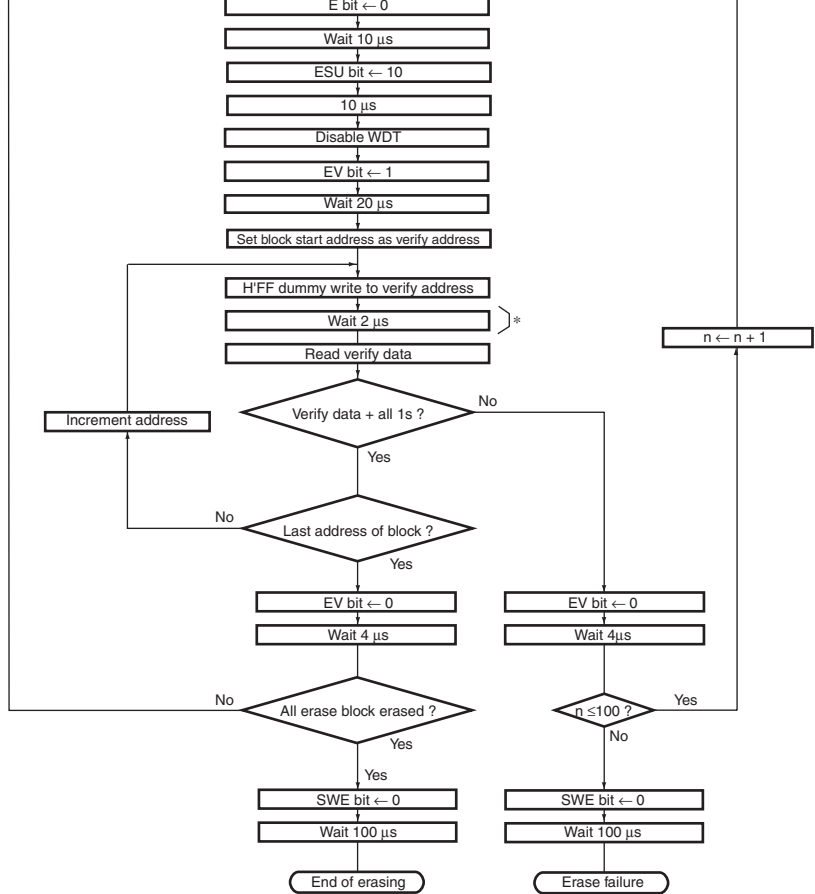
Note: Time shown in  $\mu$ s.

### 7.4.2 Erase/Erase-Verify

When erasing flash memory, the erase/erase-verify flowchart shown in figure 7.4 should be followed.

1. Prewriting (setting erase block data to all 0s) is not necessary.
2. Erasing is performed in block units. Make only a single-bit specification in the erase register (EBR1). To erase multiple blocks, each block must be erased in turn.
3. The time during which the E bit is set to 1 is the flash memory erase time.
4. The watchdog timer (WDT) is set to prevent overerasing due to program runaway, etc. overflow cycle of approximately 19.8 ms is allowed.

- or erased, or while the user program is executing, for the following three reasons:
1. Interrupt during programming/erasing may cause a violation of the programming or algorithm, with the result that normal operation cannot be assured.
  2. If interrupt exception handling starts before the vector address is written or during programming/erasing, a correct vector cannot be fetched and the CPU malfunctions.
  3. If an interrupt occurs during boot program execution, normal boot mode sequence cannot be carried out.



Note: \*The RTS instruction must not be used during a period between dummy writing of H'FF to a verify address and verify data read.

**Figure 7.4 Erase/Erase-Verify Flowchart**

entered unless the  $\overline{\text{RES}}$  pin is held low until oscillation stabilizes after powering on. In the event of a reset during operation, hold the  $\overline{\text{RES}}$  pin low for the  $\overline{\text{RES}}$  pulse width specified in the Characteristics section.

### 7.5.2 Software Protection

Software protection can be implemented against programming/erasing of all flash memory by clearing the SWE bit in FLMCR1. When software protection is in effect, setting the SWE bit in FLMCR1 does not cause a transition to program mode or erase mode. By setting the erase block register 1 (EBR1), erase protection can be set for individual blocks. When EBR1 is set to H'00, erase protection is set for all blocks.

### 7.5.3 Error Protection

In error protection, an error is detected when CPU runaway occurs during flash memory programming/erasing, or operation is not performed in accordance with the program/erase algorithm, and the program/erase operation is aborted. Aborting the program/erase operation prevents damage to the flash memory due to overprogramming or overerasing.

When the following errors are detected during programming/erasing of flash memory, the error protection bit in FLMCR2 is set to 1, and the error protection state is entered.

- When the flash memory of the relevant address area is read during programming/erasing (including vector read and instruction fetch)
- Immediately after exception handling excluding a reset during programming/erasing
- When a SLEEP instruction is executed during programming/erasing

The FLMCR1, FLMCR2, and EBR1 settings are retained, however program mode or erase mode is aborted at the point at which the error occurred. Program mode or erase mode cannot

In user mode, the flash memory will operate in either of the following states:

- Normal operating mode  
The flash memory can be read and written to at high speed.
- Power-down operating mode  
The power supply circuit of flash memory can be partly halted. As a result, flash memory can be read with low power consumption.
- Standby mode  
All flash memory circuits are halted.

Table 7.7 shows the correspondence between the operating modes of this LSI and the flash memory. In subactive mode, the flash memory can be set to operate in power-down mode by setting the PDWND bit in FLPWCR. When the flash memory returns to its normal operating state from power-down mode or standby mode, a period to stabilize operation of the power supply circuit that were stopped is needed. When the flash memory returns to its normal operating state, STS2 to STS0 in SYSCR1 must be set to provide a wait time of at least 20  $\mu$ s, even when an external clock is being used.







		H8/3692	512 kbytes	H'FD80 to H'FF7F
		H8/3691	512 kbytes	H'FD80 to H'FF7F
		H8/3690	512 kbytes	H'FD80 to H'FF7F
EEPROM stacked version	Flash memory version	H8/3694N	2 kbytes	H'F780 to H'FF7F*
	Mask-ROM version		1 kbyte	H'FB80 to H'FF7F

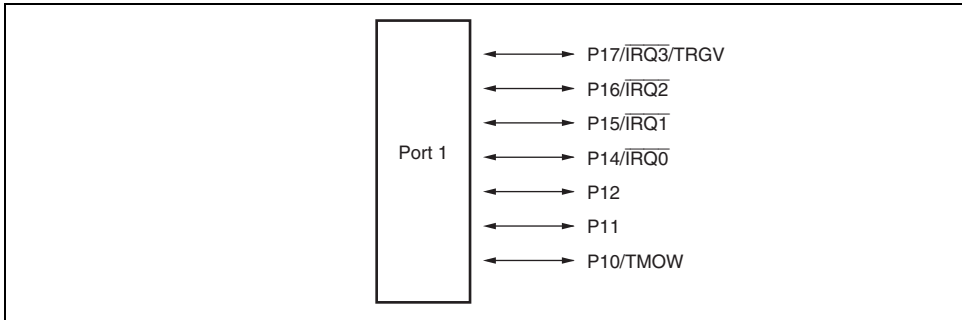
Note: \* When the E7 or E8 is used, area H'F780 to H'FB7F must not be accessed.



storing output data and can select inputs/outputs in bit units. For functions in each port, appendix B.1, I/O Port Block Diagrams. For the execution of bit manipulation instructions, port control register and port data register, see section 2.8.3, Bit Manipulation Instructions.

## 9.1 Port 1

Port 1 is a general I/O port also functioning as IRQ interrupt input pins, a timer A output pin, and a timer V input pin. Figure 9.1 shows its pin configuration.



**Figure 9.1 Port 1 Pin Configuration**

Port 1 has the following registers.

- Port mode register 1 (PMR1)
- Port control register 1 (PCR1)
- Port data register 1 (PDR1)
- Port pull-up control register 1 (PUCR1)

6	IRQ2	0	R/W	<p>P16/<math>\overline{\text{IRQ2}}</math> Pin Function Switch</p> <p>This bit selects whether pin P16/<math>\overline{\text{IRQ2}}</math> is used as <math>\overline{\text{IRQ2}}</math>.</p> <p>0: General I/O port</p> <p>1: <math>\overline{\text{IRQ2}}</math> input pin</p>
5	IRQ1	0	R/W	<p>P15/<math>\overline{\text{IRQ1}}</math> Pin Function Switch</p> <p>This bit selects whether pin P15/<math>\overline{\text{IRQ1}}</math> is used as <math>\overline{\text{IRQ1}}</math>.</p> <p>0: General I/O port</p> <p>1: <math>\overline{\text{IRQ1}}</math> input pin</p>
4	IRQ0	0	R/W	<p>P14/<math>\overline{\text{IRQ0}}</math> Pin Function Switch</p> <p>This bit selects whether pin P14/<math>\overline{\text{IRQ0}}</math> is used as <math>\overline{\text{IRQ0}}</math>.</p> <p>0: General I/O port</p> <p>1: <math>\overline{\text{IRQ0}}</math> input pin</p>
3, 2	—	All 1	—	<p>Reserved</p> <p>These bits are always read as 1.</p>
1	TXD	0	R/W	<p>P22/TXD Pin Function Switch</p> <p>This bit selects whether pin P22/TXD is used as TXD.</p> <p>0: General I/O port</p> <p>1: TXD output pin</p>
0	TMOW	0	R/W	<p>P10/TMOW Pin Function Switch</p> <p>This bit selects whether pin P10/TMOW is used as TMOW.</p> <p>0: General I/O port</p> <p>1: TMOW output pin</p>

2	PCR12	0	W
1	PCR11	0	W
0	PCR10	0	W

---

### 9.1.3 Port Data Register 1 (PDR1)

PDR1 is a general I/O port data register of port 1.

Bit	Bit Name	Initial Value	R/W	Description
7	P17	0	R/W	PDR1 stores output data for port 1 pins.
6	P16	0	R/W	If PDR1 is read while PCR1 bits are set to 1, the values stored in PDR1 are read. If PDR1 is read while PCR1 bits are cleared to 0, the pin states are read regardless of the value stored in PDR1.
5	P15	0	R/W	
4	P14	0	R/W	
3	—	1	—	Bit 3 is a reserved bit. This bit is always read as 1.
2	P12	0	R/W	
1	P11	0	R/W	
0	P10	0	R/W	

---

3	—	1	—
2	PUCR12	0	R/W
1	PUCR11	0	R/W
0	PUCR10	0	R/W

### 9.1.5 Pin Functions

The correspondence between the register specification and the port functions is shown below.

#### P17/ $\overline{\text{IRQ3}}$ /TRGV pin

Register	PMR1	PCR1	
Bit Name	IRQ3	PCR17	Pin Function
Setting value	0	0	P17 input pin
		1	P17 output pin
	1	X	$\overline{\text{IRQ3}}$ input/TRGV input pin

Legend: X: Don't care.

#### P16/ $\overline{\text{IRQ2}}$ pin

Register	PMR1	PCR1	
Bit Name	IRQ2	PCR16	Pin Function
Setting value	0	0	P16 input pin
		1	P16 output pin
	1	X	$\overline{\text{IRQ2}}$ input pin

Legend: X: Don't care.

Register	PMR1	PCR1	
Bit Name	IRQ0	PCR14	Pin Function
Setting value	0	0	P14 input pin
		1	P14 output pin
	1	X	$\overline{\text{IRQ0}}$ input pin

Legend: X: Don't care.

### P12 pin

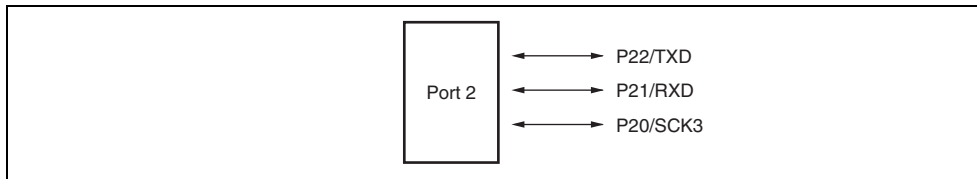
Register	PCR1	
Bit Name	PCR12	Pin Function
Setting value	0	P12 input pin
	1	P12 output pin

### P11 pin

Register	PCR1	
Bit Name	PCR11	Pin Function
Setting value	0	P11 input pin
	1	P11 output pin

## 9.2 Port 2

Port 2 is a general I/O port also functioning as a SCI3 I/O pin. Each pin of the port 2 is shown in figure 9.2. The register settings of PMR1 and SCI3 have priority for functions of the pins in the following uses.



**Figure 9.2 Port 2 Pin Configuration**

Port 2 has the following registers.

- Port control register 2 (PCR2)
- Port data register 2 (PDR2)



### 9.2.2 Port Data Register 2 (PDR2)

PDR2 is a general I/O port data register of port 2.

Bit	Bit Name	Initial Value	R/W	Description
7 to 3	—	All 1	—	Reserved These bits are always read as 1.
2	P22	0	R/W	PDR2 stores output data for port 2 pins.
1	P21	0	R/W	If PDR2 is read while PCR2 bits are set to 1, the value stored in PDR2 is read. If PDR2 is read while PCR2 bits are cleared to 0, the pin states are read regardless of the value stored in PDR2.
0	P20	0	R/W	

1	X	P22 output pin
---	---	----------------

Legend: X: Don't care.

### P21/RXD pin

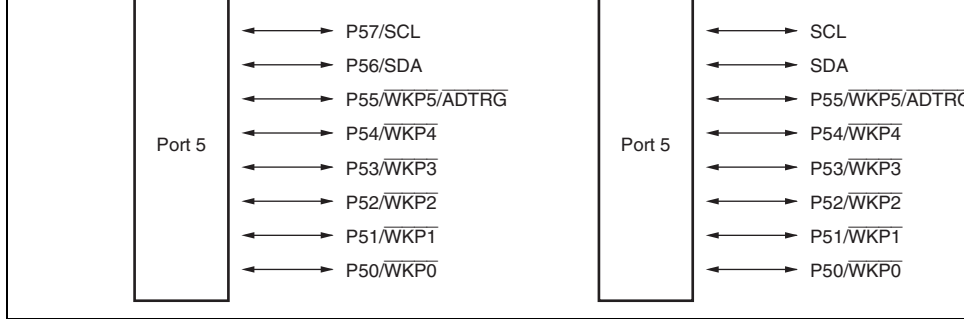
Register	SCR3	PCR2	
Bit Name	RE	PCR21	Pin Function
Setting Value	0	0	P21 input pin
		1	P21 output pin
	1	X	RXD input pin

Legend: X: Don't care.

### P20/SCK3 pin

Register	SCR3		SMR	PCR2	
Bit Name	CKE1	CKE0	COM	PCR20	Pin Function
Setting Value	0	0	0	0	P20 input pin
				1	P20 output pin
	0	0	1	X	SCK3 output pin
	0	1	X	X	SCK3 output pin
	1	X	X	X	SCK3 input pin

Legend: X: Don't care.



**Figure 9.3 Port 5 Pin Configuration**

Port 5 has the following registers.

- Port mode register 5 (PMR5)
- Port control register 5 (PCR5)
- Port data register 5 (PDR5)
- Port pull-up control register 5 (PUCR5)

				0: General I/O port 1: $\overline{\text{WKP5/ADTRG}}$ input pin
4	WKP4	0	R/W	P54/ $\overline{\text{WKP4}}$ Pin Function Switch Selects whether pin P54/ $\overline{\text{WKP4}}$ is used as P54 or $\overline{\text{WKP4}}$ . 0: General I/O port 1: $\overline{\text{WKP4}}$ input pin
3	WKP3	0	R/W	P53/ $\overline{\text{WKP3}}$ Pin Function Switch Selects whether pin P53/ $\overline{\text{WKP3}}$ is used as P53 or $\overline{\text{WKP3}}$ . 0: General I/O port 1: $\overline{\text{WKP3}}$ input pin
2	WKP2	0	R/W	P52/ $\overline{\text{WKP2}}$ Pin Function Switch Selects whether pin P52/ $\overline{\text{WKP2}}$ is used as P52 or $\overline{\text{WKP2}}$ . 0: General I/O port 1: $\overline{\text{WKP2}}$ input pin
1	WKP1	0	R/W	P51/ $\overline{\text{WKP1}}$ Pin Function Switch Selects whether pin P51/ $\overline{\text{WKP1}}$ is used as P51 or $\overline{\text{WKP1}}$ . 0: General I/O port 1: $\overline{\text{WKP1}}$ input pin
0	WKP0	0	R/W	P50/ $\overline{\text{WKP0}}$ Pin Function Switch Selects whether pin P50/ $\overline{\text{WKP0}}$ is used as P50 or $\overline{\text{WKP0}}$ . 0: General I/O port 1: $\overline{\text{WKP0}}$ input pin

3	PCR53	0	W
2	PCR52	0	W
1	PCR51	0	W
0	PCR50	0	W

### 9.3.3 Port Data Register 5 (PDR5)

PDR5 is a general I/O port data register of port 5.

Bit	Bit Name	Initial Value	R/W	Description
7	P57	0	R/W	Stores output data for port 5 pins.
6	P56	0	R/W	If PDR5 is read while PCR5 bits are set to 1, the values stored in PDR5 are read. If PDR5 is read while PCR5 bits are cleared to 0, the pin states are read regardless of the value stored in PDR5.
5	P55	0	R/W	
4	P54	0	R/W	Note: The P57 and P56 bits should not be set to 1 in H8/3694N.
3	P53	0	R/W	
2	P52	0	R/W	
1	P51	0	R/W	
0	P50	0	R/W	

3	PUCR53	0	R/W	these bits are cleared to 0.
2	PUCR52	0	R/W	
1	PUCR51	0	R/W	
0	PUCR50	0	R/W	

---

### 9.3.5 Pin Functions

The correspondence between the register specification and the port functions is shown below.

#### P57/SCL pin

Register	ICCR1	PCR5	
Bit Name	ICE	PCR57	Pin Function
Setting Value	0	0	P57 input pin
		1	P57 output pin
	1	X	SCL I/O pin

Legend: X: Don't care.

SCL performs the NMOS open-drain output, that enables a direct bus drive.

SDA performs the NMOS open-drain output, that enables a direct bus drive.

### P55/ $\overline{\text{WKP5}}$ / $\overline{\text{ADTRG}}$ pin

Register	PMR5	PCR5	
Bit Name	WKP5	PCR55	Pin Function
Setting Value	0	0	P55 input pin
		1	P55 output pin
	1	X	$\overline{\text{WKP5}}$ / $\overline{\text{ADTRG}}$ input pin

Legend: X: Don't care.

### P54/ $\overline{\text{WKP4}}$ pin

Register	PMR5	PCR5	
Bit Name	WKP4	PCR54	Pin Function
Setting Value	0	0	P54 input pin
		1	P54 output pin
	1	X	$\overline{\text{WKP4}}$ input pin

Legend: X: Don't care.

**P52/WKP2 pin**

<b>Register</b>	<b>PMR5</b>	<b>PCR5</b>	
<b>Bit Name</b>	<b>WKP2</b>	<b>PCR52</b>	<b>Pin Function</b>
Setting Value	0	0	P52 input pin
		1	P52 output pin
	1	X	WKP2 input pin

Legend: X: Don't care.

**P51/WKP1 pin**

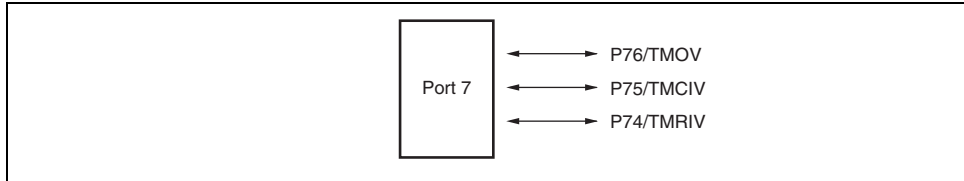
<b>Register</b>	<b>PMR5</b>	<b>PCR5</b>	
<b>Bit Name</b>	<b>WKP1</b>	<b>PCR51</b>	<b>Pin Function</b>
Setting Value	0	0	P51 input pin
		1	P51 output pin
	1	X	WKP1 input pin

Legend: X: Don't care.



## 9.4 Port 7

Port 7 is a general I/O port also functioning as a timer V I/O pin. Each pin of the port 7 is shown in figure 9.4. The register setting of TCSR<sub>V</sub> in timer V has priority for functions of pin P76/TMOV. The pins, P75/TMCIV and P74/TMRIV, are also functioning as timer V inputs that are connected to the timer V regardless of the register setting of port 7.



**Figure 9.4 Port 7 Pin Configuration**

Port 7 has the following registers.

- Port control register 7 (PCR7)
- Port data register 7 (PDR7)

---

3 to 0	—	—	—	Reserved
--------	---	---	---	----------

---

#### 9.4.2 Port Data Register 7 (PDR7)

PDR7 is a general I/O port data register of port 7.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved This bit is always read as 1.
6	P76	0	R/W	PDR7 stores output data for port 7 pins.
5	P75	0	R/W	If PDR7 is read while PCR7 bits are set to 1, the stored in PDR7 is read. If PDR7 is read while PCR7 bits are cleared to 0, the pin states are read regardless of the value stored in PDR7.
4	P74	0	R/W	
3 to 0	—	All 1	—	Reserved These bits are always read as 1.

---

Other than the above values	X	TMOV output pin
-----------------------------	---	-----------------

Legend: X: Don't care.

### P75/TMCIV pin

**Register**     **PCR7**

**Bit Name**     **PCR75**     **Pin Function**

Setting     0     P75 input/TMCIV input pin  
Value

1     P75 output/TMCIV input pin

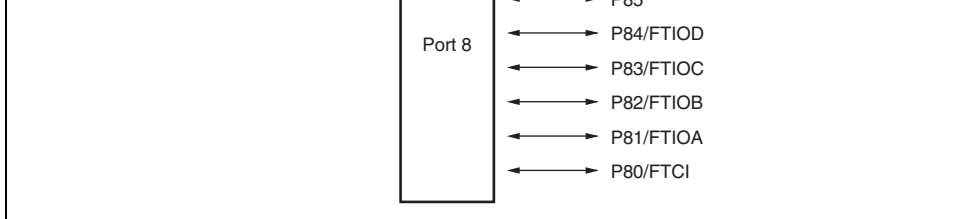
### P74/TMRIV pin

**Register**     **PCR7**

**Bit Name**     **PCR74**     **Pin Function**

Setting     0     P74 input/TMRIV input pin  
Value

1     P74 output/TMRIV input pin



**Figure 9.5 Port 8 Pin Configuration**

Port 8 has the following registers.

- Port control register 8 (PCR8)
- Port data register 8 (PDR8)

### 9.5.1 Port Control Register 8 (PCR8)

PCR8 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 8.

Bit	Bit Name	Initial Value	R/W	Description
7	PCR87	0	W	When each of the port 8 pins P87 to P80 function as a general I/O port, setting a PCR8 bit to 1 makes the corresponding pin an output port, while clearing it to 0 makes the pin an input port.
6	PCR86	0	W	
5	PCR85	0	W	
4	PCR84	0	W	
3	PCR83	0	W	
2	PCR82	0	W	
1	PCR81	0	W	
0	PCR80	0	W	

3	P83	0	R/W
2	P82	0	R/W
1	P81	0	R/W
0	P80	0	R/W

---

### 9.5.3 Pin Functions

The correspondence between the register specification and the port functions is shown below.

#### P87 pin

Register	PCR8	
Bit Name	PCR87	Pin Function
Setting Value	0	P87 input pin
	1	P87 output pin

---

#### P86 pin

Register	PCR8	
Bit Name	PCR86	Pin Function
Setting Value	0	P86 input pin
	1	P86 output pin

---

Register	TIOR1			PCR8	
Bit Name	IOD2	IOD1	IOD0	PCR84	Pin Function
Setting Value	0	0	0	0	P84 input/FTIOD input pin
				1	P84 output/FTIOD input pin
	0	0	1	X	FTIOD output pin
	0	1	X	X	FTIOD output pin
	1	X	X	0	P84 input/FTIOD input pin
				1	P84 output/FTIOD input pin

Legend: X: Don't care.

### P83/FTIOC pin

Register	TIOR1			PCR8	
Bit Name	IOC2	IOC1	IOC0	PCR83	Pin Function
Setting Value	0	0	0	0	P83 input/FTIOC input pin
				1	P83 output/FTIOC input pin
	0	0	1	X	FTIOC output pin
	0	1	X	X	FTIOC output pin
	1	X	X	0	P83 input/FTIOC input pin
				1	P83 output/FTIOC input pin

Legend: X: Don't care.

Legend: X: Don't care.

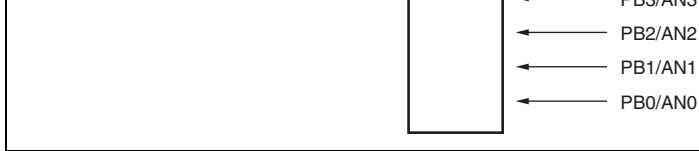
### P81/FTIOA pin

Register	TIOR0			PCR8	
	IOA2	IOA1	IOA0	PCR81	Pin Function
Setting Value	0	0	0	0	P81 input/FTIOA input pin
				1	P81 output/FTIOA input pin
	0	0	1	X	FTIOA output pin
	0	1	X	X	FTIOA output pin
	1	X	X	0	P81 input/FTIOA input pin
				1	P81 output/FTIOA input pin

Legend: X: Don't care.

### P80/FTCI pin

Register	PCR8	
Bit Name	PCR80	Pin Function
Setting Value	0	P80 input/FTCI input pin
	1	P80 output/FTCI input pin



**Figure 9.6 Port B Pin Configuration**

Port B has the following register.

- Port data register B (PDRB)

### 9.6.1 Port Data Register B (PDRB)

PDRB is a general input-only port data register of port B.

Bit	Bit Name	Initial Value	R/W	Description
7	PB7	—	R	The input value of each pin is read by reading the register.
6	PB6	—	R	
5	PB5	—	R	However, if a port B pin is designated as an analog channel by ADCSR in A/D converter, 0 is read.
4	PB4	—	R	
3	PB3	—	R	
2	PB2	—	R	
1	PB1	—	R	
0	PB0	—	R	



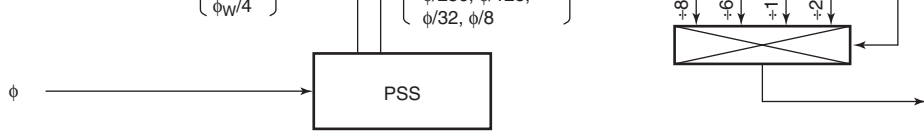
- Any of eight clock signals can be output from pin TMOW: 32.768 kHz divided by 3, 4 (1 kHz, 2 kHz, 4 kHz, 8 kHz), or the system clock divided by 32, 16, 8, or 4.

### **Interval Timer**

- Choice of eight internal clock sources ( $\phi/8192$ ,  $\phi/4096$ ,  $\phi/2048$ ,  $\phi/512$ ,  $\phi/256$ ,  $\phi/128$ ,

### **Clock Time Base**

- Choice of four overflow periods (1 s, 0.5 s, 0.25 s, 31.25 ms) when timer A is used as a time base (using a 32.768 kHz crystal oscillator).



[Legend]  
 TMA: Timer mode register A  
 TCA: Timer counter A  
 IRRTA: Timer A overflow interrupt request flag  
 PSW: Prescaler W  
 PSS: Prescaler S

Note: \* Can be selected only when the prescaler W output ( $\phi_W/128$ ) is used as the TCA input clock.

**Figure 10.1 Block Diagram of Timer A**

## 10.2 Input/Output Pins

Table 10.1 shows the timer A input/output pin.

**Table 10.1 Pin Configuration**

Name	Abbreviation	I/O	Function
Clock output	TMOW	Output	Output of waveform generated by timer A output circuit

Bit	Bit Name	Initial Value	R/W	Description
7	TMA7	0	R/W	Clock Output Select 7 to 5
6	TMA6	0	R/W	These bits select the clock output at the TMOW
5	TMA5	0	R/W	000: $\phi/32$ 001: $\phi/16$ 010: $\phi/8$ 011: $\phi/4$ 100: $\phi_w/32$ 101: $\phi_w/16$ 110: $\phi_w/8$ 111: $\phi_w/4$ For details on clock outputs, see section 10.4.3 Output.
4	—	1	—	Reserved This bit is always read as 1.
3	TMA3	0	R/W	Internal Clock Select 3 This bit selects the operating mode of the timer 0: Functions as an interval timer to count the ou prescaler S. 1: Functions as a clock-time base to count the o prescaler W.

110:  $\phi/32$

111:  $\phi/8$

These bits select the overflow period when TMA  
(when a 32.768 kHz crystal oscillator with is used)

000: 1s

001: 0.5 s

010: 0.25 s

011: 0.03125 s

1XX: Both PSW and TCA are reset

---

Legend: X: Don't care.

### 10.3.2 Timer Counter A (TCA)

TCA is an 8-bit readable up-counter, which is incremented by internal clock input. The clock source for input to this counter is selected by bits TMA3 to TMA0 in TMA. TCA values are read by the CPU in active mode, but cannot be read in subactive mode. When TCA overflows, the IRRTA bit in interrupt request register 1 (IRR1) is set to 1. TCA is cleared by setting bits TMA1 and TMA2 in TMA to B'11. TCA is initialized to H'00.

When the count value in TCR reaches H'FF, the next clock signal input causes timer A to overflow, setting bit IRRTA to 1 in interrupt Flag Register 1 (IRR1). If IENTA = 1 in interrupt enable register 1 (IENR1), a CPU interrupt is requested. At overflow, TCA returns to H'00 and starts counting up again. In this mode timer A functions as an interval timer that generates overflow output at intervals of 256 input clock pulses.

#### 10.4.2 Clock Time Base Operation

When bit TMA3 in TMA is set to 1, timer A functions as a clock-timer base by counting signals output by prescaler W. When a clock signal is input after the TCA counter value becomes H'FF, timer A overflows and IRRTA in IRR1 is set to 1. At that time, an interrupt is generated to the CPU if IENTA in the interrupt enable register 1 (IENR1) is 1. The overflow period of timer A is set by bits TMA1 and TMA0 in TMA. A choice of four periods is available. In clock time base operation (TMA3 = 1), setting bit TMA2 to 1 clears both TCA and prescaler W to H'00.

#### 10.4.3 Clock Output

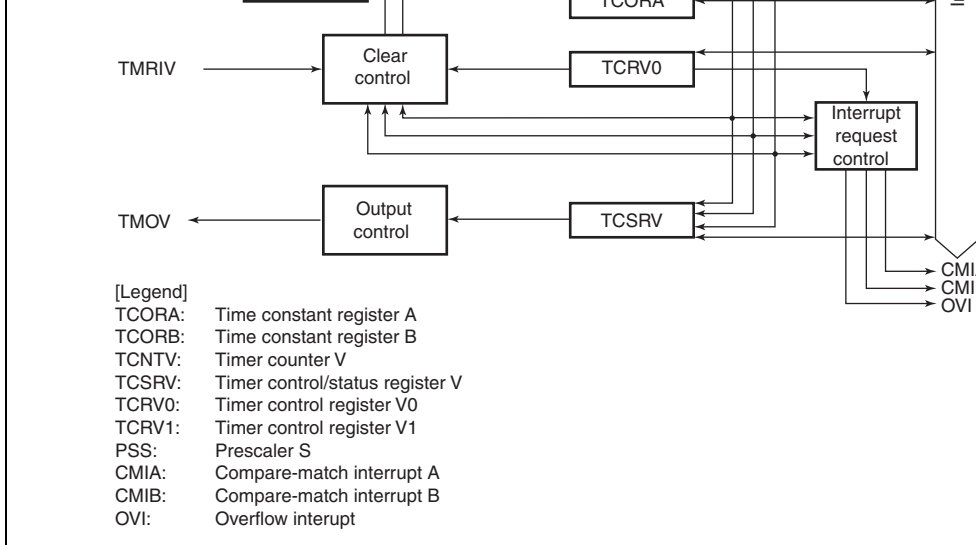
Setting bit TMOW in port mode register 1 (PMR1) to 1 causes a clock signal to be output from pin TMA0. Eight different clock output signals can be selected by means of bits TMA7 to TMA0 in TMA. The system clock divided by 32, 16, 8, or 4 can be output in active mode and sleep mode. The 32.768 kHz signal divided by 32, 16, 8, or 4 can be output in active mode, sleep mode, and subactive mode.

### 10.5 Usage Note

When the clock time base function is selected as the internal clock of TCA in active mode or sleep mode, the internal clock is not synchronous with the system clock, so it is synchronized by a synchronizing circuit. This may result in a maximum error of  $1/\phi$  (s) in the count cycle.



- Choice of seven clock signals is available.  
Choice of six internal clock sources ( $\phi/128$ ,  $\phi/64$ ,  $\phi/32$ ,  $\phi/16$ ,  $\phi/8$ ,  $\phi/4$ ) or an external clock source.
- Counter can be cleared by compare match A or B, or by an external reset signal. If the stop function is selected, the counter can be halted when cleared.
- Timer output is controlled by two independent compare match signals, enabling pulse width modulation (PWM) with an arbitrary duty cycle, PWM output, and other applications.
- Three interrupt sources: compare match A, compare match B, timer overflow
- Counting can be initiated by trigger input at the TRGV pin. The rising edge, falling edge, or both edges of the TRGV input can be selected.



**Figure 11.1 Block Diagram of Timer V**

## 11.2 Input/Output Pins

Table 11.1 shows the timer V pin configuration.

**Table 11.1 Pin Configuration**

Name	Abbreviation	I/O	Function
Timer V output	TMOV	Output	Timer V waveform output
Timer V clock input	TMCIV	Input	Clock input to TCNTV
Timer V reset input	TMRIV	Input	External input to reset TCNTV
Trigger input	TRGV	Input	Trigger input to initiate counting



### 11.3.1 Timer Counter V (TCNTV)

TCNTV is an 8-bit up-counter. The clock source is selected by bits CKS2 to CKS0 in timer control register V0 (TCRV0). The TCNTV value can be read and written by the CPU at any time. TCNTV can be cleared by an external reset input signal, or by compare match A or B. The clearing signal is selected by bits CCLR1 and CCLR0 in TCRV0.

When TCNTV overflows, OVF is set to 1 in timer control/status register V (TCSR.V).

TCNTV is initialized to H'00.

### 11.3.2 Time Constant Registers A and B (TCORA, TCORB)

TCORA and TCORB have the same function.

TCORA and TCORB are 8-bit read/write registers.

TCORA and TCNTV are compared at all times. When the TCORA and TCNTV contents are equal, CMFA is set to 1 in TCSR.V. If CMIEA is also set to 1 in TCRV0, a CPU interrupt is generated. Note that they must not be compared during the T3 state of a TCORA write cycle.

Timer output from the TMOV pin can be controlled by the identifying signal (compare match A or B) and the settings of bits OS3 to OS0 in TCSR.V.

TCORA and TCORB are initialized to H'FF.

6	CMIEA	0	R/W	Compare Match Interrupt Enable A When this bit is set to 1, interrupt request from the bit in TCSRV is enabled.
5	OVIE	0	R/W	Timer Overflow Interrupt Enable When this bit is set to 1, interrupt request from the bit in TCSRV is enabled.
4	CCLR1	0	R/W	Counter Clear 1 and 0
3	CCLR0	0	R/W	These bits specify the clearing conditions of TCNTV. 00: Clearing is disabled 01: Cleared by compare match A 10: Cleared by compare match B 11: Cleared on the rising edge of the TMRIV pin. operation of TCNTV after clearing depends on the operation in TCRV1.
2	CKS2	0	R/W	Clock Select 2 to 0
1	CKS1	0	R/W	These bits select clock signals to input to TCNTV.
0	CKS0	0	R/W	counting condition in combination with ICKS0 in table 11.2. Refer to table 11.2.

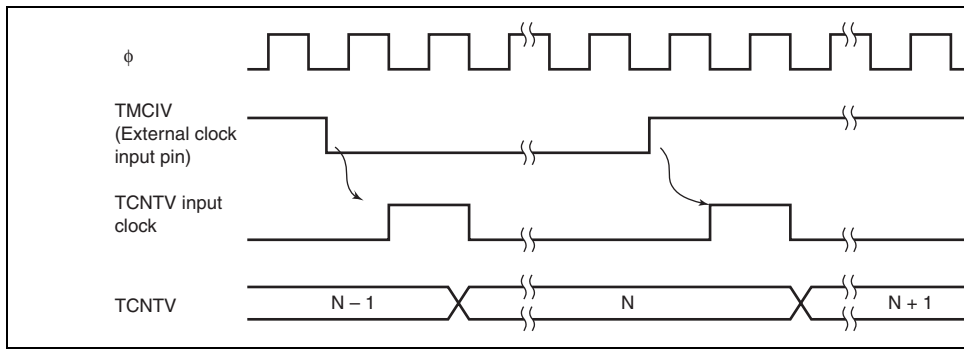
		1	0	Internal clock: counts on $\phi/64$ , falling
			1	Internal clock: counts on $\phi/128$ , falling
1	0	0	—	Clock input prohibited
		1	—	External clock: counts on rising edge
	1	0	—	External clock: counts on falling edge
		1	—	External clock: counts on rising and fa

6	CMFA	0	R/W	Compare Match Flag A Setting condition: When the TCNTV value matches the TCORA value Clearing condition: After reading CMFA = 1, cleared by writing 0 to CMFA
5	OVF	0	R/W	Timer Overflow Flag Setting condition: When TCNTV overflows from H'FF to H'00 Clearing condition: After reading OVF = 1, cleared by writing 0 to OVF
4	—	1	—	Reserved This bit is always read as 1.
3	OS3	0	R/W	Output Select 3 and 2
2	OS2	0	R/W	These bits select an output method for the TMO when the compare match of TCORB and TCNTV. 00: No change 01: 0 output 10: 1 output 11: Output toggles
1	OS1	0	R/W	Output Select 1 and 0
0	OS0	0	R/W	These bits select an output method for the TMO when the compare match of TCORA and TCNTV. 00: No change 01: 0 output 10: 1 output 11: Output toggles

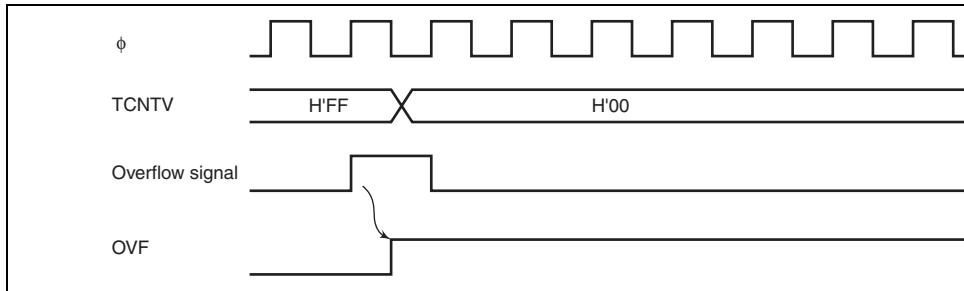
7 to 5	—	All 1	—	Reserved These bits are always read as 1.
4	TVEG1	0	R/W	TRGV Input Edge Select
3	TVEG0	0	R/W	These bits select the TRGV input edge. 00: TRGV trigger input is prohibited 01: Rising edge is selected 10: Falling edge is selected 11: Rising and falling edges are both selected
2	TRGE	0	R/W	TCNT starts counting up by the input of the edge selected by TVEG1 and TVEG0. 0: Disables starting counting-up TCNTV by the the TRGV pin and halting counting-up TCNTV. TCNTV is cleared by a compare match. 1: Enables starting counting-up TCNTV by the the TRGV pin and halting counting-up TCNTV. TCNTV is cleared by a compare match.
1	—	1	—	Reserved This bit is always read as 1.
0	ICKS0	0	R/W	Internal Clock Select 0 This bit selects clock signals to input to TCNTV combination with CKS2 to CKS0 in TCRV0. Refer to table 11.2.

will be set. The timing at this time is shown in figure 11.4. An interrupt request is sent to the CPU when OVIE in TCRV0 is 1.

3. TCNTV is constantly compared with TCORA and TCORB. Compare match flag A or B (CMFA or CMFB) is set to 1 when TCNTV matches TCORA or TCORB, respectively. A compare-match signal is generated in the last state in which the values match. Figure 11.5 shows the timing. An interrupt request is generated for the CPU when CMIEA or CMIEB in TCRV0 is 1.
4. When a compare match A or B is generated, the TMOV responds with the output value selected by bits OS3 to OS0 in TCSR.V. Figure 11.6 shows the timing when the output is toggled by compare match A.
5. When CCLR1 or CCLR0 in TCRV0 is 01 or 10, TCNTV can be cleared by the corresponding compare match. Figure 11.7 shows the timing.
6. When CCLR1 or CCLR0 in TCRV0 is 11, TCNTV can be cleared by the rising edge of the input of TMRIV pin. A TMRIV input pulse-width of at least 1.5 system clocks is necessary. Figure 11.8 shows the timing.
7. When a counter-clearing source is generated with TRGE in TCRV1 set to 1, the counter is halted as soon as TCNTV is cleared. TCNTV resumes counting-up when the edge selected by TVEG1 or TVEG0 in TCRV1 is input from the TGRV pin.



**Figure 11.3 Increment Timing with External Clock**



**Figure 11.4 OVF Set Timing**

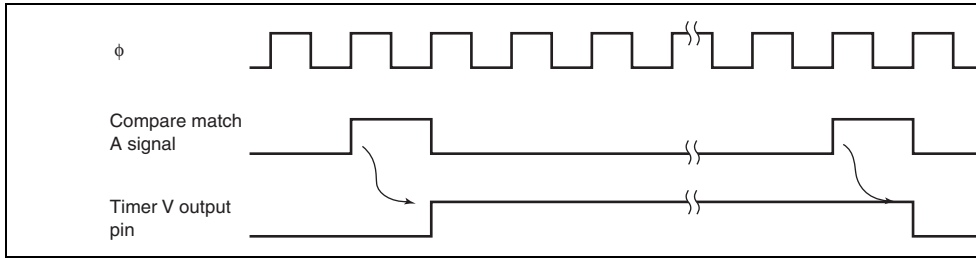


Figure 11.6 TMOV Output Timing

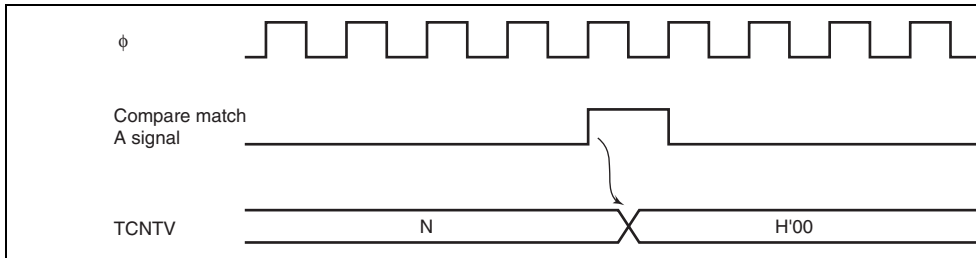
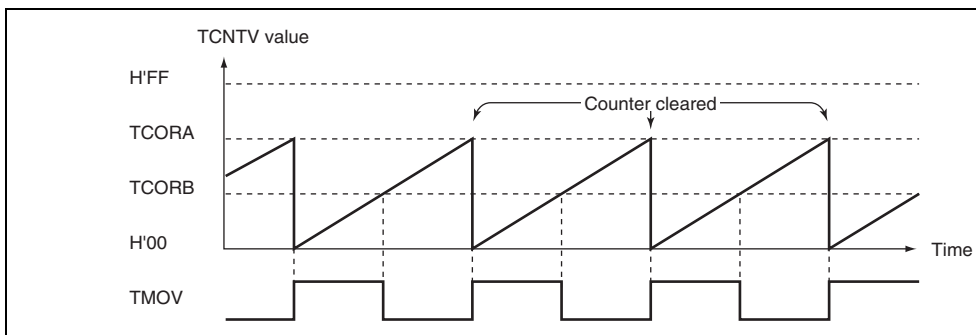


Figure 11.7 Clear Timing by Compare Match



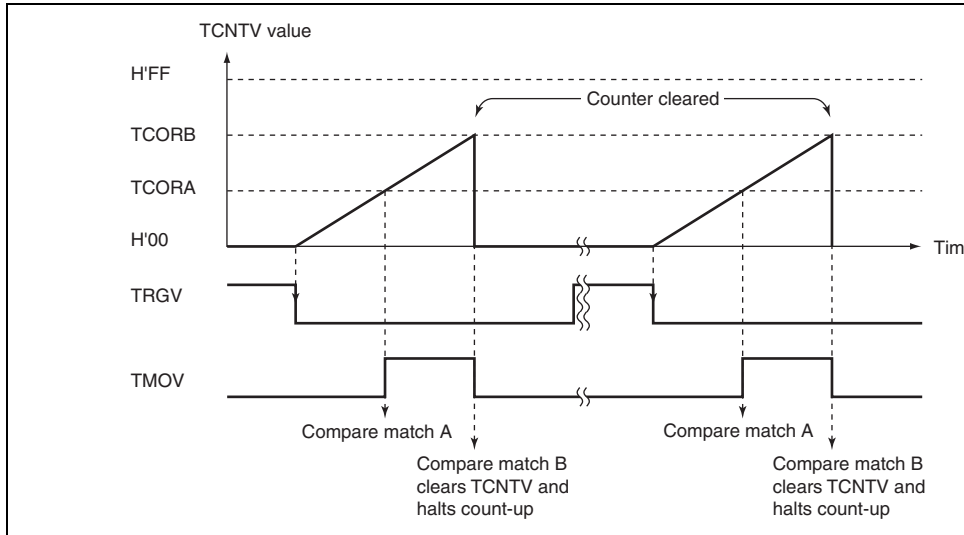


3. Set bits CKS2 to CKS0 in TCRV0 and bit ICKS0 in TCRV1 to select the desired clock.
4. With these settings, a waveform is output without further software intervention, with a period determined by TCORA and a pulse width determined by TCORB.



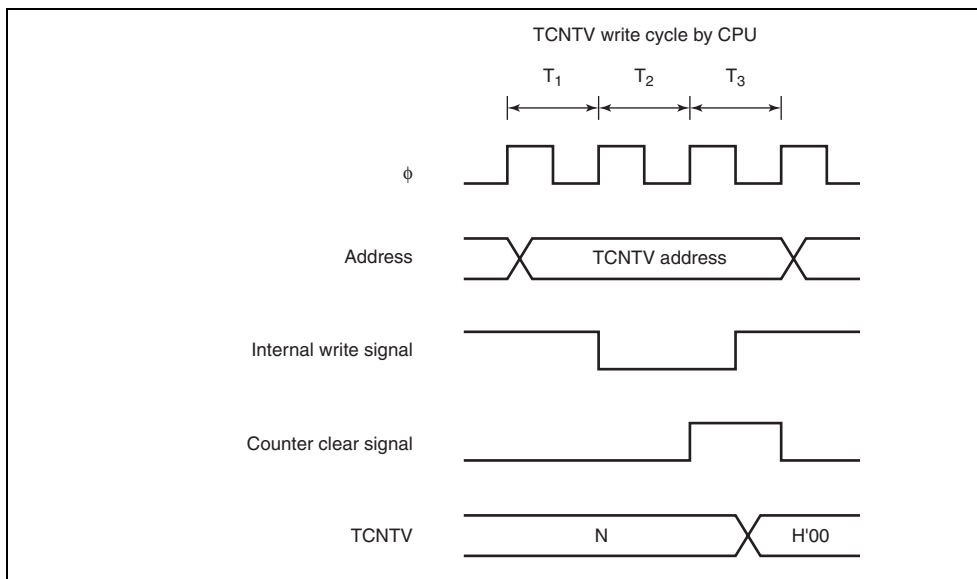
**Figure 11.9 Pulse Output Example**

- input.
- Set bits CKS2 to CKS0 in TCRV0 and bit ICKS0 in TCRV1 to select the desired clock.
  - After these settings, a pulse waveform will be output without further software intervention with a delay determined by TCORA from the TRGV input, and a pulse width determined by TCORB - TCORA.

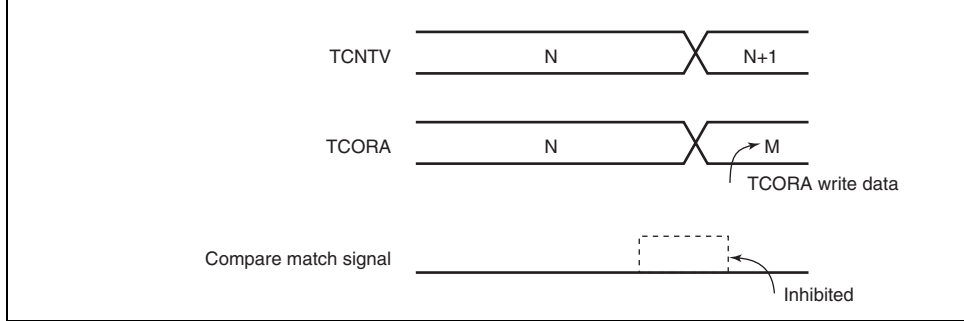


**Figure 11.10 Example of Pulse Output Synchronized to TRGV Input**

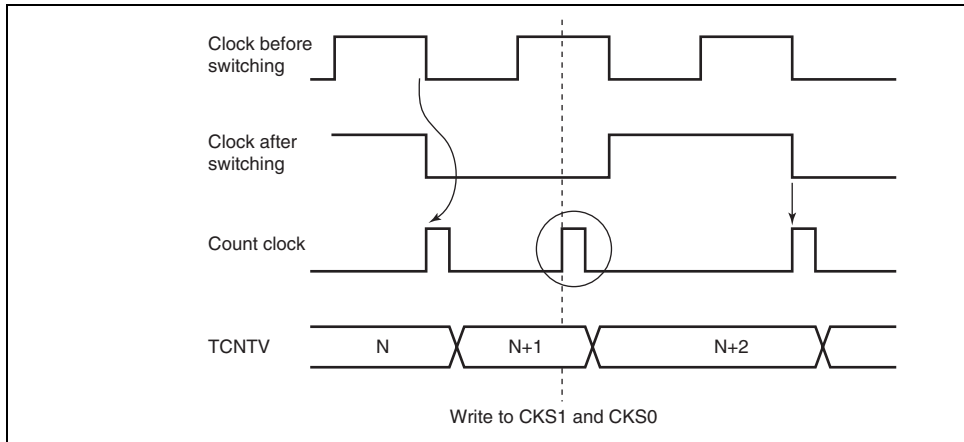
3. If compare matches A and B occur simultaneously, any conflict between the output 0 and output 1 for compare match A and compare match B is resolved by the following priority:  $\text{output } 0 > \text{output } 1 > \text{output } 0$ .
4. Depending on the timing, TCNTV may be incremented by a switch between different clock sources. When TCNTV is internally clocked, an increment pulse is generated from the falling edge of an internal clock signal, that is divided system clock ( $\phi$ ). Therefore, as seen in figure 11.3 the switch is from a high clock signal to a low clock signal, the switch is seen as a falling edge, causing TCNTV to increment. TCNTV can also be incremented by a switch between internal and external clocks.



**Figure 11.11 Contention between TCNTV Write and Clear**



**Figure 11.12 Contention between TCORA Write and Compare Match**



**Figure 11.13 Internal Clock Switching and TCNTV Operation**



- Capability to process up to four pulse outputs or four pulse inputs
- Four general registers:
  - Independently assignable output compare or input capture functions
  - Usable as two pairs of registers; one register of each pair operates as a buffer for compare or input capture register
- Four selectable operating modes :
  - Waveform output by compare match
    - Selection of 0 output, 1 output, or toggle output
  - Input capture function
    - Rising edge, falling edge, or both edges
  - Counter clearing function
    - Counters can be cleared by compare match
  - PWM mode
    - Up to three-phase PWM output can be provided with desired duty ratio.
- Any initial timer output value can be set
- Five interrupt sources
  - Four compare match/input capture interrupts and an overflow interrupt.

Table 12.1 summarizes the timer W functions, and figure 12.1 shows a block diagram of W.

		compare match	compare match			
Initial output value setting function		—	Yes	Yes	Yes	Yes
Buffer function		—	Yes	Yes	—	—
Compare	0	—	Yes	Yes	Yes	Yes
match output	1	—	Yes	Yes	Yes	Yes
	Toggle	—	Yes	Yes	Yes	Yes
Input capture function		—	Yes	Yes	Yes	Yes
PWM mode		—	—	Yes	Yes	Yes
Interrupt sources		Overflow	Compare match/input capture	Compare match/input capture	Compare match/input capture	Com mat cap



- [Legend]
- TMRW: Timer mode register W (8 bits)
- TCRW: Timer control register W (8 bits)
- TIERW: Timer interrupt enable register W (8 bits)
- TSRW: Timer status register W (8 bits)
- TIOR: Timer I/O control register (8 bits)
- TCNT: Timer counter (16 bits)
- GRA: General register A (input capture/output compare register: 16 bits)
- GRB: General register B (input capture/output compare register: 16 bits)
- GRC: General register C (input capture/output compare register: 16 bits)
- GRD: General register D (input capture/output compare register: 16 bits)
- IRRTW: Timer W interrupt request

**Figure 12.1 Timer W Block Diagram**

compare B			input pin for GRB input capture PWM output pin in PWM mode
Input capture/output compare C	FTIOC	Input/output	Output pin for GRC output capture input pin for GRC input capture PWM output pin in PWM mode
Input capture/output compare D	FTIOD	Input/output	Output pin for GRD output capture input pin for GRD input capture PWM output pin in PWM mode

## 12.3 Register Descriptions

The timer W has the following registers.

- Timer mode register W (TMRW)
- Timer control register W (TCRW)
- Timer interrupt enable register W (TIERW)
- Timer status register W (TSRW)
- Timer I/O control register 0 (TIOR0)
- Timer I/O control register 1 (TIOR1)
- Timer counter (TCNT)
- General register A (GRA)
- General register B (GRB)
- General register C (GRC)
- General register D (GRD)

5	BUFEB	0	R/W	<p>Buffer Operation B</p> <p>Selects the GRD function.</p> <p>0: GRD operates as an input capture/output compare register</p> <p>1: GRD operates as the buffer register for GRB</p>
4	BUFEA	0	R/W	<p>Buffer Operation A</p> <p>Selects the GRC function.</p> <p>0: GRC operates as an input capture/output compare register</p> <p>1: GRC operates as the buffer register for GRA</p>
3	—	1	—	<p>Reserved</p> <p>This bit is always read as 1.</p>
2	PWMD	0	R/W	<p>PWM Mode D</p> <p>Selects the output mode of the FTIOD pin.</p> <p>0: FTIOD operates normally (output compare output)</p> <p>1: PWM output</p>
1	PWMC	0	R/W	<p>PWM Mode C</p> <p>Selects the output mode of the FTIOC pin.</p> <p>0: FTIOC operates normally (output compare output)</p> <p>1: PWM output</p>
0	PWMB	0	R/W	<p>PWM Mode B</p> <p>Selects the output mode of the FTIOB pin.</p> <p>0: FTIOB operates normally (output compare output)</p> <p>1: PWM output</p>

5	CKS1	0	R/W	Select the TCNT clock source.
4	CKS0	0	R/W	000: Internal clock: counts on $\phi$ 001: Internal clock: counts on $\phi/2$ 010: Internal clock: counts on $\phi/4$ 011: Internal clock: counts on $\phi/8$ 1XX: Counts on rising edges of the external event When the internal clock source ( $\phi$ ) is selected, subactive and subsleep sources are counted in subactive and subsleep mode.
3	TOD	0	R/W	Timer Output Level Setting D Sets the output value of the FTIOD pin until the first compare match D is generated. 0: Output value is 0* 1: Output value is 1*
2	TOC	0	R/W	Timer Output Level Setting C Sets the output value of the FTIOC pin until the first compare match C is generated. 0: Output value is 0* 1: Output value is 1*
1	TOB	0	R/W	Timer Output Level Setting B Sets the output value of the FTIOB pin until the first compare match B is generated. 0: Output value is 0* 1: Output value is 1*

### 12.3.3 Timer Interrupt Enable Register W (TIERW)

TIERW controls the timer W interrupt request.

Bit	Bit Name	Initial Value	R/W	Description
7	OVIE	0	R/W	Timer Overflow Interrupt Enable When this bit is set to 1, FOVI interrupt request flag in TSRW is enabled.
6 to 4	—	All 1	—	Reserved These bits are always read as 1.
3	IMIED	0	R/W	Input Capture/Compare Match Interrupt Enable When this bit is set to 1, IMID interrupt request IMFD flag in TSRW is enabled.
2	IMIEC	0	R/W	Input Capture/Compare Match Interrupt Enable When this bit is set to 1, IMIC interrupt request IMFC flag in TSRW is enabled.
1	IMIEB	0	R/W	Input Capture/Compare Match Interrupt Enable When this bit is set to 1, IMIB interrupt request IMFB flag in TSRW is enabled.
0	IMIEA	0	R/W	Input Capture/Compare Match Interrupt Enable When this bit is set to 1, IMIA interrupt request IMFA flag in TSRW is enabled.

6 to 4	—	All 1	—	Reserved	Read OVF when OVF = 1, then write 0 in OVF
				These bits are always read as 1.	
3	IMFD	0	R/W	Input Capture/Compare Match Flag D	<p>[Setting conditions]</p> <ul style="list-style-type: none"> <li>• TCNT = GRD when GRD functions as an output compare register</li> <li>• The TCNT value is transferred to GRD by an input capture signal when GRD functions as an input capture register</li> </ul> <p>[Clearing condition]</p> <p>Read IMFD when IMFD = 1, then write 0 in IMFD</p>
2	IMFC	0	R/W	Input Capture/Compare Match Flag C	<p>[Setting conditions]</p> <ul style="list-style-type: none"> <li>• TCNT = GRC when GRC functions as an output compare register</li> <li>• The TCNT value is transferred to GRC by an input capture signal when GRC functions as an input capture register</li> </ul> <p>[Clearing condition]</p> <p>Read IMFC when IMFC = 1, then write 0 in IMFC</p>

0	IMFA	0	R/W	Input Capture/Compare Match Flag A [Setting conditions] <ul style="list-style-type: none"> <li>• TCNT = GRA when GRA functions as an output compare register</li> <li>• The TCNT value is transferred to GRA by a capture signal when GRA functions as an input capture register</li> </ul> [Clearing condition] Read IMFA when IMFA = 1, then write 0 in IMFA
---	------	---	-----	--

### 12.3.5 Timer I/O Control Register 0 (TIOR0)

TIOR0 selects the functions of GRA and GRB, and specifies the functions of the FTIOA and FTIOB pins.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved This bit is always read as 1.
6	IOB2	0	R/W	I/O Control B2 Selects the GRB function. 0: GRB functions as an output compare register 1: GRB functions as an input capture register

00: Input capture at rising edge at the FTIOB pin  
 01: Input capture at falling edge at the FTIOB pin  
 1X: Input capture at rising and falling edges of the pin

3	—	1	—	Reserved This bit is always read as 1.
2	IOA2	0	R/W	I/O Control A2 Selects the GRA function. 0: GRA functions as an output compare register 1: GRA functions as an input capture register
1	IOA1	0	R/W	I/O Control A1 and A0
0	IOA0	0	R/W	When IOA2 = 0, 00: No output at compare match 01: 0 output to the FTIOA pin at GRA compare match 10: 1 output to the FTIOA pin at GRA compare match 11: Output toggles to the FTIOA pin at GRA compare match When IOA2 = 1, 00: Input capture at rising edge of the FTIOA pin 01: Input capture at falling edge of the FTIOA pin 1X: Input capture at rising and falling edges of the pin

Legend: X: Don't care.



				Selects the GRD function. 0: GRD functions as an output compare register 1: GRD functions as an input capture register
5	IOD1	0	R/W	I/O Control D1 and D0
4	IOD0	0	R/W	When IOD2 = 0, 00: No output at compare match 01: 0 output to the FTIOD pin at GRD compare match 10: 1 output to the FTIOD pin at GRD compare match 11: Output toggles to the FTIOD pin at GRD compare match When IOD2 = 1, 00: Input capture at rising edge at the FTIOD pin 01: Input capture at falling edge at the FTIOD pin 1X: Input capture at rising and falling edges at the FTIOD pin
3	—	1	—	Reserved This bit is always read as 1.
2	IOC2	0	R/W	I/O Control C2 Selects the GRC function. 0: GRC functions as an output compare register 1: GRC functions as an input capture register

00: Input capture to GRC at rising edge of the FTIO pin  
01: Input capture to GRC at falling edge of the FTIO pin  
1X: Input capture to GRC at rising and falling edges of the FTIO pin

---

Legend: X: Don't care.

### 12.3.7 Timer Counter (TCNT)

TCNT is a 16-bit readable/writable up-counter. The clock source is selected by bits CKS0 and CKS1 in TCRW. TCNT can be cleared to H'0000 through a compare match with GRA by setting the CCLR in TCRW to 1. When TCNT overflows (changes from H'FFFF to H'0000), the overflow flag in TSRW is set to 1. If OVIE in TIERW is set to 1 at this time, an interrupt request is generated. TCNT must always be read or written in 16-bit units; 8-bit access is not allowed. TCNT is initialized to H'0000 by a reset.

### 12.3.8 General Registers A to D (GRA to GRD)

Each general register is a 16-bit readable/writable register that can function as either an input-compare register or an input-capture register. The function is selected by settings in TIOF0 and TIOR1.

When a general register is used as an input-compare register, its value is constantly compared with the TCNT value. When the two values match (a compare match), the corresponding flag (IMFB, IMFC, or IMFD) in TSRW is set to 1. An interrupt request is generated at this time if IMIEA, IMIEB, IMIEC, or IMIED is set to 1. Compare match output can be selected in TIOF0.

When a general register is used as an input-capture register, an external input-capture signal is detected and the current TCNT value is stored in the general register. The corresponding flag (IMFA, IMFB, IMFC, or IMFD) in TSRW is set to 1. If the corresponding interrupt-enable bit (IMIEA, IMIEB, IMIEC, or IMIED) is set to 1, an interrupt request is generated.

GRA whenever an input capture is generated.

GRA to GRD must be written or read in 16-bit units; 8-bit access is not allowed. GRA is initialized to H'FFFF by a reset.

## 12.4 Operation

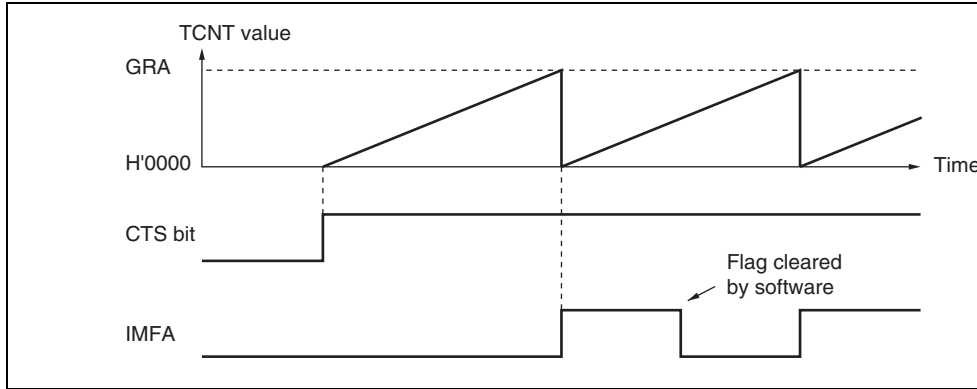
The timer W has the following operating modes.

- Normal Operation
- PWM Operation

### 12.4.1 Normal Operation

TCNT performs free-running or periodic counting operations. After a reset, TCNT is set to H'0000 and starts counting. When the CTS bit in TMRW is set to 1, TCNT starts incrementing the count. When the count overflows from H'FFFF to H'0000, the OVF flag in TSRW is set to 1. If the OVF flag in TSRW is set to 1, an interrupt request is generated. Figure 12.2 shows free-running operation.

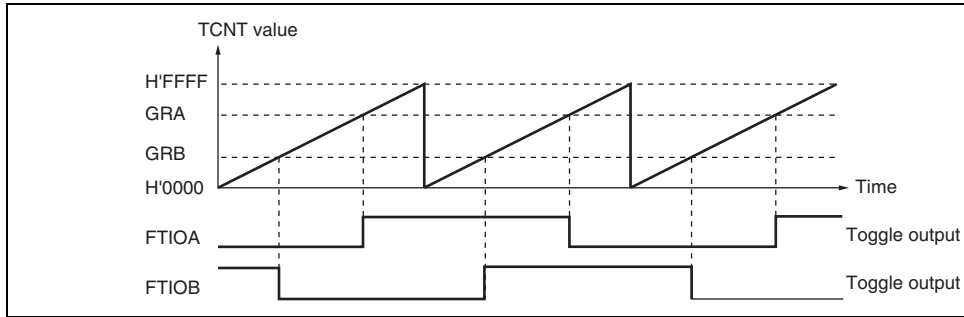
Periodic counting operation can be performed when GRA is set as an output compare register. bit CCLR in TCRW is set to 1. When the count matches GRA, TCNT is cleared to H'0000. IMFA flag in TSRW is set to 1. If the corresponding IMIEA bit in TIERW is set to 1, an request is generated. TCNT continues counting from H'0000. Figure 12.3 shows periodic counting.



**Figure 12.3 Periodic Counter Operation**

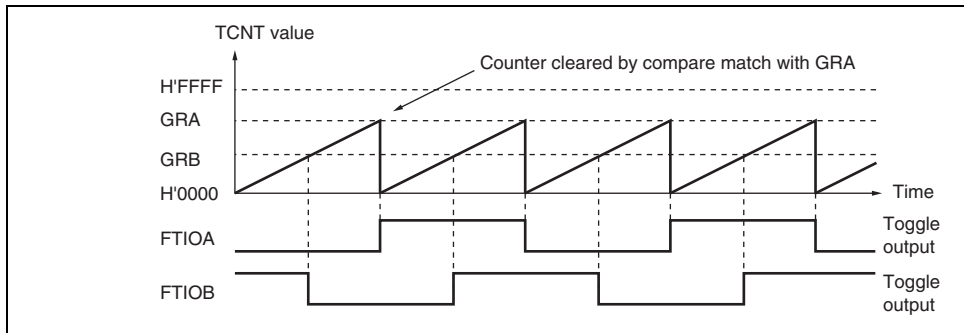
By setting a general register as an output compare register, compare match A, B, C, or D the output at the FTIOA, FTIOB, FTIOC, or FTIOD pin to output 0, output 1, or toggle. Figure 12.4 shows an example of 0 and 1 output when TCNT operates as a free-running counter. If output 1 is selected for compare match A, and 0 output is selected for compare match B. When signal is already at the selected output level, the signal level does not change at compare match.

Figure 12.5 shows an example of toggle output when TCNT operates as a free-running counter and toggle output is selected for both compare match A and B.

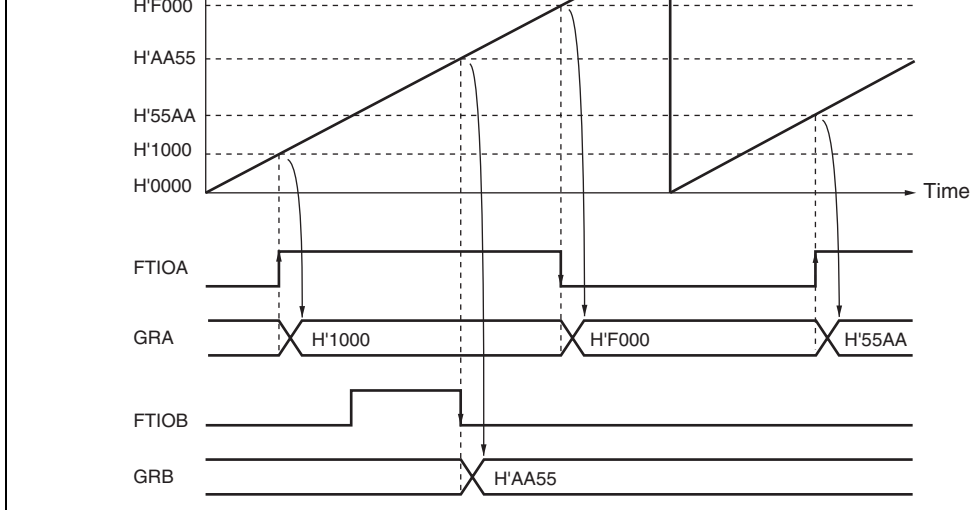


**Figure 12.5 Toggle Output Example (TOA = 0, TOB = 1)**

Figure 12.6 shows another example of toggle output when TCNT operates as a periodic counter cleared by compare match A. Toggle output is selected for both compare match A and B.

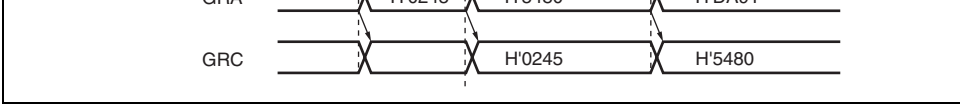


**Figure 12.6 Toggle Output Example (TOA = 0, TOB = 1)**



**Figure 12.7 Input Capture Operating Example**

Figure 12.8 shows an example of buffer operation when the GRA is set as an input-capture register and GRC is set as the buffer register for GRA. TCNT operates as a free-running counter and FTIOA captures both rising and falling edge of the input signal. Due to the buffer operation, the GRA value is transferred to GRC by input-capture A and the TCNT value is stored in



**Figure 12.8 Buffer Operation Example (Input Capture)**

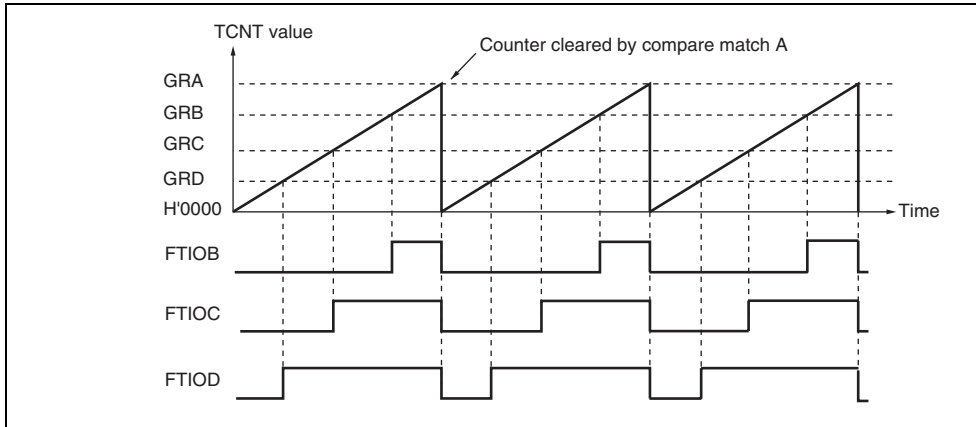
**12.4.2 PWM Operation**

In PWM mode, PWM waveforms are generated by using GRA as the period register and GRC, and GRD as duty registers. PWM waveforms are output from the FTIOB, FTIOC, FTIOD pins. Up to three-phase PWM waveforms can be output. In PWM mode, a general timer functions as an output compare register automatically. The output level of each pin depends on the corresponding timer output level set bit (TOB, TOC, and TOD) in TCRW. When TOB is 1, FTIOB output goes to 1 at compare match A and to 0 at compare match B. When TOB is 0, FTIOB output goes to 0 at compare match A and to 1 at compare match B. Thus the compare match output level settings in TIOR0 and TIOR1 are ignored for the output pin set to PWM mode. If the same value is set in the cycle register and the duty register, the output does not change when a compare match occurs.

Figure 12.9 shows an example of operation in PWM mode. The output signals go to 1 and are cleared at compare match A, and the output signals go to 0 at compare match B, C, and D. If TOC, and TOD = 1: initial output values are set to 1).

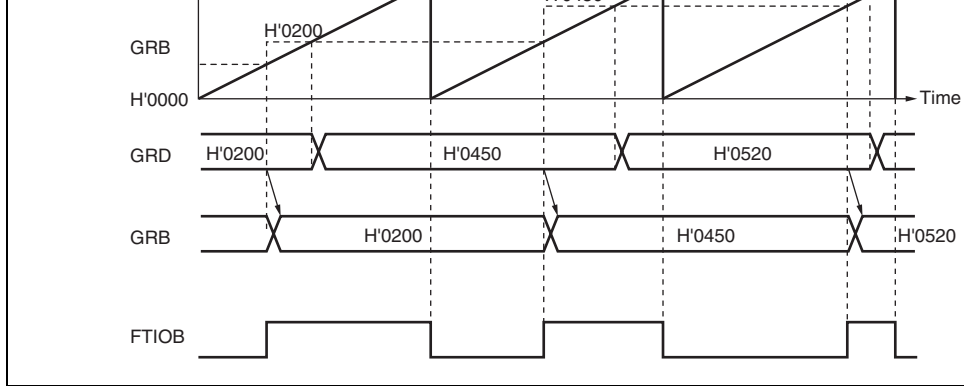
**Figure 12.9 PWM Mode Example (1)**

Figure 12.10 shows another example of operation in PWM mode. The output signals go to 1 at compare match A, and the output signals go to 0 at compare match B. TCNT is cleared at compare match A, and the output signals go to 1 at compare match B, and to 0 at compare match C and D (TOB, TOC, and TOD = 0: initial output values are set to 1).



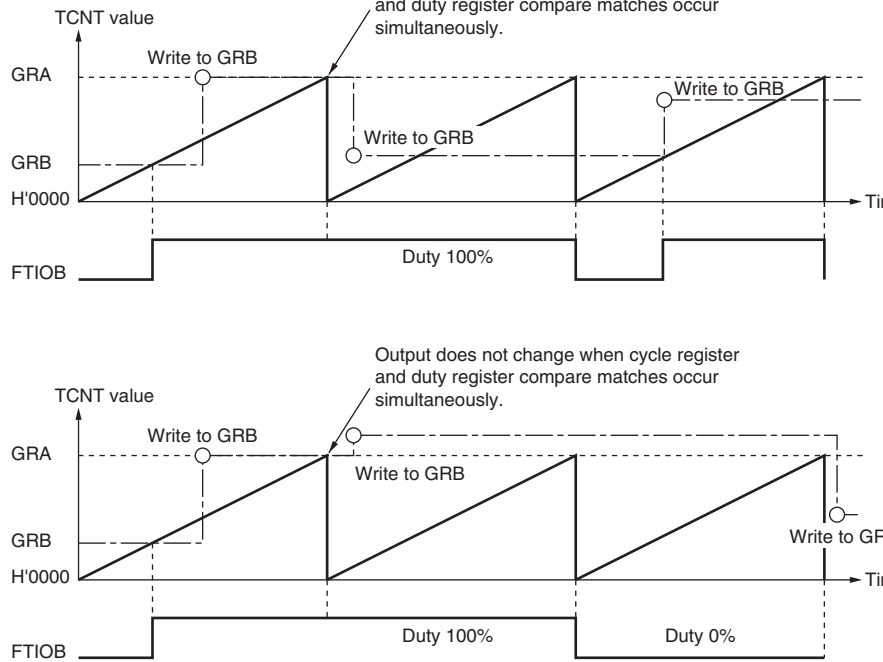
**Figure 12.10 PWM Mode Example (2)**



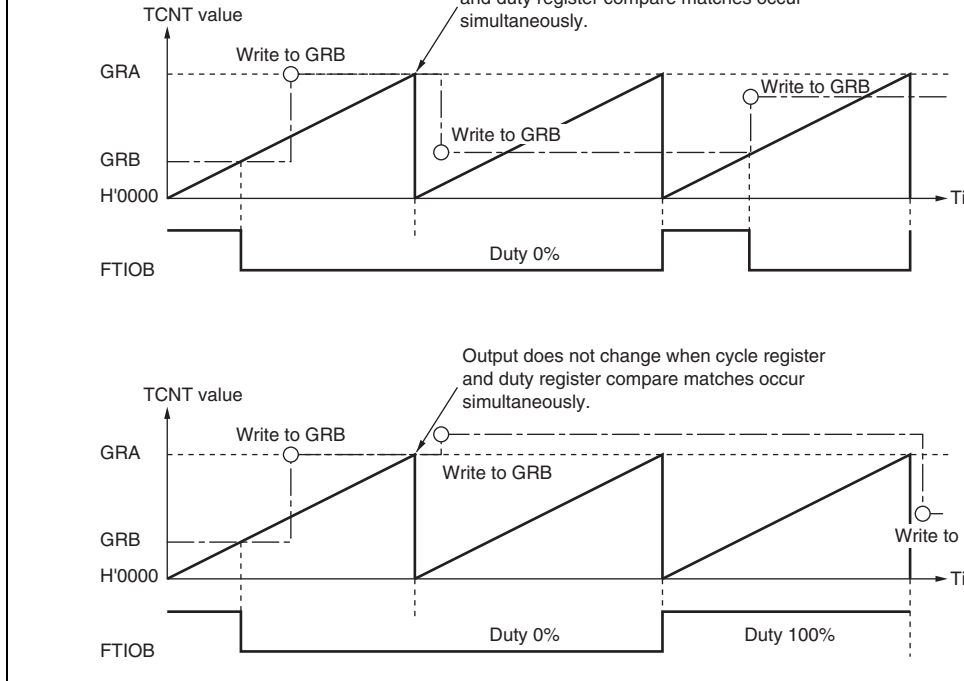


**Figure 12.11 Buffer Operation Example (Output Compare)**

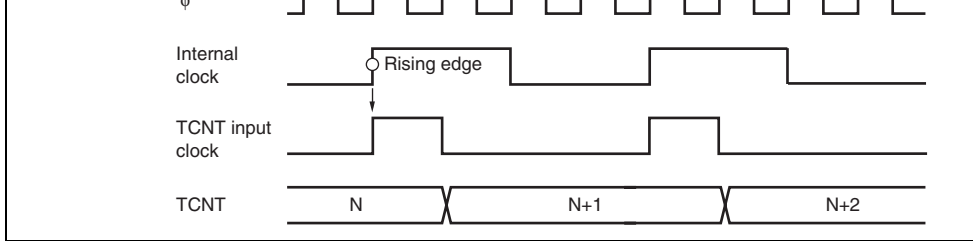
Figures 12.12 and 12.13 show examples of the output of PWM waveforms with duty cycle and 100%.



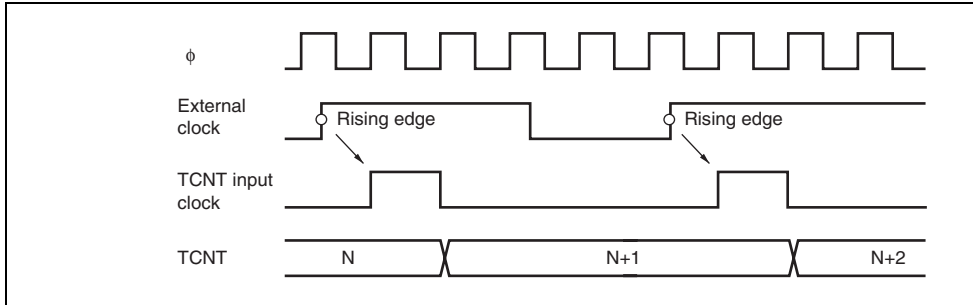
**Figure 12.12 PWM Mode Example**  
**(TOB, TOC, and TOD = 0: initial output values are set to 0)**



**Figure 12.13 PWM Mode Example**  
**(TOB, TOC, and TOD = 1: initial output values are set to 1)**



**Figure 12.14 Count Timing for Internal Clock Source**

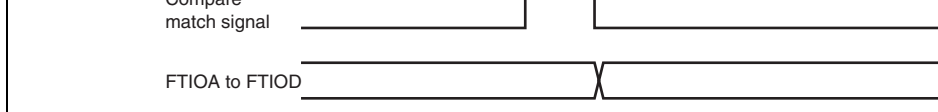


**Figure 12.15 Count Timing for External Clock Source**

### 12.5.2 Output Compare Output Timing

The compare match signal is generated in the last state in which TCNT and GR match (when TCNT changes from the matching value to the next value). When the compare match signal is generated, the output value selected in TIOR is output at the compare match output pin (FTI0B, FTIOC, or FTIOD).

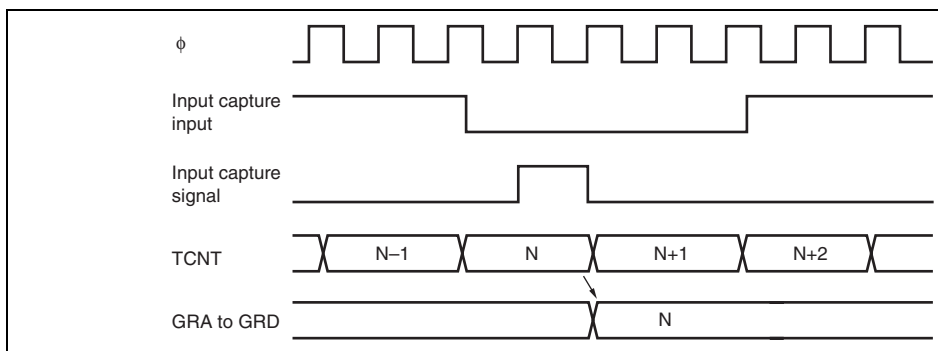
When TCNT matches GR, the compare match signal is generated only after the next count pulse is input.



**Figure 12.16 Output Compare Output Timing**

### 12.5.3 Input Capture Timing

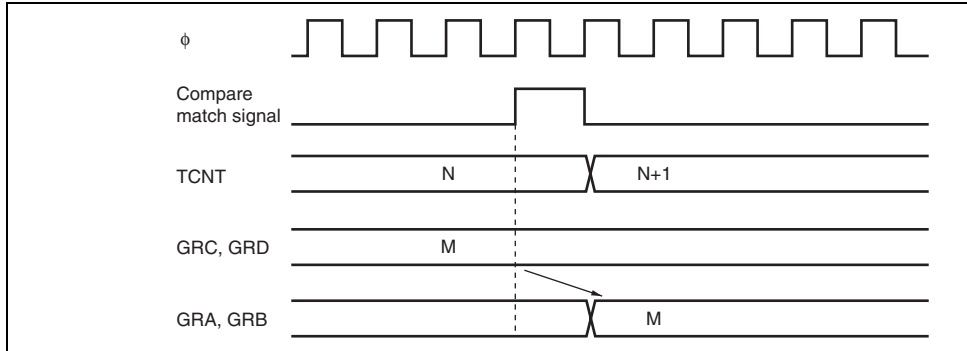
Input capture on the rising edge, falling edge, or both edges can be selected through settings TIOR0 and TIOR1. Figure 12.17 shows the timing when the falling edge is selected. The width of the input capture signal must be at least two system clock ( $\phi$ ) cycles; shorter pulses will not be detected correctly.



**Figure 12.17 Input Capture Input Signal Timing**

**Figure 12.18 Timing of Counter Clearing by Compare Match****12.5.5 Buffer Operation Timing**

Figures 12.19 and 12.20 show the buffer operation timing.

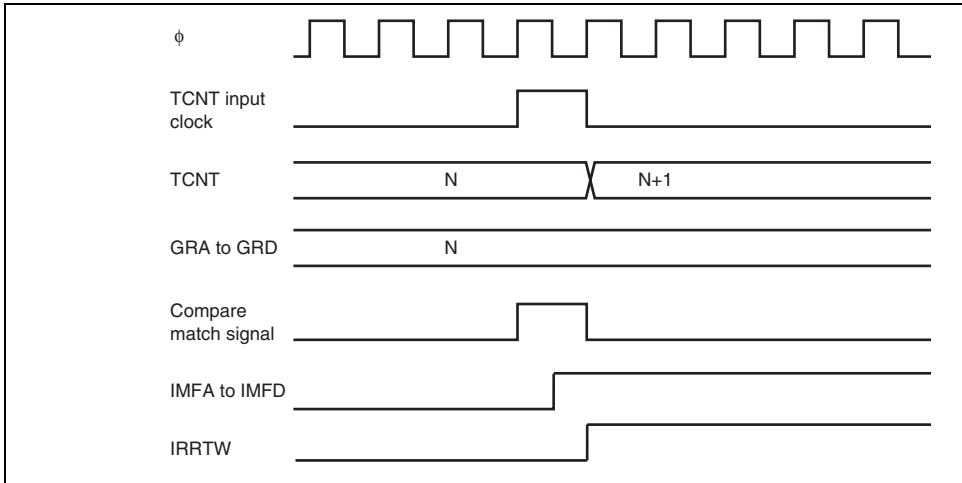
**Figure 12.19 Buffer Operation Timing (Compare Match)**

### 12.5.6 Timing of IMFA to IMFD Flag Setting at Compare Match

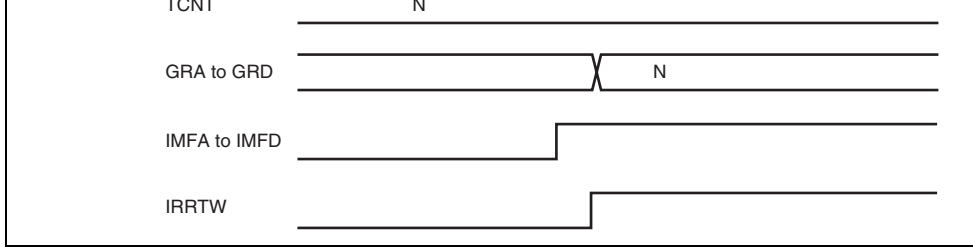
If a general register (GRA, GRB, GRC, or GRD) is used as an output compare register, corresponding IMFA, IMFB, IMFC, or IMFD flag is set to 1 when TCNT matches the general register.

The compare match signal is generated in the last state in which the values match (when updated from the matching count to the next count). Therefore, when TCNT matches a general register, the compare match signal is generated only after the next TCNT clock pulse is input.

Figure 12.21 shows the timing of the IMFA to IMFD flag setting at compare match.



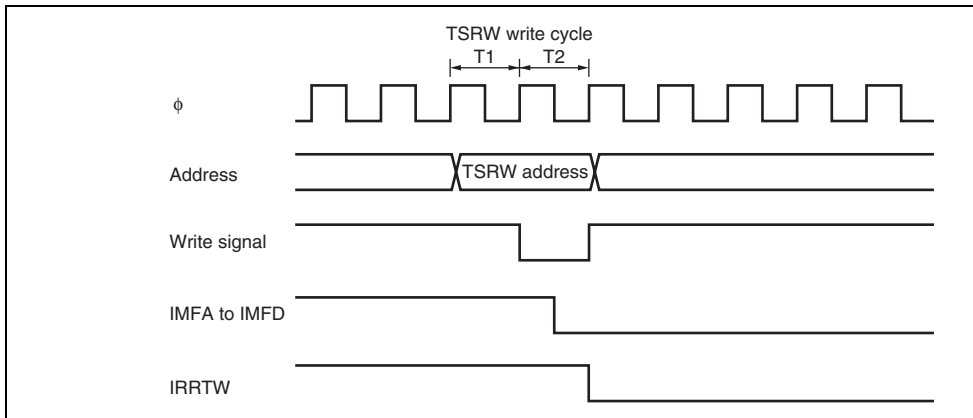
**Figure 12.21** Timing of IMFA to IMFD Flag Setting at Compare Match



**Figure 12.22 Timing of IMFA to IMFD Flag Setting at Input Capture**

### 12.5.8 Timing of Status Flag Clearing

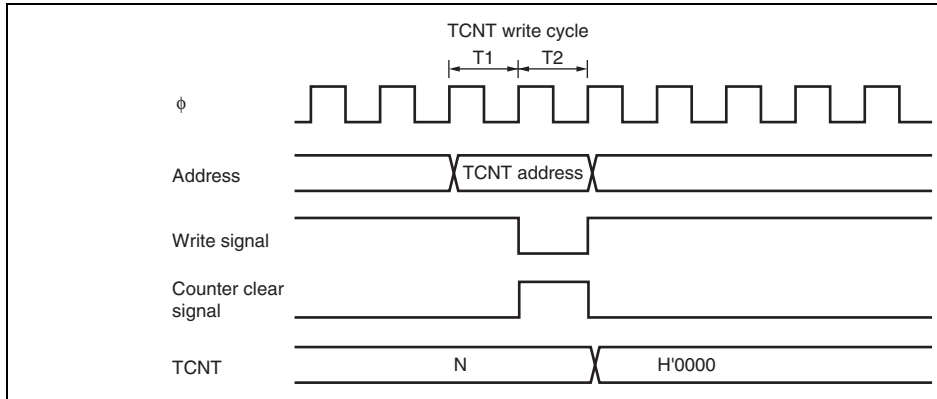
When the CPU reads a status flag while it is set to 1, then writes 0 in the status flag, the status flag is cleared. Figure 12.23 shows the status flag clearing timing.



**Figure 12.23 Timing of Status Flag Clearing by CPU**



- precedence.
- Depending on the timing, TCNT may be incremented by a switch between different clock sources. When TCNT is internally clocked, an increment pulse is generated from the rising edge of an internal clock signal, that is divided system clock ( $\phi$ ). Therefore, as shown in figure 12.25 the switch is from a low clock signal to a high clock signal, the switch occurs as a rising edge, causing TCNT to increment.
  - If timer W enters module standby mode while an interrupt request is generated, the interrupt request cannot be cleared. Before entering module standby mode, disable interrupt requests.



**Figure 12.24 Contention between TCNT Write and Clear**



bit manipulation instruction to TCRW occur at the same timing.

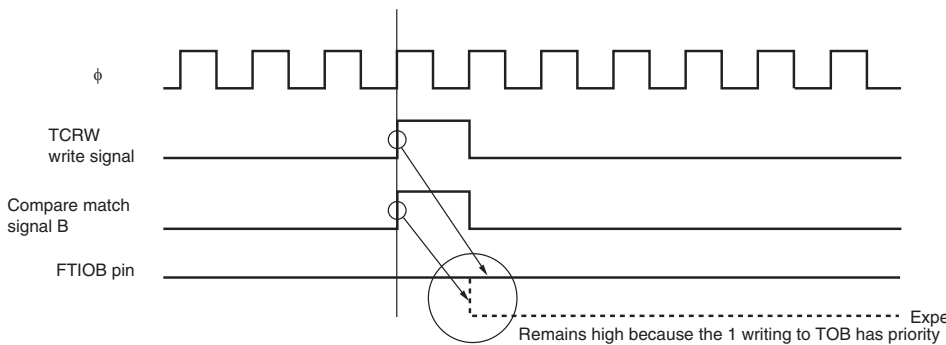
TCRW has been set to H'06. Compare match B and compare match C are used. The FTIOB pin is in the 1 output state and is set to the toggle output or the 0 output by compare match B.

When BCLR#2, @TCRW is executed to clear the TOC bit (the FTIOC signal is low) and compare match B occurs at the same timing as shown below, the H'02 writing to TCRW has priority and compare match B does not drive the FTIOB signal. The FTIOB signal remains high.

Bit	7	6	5	4	3	2	1	0
TCRW	CCLR	CKS2	CKS1	CKS0	TOD	TOC	TOB	TOA
Set value	0	0	0	0	0	1	1	0

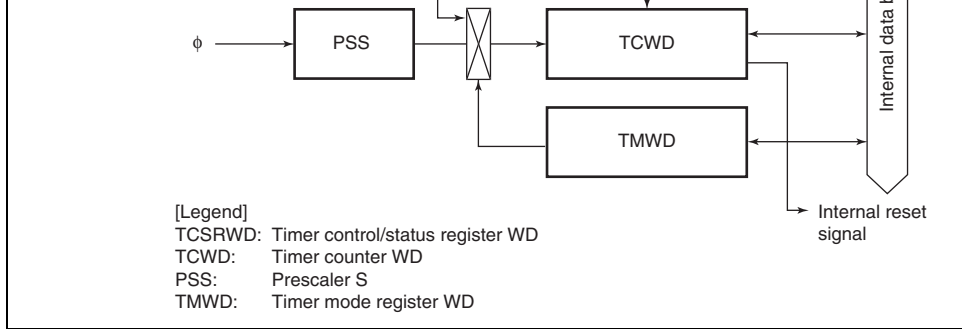
BCLR#2, @TCRW

- (1) TCRW read operation: Read H'06
- (2) Modify operation: Modify H'06 to H'02
- (3) Write operation to TCRW: Write H'02



**Figure 12.26 When Compare Match and Bit Manipulation Instruction to TCRW Occur at the Same Timing**





**Figure 13.1 Block Diagram of Watchdog Timer**

## 13.1 Features

- Selectable from nine counter input clocks.

Eight clock sources ( $\phi/64$ ,  $\phi/128$ ,  $\phi/256$ ,  $\phi/512$ ,  $\phi/1024$ ,  $\phi/2048$ ,  $\phi/4096$ , and  $\phi/8192$ ) internal oscillator can be selected as the timer-counter clock. When the internal oscillator is selected, it can operate as the watchdog timer in any operating mode.

- Reset signal generated on counter overflow

An overflow period of 1 to 256 times the selected clock can be set.

watchdog timer operation and indicates the operating state. TCSRWD must be rewritten with the MOV instruction. The bit manipulation instruction cannot be used to change the setting.

Bit	Bit Name	Initial Value	R/W	Description
7	B6WI	1	R/W	Bit 6 Write Inhibit The TCWE bit can be written only when the write enable value of the B6WI bit is 0. This bit is always read as 1.
6	TCWE	0	R/W	Timer Counter WD Write Enable TCWD can be written when the TCWE bit is set to 1. When writing data to this bit, the value for bit 7 must be 0.
5	B4WI	1	R/W	Bit 4 Write Inhibit The TCSRWE bit can be written only when the write enable value of the B4WI bit is 0. This bit is always read as 1.
4	TCSRWE	0	R/W	Timer Control/Status Register WD Write Enable The WDON and WRST bits can be written when the TCSRWE bit is set to 1. When writing data to this bit, the value for bit 5 must be 0.
3	B2WI	1	R/W	Bit 2 Write Inhibit This bit can be written to the WDON bit only when the write enable value of the B2WI bit is 0. This bit is always read as 1.

				<ul style="list-style-type: none"> <li>When 0 is written to the WDON bit while writing the B2WI when the TCSRWE bit=1</li> </ul>
1	B0WI	1	R/W	<p>Bit 0 Write Inhibit</p> <p>This bit can be written to the WRST bit only when the write value of the B0WI bit is 0. This bit is always 1.</p>
0	WRST	0	R/W	<p>Watchdog Timer Reset</p> <p>[Setting condition]</p> <p>When TCWD overflows and an internal reset signal is generated</p> <p>[Clearing conditions]</p> <ul style="list-style-type: none"> <li>Reset by <math>\overline{\text{RES}}</math> pin</li> <li>When 0 is written to the WRST bit while writing the B0WI bit when the TCSRWE bit=1</li> </ul>

### 13.2.2 Timer Counter WD (TCWD)

TCWD is an 8-bit readable/writable up-counter. When TCWD overflows from H'FF to H'00, an internal reset signal is generated and the WRST bit in TCSRWD is set to 1. TCWD is initialized to H'00.

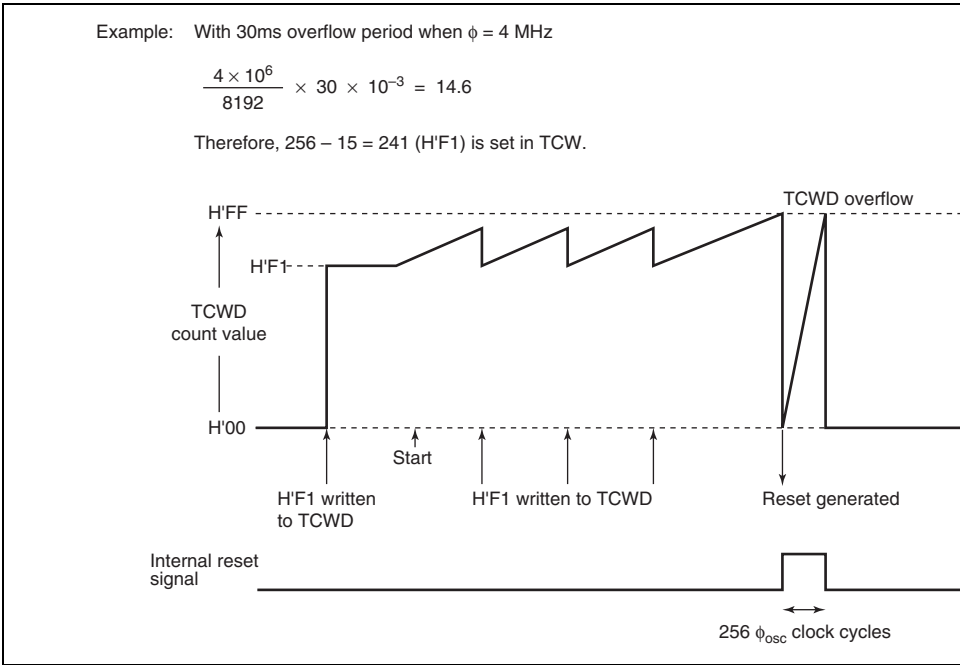
1	CKS1	1	R/W	1000: Internal clock: counts on $\phi/64$
0	CKS0	1	R/W	1001: Internal clock: counts on $\phi/128$
				1010: Internal clock: counts on $\phi/256$
				1011: Internal clock: counts on $\phi/512$
				1100: Internal clock: counts on $\phi/1024$
				1101: Internal clock: counts on $\phi/2048$
				1110: Internal clock: counts on $\phi/4096$
				1111: Internal clock: counts on $\phi/8192$
				0XXX: Internal oscillator

For the internal oscillator overflow periods, see 21, Electrical Characteristics.

---

Legend: X: Don't care.





**Figure 13.2 Watchdog Timer Operation Example**



## 14.1 Features

- Choice of asynchronous or clocked synchronous serial communication mode
- Full-duplex communication capability

The transmitter and receiver are mutually independent, enabling transmission and reception to be executed simultaneously.

Double-buffering is used in both the transmitter and the receiver, enabling continuous transmission and continuous reception of serial data.

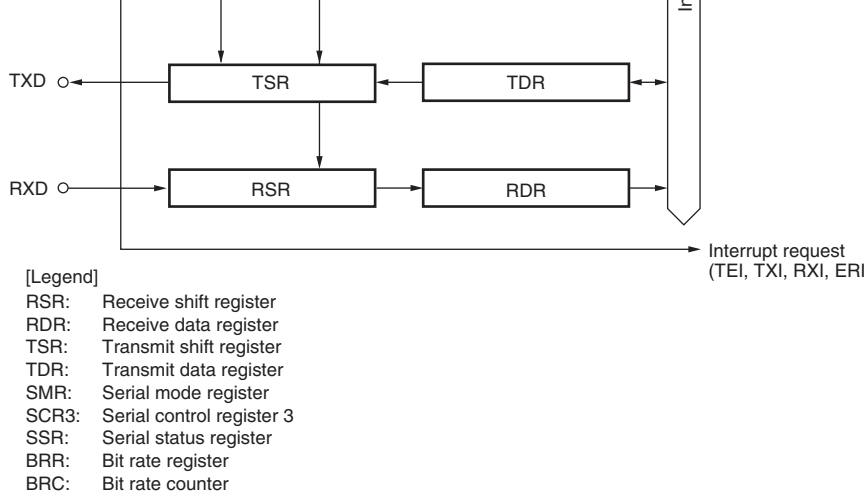
- On-chip baud rate generator allows any bit rate to be selected
- External clock or on-chip baud rate generator can be selected as a transfer clock source
- Six interrupt sources  
Transmit-end, transmit-data-empty, receive-data-full, overrun error, framing error, and parity error.

### Asynchronous mode

- Data length: 7 or 8 bits
- Stop bit length: 1 or 2 bits
- Parity: Even, odd, or none
- Receive error detection: Parity, overrun, and framing errors
- Break detection: Break can be detected by reading the RxD pin level directly in the controller during a framing error

### Clocked synchronous mode

- Data length: 8 bits
- Receive error detection: Overrun errors detected



**Figure 14.1 Block Diagram of SCI3**

## 14.3 Register Descriptions

The SCI3 has the following registers.

- Receive shift register (RSR)
- Receive data register (RDR)
- Transmit shift register (TSR)
- Transmit data register (TDR)
- Serial mode register (SMR)
- Serial control register 3 (SCR3)
- Serial status register (SSR)
- Bit rate register (BRR)

receive-enabled. As RSR and RDR function as a double buffer in this way, continuous receive operations are possible. After confirming that the RDRF bit in SSR is set to 1, read RDR once. RDR cannot be written to by the CPU. RDR is initialized to H'00.

### 14.3.3 Transmit Shift Register (TSR)

TSR is a shift register that transmits serial data. To perform serial data transmission, the SCI3 transfers transmit data from TDR to TSR automatically, then sends the data that starts from the LSB to the TXD pin. TSR cannot be directly accessed by the CPU.

### 14.3.4 Transmit Data Register (TDR)

TDR is an 8-bit register that stores data for transmission. When the SCI3 detects that TSR is empty, it transfers the transmit data written in TDR to TSR and starts transmission. The circular buffered structure of TDR and TSR enables continuous serial transmission. If the next transmit data has already been written to TDR during transmission of one-frame data, the SCI3 transfers the written data to TSR to continue transmission. To achieve reliable serial transmission, write transmit data to TDR only once after confirming that the TDRE bit in SSR is set to 1. TDR is initialized to H'FF.

6	CHR	0	R/W	Character Length (enabled only in asynchronous mode) 0: Selects 8 bits as the data length. 1: Selects 7 bits as the data length.
5	PE	0	R/W	Parity Enable (enabled only in asynchronous mode) When this bit is set to 1, the parity bit is added to the data before transmission, and the parity bit is checked during reception.
4	PM	0	R/W	Parity Mode (enabled only when the PE bit is 1 in asynchronous mode) 0: Selects even parity. 1: Selects odd parity.
3	STOP	0	R/W	Stop Bit Length (enabled only in asynchronous mode) Selects the stop bit length in transmission. 0: 1 stop bit 1: 2 stop bits For reception, only the first stop bit is checked, and the value in the bit. If the second stop bit is 0, it is treated as the start bit of the next transmit character.
2	MP	0	R/W	Multiprocessor Mode When this bit is set to 1, the multiprocessor communication function is enabled. The PE bit and PM bit settings are invalid. In clocked synchronous mode, this bit should be cleared to 0.

### 14.3.6 Serial Control Register 3 (SCR3)

SCR3 is a register that enables or disables SCI3 transfer operations and interrupt requests, also used to select the transfer clock source. For details on interrupt requests, refer to section 14.3.7, Interrupts.

Bit	Bit Name	Initial Value	R/W	Description
7	TIE	0	R/W	Transmit Interrupt Enable When this bit is set to 1, the TXI interrupt request is enabled.
6	RIE	0	R/W	Receive Interrupt Enable When this bit is set to 1, RXI and ERI interrupt requests are enabled.
5	TE	0	R/W	Transmit Enable When this bit is set to 1, transmission is enabled.
4	RE	0	R/W	Receive Enable When this bit is set to 1, reception is enabled.



	Bit	Symbol	Value	Access	Description
					When this bit is set to 1, the TEI interrupt request is enabled.
1	CKE1	0		R/W	Clock Enable 0 and 1
0	CKE0	0		R/W	Selects the clock source. Asynchronous mode: 00: Internal baud rate generator 01: Internal baud rate generator Outputs a clock of the same frequency as the clock from the SCK3 pin. 10: External clock Inputs a clock with a frequency 16 times the frequency from the SCK3 pin. 11: Reserved Clock synchronous mode: 00: Internal clock (SCK3 pin functions as clock) 01: Reserved 10: External clock (SCK3 pin functions as clock) 11: Reserved

- When the TE bit in SCR3 is 0
  - When data is transferred from TDR to TSR
- [Clearing conditions]
- When 0 is written to TDRE after reading TDR
  - When the transmit data is written to TDR

6	RDRF	0	R/W	<p>Receive Data Register Full</p> <p>Indicates that the received data is stored in RDR</p> <p>[Setting condition]</p> <ul style="list-style-type: none"> <li>• When serial reception ends normally and received data is transferred from RSR to RDR</li> </ul> <p>[Clearing conditions]</p> <ul style="list-style-type: none"> <li>• When 0 is written to RDRF after reading RDRF</li> <li>• When data is read from RDR</li> </ul>
5	OER	0	R/W	<p>Overflow Error</p> <p>[Setting condition]</p> <ul style="list-style-type: none"> <li>• When an overrun error occurs in reception</li> </ul> <p>[Clearing condition]</p> <ul style="list-style-type: none"> <li>• When 0 is written to OER after reading OER</li> </ul>
4	FER	0	R/W	<p>Framing Error</p> <p>[Setting condition]</p> <ul style="list-style-type: none"> <li>• When a framing error occurs in reception</li> </ul> <p>[Clearing condition]</p> <ul style="list-style-type: none"> <li>• When 0 is written to FER after reading FER</li> </ul>

- When TDRE = 1 at transmission of the last byte serial transmit character

[Clearing conditions]

- When 0 is written to TEND after reading TE
- When the transmit data is written to TDR

1	MPBR	0	R	<p>Multiprocessor Bit Receive</p> <p>MPBR stores the multiprocessor bit in the received character data. When the RE bit in SCR3 is cleared, its previous state is retained.</p>
0	MPBT	0	R/W	<p>Multiprocessor Bit Transfer</p> <p>MPBT stores the multiprocessor bit to be added to transmit character data.</p>

### [Asynchronous Mode]

$$N = \frac{\phi}{64 \times 2^{2n-1} \times B} \times 10^6 - 1$$

$$\text{Error (\%)} = \left\{ \frac{\phi \times 10^6}{(N + 1) \times B \times 64 \times 2^{2n-1}} - 1 \right\} \times 100$$

### [Clocked Synchronous Mode]

$$N = \frac{\phi}{8 \times 2^{2n-1} \times B} \times 10^6 - 1$$

Note: B: Bit rate (bit/s)

N: BRR setting for baud rate generator ( $0 \leq N \leq 255$ )

$\phi$ : Operating frequency (MHz)

n: CKS1 and CKS0 setting for SMR ( $0 \leq n \leq 3$ )

1200	0	51	0.16	0	54	-0.70	0	63	0.00	0	77
2400	0	25	0.16	0	26	1.14	0	31	0.00	0	38
4800	0	12	0.16	0	13	-2.48	0	15	0.00	0	19
9600	0	6	-6.99	0	6	-2.48	0	7	0.00	0	9
19200	0	2	8.51	0	2	13.78	0	3	0.00	0	4
31250	0	1	0.00	0	1	4.86	0	1	22.88	0	2
38400	0	1	-18.62	0	1	-14.67	0	1	0.00	—	—

Legend:

— : A setting is available but error occurs

Bit Rate (bits/s)	Operating Frequency $\phi$ (MHz)											
	3.6864			4			4.9152					
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	
110	2	64	0.70	2	70	0.03	2	86	0.31	2	88	
150	1	191	0.00	1	207	0.16	1	255	0.00	2	64	
300	1	95	0.00	1	103	0.16	1	127	0.00	1	12	
600	0	191	0.00	0	207	0.16	0	255	0.00	1	64	
1200	0	95	0.00	0	103	0.16	0	127	0.00	0	12	
2400	0	47	0.00	0	51	0.16	0	63	0.00	0	64	
4800	0	23	0.00	0	25	0.16	0	31	0.00	0	32	
9600	0	11	0.00	0	12	0.16	0	15	0.00	0	15	
19200	0	5	0.00	0	6	-6.99	0	7	0.00	0	7	
31250	—	—	—	0	3	0.00	0	4	-1.70	0	4	
38400	0	2	0.00	0	2	8.51	0	3	0.00	0	3	

1200	0	155	0.16	0	159	0.00	0	191	0.00	0	207
2400	0	77	0.16	0	79	0.00	0	95	0.00	0	103
4800	0	38	0.16	0	39	0.00	0	47	0.00	0	51
9600	0	19	-2.34	0	19	0.00	0	23	0.00	0	25
19200	0	9	-2.34	0	9	0.00	0	11	0.00	0	12
31250	0	5	0.00	0	5	2.40	0	6	5.33	0	7
38400	0	4	-2.34	0	4	0.00	0	5	0.00	0	6

Bit Rate (bit/s)	Operating Frequency $\phi$ (MHz)										
	9.8304			10			12			12.8	
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N
110	2	174	-0.26	2	177	-0.25	2	212	0.03	2	217
150	2	127	0.00	2	129	0.16	2	155	0.16	2	159
300	1	255	0.00	2	64	0.16	2	77	0.16	2	79
600	1	127	0.00	1	129	0.16	1	155	0.16	1	159
1200	0	255	0.00	1	64	0.16	1	77	0.16	1	79
2400	0	127	0.00	0	129	0.16	0	155	0.16	0	159
4800	0	63	0.00	0	64	0.16	0	77	0.16	0	79
9600	0	31	0.00	0	32	-1.36	0	38	0.16	0	39
19200	0	15	0.00	0	15	1.73	0	19	-2.34	0	19
31250	0	9	-1.70	0	9	0.00	0	11	0.00	0	11
38400	0	7	0.00	0	7	1.73	0	9	-2.34	0	9

1200	1	90	0.16	1	95	0.00	1	103	0.16
2400	0	181	0.16	0	191	0.00	0	207	0.16
4800	0	90	0.16	0	95	0.00	0	103	0.16
9600	0	45	-0.93	0	47	0.00	0	51	0.16
19200	0	22	-0.93	0	23	0.00	0	25	0.16
31250	0	13	0.00	0	14	-1.70	0	15	0.00
38400	—	—	—	0	11	0.00	0	12	0.16

Bit Rate (bit/s)	Operating Frequency $\phi$ (MHz)					
	18			20		
	n	N	Error (%)	n	N	Error (%)
110	3	79	-0.12	3	88	-0.25
150	2	233	0.16	3	64	0.16
300	2	116	0.16	2	129	0.16
600	1	233	0.16	2	64	0.16
1200	1	116	0.16	1	129	0.16
2400	0	233	0.16	1	64	0.16
4800	0	116	0.16	0	129	0.16
9600	0	58	-0.96	0	64	0.16
19200	0	28	1.02	0	32	-1.36
31250	0	17	0.00	0	19	0.00
38400	0	14	-2.34	0	15	1.73

Legend:

—: A setting is available but error occurs.

4.9152	153600	0	0	14.7456	460800	0
5	156250	0	0	16	500000	0
6	187500	0	0	17.2032	537600	0
6.144	192000	0	0	18	562500	0
7.3728	230400	0	0	20	625000	0



2.5k	0	199	1	99	1	199	1	249	2
5k	0	99	0	199	1	99	1	124	1
10k	0	49	0	99	0	199	0	249	1
25k	0	19	0	39	0	79	0	99	0
50k	0	9	0	19	0	39	0	49	0
100k	0	4	0	9	0	19	0	24	0
250k	0	1	0	3	0	7	0	9	0
500k	0	0*	0	1	0	3	0	4	0
1M			0	0*	0	1	—	—	0
2M					0	0*	—	—	0
2.5M							0	0*	—
4M									0

Legend:

Blank : No setting is available.

— : A setting is available but error occurs.

\* : Continuous transfer is not possible.

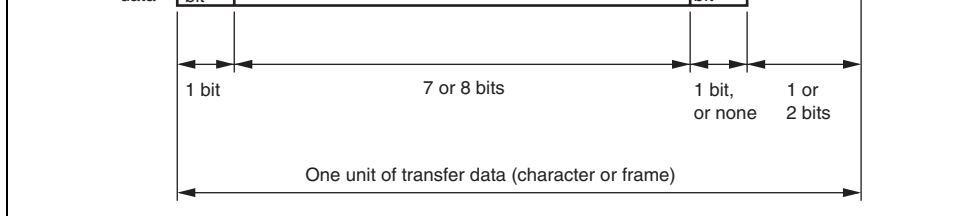
2.5k	2	112	2	124
5k	1	224	1	249
10k	1	112	1	124
25k	0	179	0	199
50k	0	89	0	99
100k	0	44	0	49
250k	0	17	0	19
500k	0	8	0	9
1M	0	4	0	4
2M	—	—	—	—
2.5M	—	—	0	1
4M	—	—	—	—

Legend:

Blank : No setting is available.

— : A setting is available but error occurs.

\* : Continuous transfer is not possible.

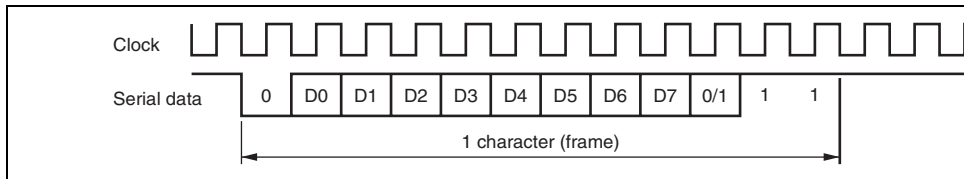


**Figure 14.2 Data Format in Asynchronous Communication**

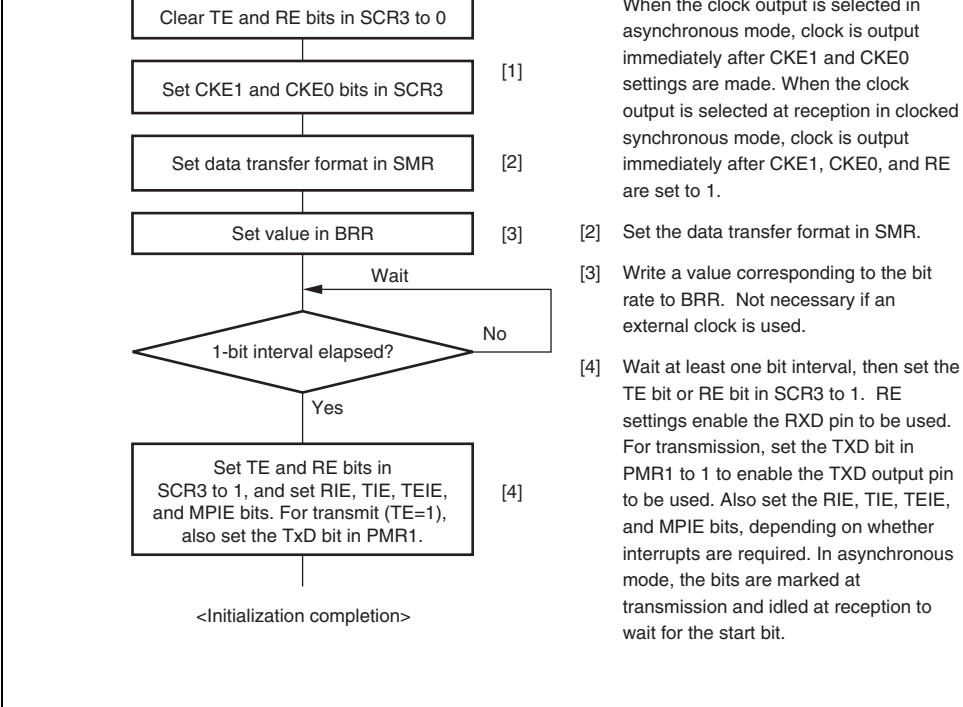
### 14.4.1 Clock

Either an internal clock generated by the on-chip baud rate generator or an external clock connected to the SCK3 pin can be selected as the SCI3's serial clock source, according to the setting of the COM bit in SMR and the CKE0 and CKE1 bits in SCR3. When an external clock is input to the SCK3 pin, the clock frequency should be 16 times the bit rate used.

When the SCI3 is operated on an internal clock, the clock can be output from the SCK3 pin. The frequency of the clock output in this case is equal to the bit rate, and the phase is such that the rising edge of the clock is in the middle of the transmit data, as shown in figure 14.3.

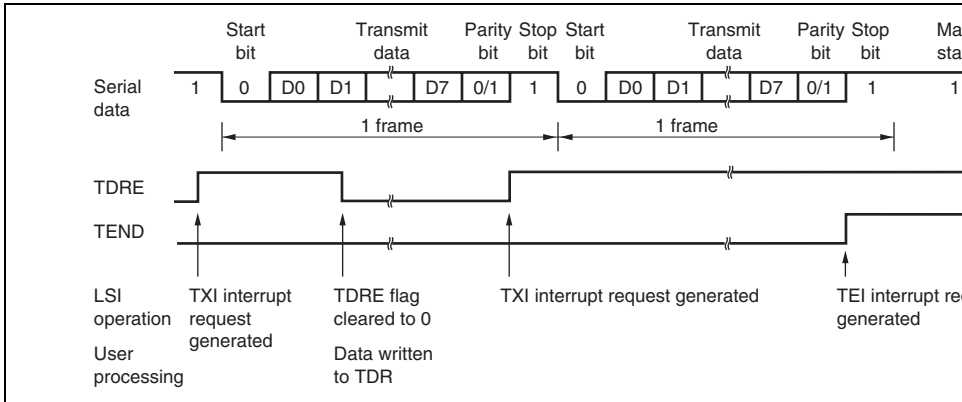


**Figure 14.3 Relationship between Output Clock and Transfer Data Phase (Asynchronous Mode) (Example with 8-Bit Data, Parity, Two Stop Bits)**



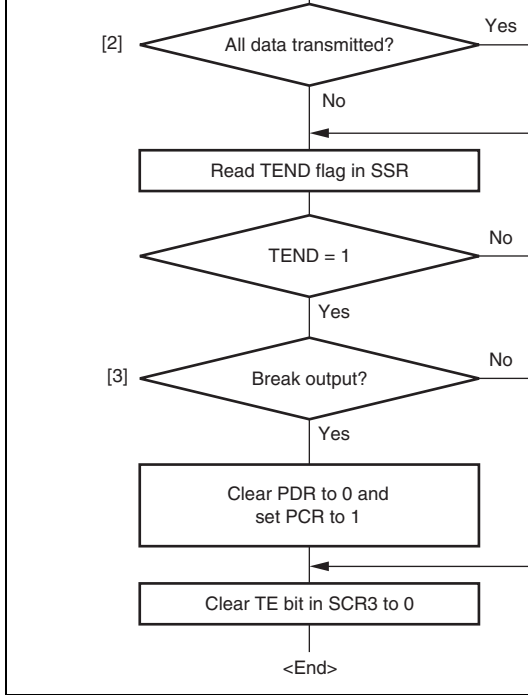
**Figure 14.4 Sample SCI3 Initialization Flowchart**

3. The SCI3 checks the TDRE flag at the timing for sending the stop bit.
4. If the TDRE flag is 0, the data is transferred from TDR to TSR, the stop bit is sent, and serial transmission of the next frame is started.
5. If the TDRE flag is 1, the TEND flag in SSR is set to 1, the stop bit is sent, and then state" is entered, in which 1 is output. If the TEIE bit in SCR3 is set to 1 at this time, interrupt request is generated.
6. Figure 14.6 shows a sample flowchart for transmission in asynchronous mode.



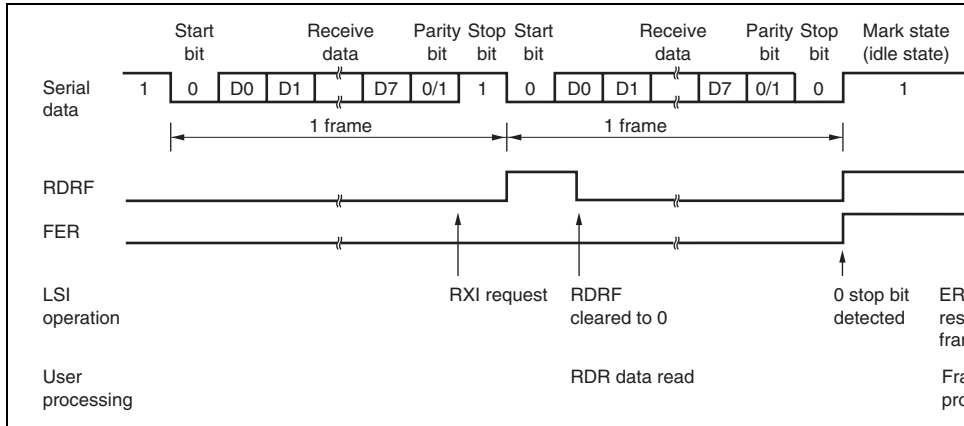
**Figure 14.5 Example SCI3 Operation in Transmission in Asynchronous Mode (8-Bit Data, Parity, One Stop Bit)**

and PDR to 0, clear TxD in PMR1 to 0, then clear the TE bit in SCR3 to 0.



**Figure 14.6 Sample Serial Transmission Flowchart (Asynchronous Mode)**

3. If a parity error is detected, the FER bit in SSR3 is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an ERI interrupt request is generated.
4. If a framing error is detected (when the stop bit is 0), the FER bit in SSR is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an ERI interrupt request is generated.
5. If reception is completed successfully, the RDRF bit in SSR is set to 1, and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an RXI interrupt request is generated. Continuous reception is possible because the RXI interrupt routine reads the data transferred to RDR before reception of the next receive data has been completed.

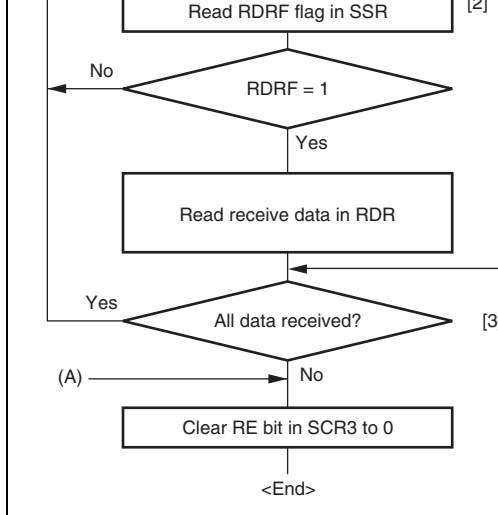


**Figure 14.7 Example SCI3 Operation in Reception in Asynchronous Mode (8-Bit Data, Parity, One Stop Bit)**

0	0	1	0	Transferred to RDR	Framing error
0	0	0	1	Transferred to RDR	Parity error
1	1	1	0	Lost	Overrun error + framing error
1	1	0	1	Lost	Overrun error + parity error
0	0	1	1	Transferred to RDR	Framing error + parity error
1	1	1	1	Lost	Overrun error + framing error + parity error

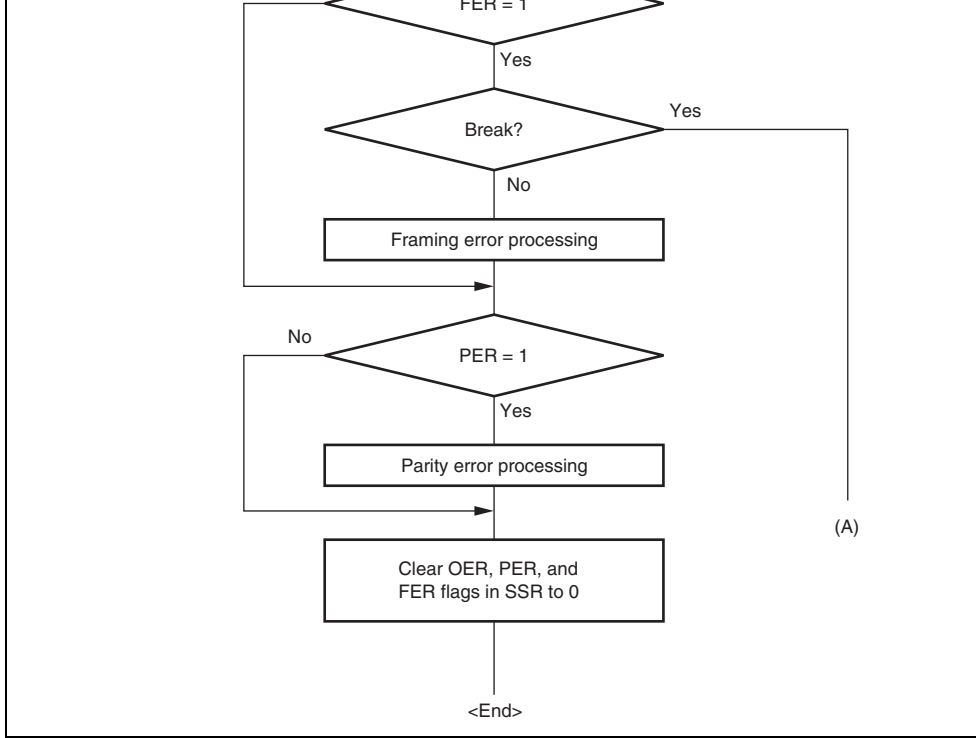
Note: \* The RDRF flag retains the state it had before data reception.





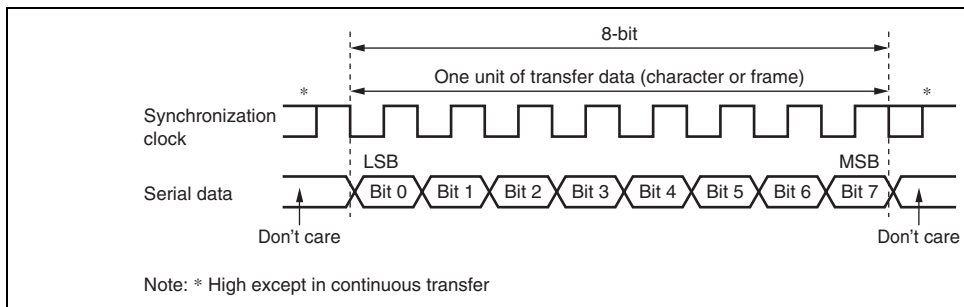
the error. After performing the appropriate error processing, ensure that the OER, PER, and FER flags are all cleared to 0. Reception can be resumed if any of these flags are cleared to 0. In the case of a framing error, a break can be detected by reading the value of the input port corresponding to the RxD pin.

**Figure 14.8 Sample Serial Data Reception Flowchart (Asynchronous mode)**



**Figure 14.8 Sample Serial Reception Data Flowchart (2)**

through the use of a common clock. Both the transmitter and the receiver also have a double-buffered structure, so data can be read or written during transmission or reception, enabling continuous data transfer.



**Figure 14.9 Data Format in Clocked Synchronous Communication**

### 14.5.1 Clock

Either an internal clock generated by the on-chip baud rate generator or an external synchronization clock input at the SCK3 pin can be selected, according to the setting of bit in SMR and CKE0 and CKE1 bits in SCR3. When the SCI3 is operated on an internal clock, the serial clock is output from the SCK3 pin. Eight serial clock pulses are output in the transfer period of one character, and when no transfer is performed the clock is fixed high.

### 14.5.2 SCI3 Initialization

Before transmitting and receiving data, the SCI3 should be initialized as described in a flowchart in figure 14.4.

mode has been specified, and synchronized with the input clock when use of an external clock has been specified. Serial data is transmitted sequentially from the LSB (bit 0), from the MSB (bit 7), and from the SCK3 pin.

4. The SCI checks the TDRE flag at the timing for sending the MSB (bit 7).
5. If the TDRE flag is cleared to 0, data is transferred from TDR to TSR, and serial transmission of the next frame is started.
6. If the TDRE flag is set to 1, the TEND flag in SSR is set to 1, and the TDRE flag maintains the output state of the last bit. If the TEIE bit in SCR3 is set to 1 at this time, a TEI interrupt request is generated.
7. The SCK3 pin is fixed high.

Figure 14.11 shows a sample flowchart for serial data transmission. Even if the TDRE flag is cleared to 0, transmission will not start while a receive error flag (OER, FER, or PER) is set. Make sure that the receive error flags are cleared to 0 before starting transmission.

operation request  
generated

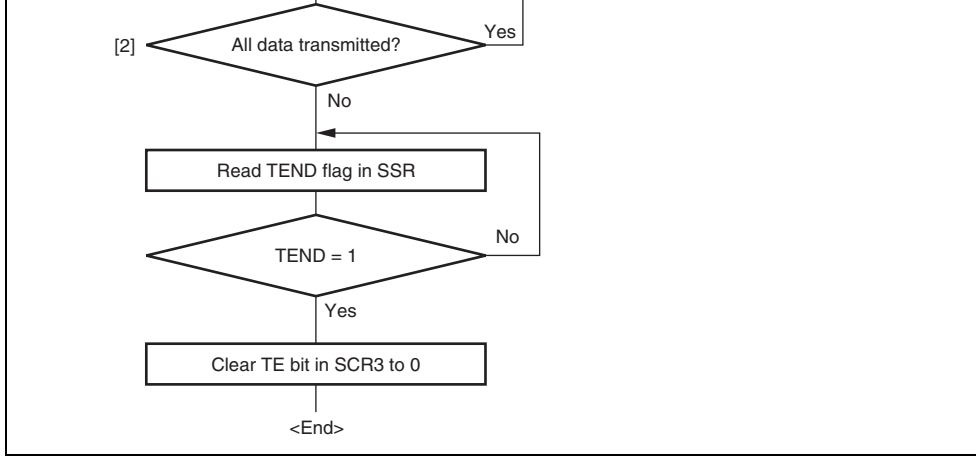
cleared  
to 0

generated

User  
processing

Data written  
to TDR

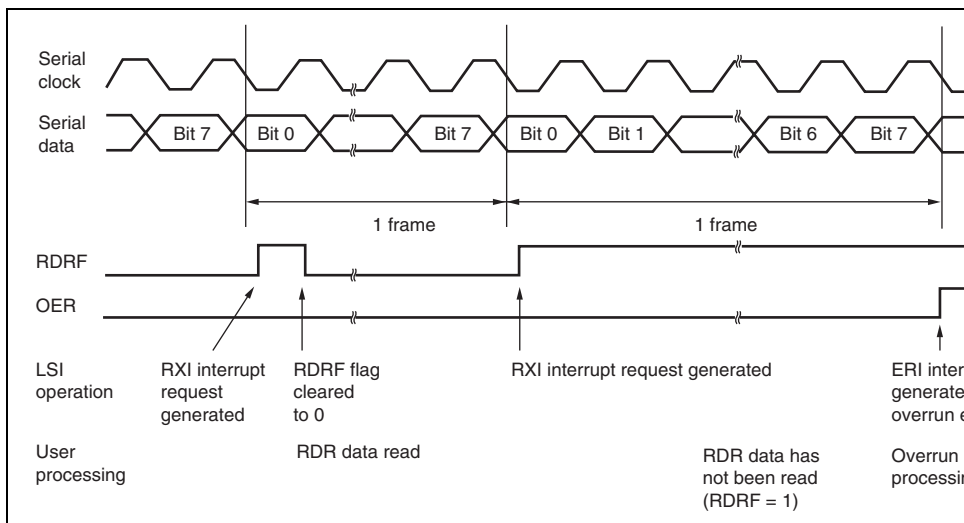
**Figure 14.10 Example of SCI3 Operation in Transmission in Clocked Synchron**



**Figure 14.11 Sample Serial Transmission Flowchart (Clocked Synchronous M**

time, an RXI interrupt request is generated, receive data is not transferred to RDR, and RDRF flag remains to be set to 1.

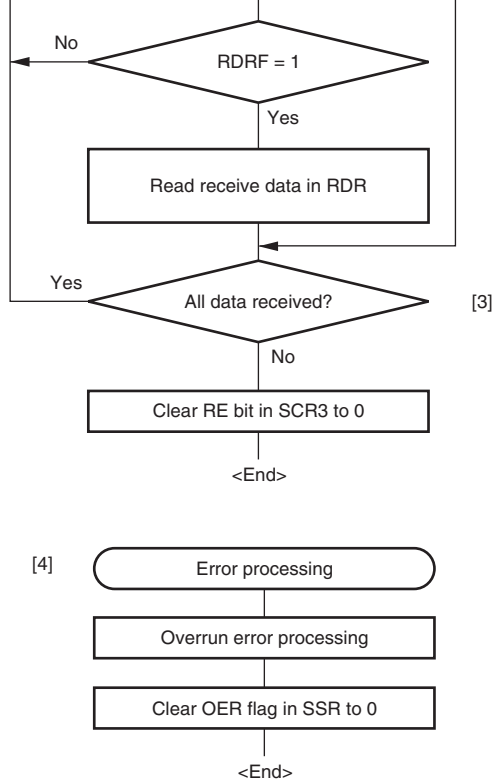
4. If reception is completed successfully, the RDRF bit in SSR is set to 1, and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an RXI interrupt request is generated.



**Figure 14.12 Example of SCI3 Reception Operation in Clocked Synchronous Mode**

Reception cannot be resumed while a receive error flag is set to 1. Accordingly, clear the FER, PER, and RDRF bits to 0 before resuming reception. Figure 14.13 shows a sample sequence for serial data reception.

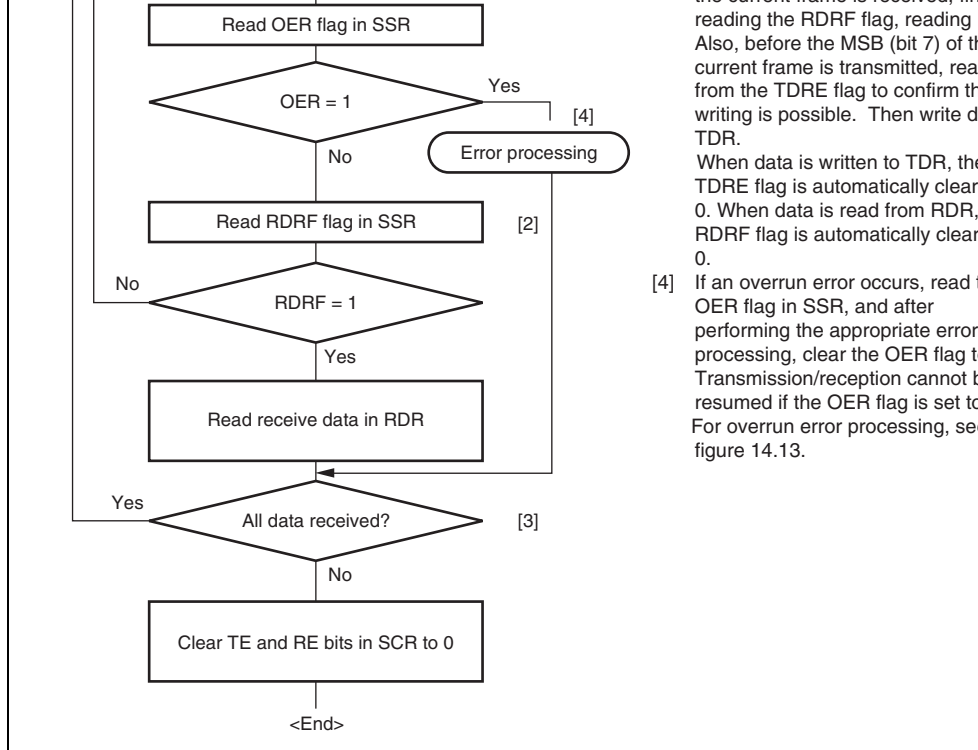
cleared to 0.  
 [4] If an overrun error occurs, read the OER flag in SSR, and after performing the appropriate error processing, clear the OER flag to 0. Reception cannot be resumed until the OER flag is set to 1.



**Figure 14.13 Sample Serial Reception Flowchart (Clocked Synchronous Mode)**







reading the RDRF flag, reading  
 Also, before the MSB (bit 7) of the  
 current frame is transmitted, read  
 from the TDRE flag to confirm th  
 writing is possible. Then write d  
 TDR.  
 When data is written to TDR, the  
 TDRE flag is automatically clear  
 0. When data is read from RDR,  
 RDRF flag is automatically clear  
 0.  
 [4] If an overrun error occurs, read  
 OER flag in SSR, and after  
 performing the appropriate error  
 processing, clear the OER flag t  
 Transmission/reception cannot b  
 resumed if the OER flag is set to  
 For overrun error processing, see  
 figure 14.13.

**Figure 14.14 Sample Flowchart of Simultaneous Serial Transmit and Receive Operation (Clocked Synchronous Mode)**

cycle is a data transmission cycle. Figure 14.13 shows an example of inter-processor communication using the multiprocessor format. The transmitting station first sends the ID of the receiving station with which it wants to perform serial communication as data with a 0 multiprocessor bit added. It then sends transmit data as data with a 0 multiprocessor bit added. When data with a 1 multiprocessor bit is received, the receiving station compares that data with its own ID. The station whose ID matches then receives the data sent next. Stations whose ID does not match continue to skip data until data with a 1 multiprocessor bit is again received.

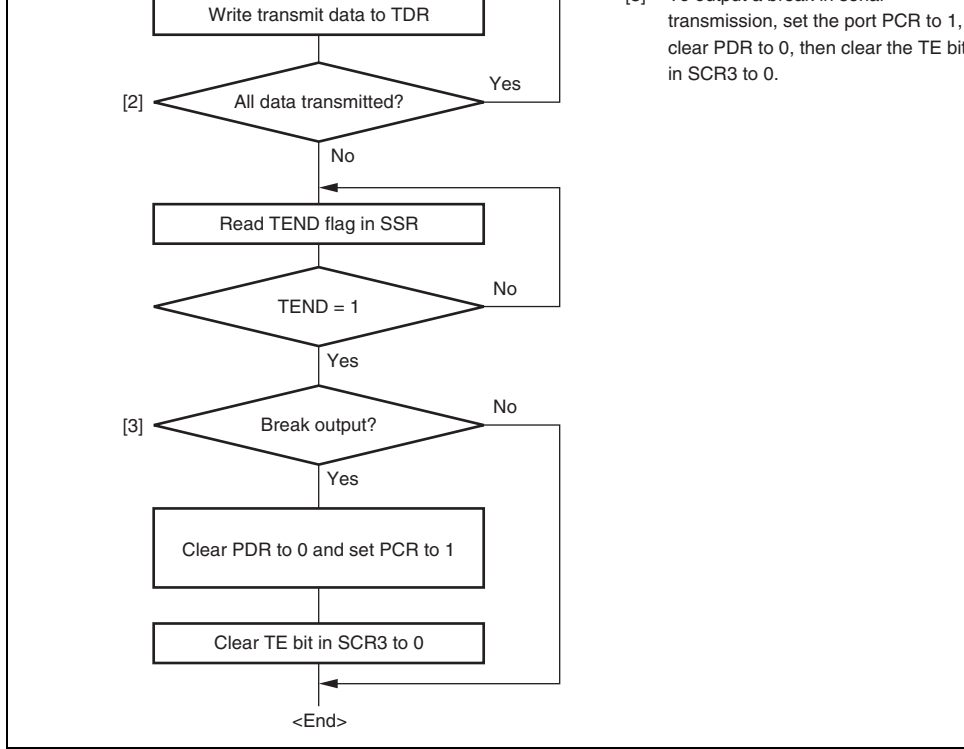
The SCI3 uses the MPIE bit in SCR3 to implement this function. When the MPIE bit is set to 1, the transfer of receive data from RSR to RDR, error flag detection, and setting the SSR status bits RDRF, FER, and OER to 1, are inhibited until data with a 1 multiprocessor bit is received. Upon reception of a receive character with a 1 multiprocessor bit, the MPBR bit in SSR is set to 1. When the MPIE bit is automatically cleared, thus normal reception is resumed. If the RIE bit in SCR3 is set to 1 at this time, an RXI interrupt is generated.

When the multiprocessor format is selected, the parity bit setting is rendered invalid. All other settings are the same as those in normal asynchronous mode. The clock used for multiprocessor communication is the same as that in normal asynchronous mode.

## Figure 14.15 Example of Communication Using Multiprocessor Format (Transmission of Data H'AA to Receiving Station A)

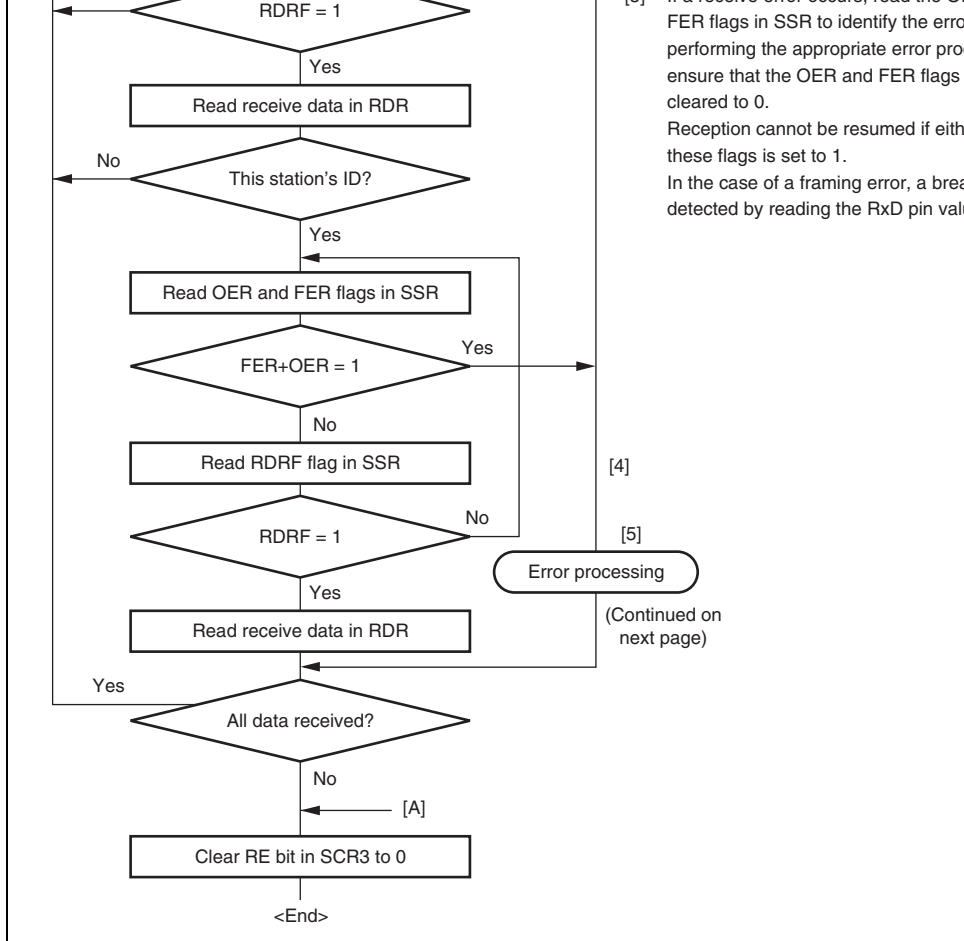
### 14.6.1 Multiprocessor Serial Data Transmission

Figure 14.16 shows a sample flowchart for multiprocessor serial data transmission. For a transmission cycle, set the MPBT bit in SSR to 1 before transmission. For a data transmission cycle, clear the MPBT bit in SSR to 0 before transmission. All other SCI3 operations are as those in asynchronous mode.

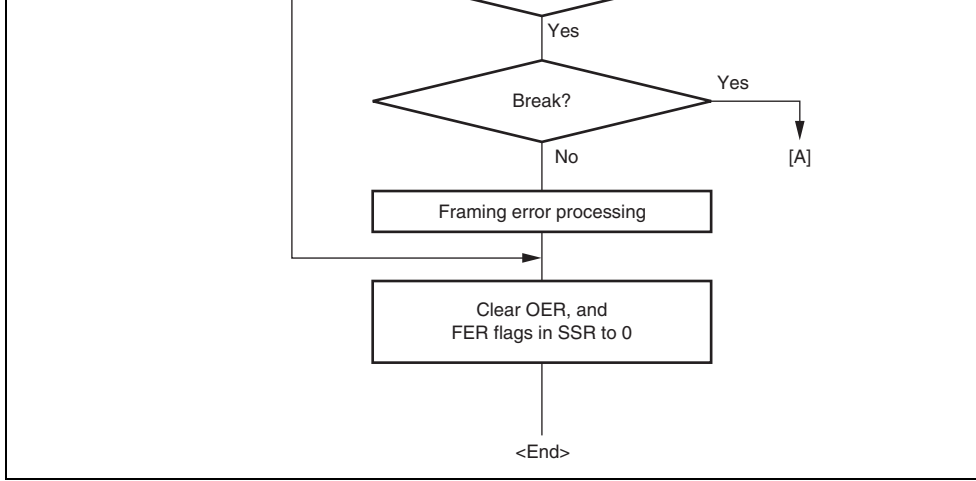


**Figure 14.16 Sample Multiprocessor Serial Transmission Flowchart**





**Figure 14.17 Sample Multiprocessor Serial Reception Flowchart (1)**



**Figure 14.17 Sample Multiprocessor Serial Reception Flowchart (2)**



LSI operation  
 User processing

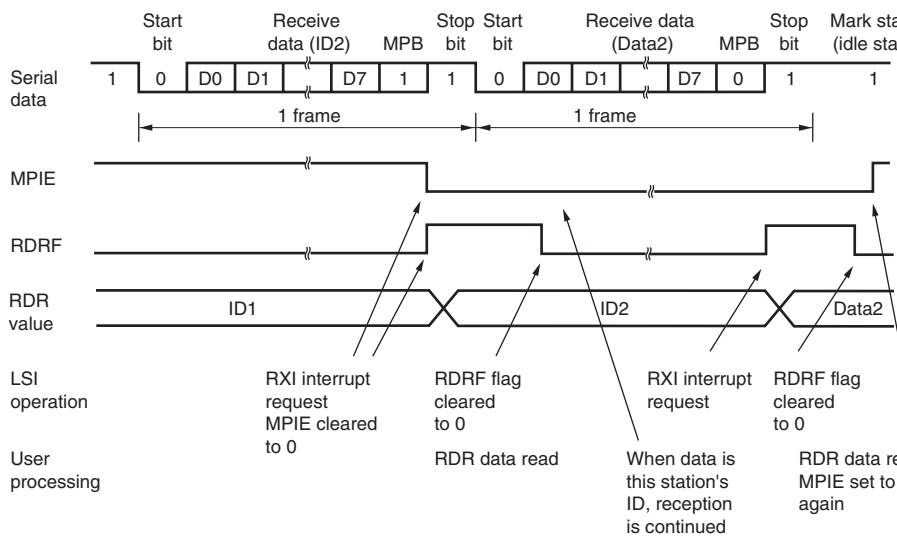
RXI interrupt request  
 MPIE cleared to 0

RDRF flag cleared to 0  
 RDR data read

When data is not this station's ID, MPIE is set to 1 again

RXI interrupt is not generated  
 RDR retains its value

(a) When data does not match this receiver's ID



(b) When data matches this receiver's ID

**Figure 14.18 Example of SCI3 Operation in Reception Using Multiprocessor Mode (Example with 8-Bit Data, Multiprocessor Bit, One Stop Bit)**

The initial value of the TDRE flag in SSR is 1. Thus, when the TIE bit in SCR3 is set to 1 before transferring the transmit data to TDR, a TXI interrupt request is generated even if the transmit data is not ready. The initial value of the TEND flag in SSR is 1. Thus, when the TEIE bit in SCR3 is set to 1 before transferring the transmit data to TDR, a TEI interrupt request is generated even if the transmit data has not been sent. It is possible to make use of the most of these interrupt requests efficiently by transferring the transmit data to TDR in the interrupt routine. To prevent the generation of these interrupt requests (TXI and TEI), set the enable bits (TIE and TEIE) to 0. To correspond to these interrupt requests to 1, after transferring the transmit data to TDR.

When TE is 0, the TxD pin is used as an I/O port whose direction (input or output) and level are determined by PCR and PDR. This can be used to set the TxD pin to mark state (high level) to send a break during serial data transmission. To maintain the communication line at mark state until TE is set to 1, set both PCR and PDR to 1. As TE is cleared to 0 at this point, the TxD pin becomes an I/O port, and 1 is output from the TxD pin. To send a break during serial transmission, first set PCR to 1 and PDR to 0, and then clear TE to 0. When TE is cleared to 0, the transmission is initialized regardless of the current transmission state, the TxD pin becomes an I/O port, and 1 is output from the TxD pin.

### 14.8.3 Receive Error Flags and Transmit Operations (Clocked Synchronous Mode)

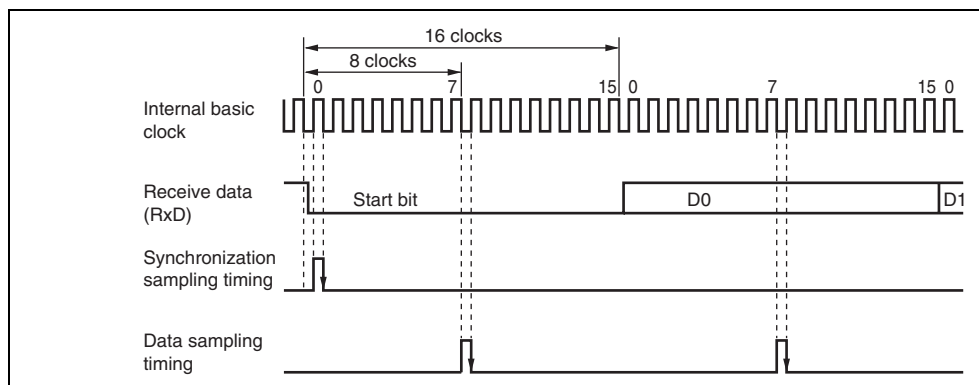
Transmission cannot be started when a receive error flag (OER, PER, or FER) is set to 1. To start transmission, the TDRE flag is cleared to 0. Be sure to clear the receive error flags to 0 before starting transmission. Note also that receive error flags cannot be cleared to 0 even if the RE bit is set to 0.

Where N : Ratio of bit rate to clock (N = 16)  
 D : Clock duty (D = 0.5 to 1.0)  
 L : Frame length (L = 9 to 12)  
 F : Absolute value of clock rate deviation

Assuming values of F (absolute value of clock rate deviation) = 0 and D (clock duty) = 0.5, formula (1), the reception margin can be given by the formula.

$$M = \{0.5 - 1/(2 \times 16)\} \times 100 [\%] = 46.875\%$$

However, this is only the computed value, and a margin of 20% to 30% should be allowed in system design.



**Figure 14.19 Receive Data Sampling Timing in Asynchronous Mode**

## 13.1 Features

- Selection of I<sup>2</sup>C format or clocked synchronous serial format
- Continuous transmission/reception

Since the shift register, transmit data register, and receive data register are independent of each other, the continuous transmission/reception can be performed.

### I<sup>2</sup>C bus format

- Start and stop conditions generated automatically in master mode
- Selection of acknowledge output levels when receiving
- Automatic loading of acknowledge bit when transmitting
- Bit synchronization/wait function

In master mode, the state of SCL is monitored per bit, and the timing is synchronized automatically.

If transmission/reception is not yet possible, set the SCL to low until preparations are completed.

- Six interrupt sources

Transmit data empty (including slave-address match), transmit end, receive data full (including slave-address match), arbitration lost, NACK detection, and stop condition detection

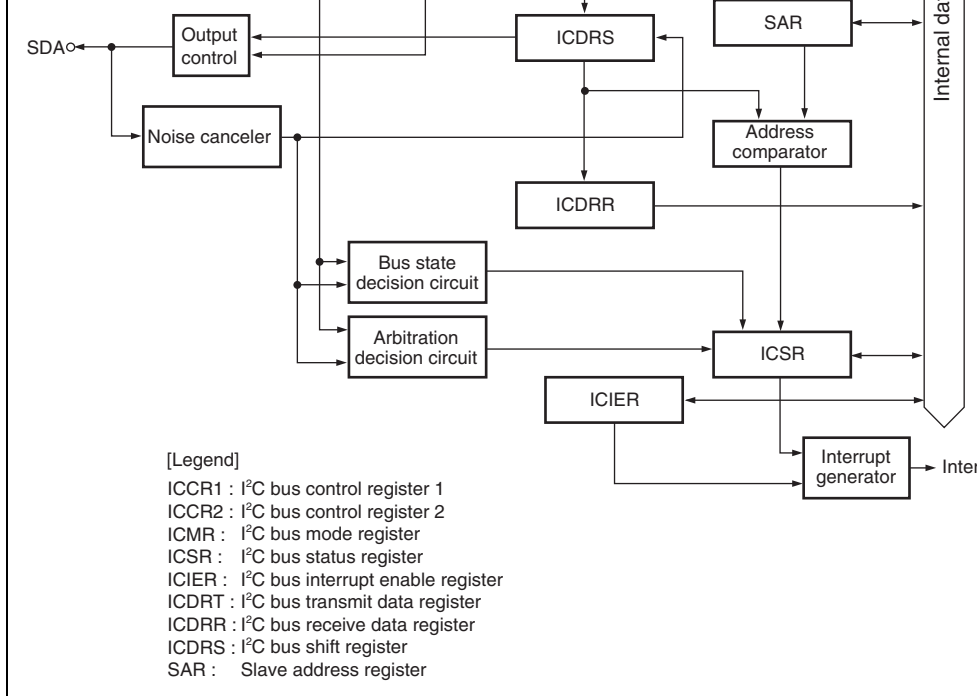
- Direct bus drive

Two pins, SCL and SDA pins, function as NMOS open-drain outputs when the bus control function is selected.

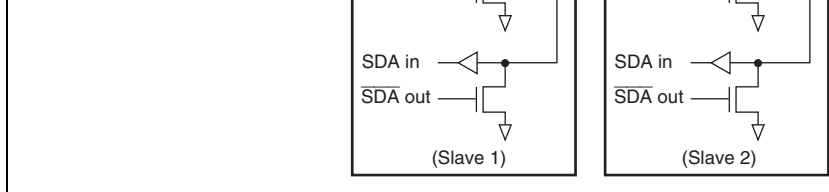
### Clocked synchronous format

- Four interrupt sources

Transmit-data-empty, transmit-end, receive-data-full, and overrun error



**Figure 15.1 Block Diagram of I<sup>2</sup>C Bus Interface 2**



**Figure 15.2 External Circuit Connections of I/O Pins**

## 15.2 Input/Output Pins

Table 15.1 summarizes the input/output pins used by the I<sup>2</sup>C bus interface 2.

**Table 15.1 I<sup>2</sup>C Bus Interface Pins**

Name	Abbreviation	I/O	Function
Serial clock	SCL	I/O	IIC serial clock input/output
Serial data	SDA	I/O	IIC serial data input/output

## 15.3 Register Descriptions

The I<sup>2</sup>C bus interface 2 has the following registers:

- I<sup>2</sup>C bus control register 1 (ICCR1)
- I<sup>2</sup>C bus control register 2 (ICCR2)
- I<sup>2</sup>C bus mode register (ICMR)
- I<sup>2</sup>C bus interrupt enable register (ICIER)
- I<sup>2</sup>C bus status register (ICSR)
- I<sup>2</sup>C bus slave address register (SAR)

7	ICE	0	R/W	<p>I<sup>2</sup>C Bus Interface Enable</p> <p>0: This module is halted. (SCL and SDA pins are in high-impedance function.)</p> <p>1: This bit is enabled for transfer operations. (SCL and SDA pins are bus drive state.)</p>
6	RCVD	0	R/W	<p>Reception Disable</p> <p>This bit enables or disables the next operation when the ICDRR is 0 and ICDRR is read.</p> <p>0: Enables next reception</p> <p>1: Disables next reception</p>
5	MST	0	R/W	Master/Slave Select
4	TRS	0	R/W	<p>Transmit/Receive Select</p> <p>In master mode with the I<sup>2</sup>C bus format, when arbitration is lost, MST and TRS are both reset by hardware, causing a transition to slave receive mode. Modification of the TRS should be made between transfer frames.</p> <p>After data receive has been started in slave receive mode, when the first seven bits of the receive data agree with the slave address that is set to SAR and the eighth bit disagrees, TRS is automatically set to 1. If an overrun error occurs in master mode with the clock synchronous serial format, TRS is cleared to 0 and slave receive mode is entered.</p> <p>Operating modes are described below according to the TRS and TRS combination. When clocked synchronous serial format is selected and MST is 1, clock is output.</p> <p>00: Slave receive mode</p> <p>01: Slave transmit mode</p> <p>10: Master receive mode</p> <p>11: Master transmit mode</p>



Bit 3	Bit 2	Bit 1	Bit 0		Transfer Rate			
CKS3	CKS2	CKS1	CKS0	Clock	$\phi = 5$ MHz	$\phi = 8$ MHz	$\phi = 10$ MHz	$\phi = 16$ MHz
0	0	0	0	$\phi/28$	179 kHz	286 kHz	357 kHz	571 kHz
			1	$\phi/40$	125 kHz	200 kHz	250 kHz	400 kHz
		1	0	$\phi/48$	104 kHz	167 kHz	208 kHz	333 kHz
			1	$\phi/64$	78.1 kHz	125 kHz	156 kHz	250 kHz
	1	0	0	$\phi/80$	62.5 kHz	100 kHz	125 kHz	200 kHz
			1	$\phi/100$	50.0 kHz	80.0 kHz	100 kHz	160 kHz
		1	0	$\phi/112$	44.6 kHz	71.4 kHz	89.3 kHz	143 kHz
			1	$\phi/128$	39.1 kHz	62.5 kHz	78.1 kHz	125 kHz
1	0	0	0	$\phi/56$	89.3 kHz	143 kHz	179 kHz	286 kHz
			1	$\phi/80$	62.5 kHz	100 kHz	125 kHz	200 kHz
		1	0	$\phi/96$	52.1 kHz	83.3 kHz	104 kHz	167 kHz
			1	$\phi/128$	39.1 kHz	62.5 kHz	78.1 kHz	125 kHz
	1	0	0	$\phi/160$	31.3 kHz	50.0 kHz	62.5 kHz	100 kHz
			1	$\phi/200$	25.0 kHz	40.0 kHz	50.0 kHz	80.0 kHz
		1	0	$\phi/224$	22.3 kHz	35.7 kHz	44.6 kHz	71.4 kHz
			1	$\phi/256$	19.5 kHz	31.3 kHz	39.1 kHz	62.5 kHz

format, this bit has no meaning. With the I<sup>2</sup>C bus, this bit is set to 1 when the SDA level changes from high to low under the condition of SCL = high, assuming that the start condition has been issued. This bit is cleared to 0 when the SDA level changes from low to high under the condition of SCL = high, assuming that the stop condition has been issued. Write 1 to BBSY and 0 to SCP to issue a start condition. Follow this procedure when also transmitting a start condition. Write 0 in BBSY and 1 to SCP to issue a stop condition. To issue start/stop conditions, use the MOV instruction.

6	SCP	1	W	<p>Start/Stop Issue Condition Disable</p> <p>The SCP bit controls the issue of start/stop conditions in master mode.</p> <p>To issue a start condition, write 1 in BBSY and 0 in SCP. A retransmit start condition is issued in the same manner. To issue a stop condition, write 0 in BBSY and 0 in SCP. This bit is always read as 1. If 1 is written, the data is stored.</p>
5	SDAO	1	R/W	<p>SDA Output Value Control</p> <p>This bit is used with SDAOP when modifying output value of SDA. This bit should not be manipulated during data transfer.</p> <p>0: When reading, SDA pin outputs low. When writing, SDA pin is changed to output low.</p> <p>1: When reading, SDA pin outputs high. When writing, SDA pin is changed to output high (outputs high by external pull-up resistance).</p>

1	IICRST	0	R/W	IIC Control Part Reset This bit resets the control part except for I <sup>2</sup> C register. When this bit is set to 1 when hang-up occurs because of communication failure during I <sup>2</sup> C operation, I <sup>2</sup> C control part can be reset without setting ports and initial registers.
0	—	1	—	Reserved This bit is always read as 1, and cannot be modified.

### 15.3.3 I<sup>2</sup>C Bus Mode Register (ICMR)

ICMR selects whether the MSB or LSB is transferred first, performs master mode wait insertion, and selects the transfer bit count.

Bit	Bit Name	Initial Value	R/W	Description
7	MLS	0	R/W	MSB-First/LSB-First Select 0: MSB-first 1: LSB-first Set this bit to 0 when the I <sup>2</sup> C bus format is used.
6	WAIT	0	R/W	Wait Insertion Bit In master mode with the I <sup>2</sup> C bus format, this bit selects whether to insert a wait after data transfer except for the acknowledge bit. When WAIT is set to 1, after the clock for the final data bit, low period is extended by two transfer clocks. If WAIT is cleared to 0, data and acknowledge bits are transferred consecutively without wait inserted. The setting of this bit is invalid in slave mode with the I <sup>2</sup> C bus format or with the clocked synchronous serial bus format.

2	BC2	0	R/W	Bit Counter 2 to 0
1	BC1	0	R/W	These bits specify the number of bits to be trans next. When read, the remaining number of trans indicated. With the I <sup>2</sup> C bus format, the data is tra with one addition acknowledge bit. Bit BC2 to BC settings should be made during an interval betw transfer frames. If bits BC2 to BC0 are set to a v other than 000, the setting should be made whil SCL pin is low. The value returns to 000 at the e data transfer, including the acknowledge bit. Wit clock synchronous serial format, these bits shou modified.
0	BC0	0	R/W	
				I <sup>2</sup> C Bus Format
				Clock Synchronous Serial
				000: 9 bits
				000: 8 bits
				001: 2 bits
				001: 1 bits
				010: 3 bits
				010: 2 bits
				011: 4 bits
				011: 3 bits
				100: 5 bits
				100: 4 bits
				101: 6 bits
				101: 5 bits
				110: 7 bits
				110: 6 bits
				111: 8 bits
				111: 7 bits

				1: Transmit data empty interrupt request (TXI) is enabled.
6	TEIE	0	R/W	<p>Transmit End Interrupt Enable</p> <p>This bit enables or disables the transmit end interrupt request (TEI) at the rising of the ninth clock while the TEIEN bit in ICSR is 1. TEI can be canceled by clearing the TEIEN bit or the TEIE bit to 0.</p> <p>0: Transmit end interrupt request (TEI) is disabled.</p> <p>1: Transmit end interrupt request (TEI) is enabled.</p>
5	RIE	0	R/W	<p>Receive Interrupt Enable</p> <p>This bit enables or disables the receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format, when the receive data is transferred from ICDRS to ICDFR. The RDRF bit in ICSR is set to 1. RXI can be canceled by clearing the RDRF or RIE bit to 0.</p> <p>0: Receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format are disabled.</p> <p>1: Receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format are enabled.</p>
4	NAKIE	0	R/W	<p>NACK Receive Interrupt Enable</p> <p>This bit enables or disables the NACK receive interrupt request (NAKI) and the overrun error (setting of the OVE bit in ICSR) interrupt request (ERI) with the clocked synchronous format, when the NACKF and ALACKF bits in ICSR are set to 1. NAKI can be canceled by clearing the NACKF, OVE, or NAKIE bit to 0.</p> <p>0: NACK receive interrupt request (NAKI) is disabled.</p> <p>1: NACK receive interrupt request (NAKI) is enabled.</p>

1: If the receive acknowledge bit is 1, continuous  
is halted.

---

1	ACKBR	0	R	Receive Acknowledge In transmit mode, this bit stores the acknowledge that are returned by the receive device. This bit modified. 0: Receive acknowledge = 0 1: Receive acknowledge = 1
0	ACKBT	0	R/W	Transmit Acknowledge In receive mode, this bit specifies the bit to be sent acknowledge timing. 0: 0 is sent at the acknowledge timing. 1: 1 is sent at the acknowledge timing.

---

- When TRS is set
- When a start condition (including re-transfer) has been issued
- When transmit mode is entered from receive or slave mode

[Clearing conditions]

- When 0 is written in TDRE after reading TDRT
- When data is written to ICDRT with an instruction

6	TEND	0	R/W	Transmit End
[Setting conditions]				
<ul style="list-style-type: none"> <li>• When the ninth clock of SCL rises with the start condition in I2C format while the TDRE flag is 1</li> <li>• When the final bit of transmit frame is sent with the start condition in clock synchronous serial format</li> </ul>				
[Clearing conditions]				
<ul style="list-style-type: none"> <li>• When 0 is written in TEND after reading TDRT</li> <li>• When data is written to ICDRT with an instruction</li> </ul>				
5	RDRF	0	R/W	Receive Data Register Full
[Setting condition]				
<ul style="list-style-type: none"> <li>• When a receive data is transferred from ICDRT to ICDRR</li> </ul>				
[Clearing conditions]				
<ul style="list-style-type: none"> <li>• When 0 is written in RDRF after reading RDRD</li> <li>• When ICDRR is read with an instruction</li> </ul>				

[Setting conditions]

- In master mode, when a stop condition is detected after frame transfer
- In slave mode, when a stop condition is detected after the general call address or the first byte of the address, next to detection of start condition, with the address set in SAR

[Clearing condition]

- When 0 is written in STOP after reading STOP
-



- If the internal SDA and SDA pin disagree at the start of a transmission on the I<sup>2</sup>C SCL in master transmit mode
- When the SDA pin outputs high in master mode when a start condition is detected
- When the final bit is received with the clock in master mode in synchronous format while RDRF = 1

[Clearing condition]

- When 0 is written in AL/OVE after reading AL/OVE

---

1	AAS	0	R/W
---	-----	---	-----

Slave Address Recognition Flag

In slave receive mode, this flag is set to 1 if the slave address following a start condition matches bits SVA6 to SVA0 of the SAR.

[Setting conditions]

- When the slave address is detected in slave receive mode
- When the general call address is detected in slave receive mode.

[Clearing condition]

- When 0 is written in AAS after reading AAS

---

0	ADZ	0	R/W
---	-----	---	-----

General Call Address Recognition Flag

This bit is valid in I<sup>2</sup>C bus format slave receive mode.

[Setting condition]

- When the general call address is detected in slave receive mode

[Clearing condition]

- When 0 is written in ADZ after reading ADZ
-

connected to the I<sup>2</sup>C bus.

---

0	FS	0	R/W	Format Select
				0: I <sup>2</sup> C bus format is selected.
				1: Clocked synchronous serial format is selected.

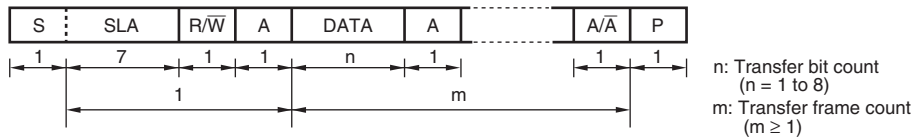
---

ICDRR is an 8-bit register that stores the receive data. When data of one byte is received, ICDRT transfers the receive data from ICDRS to ICDRR and the next data can be received. ICDRS is a receive-only register, therefore the CPU cannot write to this register. The initial value of ICDRS is H'FF.

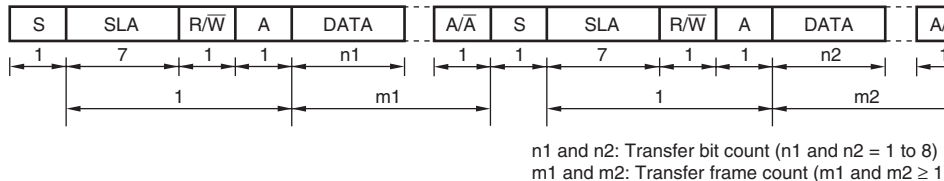
### **15.3.9 I<sup>2</sup>C Bus Shift Register (ICDRS)**

ICDRS is a register that is used to transfer/receive data. In transmission, data is transferred from ICDRT to ICDRS and the data is sent from the SDA pin. In reception, data is transferred from ICDRS to ICDRR after data of one byte is received. This register cannot be read directly by the CPU.

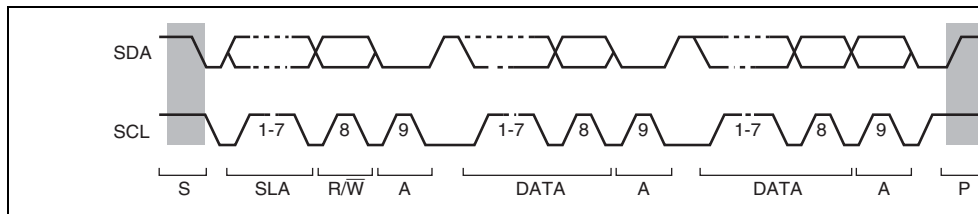
(a) I<sup>2</sup>C bus format (FS = 0)



(b) I<sup>2</sup>C bus format (Start condition retransmission, FS = 0)



**Figure 15.3 I<sup>2</sup>C Bus Formats**



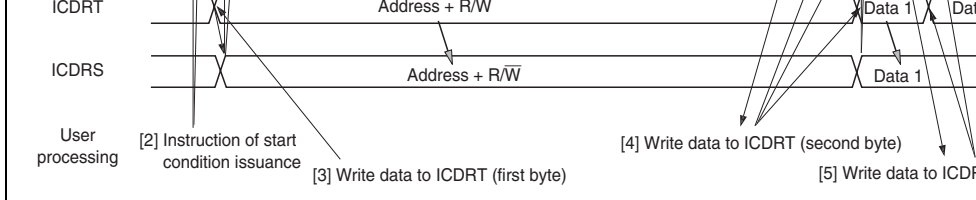
**Figure 15.4 I<sup>2</sup>C Bus Timing**

**Legend**

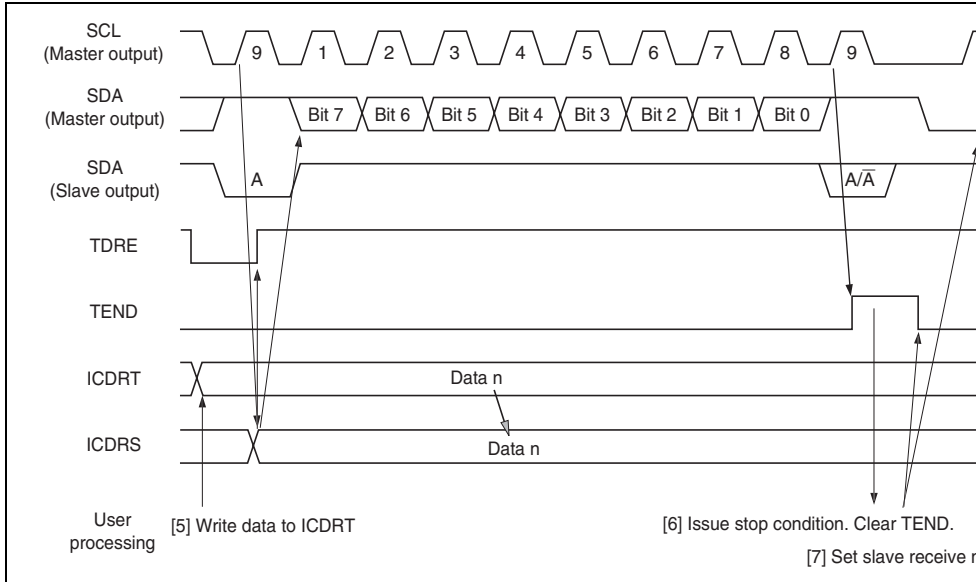
- S: Start condition. The master device drives SDA from high to low while SCL is high
- SLA: Slave address

described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 to 1. Set the bits in ICCR1 to 1. (Initial setting)
2. Read the BBSY flag in ICCR2 to confirm that the bus is free. Set the MST and TRS bits in ICCR1 to select master transmit mode. Then, write 1 to BBSY and 0 to SCP using MOV instruction. (Start condition issued) This generates the start condition.
3. After confirming that TDRE in ICSR has been set, write the transmit data (the first byte shows the slave address and  $R/\overline{W}$ ) to ICDRT. At this time, TDRE is automatically cleared and data is transferred from ICDRT to ICDRS. TDRE is set again.
4. When transmission of one byte data is completed while TDRE is 1, TEND in ICSR is set at the rise of the 9th transmit clock pulse. Read the ACKBR bit in ICIER, and confirm that the slave device has been selected. Then, write second byte data to ICDRT. When ACKBR is 1, the slave device has not been acknowledged, so issue the stop condition. To issue the stop condition, write 0 to BBSY and SCP using MOV instruction. SCL is fixed low until transmit data is prepared or the stop condition is issued.
5. The transmit data after the second byte is written to ICDRT every time TDRE is set.
6. Write the number of bytes to be transmitted to ICDRT. Wait until TEND is set (the end of byte data transmission) while TDRE is 1, or wait for NACK (NACKF in ICSR = 1) from the receive device while ACKE in ICIER is 1. Then, issue the stop condition to clear TEND and NACKF.
7. When the STOP bit in ICSR is set to 1, the operation returns to the slave receive mode.

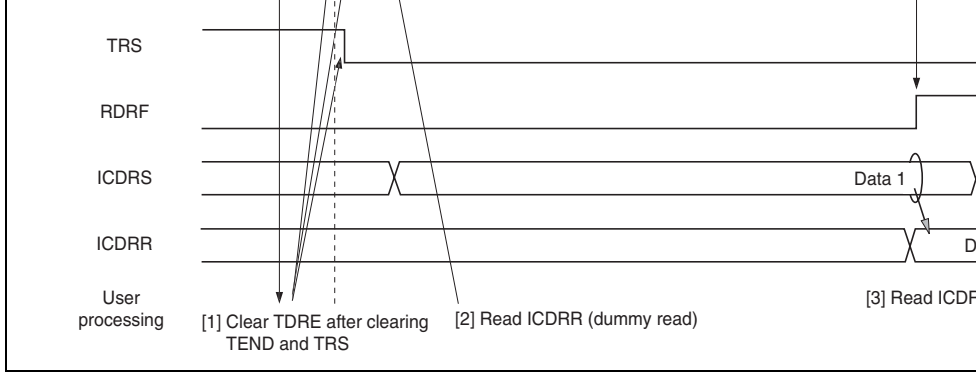


**Figure 15.5 Master Transmit Mode Operation Timing (1)**



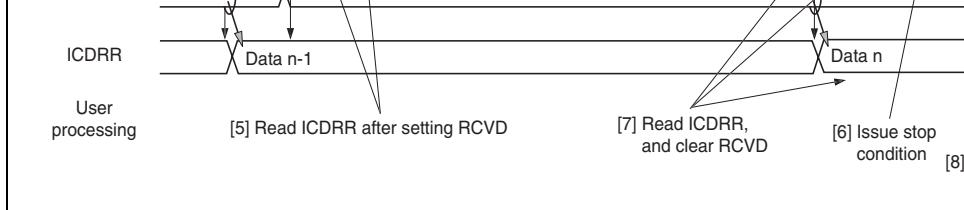
**Figure 15.6 Master Transmit Mode Operation Timing (2)**

- and data received, in synchronization with the internal clock. The master device outputs the acknowledge signal at the level specified by ACKBT in ICIER to SDA, at the 9th receive clock pulse.
3. After the reception of first frame data is completed, the RDRF bit in ICST is set to 1 at the rise of 9th receive clock pulse. At this time, the receive data is read by reading ICDRR, and RDRF is cleared to 0.
  4. The continuous reception is performed by reading ICDRR every time RDRF is set. ICDRR is read at the fall of each receive clock pulse falls after reading ICDRR by the other processing while RDRF is set. RDRF is fixed low until ICDRR is read.
  5. If next frame is the last receive data, set the RCVD bit in ICCR1 to 1 before reading ICDRR. This enables the issuance of the stop condition after the next reception.
  6. When the RDRF bit is set to 1 at rise of the 9th receive clock pulse, issue the stage command.
  7. When the STOP bit in ICSR is set to 1, read ICDRR. Then clear the RCVD bit to 0.
  8. The operation returns to the slave receive mode.



**Figure 15.7 Master Receive Mode Operation Timing (1)**





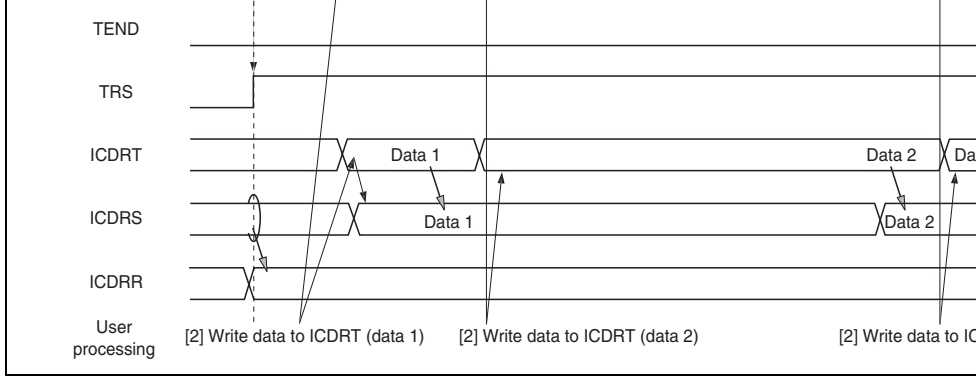
**Figure 15.8 Master Receive Mode Operation Timing (2)**

#### 15.4.4 Slave Transmit Operation

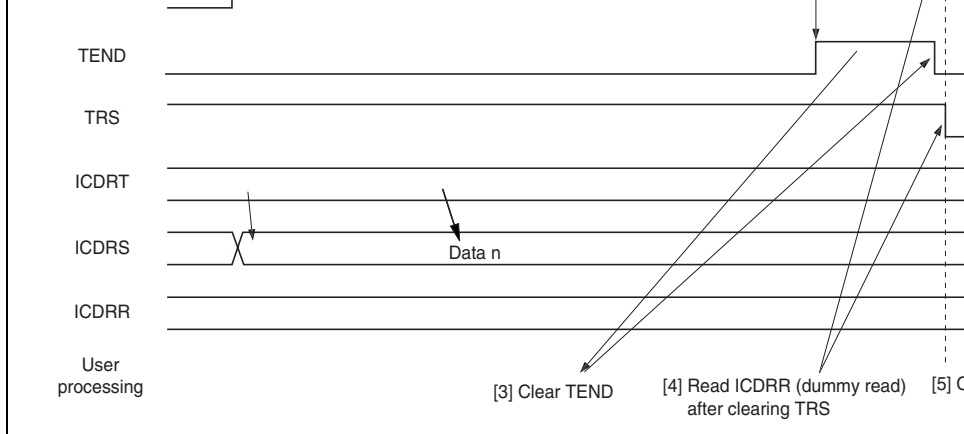
In slave transmit mode, the slave device outputs the transmit data, while the master device provides the receive clock and returns an acknowledge signal. For slave transmit mode operation timing, refer to figures 15.9 and 15.10.

The transmission procedure and operations in slave transmit mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 to 1. Set the CKS2 and CKS1 bits in ICCR1 to 1. (Initial setting) Set the MST and TRS bits in ICCR1 to select slave transmit mode, and wait until the slave address matches.
2. When the slave address matches in the first frame following detection of the start condition, the slave device outputs the level specified by ACKBT in ICIER to SDA, at the rise of the receive clock pulse. At this time, if the 8th bit data ( $R/\bar{W}$ ) is 1, the TRS and ICSR bits in ICCR1 are set to 1, and the mode changes to slave transmit mode automatically. The continuous transmission is performed by writing transmit data to ICDRT every time TDRE is set.
3. If TDRE is set after writing last transmit data to ICDRT, wait until TEND in ICSR is set with TDRE = 1. When TEND is set, clear TEND.
4. Clear TRS for the end processing, and read ICDRR (dummy read). SCL is free.
5. Clear TDRE.



**Figure 15.9 Slave Transmit Mode Operation Timing (1)**

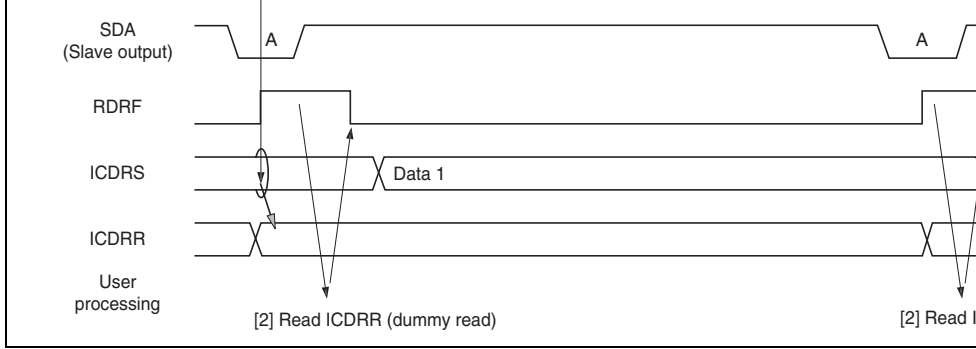


**Figure 15.10 Slave Transmit Mode Operation Timing (2)**

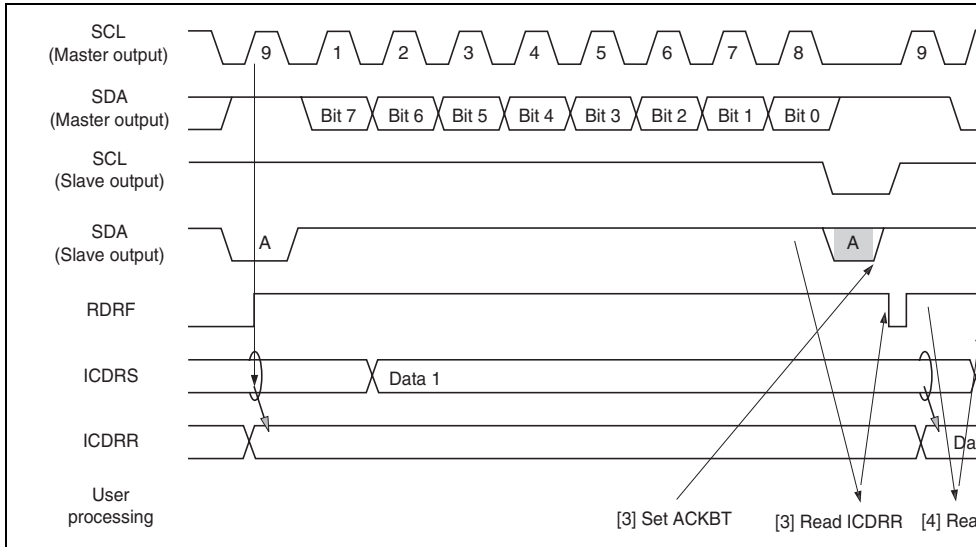
### 15.4.5 Slave Receive Operation

In slave receive mode, the master device outputs the transmit clock and transmit data, and the slave device returns an acknowledge signal. For slave receive mode operation timing, refer to figures 15.11 and 15.12. The reception procedure and operations in slave receive mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 bits in ICCR1 to 1. (Initial setting) Set the MST and TRS bits in ICCR1 to select slave mode, and wait until the slave address matches.
2. When the slave address matches in the first frame following detection of the start condition, the slave device outputs the level specified by ACKBT in ICIER to SDA, at the rise of the clock pulse. At the same time, RDRF in ICSR is set to read ICDRR (dummy read). (The read data show the slave address and R/ $\overline{W}$ , it is not used.)

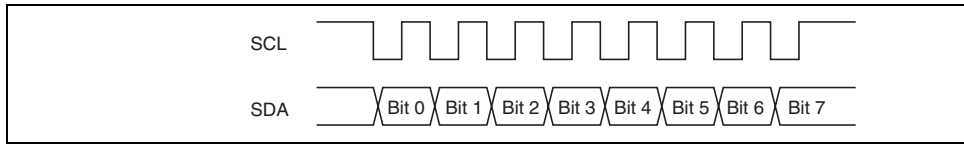


**Figure 15.11 Slave Receive Mode Operation Timing (1)**



**Figure 15.12 Slave Receive Mode Operation Timing (2)**

MSB first or LSB first. The output level of SDA can be changed during the transfer wait  
SDAO bit in ICCR2.



**Figure 15.13 Clocked Synchronous Serial Transfer Format**

### Transmit Operation

In transmit mode, transmit data is output from SDA, in synchronization with the fall of the transfer clock. The transfer clock is output when MST in ICCR1 is 1, and is input when MST is 0. For transmit mode operation timing, refer to figure 15.14. The transmission procedure and operation in transmit mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MST and CKS3 to CKS0 bits in ICCR1 to 1. (Clock setting)
2. Set the TRS bit in ICCR1 to select the transmit mode. Then, TDRE in ICSR is set.
3. Confirm that TDRE has been set. Then, write the transmit data to ICDRT. The data is transferred from ICDRT to ICDSR, and TDRE is set automatically. The continuous transmission is performed by writing data to ICDRT every time TDRE is set. When switching from transmit mode to receive mode, clear TRS while TDRE is 1.

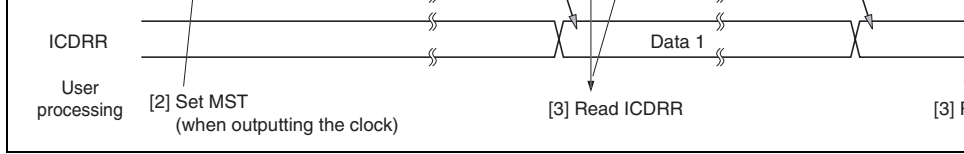


**Figure 15.14 Transmit Mode Operation Timing**

### Receive Operation

In receive mode, data is latched at the rise of the transfer clock. The transfer clock is output when MST in ICCR1 is 1, and is input when MST is 0. For receive mode operation timing, refer to figure 15.15. The reception procedure and operations in receive mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MST and CKS3 to CKS0 bits in ICCR1 to 1. (Initial setting)
2. When the transfer clock is output, set MST to 1 to start outputting the receive clock.
3. When the receive operation is completed, data is transferred from ICDRS to ICDRR and RDRF in ICSR is set. When MST = 1, the next byte can be received, so the clock is continually output. The continuous reception is performed by reading ICDRR every time RDRF is set. When the 8th clock is risen while RDRF is 1, the overrun is detected and AL/OVE in ICSR is set. At this time, the previous reception data is retained in ICDRR.
4. To stop receiving when MST = 1, set RCVD in ICCR1 to 1, then read ICDRR. Then, MST is fixed high after receiving the next byte data.

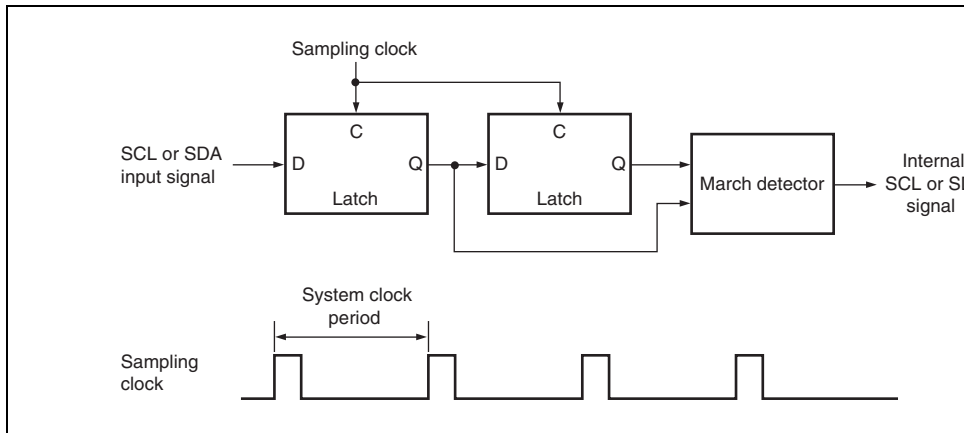


**Figure 15.15 Receive Mode Operation Timing**

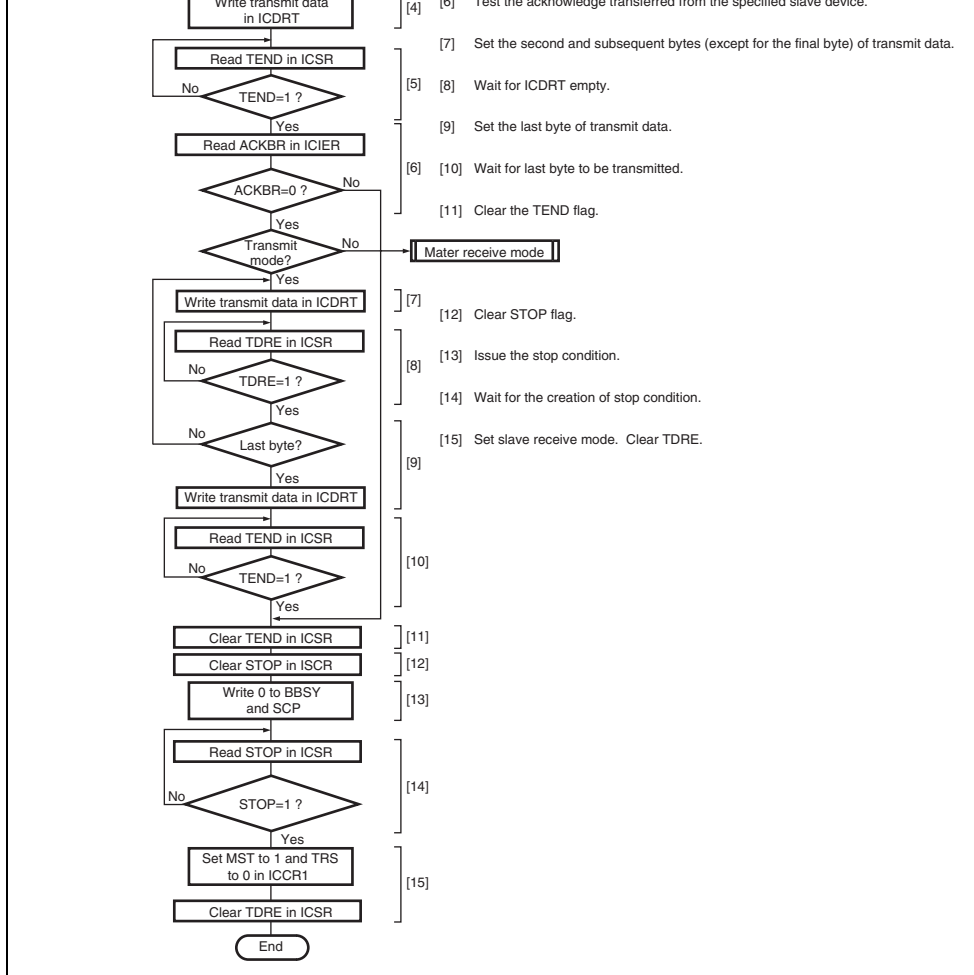
### 15.4.7 Noise Canceler

The logic levels at the SCL and SDA pins are routed through noise cancelers before being processed internally. Figure 15.16 shows a block diagram of the noise canceler circuit.

The noise canceler consists of two cascaded latches and a match detector. The SCL (or SDA) input signal is sampled on the system clock, but is not passed forward to the next circuit until the outputs of both latches agree. If they do not agree, the previous value is held.

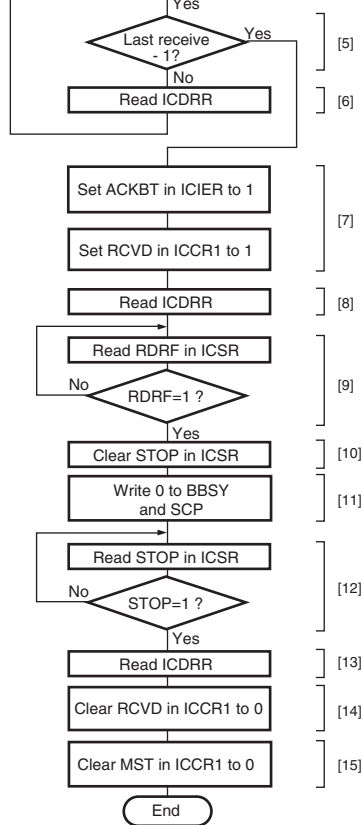


**Figure 15.16 Block Diagram of Noise Canceler**



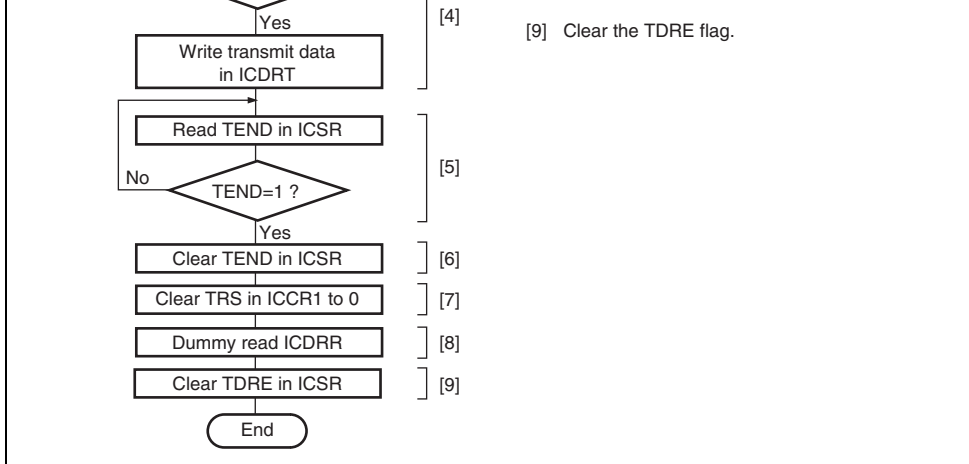
**Figure 15.17 Sample Flowchart for Master Transmit Mode**



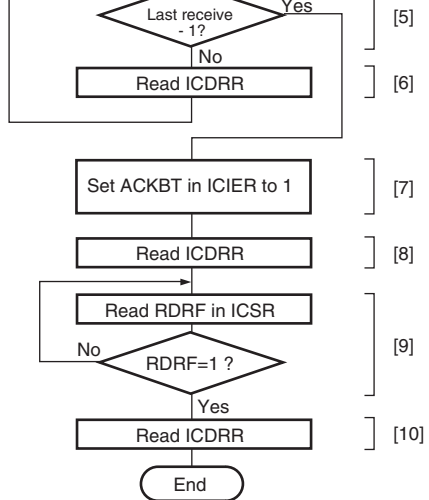


- [5] Wait for the last byte to be receive.
  - [6] Clear STOP flag.
  - [7] Set ACKBT in ICIER to 1.
  - [8] Set RCVD in ICCR1 to 1.
  - [9] Read ICDRR.
  - [10] Read RDRF in ICSR.
  - [11] Clear STOP in ICSR.
  - [12] Write 0 to BBSY and SCP.
  - [13] Read STOP in ICSR.
  - [14] Read ICDRR.
  - [15] Clear RCVD in ICCR1 to 0.
  - [16] Clear MST in ICCR1 to 0.
- Note: Do not activate an interrupt during the execution of steps [1] to [3].  
 Supplementary explanation: When one byte is received, steps [2] to [6] are skipped after step [1], before jumping to step [7].  
 The step [8] is dummy-read in ICDRR.

**Figure 15.18 Sample Flowchart for Master Receive Mode**



**Figure 15.19 Sample Flowchart for Slave Transmit Mode**



- [5] Read the (last byte - 1) of receive data.
- [6] Wait the last byte to be received.
- [7] Read for the last byte of receive data.
- [8] Read the (last byte - 1) of receive data.
- [9] Wait the last byte to be received.
- [10] Read for the last byte of receive data.

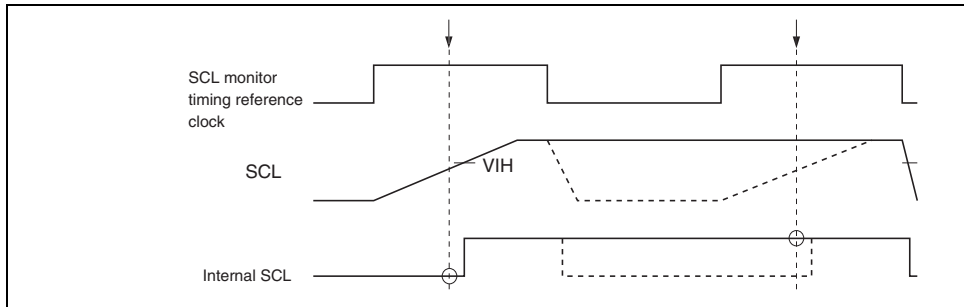
Supplementary explanation: When one byte is received, steps [2] to [6] are skipped after step [1], before jumping to step [7]. The step [8] is dummy-read in ICDRR.

**Figure 15.20 Sample Flowchart for Slave Receive Mode**

Transmit Data Empty	TXI	$(TDRE = 1) \cdot (TIE = 1)$	○	○
Transmit End	TEI	$(TEND = 1) \cdot (TEIE = 1)$	○	○
Receive Data Full	RXI	$(RDRF = 1) \cdot (RIE = 1)$	○	○
STOP Recognition	STPI	$(STOP = 1) \cdot (STIE = 1)$	○	×
NACK Receive	NAKI	$\{(NACKF = 1) + (AL = 1)\} \cdot (NAKIE = 1)$	○	×
Arbitration Lost/Overrun			○	○

When interrupt conditions described in table 15.3 are 1 and the I bit in CCR is 0, the CPU executes an interrupt exception processing. Interrupt sources should be cleared in the exception processing. TDRE and TEND are automatically cleared to 0 by writing the transmit data to ICDRT. RDRF are automatically cleared to 0 by reading ICDRR. TDRE is set to 1 again at the same time when transmit data is written to ICDRT. When TDRE is cleared to 0, then an amount of data of one byte may be transmitted.

Figure 15.21 shows the timing of the bit synchronous circuit and table 15.4 shows the time for monitoring SCL output changes from low to Hi-Z then SCL is monitored.



**Figure 15.21 The Timing of the Bit Synchronous Circuit**

**Table 15.4 Time for Monitoring SCL**

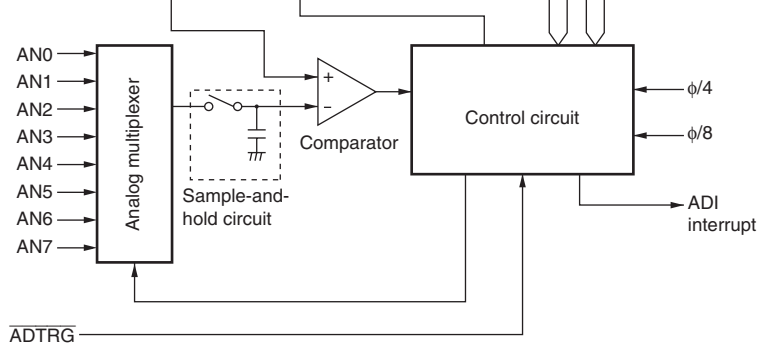
CKS3	CKS2	Time for Monitoring SCL
0	0	7.5 tcyc
	1	19.5 tcyc
1	0	17.5 tcyc
	1	41.5 tcyc

- Circuit, by the load of the SCL bus (load capacitance or pull-up resistance)
2. When the bit synchronous circuit is activated by extending the low period of eighth and ninth clocks, that is driven by the slave device

### **15.7.2 WAIT Setting in I<sup>2</sup>C Bus Mode Register (ICMR)**

If the WAIT bit is set to 1, and the SCL signal is driven low for two or more transfer clocks by the slave device at the eighth and ninth clocks, the high period of ninth clock may be shortened. To avoid this, set the WAIT bit in ICMR to 0.

- Conversion time: at least 3.5  $\mu$ s per channel (at 20-MHz operation)
- Two operating modes
  - Single mode: Single-channel A/D conversion
  - Scan mode: Continuous A/D conversion on 1 to 4 channels
- Four data registers
  - Conversion results are held in a data register for each channel
- Sample-and-hold function
- Two conversion start methods
  - Software
  - External trigger signal
- Interrupt request
  - An A/D conversion end interrupt request (ADI) can be generated



[Legend]

ADCR: A/D control register  
 ADCSR: A/D control/status register  
 ADDRA: A/D data register A  
 ADDR B: A/D data register B  
 ADDR C: A/D data register C  
 ADDR D: A/D data register D

**Figure 16.1 Block Diagram of A/D Converter**



Analog input pin 0	AN0	Input	Group 0 analog input
Analog input pin 1	AN1	Input	
Analog input pin 2	AN2	Input	
Analog input pin 3	AN3	Input	
Analog input pin 4	AN4	Input	Group 1 analog input
Analog input pin 5	AN5	Input	
Analog input pin 6	AN6	Input	
Analog input pin 7	AN7	Input	
A/D external trigger input pin	$\overline{\text{ADTRG}}$	Input	External trigger input for s A/D conversion

### 16.3.1 A/D Data Registers A to D (ADDRA to ADDR D)

There are four 16-bit read-only ADDR registers; ADDRA to ADDR D, used to store the result of the A/D conversion. The ADDR registers, which store a conversion result for each analog input channel, are shown in table 16.2.

The converted 10-bit data is stored in bits 15 to 6. The lower 6 bits are always read as 0.

The data bus width between the CPU and the A/D converter is 8 bits. The upper byte can be read directly from the CPU, however the lower byte should be read via a temporary register. The lower 6 bits of the temporary register contents are transferred from the ADDR when the upper byte data is read. Therefore byte access to ADDR should be done by reading the upper byte first then the lower byte. Word access is also possible. ADDR is initialized to H'0000.

**Table 16.2 Analog Input Channels and Corresponding ADDR Registers**

Analog Input Channel		A/D Data Register to Be Stored Results of A/D Conversion
Group 0	Group 1	
AN0	AN4	ADDRA
AN1	AN5	ADDRB
AN2	AN6	ADDRC
AN3	AN7	ADDRD

channels selected in scan mode

[Clearing condition]

- When 0 is written after reading ADF = 1

---

6	ADIE	0	R/W	A/D Interrupt Enable A/D conversion end interrupt request (ADI) is by ADF when this bit is set to 1
5	ADST	0	R/W	A/D Start Setting this bit to 1 starts A/D conversion. In mode, this bit is cleared to 0 automatically wh conversion on the specified channel is comple scan mode, conversion continues sequentiall specified channels until this bit is cleared to 0 software, a reset, or a transition to standby m
4	SCAN	0	R/W	Scan Mode Selects single mode or scan mode as the A/D conversion operating mode. 0: Single mode 1: Scan mode
3	CKS	0	R/W	Clock Select Selects the A/D conversions time. 0: Conversion time = 134 states (max.) 1: Conversion time = 70 states (max.) Clear the ADST bit to 0 before switching the c time.

---

101: AN5	101: AN4 and AN5
110: AN6	110: AN4 to AN6
111: AN7	111: AN4 to AN7

---

### 16.3.3 A/D Control Register (ADCR)

ADCR enables A/D conversion started by an external trigger signal.

Bit	Bit Name	Initial Value	R/W	Description
7	TRGE	0	R/W	<p>Trigger Enable</p> <p>A/D conversion is started at the falling edge and rising edge of the external trigger signal (<math>\overline{ADTF}</math>) when this bit is set to 1.</p> <p>The selection between the falling edge and rising edge of the external trigger pin (<math>\overline{ADTRG}</math>) conforms to WPEG5 bit in the interrupt edge select register (IEGR2)</p>
6 to 1	—	All 1	—	<p>Reserved</p> <p>These bits are always read as 1.</p>
0	—	0	R/W	<p>Reserved</p> <p>Do not set this bit to 1, though the bit is readable/writable.</p>

channel as follows.

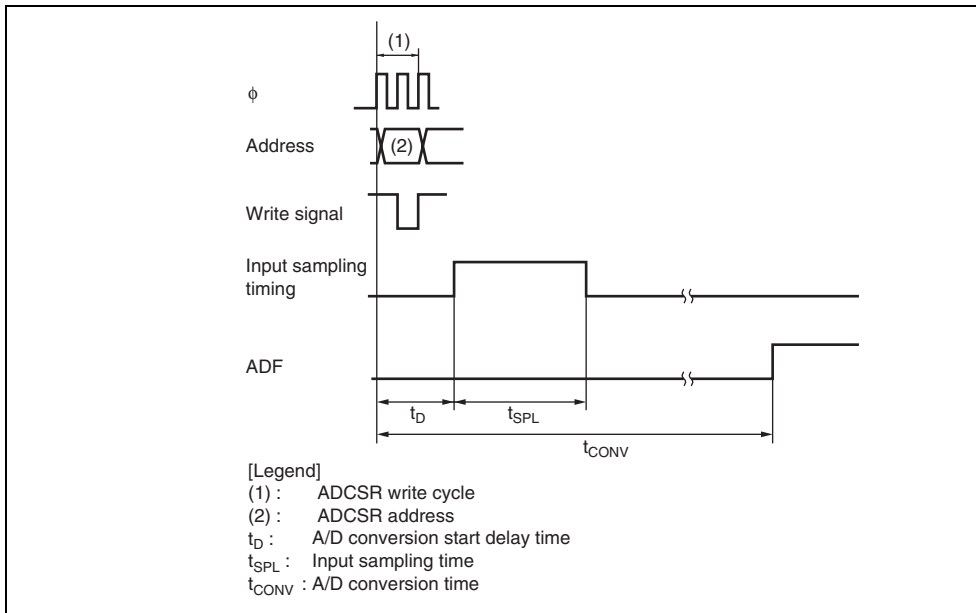
1. A/D conversion is started when the ADST bit in ADCSR is set to 1, according to software or external trigger input.
2. When A/D conversion is completed, the result is transferred to the corresponding A/D register of the channel.
3. On completion of conversion, the ADF bit in ADCSR is set to 1. If the ADIE bit is set to 1 at this time, an ADI interrupt request is generated.
4. The ADST bit remains set to 1 during A/D conversion. When A/D conversion ends, the ADST bit is automatically cleared to 0 and the A/D converter enters the wait state.

#### 16.4.2 Scan Mode

In scan mode, A/D conversion is performed sequentially for the analog input of the specified channels (four channels maximum) as follows:

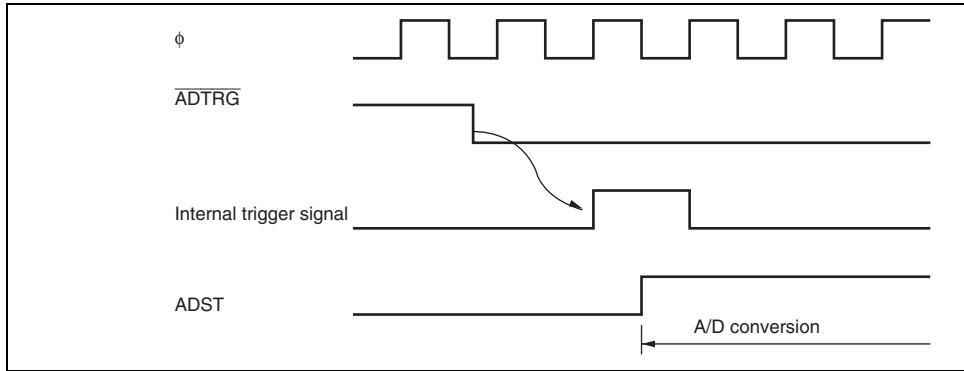
1. When the ADST bit in ADCSR is set to 1 by software or external trigger input, A/D conversion starts on the first channel in the group (AN0 when CH2 = 0, AN4 when CH2 = 1).
2. When A/D conversion for each channel is completed, the result is sequentially transferred to the A/D data register corresponding to each channel.
3. When conversion of all the selected channels is completed, the ADF flag in ADCSR is set to 1. If the ADIE bit is set to 1 at this time, an ADI interrupt request is generated. A/D conversion starts again on the first channel in the group.
4. The ADST bit is not automatically cleared to 0. Steps [2] and [3] are repeated as long as the ADST bit remains set to 1. When the ADST bit is cleared to 0, A/D conversion stops.

In scan mode, the values given in table 16.3 apply to the first conversion time. In the second subsequent conversions, the conversion time is 128 states (fixed) when CKS = 0 and 66 states (fixed) when CKS = 1.



**Figure 16.2 A/D Conversion Timing**

A/D conversion can also be started by an external trigger input. When the TRGE bit in ADSC is set to 1, external trigger input is enabled at the ADTRG pin. A falling edge at the ADTRG pin sets the ADST bit in ADCSR to 1, starting A/D conversion. Other operations, in both single and scan modes, are the same as when the bit ADST has been set to 1 by software. Figure 16.3 shows the timing.



**Figure 16.3 External Trigger Input Timing**

when the digital output changes from the minimum voltage value 0000000000 to 0000000001 (see figure 16.5).

- Full-scale error

The deviation of the analog input voltage value from the ideal A/D conversion characteristic when the digital output changes from 1111111110 to 1111111111 (see figure 16.5).

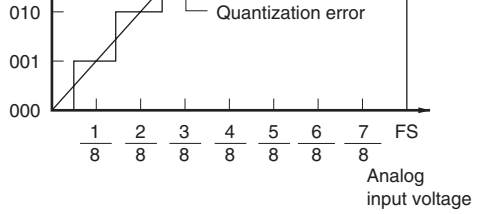
- Nonlinearity error

The deviation from the ideal A/D conversion characteristic as the voltage changes from 0 to full scale. This does not include the offset error, full-scale error, or quantization error.

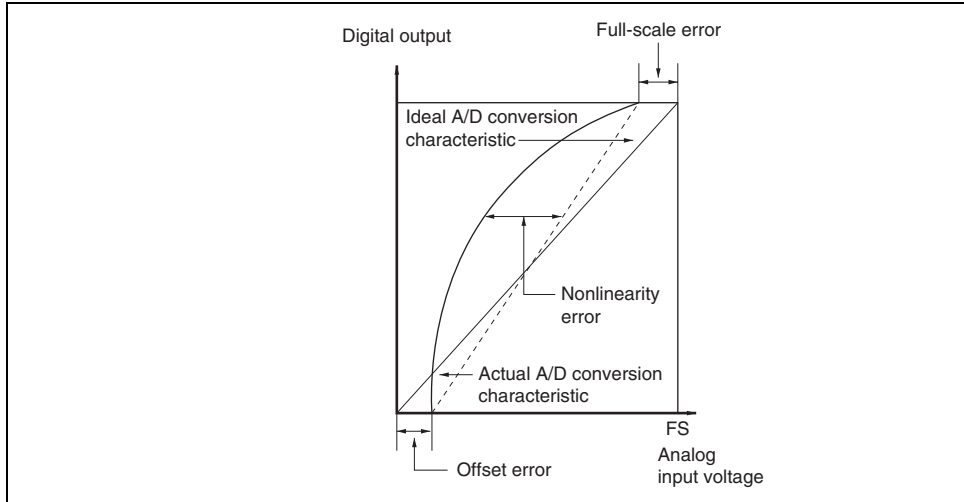
- Absolute accuracy

The deviation between the digital value and the analog input value. Includes offset error, full-scale error, quantization error, and nonlinearity error.





**Figure 16.4 A/D Conversion Accuracy Definitions (1)**



**Figure 16.5 A/D Conversion Accuracy Definitions (2)**

filter effect is obtained in this case, it may not be possible to follow an analog signal with a differential coefficient (e.g., 5 mV/ $\mu$ s or greater) (see figure 16.6). When converting a high-frequency analog signal or converting in scan mode, a low-impedance buffer should be inserted.

### 16.6.2 Influences on Absolute Accuracy

Adding capacitance results in coupling with GND, and therefore noise in GND may adversely affect absolute accuracy. Be sure to make the connection to an electrically stable GND.

Care is also required to ensure that filter circuits do not interfere with digital signals or antennas on the mounting board.

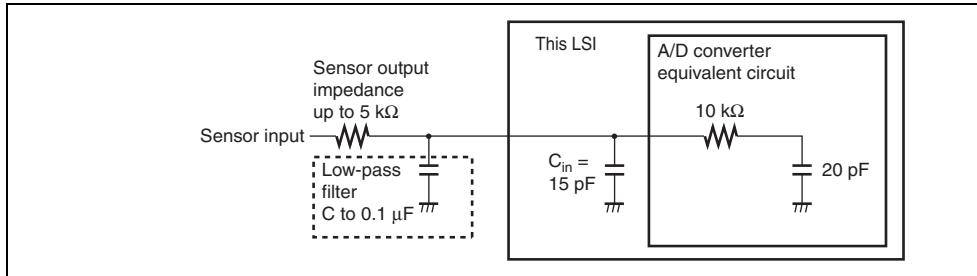
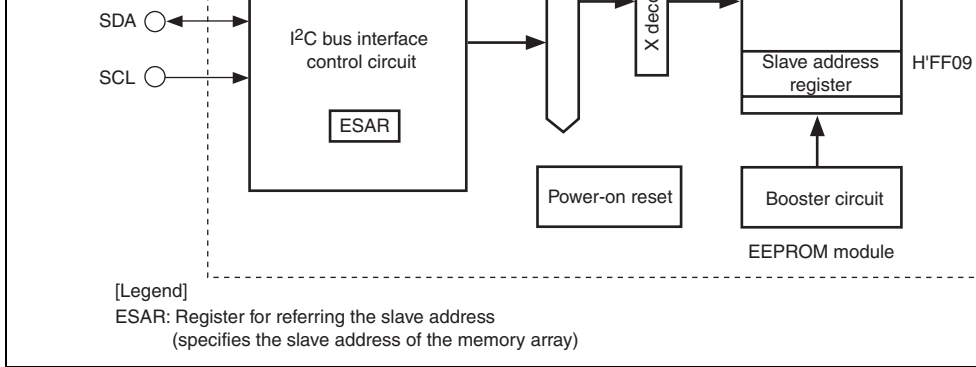


Figure 16.6 Analog Input Circuit Example

- Three reading methods:
  - Current address read
  - Random address read
  - Sequential read
- Acknowledge polling possible
- Write cycle time:
  - 10 ms (power supply voltage  $V_{cc} = 2.7\text{ V}$  or more)
- Write/Erase endurance:
  - $10^4$  cycles/byte (byte write mode),  $10^5$  cycles/page (page write mode)
- Data retention:
  - 10 years after the write cycle of  $10^4$  cycles (page write mode)
- Interface with the CPU
  - I<sup>2</sup>C bus interface (complies with the standard of Philips Corporation)
  - Device code 1010
  - Sleep address code can be changed (initial value: 000)
  - The I<sup>2</sup>C bus is open to the outside, so the EEPROM can be directly accessed from the



**Figure 17.1 Block Diagram of EEPROM**

pin is open-drain driven structure of the I<sup>2</sup>C. Proper resistor value for your system by considering V<sub>OL</sub>, I<sub>OL</sub> and the C<sub>IN</sub> pin capacitance in section 21.2.3, DC Characteristics and in section 21.2.3, AC Characteristics. Maximum clock frequency is 100 kHz.

---

Serial data pin	SDA	Input/Output	The SDA pin is bidirectional for serial data transfer. The SDA pin needs to be pulled up by resistor. The pin is open-drain driven structure. Use proper resistor value for your system by considering V <sub>OL</sub> , I <sub>OL</sub> and the C <sub>IN</sub> pin capacitance in section 21.2.3, DC Characteristics and in section 21.2.3, AC Characteristics. Except for a start condition and stop condition which will be discussed later, the to-low and low-to-high change of SDA input/output should be done during SCL low periods.
-----------------	-----	--------------	---

---

## 17.3 Register Description

The EEPROM has a following register.

- EEPROM key register (EKR)

### 17.3.1 EEPROM Key Register (EKR)

EKR is an 8-bit readable/writable register, which changes the slave address code written to the EEPROM. The slave address code is changed by writing H'5F in EKR and then writing H'00 to H'07 as an address code to the H'FF09 address in the EEPROM by the byte write command. EKR is initialized to H'FF.

## 17.4.2 Bus Format and Timing

The I<sup>2</sup>C bus format and the I<sup>2</sup>C bus timing follow section 15.4.1, I<sup>2</sup>C Bus Format. The bus specific for the EEPROM are the following two.

1. The EEPROM address is configured of two bytes, the write data is transferred in the upper address and lower address from each MSB side.
2. The write data is transmitted from the MSB side.

The bus format and bus timing of the EEPROM are shown in figure 17.2.

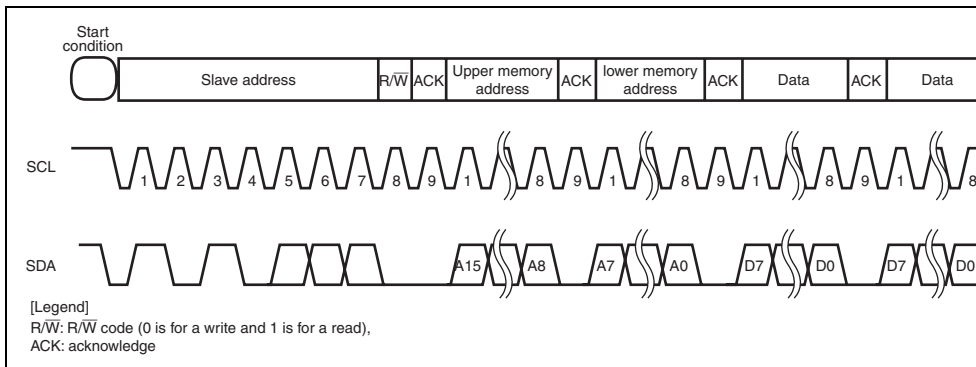


Figure 17.2 EEPROM Bus Format and Bus Timing

## 17.4.3 Start Condition

A high-to-low transition of the SDA input with the SCL input high is needed to generate condition for starting read, write operation.

All address data and serial data such as read data and write data are transmitted to and from the 8-bit unit. The acknowledgement is the signal that indicates that this 8-bit data is normally transmitted to and from.

In the write operation, EEPROM sends "0" to acknowledge in the ninth cycle after receiving data. In the read operation, EEPROM sends a read data following the acknowledgement of receiving the data. After sending read data, the EEPROM enters the bus open state. If the EEPROM receives "0" as an acknowledgement, it sends read data of the next address. If the EEPROM does not receive acknowledgement "0" and receives a following stop condition, the read operation and enters a standby mode. If the EEPROM receives neither acknowledgement "0" nor a stop condition, the EEPROM keeps bus open without sending read data.

#### 17.4.6 Slave Addressing

The EEPROM device receives a 7-bit slave address and a 1-bit  $\overline{R/\overline{W}}$  code following the start conditions. The EEPROM enables the chip for a read or a write operation with the slave address operation.

The slave address consists of a former 4-bit device code and latter 3-bit slave address as shown in table 17.2. The device code is used to distinguish device type and this LSI uses "1010" in the same manner as in a general-purpose EEPROM. The slave address code selects one out of all devices with device code 1010 (8 devices in maximum) which are connected to the bus. This means that the device is selected if the inputted slave address code received in the address of A2, A1, A0 is equal to the corresponding slave address reference register (ESAR).

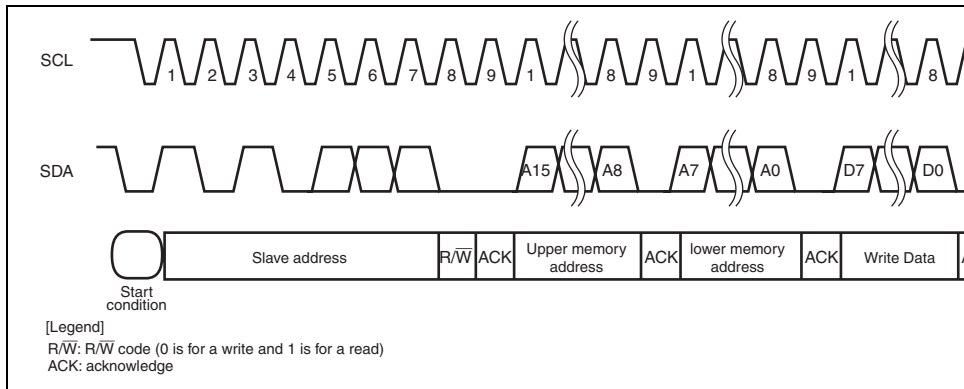
The slave address code is stored in the address H'FF09 in the EEPROM. It is transferred from the slave address register in the memory array during 10 ms after the reset is released. Access to the EEPROM is not allowed during transfer.

7	Device code D3	—	1	
6	Device code D2	—	0	
5	Device code D1	—	1	
4	Device code D0	—	0	
3	Slave address code A2	0	A2	The initial value can be changed
2	Slave address code A1	0	A1	The initial value can be changed
1	Slave address code A0	0	A0	The initial value can be changed



and receives a following 8-bit write data. After receipt of write data, the EEPROM enters an internally controlled write cycle and terminates receipt of SCL and SDA inputs until completion of the write cycle. The EEPROM returns to a standby mode after completing the write cycle.

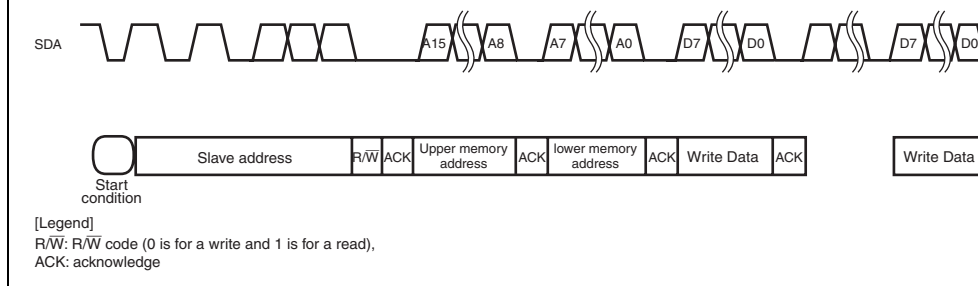
The byte write operation is shown in figure 17.3.



**Figure 17.3 Byte Write Operation**

## 2. Page Write

This LSI is capable of the page write operation which allows any number of bytes up to 16 to be written in a single write cycle. The write data is input in the same sequence as a single byte write in the order of a start condition, slave address + R/W code, memory address (n), write data (Dn) with every ninth bit acknowledgement "0" output. The EEPROM enters a page write operation if the EEPROM receives more write data (Dn+1) is input instead of receiving a stop condition after receiving the write data (Dn). LSB 3 bits (A2 to A0) of the EEPROM address are automatically incremented to be the (n+1) address upon receiving the next write data (Dn+1). Thus the write data can be received sequentially.



**Figure 17.4 Page Write Operation**

### 17.4.8 Acknowledge Polling

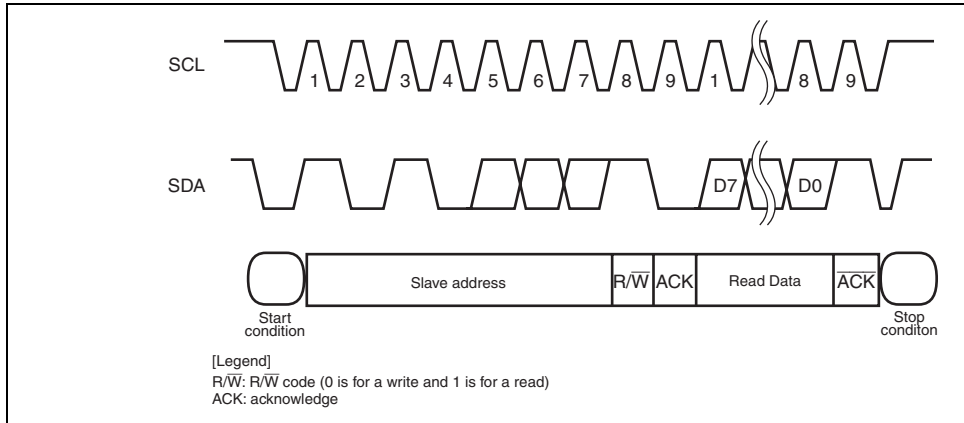
Acknowledge polling feature is used to show if the EEPROM is in an internally-timed write cycle or not. This feature is initiated by the input of the 8-bit slave address + R/W code following a start condition during an internally-timed write cycle. Acknowledge polling will operate with the R/W code = "0". The ninth acknowledgement judges if the EEPROM is in an internally-timed write cycle or not. Acknowledgement "1" shows the EEPROM is in an internally-timed write cycle and acknowledgement "0" shows the internally-timed write cycle has been completed. The acknowledge polling starts to function after a write data is input, i.e., when the stop condition is input.

the EEPROM outputs the 1-byte data of the (n+1) address from the most significant following acknowledgement "0". If the EEPROM receives in the order of acknowledgement "1" and a following stop condition, the EEPROM stops the read operation and is turned into standby state.

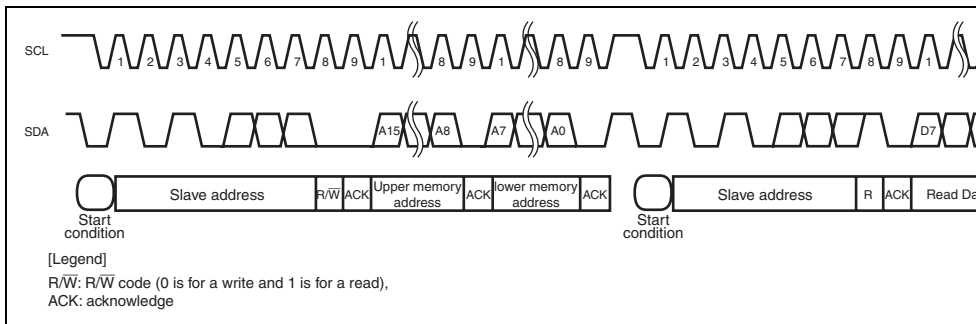
In case the EEPROM has accessed the last address H'01FF at previous read operation, the current address will roll over and returns to zero address. In case the EEPROM has accessed the last address of the page at previous write operation, the current address will roll over and returns to the first address in the same page.

The current address is valid while power is on. The current address after power on is undefined. After power is turned on, define the address by the random address read operation described below is necessary.

The current address read operation is shown in figure 17.5.



**Figure 17.5 Current Address Read Operation**



**Figure 17.6 Random Address Read Operation**

### 3. Sequential Read

This is a mode to read the data sequentially. Data is sequential read by either a current read or a random address read. If the EEPROM receives acknowledgement "0" after read data is output, the read address is incremented and the next 1-byte read data are output. Data is output sequentially by incrementing addresses as long as the EEPROM receives acknowledgement "0" after the data is output. The address will roll over and returns a zero if it reaches the last address H'01FF. The sequential read can be continued after a random address read. The sequential read is terminated if the EEPROM receives acknowledgement "1" and a stop condition in the following stop condition as the same manner as in the random address read.

The condition of a sequential read when the current address read is used is shown in Figure 17.7.

[Legend]

R/W: R/W code (0 is for a write and 1 is for a read)

ACK: acknowledge

## Figure 17.7 Sequential Read Operation (when current address read is use

turned on from the ground level ( $V_{SS}$ ).

4.  $V_{CC}$  turn on speed should be longer than 10  $\mu$ s.

### **17.5.2 Write/Erase Endurance**

The endurance is  $10^5$  cycles/page (1% cumulative failure rate) in case of page programming and  $10^4$  cycles/byte in case of byte programming. The data retention time is more than 10 years if the device is page-programmed less than  $10^4$  cycles.

### **17.5.3 Noise Suppression Time**

This EEPROM has a noise suppression function at SCL and SDA inputs, that cuts noise of width less than 50 ns. Be careful not to allow noise of width more than 50 ns because the noise of width more than 50 ns is recognized as an active pulse.

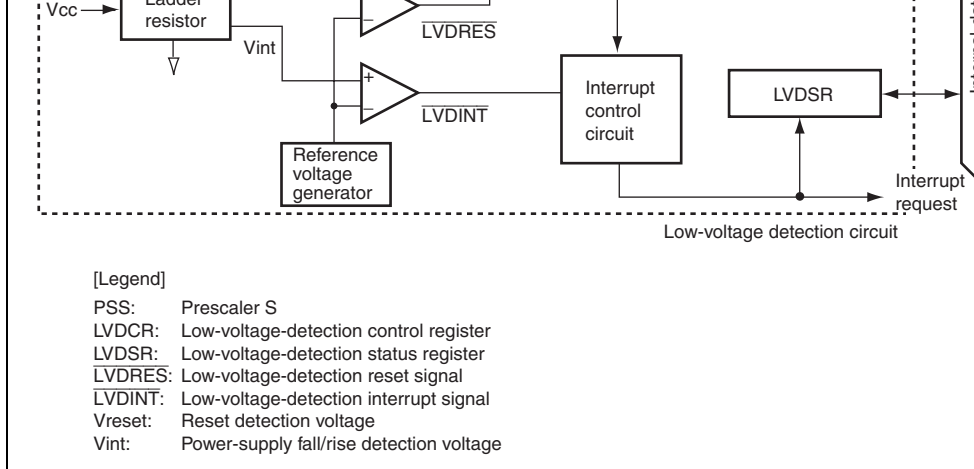
power supply voltage rises again.

Even if the power supply voltage falls, the unstable state when the power supply voltage is below the guaranteed operating voltage can be removed by entering standby mode when the power supply voltage rises again. Thus, system operation can be improved. If the power supply voltage falls more, the reset state is automatically entered. If the power supply voltage rises again, the reset state is held for a specified period, then a standby mode is automatically entered.

Figure 18.1 is a block diagram of the power-on reset circuit and the low-voltage detection circuit.

## 18.1 Features

- Power-on reset circuit
    - Uses an external capacitor to generate an internal reset signal when power is first supplied.
  - Low-voltage detection circuit
    - LVDR: Monitors the power-supply voltage, and generates an internal reset signal when the voltage falls below a specified value.
    - LVDI: Monitors the power-supply voltage, and generates an interrupt when the voltage falls below or rises above respective specified values.
- Two pairs of detection levels for reset generation voltage are available: when only the LVDR circuit is used, or when the LVDI and LVDR circuits are both used.



**Figure 18.1 Block Diagram of Power-On Reset Circuit and Low-Voltage Detection**

## 18.2 Register Descriptions

The low-voltage detection circuit has the following registers.

- Low-voltage-detection control register (LVDCR)
- Low-voltage-detection status register (LVDSR)

### 18.2.1 Low-Voltage-Detection Control Register (LVDCR)

LVDCR is used to enable or disable the low-voltage detection circuit, set the detection level, enable or disable the LVDR function, and enable or disable generation of an interrupt when the power-supply voltage rises above or falls below the respective levels.



3	LVDSEL	0*	R/W	<p>LVDR Detection Level Select</p> <p>0: Reset detection voltage is 2.3 V (typ.)</p> <p>1: Reset detection voltage is 3.6 V (typ.)</p> <p>When the falling or rising voltage detection interrupt is used, reset detection voltage of 2.3 V (typ.) should be used. When only a reset detection interrupt is used, reset detection voltage of 3.6 V (typ.) should be used.</p>
2	LVDRE	0*	R/W	<p>LVDR Enable</p> <p>0: Disables the LVDR function</p> <p>1: Enables the LVDR function</p>
1	LVDDE	0	R/W	<p>Voltage-Fall-Interrupt Enable</p> <p>0: Interrupt on the power-supply voltage falling at the selected detection level disabled</p> <p>1: Interrupt on the power-supply voltage falling at the selected detection level enabled</p>
0	LVDUE	0	R/W	<p>Voltage-Rise-Interrupt Enable</p> <p>0: Interrupt on the power-supply voltage rising at the selected detection level disabled</p> <p>1: Interrupt on the power-supply voltage rising at the selected detection level enabled</p>

Note: \* Not initialized by LVDR but initialized by a power-on reset or WDT reset.

Legend: \*: means invalid.

### 18.2.2 Low-Voltage-Detection Status Register (LVDSR)

LVDSR indicates whether the power-supply voltage falls below or rises above the respective specified values.

Bit	Bit Name	Initial Value	R/W	Description
7 to 2	—	All 1	—	Reserved These bits are always read as 1, and cannot be
1	LVDDF	0*	R/W	LVD Power-Supply Voltage Fall Flag [Setting condition] When the power-supply voltage falls below $V_{int}$ (= 3.7 V) [Clearing condition] Writing 0 to this bit after reading it as 1
0	LVDFUF	0*	R/W	LVD Power-Supply Voltage Rise Flag [Setting condition] When the power supply voltage falls below $V_{int}$ and the LVDFUE bit in LVDFCR is set to 1, then rises above $V_{int}$ (U) (typ. = 4.0 V) before falling below $V_{reset1}$ (typ. = 3.7 V) [Clearing condition] Writing 0 to this bit after reading it as 1

Note: \* Initialized by LVDR.

prevent the incorrect operation of the chip by noise on the  $\overline{\text{RES}}$  pin.

To achieve stable operation of this LSI, the power supply needs to rise to its full level and within the specified time. The maximum time required for the power supply to rise and power has been supplied ( $t_{\text{PWON}}$ ) is determined by the oscillation frequency ( $f_{\text{OSC}}$ ) and capacitor which is connected to  $\overline{\text{RES}}$  pin ( $C_{\overline{\text{RES}}}$ ). If  $t_{\text{PWON}}$  means the time required to reach 90 % of supply voltage, the power supply circuit should be designed to satisfy the following formula.

$$t_{\text{PWON}} \text{ (ms)} \leq 90 \times C_{\overline{\text{RES}}} \text{ (\mu F)} + 162/f_{\text{OSC}} \text{ (MHz)}$$

$$(t_{\text{PWON}} \leq 3000 \text{ ms, } C_{\overline{\text{RES}}} \geq 0.22 \text{ }\mu\text{F, and } f_{\text{OSC}} = 10 \text{ in 2-MHz to 10-MHz operation)}$$

Note that the power supply voltage ( $V_{\text{CC}}$ ) must fall below  $V_{\text{por}} = 100 \text{ mV}$  and rise after the  $\overline{\text{RES}}$  pin is removed. To remove charge on the  $\overline{\text{RES}}$  pin, it is recommended that the capacitor should be placed near  $V_{\text{CC}}$ . If the power supply voltage ( $V_{\text{CC}}$ ) rises from the point above, power-on reset may not occur.

**Figure 18.2 Operational Timing of Power-On Reset Circuit**

### 18.3.2 Low-Voltage Detection Circuit

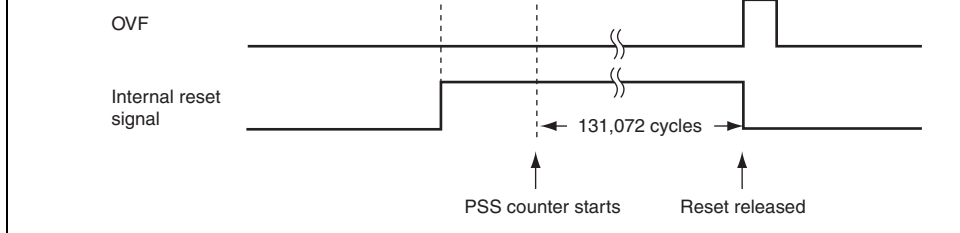
#### LVDR (Reset by Low Voltage Detect) Circuit:

Figure 18.3 shows the timing of the LVDR function. The LVDR enters the module-stand after a power-on reset is canceled. To operate the LVDR, set the LVDE bit in LVDCR to 1 for 50  $\mu\text{s}$  ( $t_{\text{LVDRON}}$ ) until the reference voltage and the low-voltage-detection power supply has stabilized by a software timer, etc., then set the LVDRE bit in LVDCR to 1. After that, the settings of ports must be made. To cancel the low-voltage detection circuit, first the LVDRE bit should be cleared to 0 and then the LVDE bit should be cleared to 0. The LVDE and LVDRE bits must not be cleared to 0 simultaneously because incorrect operation may occur.

When the power-supply voltage falls below the Vreset voltage (typ. = 2.3 V or 3.6 V), the LVDR clears the LVDRES signal to 0, and resets the prescaler S. The low-voltage detection reset signal remains in place until a power-on reset is generated. When the power-supply voltage rises above the Vreset voltage again, the prescaler S starts counting. It counts 131,072 clock ( $\phi$ ) cycles and then releases the internal reset signal. In this case, the LVDE, LVDSEL, and LVDRE bits in LVDCR are not initialized.

Note that if the power supply voltage ( $V_{\text{CC}}$ ) falls below  $V_{\text{LVDRmin}} = 1.0 \text{ V}$  and then rises from this point, the low-voltage detection reset may not occur.

If the power supply voltage ( $V_{\text{CC}}$ ) falls below  $V_{\text{POR}} = 100 \text{ mV}$ , a power-on reset occurs.



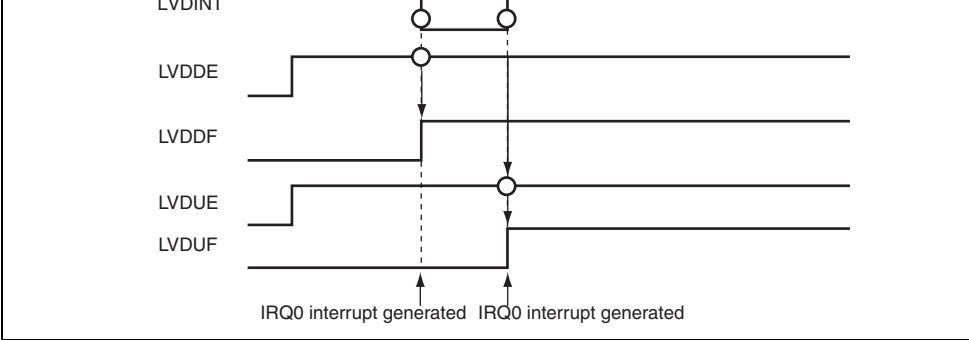
**Figure 18.3 Operational Timing of LVDR Circuit**

**LVDI (Interrupt by Low Voltage Detect) Circuit:**

Figure 18.4 shows the timing of LVDI functions. The LVDI enters the module-standby mode when a power-on reset is canceled. To operate the LVDI, set the LVDE bit in LVDCR to 1, wait  $t_{LV\text{DON}}$  until the reference voltage and the low-voltage-detection power supply have stabilized by a software timer, etc., then set the LVDDE and LVDUE bits in LVDCR to 1. After the output settings of ports must be made. To cancel the low-voltage detection circuit, first the LVDDE and LVDUE bits should all be cleared to 0 and then the LVDE bit should be cleared. The LVDE bit must not be cleared to 0 at the same timing as the LVDDE and LVDUE bits because incorrect operation may occur.

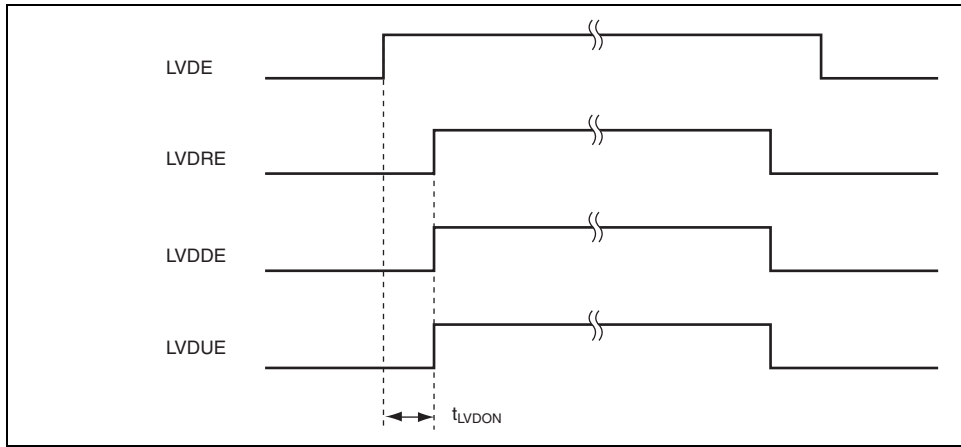
When the power-supply voltage falls below  $V_{\text{int}}(D)$  (typ. = 3.7 V) voltage, the LVDI circuit sets the  $\overline{\text{LVDINT}}$  signal to 0 and the LVDDF bit in LVDSR is set to 1. If the LVDDE bit is 1 at this time, an IRQ0 interrupt request is simultaneously generated. In this case, the necessary data must be saved in the external EEPROM, etc, and a transition must be made to standby mode or sleep mode. Until this processing is completed, the power supply voltage must be higher than the minimum limit of the guaranteed operating voltage.

When the power-supply voltage does not fall below  $V_{\text{reset1}}$  (typ. = 2.3 V) voltage but rises above  $V_{\text{int}}(U)$  (typ. = 4.0 V) voltage, the LVDI sets the  $\overline{\text{LVDINT}}$  signal to 1. If the LVDUE bit is 1 at this time, an IRQ0 interrupt request is simultaneously generated.



**Figure 18.4 Operational Timing of LVDI Circuit**

LVDUE bits to 0. Then clear the LVDE bit to 0. The LVDE bit must not be cleared at the same timing as the LVDRE, LVDDE, and LVDUE bits because incorrect operation



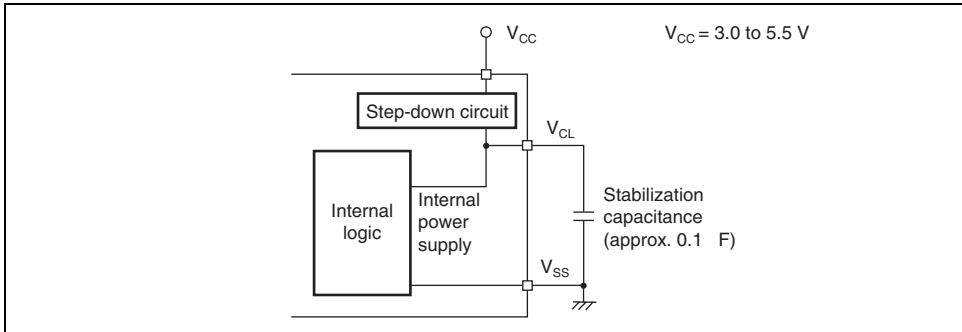
**Figure 18.5 Timing for Operation/Release of Low-Voltage Detection Circuit**



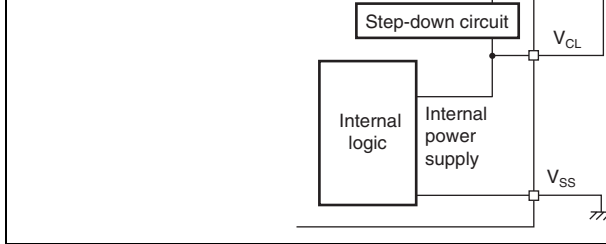


## 19.1 When Using Internal Power Supply Step-Down Circuit

Connect the external power supply to the  $V_{CC}$  pin, and connect a capacitance of approximately  $\mu\text{F}$  between  $V_{CL}$  and  $V_{SS}$ , as shown in figure 19.1. The internal step-down circuit is made simply by adding this external circuit. In the external circuit interface, the external power voltage connected to  $V_{CC}$  and the GND potential connected to  $V_{SS}$  are the reference levels. For example, for port input/output levels, the  $V_{CC}$  level is the reference for the high level, and the  $V_{SS}$  level is that for the low level. The A/D converter analog power supply is not affected by the internal step-down circuit.



**Figure 19.1 Power Supply Connection when Internal Step-Down Circuit is Used**



**Figure 19.2 Power Supply Connection when Internal Step-Down Circuit is Not**

Do not attempt to access reserved addresses.

- When the address is 16-bit wide, the address of the upper byte is given in the list.
- Registers are classified by functional modules.
- The data bus width is indicated.
- The number of access states is indicated.

## 2. Register bits

- Bit configurations of the registers are described in the same order as the register address.
- Reserved bits are indicated by — in the bit name column.
- When registers consist of 16 bits, bits are described from the MSB side.

## 3. Register states in each operating mode

- Register states are described in the same order as the register addresses.
- The register states described here are for the basic operating modes. If there is a special mode for an on-chip peripheral module, refer to the section on that on-chip peripheral module.

—	—	—	H'F000 to H'F72F	—	—
Low-voltage detection control register	LVDCR	8	H'F730	LVDC* <sup>1</sup>	8
Low-voltage detection status register	LVDSR	8	H'F731	LVDC* <sup>1</sup>	8
—	—	—	H'F732 to H'F747	—	—
I <sup>2</sup> C bus control register 1	ICCR1	8	H'F748	IIC2	8
I <sup>2</sup> C bus control register 2	ICCR2	8	H'F749	IIC2	8
I <sup>2</sup> C bus mode register	ICMR	8	H'F74A	IIC2	8
I <sup>2</sup> C bus interrupt enable register	ICIER	8	H'F74B	IIC2	8
I <sup>2</sup> C bus status register	ICSR	8	H'F74C	IIC2	8
Slave address register	SAR	8	H'F74D	IIC2	8
I <sup>2</sup> C bus transmit data register	ICDRT	8	H'F74E	IIC2	8
I <sup>2</sup> C bus receive data register	ICDRR	8	H'F74F	IIC2	8
—	—	—	H'F750 to H'FF7F	—	—
Timer mode register W	TMRW	8	H'FF80	Timer W	8
Timer control register W	TCRW	8	H'FF81	Timer W	8
Timer interrupt enable register W	TIERW	8	H'FF82	Timer W	8
Timer status register W	TSRW	8	H'FF83	Timer W	8
Timer I/O control register 0	TIOR0	8	H'FF84	Timer W	8
Timer I/O control register 1	TIOR1	8	H'FF85	Timer W	8
Timer counter	TCNT	16	H'FF86	Timer W	16* <sup>2</sup>
General register A	GRA	16	H'FF88	Timer W	16* <sup>2</sup>

—	—	—	H'FF94 to H'FF9A	—	—
Flash memory enable register	FENR	8	H'FF9B	ROM	8
—	—	—	H'FF9C to H'FF9F	—	—
Timer control register V0	TCRV0	8	H'FFA0	Timer V	8
Timer control/status register V	TCSRV	8	H'FFA1	Timer V	8
Timer constant register A	TCORA	8	H'FFA2	Timer V	8
Timer constant register B	TCORB	8	H'FFA3	Timer V	8
Timer counter V	TCNTV	8	H'FFA4	Timer V	8
Timer control register V1	TCRV1	8	H'FFA5	Timer V	8
Timer mode register A	TMA	8	H'FFA6	Timer A	8
Timer counter A	TCA	8	H'FFA7	Timer A	8
Serial mode register	SMR	8	H'FFA8	SCI3	8
Bit rate register	BRR	8	H'FFA9	SCI3	8
Serial control register 3	SCR3	8	H'FFAA	SCI3	8
Transmit data register	TDR	8	H'FFAB	SCI3	8
Serial status register	SSR	8	H'FFAC	SCI3	8
Receive data register	RDR	8	H'FFAD	SCI3	8
—	—	—	H'FFAE, H'FFAF	—	—
A/D data register A	ADDRA	16	H'FFB0	A/D converter	8

A/D control register	ADCR	8	H'FFB9	A/D converter	8
—	—	—	H'FFBA to H'FFBF	—	—
Timer control/status register WD	TCSRWD	8	H'FFC0	WDT* <sup>3</sup>	8
Timer counter WD	TCWD	8	H'FFC1	WDT* <sup>3</sup>	8
Timer mode register WD	TMWD	8	H'FFC2	WDT* <sup>3</sup>	8
—	—	—	H'FFC3	—	—
—	—	—	H'FFC4 to H'FFC7	—	—
Address break control register	ABRKCR	8	H'FFC8	Address break	8
Address break status register	ABRKSR	8	H'FFC9	Address break	8
Break address register H	BARH	8	H'FFCA	Address break	8
Break address register L	BARL	8	H'FFCB	Address break	8
Break data register H	BDRH	8	H'FFCC	Address break	8
Break data register L	BDRL	8	H'FFCD	Address break	8
—	—	—	H'FFCE, H'FFCF	—	—

			H'FFD7		
Port data register 5	PDR5	8	H'FFD8	I/O port	8
—	—	—	H'FFD9	I/O port	—
Port data register 7	PDR7	8	H'FFDA	I/O port	8
Port data register 8	PDR8	8	H'FFDB	I/O port	8
—	—	—	H'FFDC	I/O port	—
Port data register B	PDRB	8	H'FFDD	I/O port	8
—	—	—	H'FFDE, H'FFDF	I/O port	—
Port mode register 1	PMR1	8	H'FFE0	I/O port	8
Port mode register 5	PMR5	8	H'FFE1	I/O port	8
—	—	—	H'FFE2, H'FFE3	I/O port	—
Port control register 1	PCR1	8	H'FFE4	I/O port	8
Port control register 2	PCR2	8	H'FFE5	I/O port	8
—	—	—	H'FFE6, H'FFE7	I/O port	—
Port control register 5	PCR5	8	H'FFE8	I/O port	8
—	—	—	H'FFE9	I/O port	—
Port control register 7	PCR7	8	H'FFEA	I/O port	8
Port control register 8	PCR8	8	H'FFEB	I/O port	8
—	—	—	H'FFEC to H'FFEF	I/O port	—

—	—	—	H'FFE7	I/O port	—
Wake-up interrupt flag register	IWPR	8	H'FFF8	Interrupts	8
Module standby control register 1	MSTCR1	8	H'FFF9	Power-down	8
—	—	—	H'FFFA to H'FFFF	—	—

- EEPROM

Register Name	Abbreviation	Bit No	Address	Module Name	Data Bus Width
EEPROM slave address register	—	8	H'FF09	EEPROM	—
EEPROM key register	EKR	8	H'FF10	EEPROM	—

Notes: 1. LVDC: Low-voltage detection circuits (optional)  
2. Only word access can be used.  
3. WDT: Watchdog timer



ICCR1	ICE	RCVD	MST	TRS	CKS3	CKS2	CKS1	CKS0	II
ICCR2	BBSY	SCP	SDAO	SDAOP	SCKO	—	IICRST	—	
ICMR	MLS	WAIT	—	—	BCWP	BC2	BC1	BC0	
ICIER	TIE	TEIE	RIE	NAKIE	STIE	ACKE	ACKBR	ACKBT	
ICSR	TDRE	TEND	RDRF	NACKF	STOP	AL/OVE	AAS	ADZ	
SAR	SVA6	SVA5	SVA4	SVA3	SVA2	SVA1	SVA0	FS	
ICDRT	ICDRT7	ICDRT6	ICDRT5	ICDRT4	ICDRT3	ICDRT2	ICDRT1	ICDRT0	
ICDRR	ICDRR7	ICDRR6	ICDRR5	ICDRR4	ICDRR3	ICDRR2	ICDRR1	ICDRR0	
—	—	—	—	—	—	—	—	—	—
TMRW	CTS	—	BUFEB	BUFEA	—	PWMD	PWMC	PWMB	T
TCRW	CCLR	CKS2	CKS1	CKS0	TOD	TOC	TOB	TOA	
TIERW	OVIE	—	—	—	IMIED	IMIEC	IMIEB	IMIEA	
TSRW	OVF	—	—	—	IMFD	IMFC	IMFB	IMFA	
TIOR0	—	IOB2	IOB1	IOB0	—	IOA2	IOA1	IOA0	
TIOR1	—	IOD2	IOD1	IOD0	—	IOC2	IOC1	IOC0	
TCNT	TCNT15	TCNT14	TCNT13	TCNT12	TCNT11	TCNT10	TCNT9	TCNT8	
	TCNT7	TCNT6	TCNT5	TCNT4	TCNT3	TCNT2	TCNT1	TCNT0	
GRA	GRA15	GRA14	GRA13	GRA12	GRA11	GRA10	GRA9	GRA8	
	GRA7	GRA6	GRA5	GRA4	GRA3	GRA2	GRA1	GRA0	
GRB	GRB15	GRB14	GRB13	GRB12	GRB11	GRB10	GRB9	GRB8	
	GRB7	GRB6	GRB5	GRB4	GRB3	GRB2	GRB1	GRB0	
GRC	GRC15	GRC14	GRC13	GRC12	GRC11	GRC10	GRC9	GRC8	
	GRC7	GRC6	GRC5	GRC4	GRC3	GRC2	GRC1	GRC0	
GRD	GRD15	GRD14	GRD13	GRD12	GRD11	GRD10	GRD9	GRD8	
	GRD7	GRD6	GRD5	GRD4	GRD3	GRD2	GRD1	GRD0	

TCORB	TCORB7	TCORB6	TCORB5	TCORB4	TCORB3	TCORB2	TCORB1	TCORB0	
TCNTV	TCNTV7	TCNTV6	TCNTV5	TCNTV4	TCNTV3	TCNTV2	TCNTV1	TCNTV0	
TCRV1	—	—	—	TVEG1	TVEG0	TRGE	—	ICKS0	
TMA	TMA7	TMA6	TMA5	—	TMA3	TMA2	TMA1	TMA0	Tir
TCA	TCA7	TCA6	TCA5	TCA4	TCA3	TCA2	TCA1	TCA0	
SMR	COM	CHR	PE	PM	STOP	MP	CKS1	CKS0	SC
BRR	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0	
SCR3	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	
TDR	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0	
SSR	TDRE	RDRF	OER	FER	PER	TEND	MPBR	MPBT	
RDR	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0	
ADDRA	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	A/
	AD1	AD0	—	—	—	—	—	—	co
ADDRB	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADDRC	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADDRD	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADCSR	ADF	ADIE	ADST	SCAN	CKS	CH2	CH1	CH0	
ADCR	TRGE	—	—	—	—	—	—	—	
—	—	—	—	—	—	—	—	—	—
TCSRWD	B6WI	TCWE	B4WI	TCSRWE	B2WI	WDON	B0WI	WRST	WI
TCWD	TCWD7	TCWD6	TCWD5	TCWD4	TCWD3	TCWD2	TCWD1	TCWD0	

—	—	—	—	—	—	—	—	—	—
PUCR1	PUCR17	PUCR16	PUCR15	PUCR14	—	PUCR12	PUCR11	PUCR10	W
PUCR5	—	—	PUCR55	PUCR54	PUCR53	PUCR52	PUCR51	PUCR50	
PDR1	P17	P16	P15	P14	—	P12	P11	P10	
PDR2	—	—	—	—	—	P22	P21	P20	
PDR5	P57* <sup>3</sup>	P56* <sup>3</sup>	P55	P54	P53	P52	P51	P50	
PDR7	—	P76	P75	P74	—	—	—	—	
PDR8	P87	P86	P85	P84	P83	P82	P81	P80	
PDRB	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	
PMR1	IRQ3	IRQ2	IRQ1	IRQ0	—	—	TXD	TMOW	
PMR5	—	—	WKP5	WKP4	WKP3	WKP2	WKP1	WKPO	
PCR1	PCR17	PCR16	PCR15	PCR14	—	PCR12	PCR11	PCR10	
PCR2	—	—	—	—	—	PCR22	PCR21	PCR20	
PCR5	PCR57* <sup>3</sup>	PCR56* <sup>3</sup>	PCR55	PCR54	PCR53	PCR52	PCR51	PCR50	
PCR7	—	PCR76	PCR75	PCR74	—	—	—	—	
PCR8	PCR87	PCR86	PCR85	PCR84	PCR83	PCR82	PCR81	PCR80	
SYSCR1	SSBY	STS2	STS1	STS0	NESEL	—	—	—	P
SYSCR2	SMSSEL	LSON	DTON	MA2	MA1	MA0	SA1	SA0	
IEGR1	NMIEG	—	—	—	IEG3	IEG2	IEG1	IEG0	Ir
IEGR2	—	—	WPEG5	WPEG4	WPEG3	WPEG2	WPEG1	WPEG0	
IENR1	IENDT	IENTA	IENWP	—	IEN3	IEN2	IEN1	IEN0	
IRR1	IRRDT	IRRRTA	—	—	IRRI3	IRRI2	IRRI1	IRRI0	
IWPR	—	—	IWPF5	IWPF4	IWPF3	IWPF2	IWPF1	IWPF0	
MSTCR1	—	MSTIIC	MSTS3	MSTAD	MSTWD	MSTTW	MSTTV	MSTTA	P
—	—	—	—	—	—	—	—	—	—



ICSR	Initialized	—	—	—	—	—	
SAR	Initialized	—	—	—	—	—	
ICDRT	Initialized	—	—	—	—	—	
ICDRR	Initialized	—	—	—	—	—	
TMRW	Initialized	—	—	—	—	—	Timer
TCRW	Initialized	—	—	—	—	—	
TIERW	Initialized	—	—	—	—	—	
TSRW	Initialized	—	—	—	—	—	
TIOR0	Initialized	—	—	—	—	—	
TIOR1	Initialized	—	—	—	—	—	
TCNT	Initialized	—	—	—	—	—	
GRA	Initialized	—	—	—	—	—	
GRB	Initialized	—	—	—	—	—	
GRC	Initialized	—	—	—	—	—	
GRD	Initialized	—	—	—	—	—	
FLMCR1	Initialized	—	—	Initialized	Initialized	Initialized	ROM
FLMCR2	Initialized	—	—	—	—	—	
FLPWCR	Initialized	—	—	—	—	—	
EBR1	Initialized	—	—	Initialized	Initialized	Initialized	
FENR	Initialized	—	—	—	—	—	
TCRV0	Initialized	—	—	Initialized	Initialized	Initialized	Timer
TCSRv	Initialized	—	—	Initialized	Initialized	Initialized	
TCORA	Initialized	—	—	Initialized	Initialized	Initialized	
TCORB	Initialized	—	—	Initialized	Initialized	Initialized	

SSR	Initialized	—	—	Initialized	Initialized	Initialized	
RDR	Initialized	—	—	Initialized	Initialized	Initialized	
ADDRA	Initialized	—	—	Initialized	Initialized	Initialized	A/D con
ADDRB	Initialized	—	—	Initialized	Initialized	Initialized	
ADDRC	Initialized	—	—	Initialized	Initialized	Initialized	
ADDRD	Initialized	—	—	Initialized	Initialized	Initialized	
ADCSR	Initialized	—	—	Initialized	Initialized	Initialized	
ADCR	Initialized	—	—	Initialized	Initialized	Initialized	
TCSRWD	Initialized	—	—	—	—	—	WDT* <sup>2</sup>
TCWD	Initialized	—	—	—	—	—	
TMWD	Initialized	—	—	—	—	—	
ABRKCR	Initialized	—	—	—	—	—	Address
ABRKSR	Initialized	—	—	—	—	—	
BARH	Initialized	—	—	—	—	—	
BARL	Initialized	—	—	—	—	—	
BDRH	Initialized	—	—	—	—	—	
BDRL	Initialized	—	—	—	—	—	
PUCR1	Initialized	—	—	—	—	—	I/O port
PUCR5	Initialized	—	—	—	—	—	
PDR1	Initialized	—	—	—	—	—	
PDR2	Initialized	—	—	—	—	—	
PDR5	Initialized	—	—	—	—	—	
PDR7	Initialized	—	—	—	—	—	
PDR8	Initialized	—	—	—	—	—	
PDRB	Initialized	—	—	—	—	—	

SYSCR2	Initialized	—	—	—	—	—	Power-
IEGR1	Initialized	—	—	—	—	—	Interrup
IEGR2	Initialized	—	—	—	—	—	Interrup
IENR1	Initialized	—	—	—	—	—	Interrup
IRR1	Initialized	—	—	—	—	—	Interrup
IWPR	Initialized	—	—	—	—	—	Interrup
MSTCR1	Initialized	—	—	—	—	—	Power-

- EEPROM

Register Name	Reset	Active	Sleep	Subactive	Subsleep	Standby	Modul
EKR	—	—	—	—	—	—	EEPR

Notes: — is not initialized

1. LVDC: Low-voltage detection circuits (optional)
2. WDT: Watchdog timer





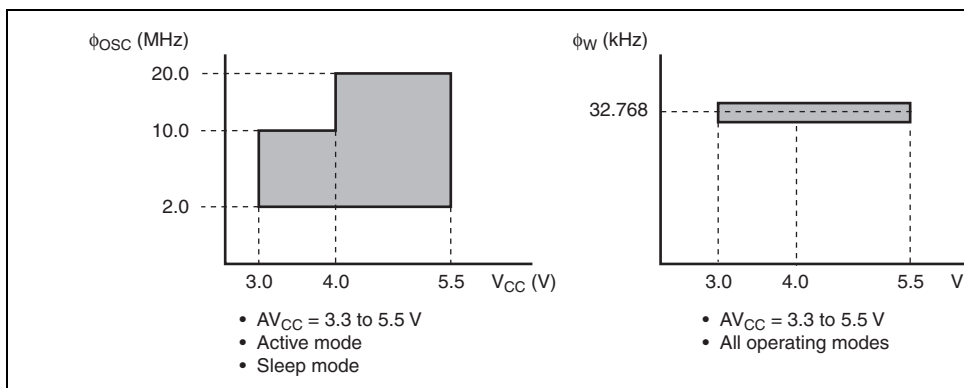
	B and X1		
	Port B		-0.3 to $AV_{CC} + 0.3$ V
	X1		-0.3 to 4.3 V
Operating temperature	$T_{opr}$	-20 to +75	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note: \* Permanent damage may result if maximum ratings are exceeded. Normal operation should be under the conditions specified in Electrical Characteristics. Exceeding these values can result in incorrect operation and reduced reliability.

## 21.2 Electrical Characteristics (F-ZTAT™ Version, EEPROM Standard Version, F-ZTAT™ Version)

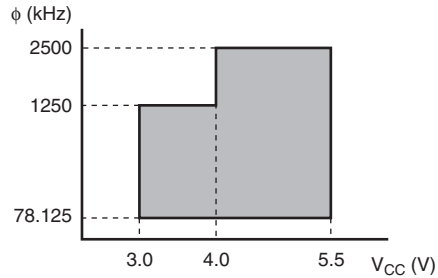
### 21.2.1 Power Supply Voltage and Operating Ranges

#### Power Supply Voltage and Oscillation Frequency Range



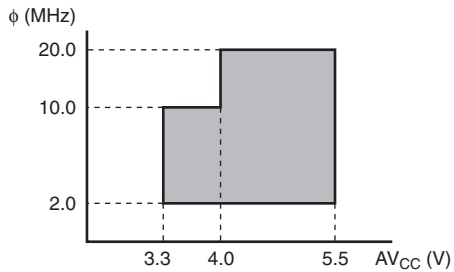
- $AV_{CC} = 3.3$  to  $5.5$  V
- Active mode
- Sleep mode  
(When MA2 in SYSCR2 = 0)

- $AV_{CC} = 3.3$  to  $5.5$  V
- Subactive mode
- Subsleep mode

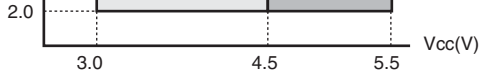


- $AV_{CC} = 3.3$  to  $5.5$  V
- Active mode
- Sleep mode  
(When MA2 in SYSCR2 = 1)

### Analog Power Supply Voltage and A/D Converter Accuracy Guarantee Range



- $V_{CC} = 3.0$  to  $5.5$  V
- Active mode
- Sleep mode



- Operation guarantee range
- Operation guarantee range except A/D conversion accuracy

		TMCIV, FTICL, FTIOA to FTIOD, SCK3, TRGV	$V_{cc} \times 0.9$	—	$V_{cc} + 0.3$	
		RXD, SCL, SDA, P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76, P80 to P87	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} \times 0.7$	—	$V_{cc} + 0.3$ V
				$V_{cc} \times 0.8$	—	$V_{cc} + 0.3$
		PB0 to PB7	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} \times 0.7$	—	$AV_{cc} + 0.3$ V
				$V_{cc} \times 0.8$	—	$AV_{cc} + 0.3$
		OSC1	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} - 0.5$	—	$V_{cc} + 0.3$ V
				$V_{cc} - 0.3$	—	$V_{cc} + 0.3$
Input low voltage	$V_{IL}$	RES, NMI, WKPO to WKP5, IRQ0 to IRQ3, ADTRG, TMRIV, TMCIV, FTICL, FTIOA to FTIOD, SCK3, TRGV	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	$V_{cc} \times 0.2$ V
		RXD, SCL, SDA, P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76, P80 to P87 PB0 to PB7	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	$V_{cc} \times 0.3$ V
				-0.3	—	$V_{cc} \times 0.2$
		OSC1	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	0.5 V
				-0.3	—	0.3

Output low voltage	$V_{OL}$	P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76	$I_{OH} = 0.1 \text{ mA}$	—	—	0.6	V
			$V_{CC} = 4.0 \text{ to } 5.5$ $V_{IOL} = 1.6 \text{ mA}$	—	—	0.4	
		P80 to P87	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	1.5	V
			$I_{OL} = 20.0 \text{ mA}$	—	—	1.0	
			$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.4	
			$I_{OL} = 10.0 \text{ mA}$	—	—	0.4	
			$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.4	
SCL, SDA	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.6	V		
	$I_{OL} = 6.0 \text{ mA}$	—	—	0.4			
	$I_{OL} = 3.0 \text{ mA}$	—	—	0.4			
Input/output leakage current	$ I_{IL} $	OSC1, $\overline{NMI}$ , $\overline{WKP0}$ to $\overline{WKP5}$ , $\overline{IRQ0}$ to $\overline{IRQ3}$ , $\overline{ADTRG}$ , TRGV, TMRIV, TMCIV, FTCL, FTIOA to FTIOD, RXD, SCK3, SCL, SDA	$V_{IN} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$
			$V_{IN} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$
			$V_{IN} = 0.5 \text{ V to } (AV_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$

mode current consump- tion			$V_{CC} = 5.0\text{ V}$ , $f_{OSC} = 20\text{ MHz}$						*
			Active mode 1 $V_{CC} = 3.0\text{ V}$ , $f_{OSC} = 10\text{ MHz}$	—	8.0	—			Refe valu
	$I_{OPE2}$	$V_{CC}$	Active mode 2 $V_{CC} = 5.0\text{ V}$ , $f_{OSC} = 20\text{ MHz}$	—	2.0	3.0	mA	*	
			Active mode 2 $V_{CC} = 3.0\text{ V}$ , $f_{OSC} = 10\text{ MHz}$	—	1.2	—			Refe valu
Sleep mode current consump- tion	$I_{SLEEP1}$	$V_{CC}$	Sleep mode 1 $V_{CC} = 5.0\text{ V}$ , $f_{OSC} = 20\text{ MHz}$	—	16.0	22.5	mA	*	
			Sleep mode 1 $V_{CC} = 3.0\text{ V}$ , $f_{OSC} = 10\text{ MHz}$	—	8.0	—		Refe valu	
	$I_{SLEEP2}$	$V_{CC}$	Sleep mode 2 $V_{CC} = 5.0\text{ V}$ , $f_{OSC} = 20\text{ MHz}$	—	1.8	2.7	mA	*	
			Sleep mode 2 $V_{CC} = 3.0\text{ V}$ , $f_{OSC} = 10\text{ MHz}$	—	1.2	—		Refe valu	
Subactive mode current consump- tion	$I_{SUB}$	$V_{CC}$	$V_{CC} = 3.0\text{ V}$ 32-kHz crystal resonator ( $\phi_{SUB} = \phi_W/2$ )	—	40.0	70.0	$\mu\text{A}$	*	
			$V_{CC} = 3.0\text{ V}$ 32-kHz crystal resonator ( $\phi_{SUB} = \phi_W/8$ )	—	30.0	—		Refe valu	

Note: \* Pin states during current consumption measurement are given below (excluding the pull-up MOS transistors and output buffers).

Mode	$\overline{\text{RES}}$ Pin	Internal State	Other Pins	Oscillator Pin
Active mode 1	V <sub>CC</sub>	Operates	V <sub>CC</sub>	Main clock: ceramic or crystal resonator
Active mode 2		Operates ( $\phi\text{OSC}/64$ )		Subclock: Pin X1 = V <sub>SS</sub>
Sleep mode 1	V <sub>CC</sub>	Only timers operate	V <sub>CC</sub>	
Sleep mode 2		Only timers operate ( $\phi\text{OSC}/64$ )		
Subactive mode	V <sub>CC</sub>	Operates	V <sub>CC</sub>	Main clock: ceramic or crystal resonator
Subsleep mode	V <sub>CC</sub>	Only timers operate	V <sub>CC</sub>	Subclock: crystal resonator
Standby mode	V <sub>CC</sub>	CPU and timers both stop	V <sub>CC</sub>	Main clock: ceramic or crystal resonator  Subclock: Pin X1 = V <sub>SS</sub>

Note: \* The current consumption of the EEPROM chip is shown.  
For the current consumption of H8/3694N, add the above current values to the  
consumption of H8/3694F.



		SCL and SDA		—	—	6.0
		Output pins except port 8, SCL, and SDA		—	—	0.5
Allowable output low current (total)	$\Sigma I_{OL}$	Output pins except port 8, SCL, and SDA	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	40.0
		Port 8, SCL, and SDA		—	—	80.0
		Output pins except port 8, SCL, and SDA		—	—	20.0
		Port 8, SCL, and SDA		—	—	40.0
Allowable output high current (per pin)	$  -I_{OH}  $	All output pins	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	2.0
				—	—	0.2
Allowable output high current (total)	$  -\Sigma I_{OH}  $	All output pins	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	30.0
				—	—	8.0

cycle time				—	—	12.8	$\mu\text{s}$
Subclock oscillation frequency	$f_W$	X1, X2		—	32.768	—	kHz
Watch clock ( $\phi_W$ ) cycle time	$t_W$	X1, X2		—	30.5	—	$\mu\text{s}$
Subclock ( $\phi_{\text{SUB}}$ ) cycle time	$t_{\text{subcyc}}$			2	—	8	$t_W$ *
Instruction cycle time				2	—	—	$t_{\text{cyc}}$ $t_{\text{subcyc}}$
Oscillation stabilization time (crystal resonator)	$t_{\text{rc}}$	OSC1, OSC2		—	—	10.0	ms
Oscillation stabilization time (ceramic resonator)	$t_{\text{rc}}$	OSC1, OSC2		—	—	5.0	ms
Oscillation stabilization time	$t_{\text{rcx}}$	X1, X2		—	—	2.0	s
External clock high width	$t_{\text{CPH}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	20.0	—	—	ns
External clock low width	$t_{\text{CPL}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	20.0	—	—	ns
External clock rise time	$t_{\text{CPr}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	10.0	ns
External clock fall time	$t_{\text{CPf}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	10.0	ns
RES pin low width	$t_{\text{REL}}$	$\overline{\text{RES}}$	At power-on and in modes other than those below	$t_{\text{rc}}$	—	—	ms
			In active mode and sleep mode operation	200	—	—	ns

		FTIOD			
Input pin low width	$t_{IL}$	$\overline{NMI}$ , $\overline{IRQ0}$ to $\overline{IRQ3}$ , $\overline{WKP0}$ to $\overline{WKP5}$ , $\overline{TMCIV}$ , $\overline{TMRIV}$ , $\overline{TRGV}$ , $\overline{ADTRG}$ , $\overline{FTCI}$ , $\overline{FTIOA}$ to $\overline{FTIOD}$	2	—	—

- Notes:
1. When an external clock is input, the minimum system clock oscillation frequency is 1.0 MHz.
  2. Determined by MA2, MA1, MA0, SA1, and SA0 of system control register 2 (SCR2).

SCL and SDA input spike pulse removal time	$t_{SP}$	—	—	$1t_{cyc}$	ns	
SDA input bus-free time	$t_{BUF}$	$5t_{cyc}$	—	—	ns	
Start condition input hold time	$t_{STAH}$	$3t_{cyc}$	—	—	ns	
Retransmission start condition input setup time	$t_{STAS}$	$3t_{cyc}$	—	—	ns	
Setup time for stop condition input	$t_{STOS}$	$3t_{cyc}$	—	—	ns	
Data-input setup time	$t_{SDAS}$	$1t_{cyc}+20$	—	—	ns	
Data-input hold time	$t_{SDAH}$	0	—	—	ns	
Capacitive load of SCL and SDA	$c_b$	0	—	400	pF	
SCL and SDA output fall time	$t_{Sf}$	$V_{CC} = 4.0$ to $5.5$ V	—	—	250	ns
			—	—	300	

width								
Transmit data delay time (clocked synchronous)	$t_{TXD}$	TXD	$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$	—	—	1	$t_{cyc}$	F
				—	—	1		
Receive data setup time (clocked synchronous)	$t_{RXS}$	RXD	$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$	50.0	—	—	ns	
				100.0	—	—		
Receive data hold time (clocked synchronous)	$t_{RXH}$	RXD	$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$	50.0	—	—	ns	
				100.0	—	—		

Analog power supply current	$I_{\text{OPE}}$	$AV_{\text{CC}}$	$AV_{\text{CC}} = 5.0 \text{ V}$	—	—	2.0	mA
			$f_{\text{OSC}} = 20 \text{ MHz}$				
	$AI_{\text{STOP1}}$	$AV_{\text{CC}}$		—	50	—	$\mu\text{A}$
	$AI_{\text{STOP2}}$	$AV_{\text{CC}}$		—	—	5.0	$\mu\text{A}$
Analog input capacitance	$C_{\text{AIN}}$	AN0 to AN7		—	—	30.0	pF
Allowable signal source impedance	$R_{\text{AIN}}$	AN0 to AN7		—	—	5.0	k $\Omega$
Resolution (data length)				10	10	10	bit
Conversion time (single mode)			$AV_{\text{CC}} = 3.3 \text{ to } 5.5 \text{ V}$	134	—	—	$t_{\text{cyc}}$
Nonlinearity error				—	—	$\pm 7.5$	LSB
Offset error				—	—	$\pm 7.5$	LSB
Full-scale error				—	—	$\pm 7.5$	LSB
Quantization error				—	—	$\pm 0.5$	LSB
Absolute accuracy				—	—	$\pm 8.0$	LSB
Conversion time (single mode)			$AV_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	70	—	—	$t_{\text{cyc}}$
Nonlinearity error				—	—	$\pm 7.5$	LSB
Offset error				—	—	$\pm 7.5$	LSB
Full-scale error				—	—	$\pm 7.5$	LSB
Quantization error				—	—	$\pm 0.5$	LSB
Absolute accuracy				—	—	$\pm 8.0$	LSB

2.  $I_{STOP1}$  is the current in active and sleep modes while the A/D converter is idle.
3.  $I_{STOP2}$  is the current at reset and in standby, subactive, and subsleep modes when the A/D converter is idle.

### 21.2.5 Watchdog Timer Characteristics

**Table 21.7 Watchdog Timer Characteristics**

$V_{CC} = 3.0$  to  $5.5$  V,  $V_{SS} = 0.0$  V,  $T_a = -20$  to  $+75^\circ\text{C}$ , unless otherwise indicated.

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min	Typ	Max	
On-chip oscillator overflow time	$t_{OVF}$			0.2	0.4	—	s

Note: \* Shows the time to count from 0 to 255, at which point an internal reset is generated when the internal oscillator is selected.

Programming	Wait time after SWE bit setting* <sup>1</sup>	x	1	—	—
	Wait time after PSU bit setting* <sup>1</sup>	y	50	—	—
	Wait time after P bit setting* <sup>1</sup> * <sup>1</sup> * <sup>4</sup>	z1	1 ≤ n ≤ 6	28	30
		z2	7 ≤ n ≤ 1000	198	200
		z3	Additional-programming	8	10
	Wait time after P bit clear* <sup>1</sup>	α	5	—	—
	Wait time after PSU bit clear* <sup>1</sup>	β	5	—	—
	Wait time after PV bit setting* <sup>1</sup>	γ	4	—	—
	Wait time after dummy write* <sup>1</sup>	ε	2	—	—
	Wait time after PV bit clear* <sup>1</sup>	η	2	—	—
	Wait time after SWE bit clear* <sup>1</sup>	θ	100	—	—
	Maximum programming count* <sup>1</sup> * <sup>4</sup> * <sup>5</sup>	N	—	—	1000



Wait time after EV bit setting* <sup>1</sup>	$\gamma$	20	—	—
Wait time after dummy write* <sup>1</sup>	$\epsilon$	2	—	—
Wait time after EV bit clear* <sup>1</sup>	$\eta$	4	—	—
Wait time after SWE bit clear* <sup>1</sup>	$\theta$	100	—	—
Maximum erase count * <sup>1</sup> * <sup>6</sup> * <sup>7</sup>	N	—	—	120

- Notes:
1. Make the time settings in accordance with the program/erase algorithms.
  2. The programming time for 128 bytes. (Indicates the total time for which the P memory control register 1 (FLMCR1) is set. The program-verify time is not included.)
  3. The time required to erase one block. (Indicates the time for which the E bit in memory control register 1 (FLMCR1) is set. The erase-verify time is not included.)
  4. Programming time maximum value ( $t_p$  (max.)) = wait time after P bit setting (z) × maximum programming count (N)
  5. Set the maximum programming count (N) according to the actual set values of (z1, z2) and z3, so that it does not exceed the programming time maximum value ( $t_p$  (max.)). The wait time after P bit setting (z1, z2) should be changed as follows according to the value of the programming count (n).

Programming count (n)

$$1 \leq n \leq 6 \quad z1 = 30 \mu\text{s}$$

$$7 \leq n \leq 1000 \quad z2 = 200 \mu\text{s}$$

6. Erase time maximum value ( $t_e$  (max.)) = wait time after E bit setting (z) × maximum erase count (N)
7. Set the maximum erase count (N) according to the actual set value of (z), so that it does not exceed the erase time maximum value ( $t_e$  (max.)).

SCL, SDA input spike pulse removal time	$t_{SP}$	—	—	50	ns
SDA input bus-free time	$t_{BUF}$	1200	—	—	ns
Start condition input hold time	$t_{STAH}$	600	—	—	ns
Retransmit start condition input setup time	$t_{STAS}$	600	—	—	ns
Stop condition input setup time	$t_{STOS}$	600	—	—	ns
Data input setup time	$t_{SDAS}$	160	—	—	ns
Data input hold time	$t_{SDAH}$	0	—	—	ns
SCL, SDA input fall time	$t_{Sf}$	—	—	300	ns
SDA input rise time	$t_{Sr}$	—	—	300	ns
Data output hold time	$t_{DH}$	50	—	—	ns
SCL, SDA capacitive load	$C_b$	0	—	400	pF
Access time	$t_{AA}$	100	—	900	ns
Cycle time at writing*	$t_{WC}$	—	—	10	ms
Reset release time	$t_{RES}$	—	—	13	ms

Note: \* Cycle time at writing is a time from the stop condition to write completion (interfere control).

Voltage					
Reset detection voltage 1* <sup>1</sup>	Vreset1	LVDSSEL = 0	—	2.3	2.7
Reset detection voltage 2* <sup>2</sup>	Vreset2	LVDSSEL = 1	3.0	3.6	4.2
Lower-limit voltage of LVDR operation* <sup>3</sup>	V <sub>LVDRmin</sub>		1.0	—	—
LVD stabilization time	t <sub>LVDRON</sub>		50	—	—
Current consumption in standby mode	I <sub>STBY</sub>	LVDE = 1, Vcc = 5.0 V, When a 32- kHz crystal resonator is not used	—	—	350

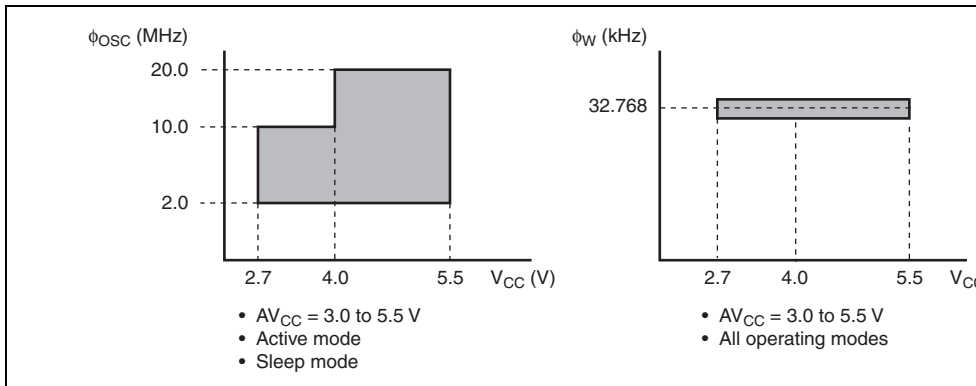
- Notes:
1. This voltage should be used when the falling and rising voltage detection function is used.
  2. Select the low-voltage reset 2 when only the low-voltage detection reset is used.
  3. When the power-supply voltage (Vcc) falls below V<sub>LVDRmin</sub> = 1.0 V and then rises, a reset may not occur. Therefore sufficient evaluation is required.

Note: The power supply voltage ( $V_{CC}$ ) must fall below  $V_{POR} = 100$  mV and then rise. The charge of the RES pin is removed completely. In order to remove charge of the RES pin, it is recommended that the diode be placed in the  $V_{CC}$  side. If the power-supply voltage ( $V_{CC}$ ) rises from the point over 100 mV, a power-on reset may not occur.

## 21.3 Electrical Characteristics (Mask-ROM Version, EEPROM Standard Version, Mask-ROM Version)

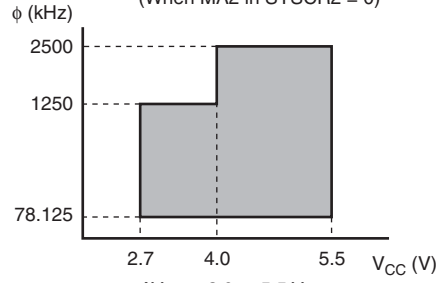
### 21.3.1 Power Supply Voltage and Operating Ranges

#### Power Supply Voltage and Oscillation Frequency Range



- $V_{CC} = 3.0$  to  $5.5$  V
- Active mode
- Sleep mode  
(When MA2 in SYSCR2 = 0)

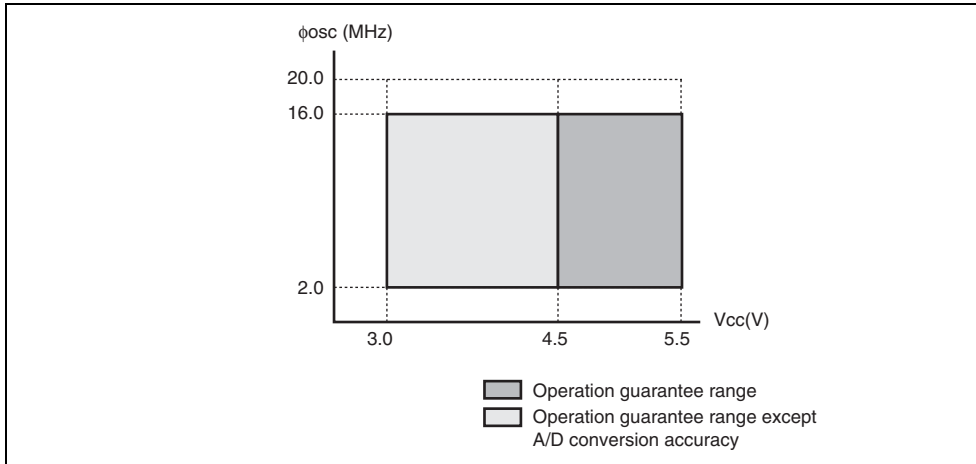
- $V_{CC} = 3.0$  to  $5.5$  V
- Subactive mode
- Subsleep mode



- $V_{CC} = 3.0$  to  $5.5$  V
- Active mode
- Sleep mode  
(When MA2 in SYSCR2 = 1)

- $V_{CC} = 2.7$  to  $5.5$  V
- Active mode
- Sleep mode

## Range of Power Supply Voltage and Oscillation Frequency when Low-Voltage Detect Circuit is Used



		TMCIV, FTCl, FTIOA to FTIOD, SCK3, TRGV	$V_{cc} \times 0.9$	—	$V_{cc} + 0.3$	
		RXD, SCL, SDA, P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76, P80 to P87	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} \times 0.7$	—	$V_{cc} + 0.3$ V
				$V_{cc} \times 0.8$	—	$V_{cc} + 0.3$
		PB0 to PB7	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} \times 0.7$	—	$AV_{cc} + 0.3$ V
				$V_{cc} \times 0.8$	—	$AV_{cc} + 0.3$
		OSC1	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	$V_{cc} - 0.5$	—	$V_{cc} + 0.3$ V
				$V_{cc} - 0.3$	—	$V_{cc} + 0.3$
Input low voltage	$V_{IL}$	RES, NMI, WKP0 to WKP5, IRQ0 to IRQ3, ADTRG, TMRIV, TMCIV, FTCl, FTIOA to FTIOD, SCK3, TRGV	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	$V_{cc} \times 0.2$ V
		RXD, SCL, SDA, P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76, P80 to P87, PB0 to PB7	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	$V_{cc} \times 0.3$ V
				-0.3	—	$V_{cc} \times 0.2$
		OSC1	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$	-0.3	—	0.5 V
				-0.3	—	0.3

Output low voltage	$V_{OL}$	P10 to P12, P14 to P17, P20 to P22,	$I_{OH} = 0.1 \text{ mA}$	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.6	V
			$I_{OL} = 1.6 \text{ mA}$					
		P50 to P57, P74 to P76	$I_{OL} = 0.4 \text{ mA}$	—	—	0.4		
		P80 to P87	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	1.5	V	
			$I_{OL} = 20.0 \text{ mA}$					
			$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	1.0		
			$I_{OL} = 10.0 \text{ mA}$					
			$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.4		
			$I_{OL} = 1.6 \text{ mA}$					
			$I_{OL} = 0.4 \text{ mA}$	—	—	0.4		
SCL, SDA			$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	0.6	V	
			$I_{OL} = 6.0 \text{ mA}$					
			$I_{OL} = 3.0 \text{ mA}$	—	—	0.4		
Input/output leakage current	$ I_{IL} $	OSC1, $\overline{NMI}$ , $\overline{WKP0}$ to $\overline{WKP5}$ , $\overline{IRQ0}$ to $\overline{IRQ3}$ , $\overline{ADTRG}$ , $\overline{TRGV}$ , $\overline{TMRIV}$ , $\overline{TMCIV}$ , $\overline{FTCI}$ , $\overline{FTIOA}$ to $\overline{FTIOD}$ , $\overline{RXD}$ , $\overline{SCK3}$ , $\overline{SCL}$ , $\overline{SDA}$	$V_{IN} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$	
		P10 to P12, P14 to P17, P20 to P22, P50 to P57, P74 to P76, P80 to P87	$V_{IN} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$	
		PB0 to PB7	$V_{IN} = 0.5 \text{ V to } (AV_{CC} - 0.5 \text{ V})$	—	—	1.0	$\mu\text{A}$	



mode current consump- tion			$V_{CC} = 5.0\text{ V},$ $f_{OSC} = 20\text{ MHz}$	—	8.0	—		*
			Active mode 1 $V_{CC} = 3.0\text{ V},$ $f_{OSC} = 10\text{ MHz}$	—	8.0	—		Re va
Sleep mode current consump- tion	$I_{OPE2}$	$V_{CC}$	Active mode 2 $V_{CC} = 5.0\text{ V},$ $f_{OSC} = 20\text{ MHz}$	—	2.0	3.0	mA	*
			Active mode 2 $V_{CC} = 3.0\text{ V},$ $f_{OSC} = 10\text{ MHz}$	—	1.2	—		* Re va
	$I_{SLEEP1}$	$V_{CC}$	Sleep mode 1 $V_{CC} = 5.0\text{ V},$ $f_{OSC} = 20\text{ MHz}$	—	10.0	17.5	mA	*
			Sleep mode 1 $V_{CC} = 3.0\text{ V},$ $f_{OSC} = 10\text{ MHz}$	—	5.5	—		* Re va
$I_{SLEEP2}$	$V_{CC}$	Sleep mode 2 $V_{CC} = 5.0\text{ V},$ $f_{OSC} = 20\text{ MHz}$	—	1.6	2.4	mA	*	
		Sleep mode 2 $V_{CC} = 3.0\text{ V},$ $f_{OSC} = 10\text{ MHz}$	—	0.8	—		* Re va	
Subactive mode current consump- tion	$I_{SUB}$	$V_{CC}$	$V_{CC} = 3.0\text{ V}$ 32-kHz crystal resonator ( $\phi_{SUB} = \phi_W/2$ )	—	40.0	70.0	$\mu\text{A}$	*
			$V_{CC} = 3.0\text{ V}$ 32-kHz crystal resonator ( $\phi_{SUB} = \phi_W/8$ )	—	30.0	—		* Re va

Note: \* Pin states during current consumption measurement are given below (excluding in the pull-up MOS transistors and output buffers).

Mode	$\overline{RES}$ Pin	Internal State	Other Pins	Oscillator Pin
Active mode 1	$V_{CC}$	Operates	$V_{CC}$	Main clock: ceramic or cry- resonator
Active mode 2		Operates ( $\phi_{OSC}/64$ )		Subclock: Pin X1 = $V_{SS}$
Sleep mode 1	$V_{CC}$	Only timers operate	$V_{CC}$	
Sleep mode 2		Only timers operate ( $\phi_{OSC}/64$ )		
Subactive mode	$V_{CC}$	Operates	$V_{CC}$	Main clock: ceramic or cry- resonator
Subsleep mode	$V_{CC}$	Only timers operate	$V_{CC}$	Subclock: crystal resonat
Standby mode	$V_{CC}$	CPU and timers both stop	$V_{CC}$	Main clock: ceramic or cry- resonator  Subclock: Pin X1 = $V_{SS}$

Note: \* The current consumption of the EEPROM chip is shown.  
For the current consumption of H8/3694N, add the above current values to the  
consumption of H8/3694.

		Output pins except port 8, SCL, and SDA		—	—	0.5
Allowable output low current (total)	$\Sigma I_{OL}$	Output pins except port 8, SCL, and SDA	$V_{CC} = 4.0$ to $5.5$ V	—	—	40.0
		Port 8, SCL, and SDA		—	—	80.0
		Output pins except port 8, SCL, and SDA		—	—	20.0
		Port 8, SCL, and SDA		—	—	40.0
Allowable output high current (per pin)	$  -I_{OH}  $	All output pins	$V_{CC} = 4.0$ to $5.5$ V	—	—	2.0
				—	—	0.2
Allowable output high current (total)	$  -\Sigma I_{OH}  $	All output pins	$V_{CC} = 4.0$ to $5.5$ V	—	—	30.0
				—	—	8.0

cycle time				—	—	12.8	$\mu\text{s}$
Subclock oscillation frequency	$f_W$	X1, X2		—	32.768	—	kHz
Watch clock ( $\phi_W$ ) cycle time	$t_W$	X1, X2		—	30.5	—	$\mu\text{s}$
Subclock ( $\phi_{\text{SUB}}$ ) cycle time	$t_{\text{subcyc}}$			2	—	8	$t_W$
Instruction cycle time				2	—	—	$t_{\text{cyc}}$ $t_{\text{subcyc}}$
Oscillation stabilization time (crystal resonator)	$t_{\text{rc}}$	OSC1, OSC2		—	—	10.0	ms
Oscillation stabilization time (ceramic resonator)	$t_{\text{rc}}$	OSC1, OSC2		—	—	5.0	ms
Oscillation stabilization time	$t_{\text{rcx}}$	X1, X2		—	—	2.0	s
External clock high width	$t_{\text{CPH}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	20.0	—	—	ns
				40.0	—	—	
External clock low width	$t_{\text{CPL}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	20.0	—	—	ns
				40.0	—	—	
External clock rise time	$t_{\text{CPr}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	10.0	ns
				—	—	15.0	
External clock fall time	$t_{\text{CPf}}$	OSC1	$V_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	10.0	ns
				—	—	15.0	
$\overline{\text{RES}}$ pin low width	$t_{\text{REL}}$	$\overline{\text{RES}}$	At power-on and in $t_{\text{rc}}$ modes other than those below	—	—	—	ms
			In active mode and 200 sleep mode operation	—	—	—	ns

		FTI0D			
Input pin low width	$t_{L}$	$\overline{NMI}$ , $\overline{IRQ0}$ to $\overline{IRQ3}$ , $\overline{WKP0}$ to $\overline{WKP5}$ , TMCIV, TMRIV, TRGV, $\overline{ADTRG}$ , FTCI, FTIOA to FTIOD	2	—	—

$t_{cyc}$   
 $t_{subcyc}$

- Notes: 1 When an external clock is input, the minimum system clock oscillation frequency is 1.0 MHz.
2. Determined by MA2, MA1, MA0, SA1, and SA0 of system control register 2 (S



SCL and SDA input spike pulse removal time	$t_{SP}$	—	—	$1t_{cyc}$	ns	
SDA input bus-free time	$t_{BUF}$	$5t_{cyc}$	—	—	ns	
Start condition input hold time	$t_{STAH}$	$3t_{cyc}$	—	—	ns	
Retransmission start condition input setup time	$t_{STAS}$	$3t_{cyc}$	—	—	ns	
Setup time for stop condition input	$t_{STOS}$	$3t_{cyc}$	—	—	ns	
Data-input setup time	$t_{SDAS}$	$1t_{cyc}+20$	—	—	ns	
Data-input hold time	$t_{SDAH}$	0	—	—	ns	
Capacitive load of SCL and SDA	$c_b$	0	—	400	pF	
SCL and SDA output fall time	$t_{Sf}$	$V_{CC} = 4.0$ to $5.5$ V	—	—	250	ns
			—	—	300	

Transmit data delay time (clocked synchronous)	$t_{TXD}$	TXD	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	—	—	1	$t_{cyc}$	Fi
				—	—	1		
Receive data setup time (clocked synchronous)	$t_{RXS}$	RXD	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	50.0	—	—	ns	
				100.0	—	—		
Receive data hold time (clocked synchronous)	$t_{RXH}$	RXD	$V_{CC} = 4.0 \text{ to } 5.5 \text{ V}$	50.0	—	—	ns	
				100.0	—	—		



Analog power supply current	$AI_{\text{OPE}}$	$AV_{\text{CC}}$	$AV_{\text{CC}} = 5.0 \text{ V}$	—	—	2.0	mA
			$f_{\text{OSC}} = 20 \text{ MHz}$				
	$AI_{\text{STOP1}}$	$AV_{\text{CC}}$		—	50	—	$\mu\text{A}$
	$AI_{\text{STOP2}}$	$AV_{\text{CC}}$		—	—	5.0	$\mu\text{A}$
Analog input capacitance	$C_{\text{AIN}}$	AN0 to AN7		—	—	30.0	pF
Allowable signal source impedance	$R_{\text{AIN}}$	AN0 to AN7		—	—	5.0	k $\Omega$
Resolution (data length)				10	10	10	bit
Conversion time (single mode)			$AV_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}$	134	—	—	$t_{\text{cyc}}$
Nonlinearity error				—	—	$\pm 7.5$	LSB
Offset error				—	—	$\pm 7.5$	LSB
Full-scale error				—	—	$\pm 7.5$	LSB
Quantization error				—	—	$\pm 0.5$	LSB
Absolute accuracy				—	—	$\pm 8.0$	LSB
Conversion time (single mode)			$AV_{\text{CC}} = 4.0 \text{ to } 5.5 \text{ V}$	70	—	—	$t_{\text{cyc}}$
Nonlinearity error				—	—	$\pm 7.5$	LSB
Offset error				—	—	$\pm 7.5$	LSB
Full-scale error				—	—	$\pm 7.5$	LSB
Quantization error				—	—	$\pm 0.5$	LSB
Absolute accuracy				—	—	$\pm 8.0$	LSB

2.  $I_{STOP1}$  is the current in active and sleep modes while the A/D converter is idle.
3.  $I_{STOP2}$  is the current at reset and in standby, subactive, and subsleep modes while the A/D converter is idle.

### 21.3.5 Watchdog Timer Characteristics

**Table 21.17 Watchdog Timer Characteristics**

$V_{CC} = 2.7$  to  $5.5$  V,  $V_{SS} = 0.0$  V,  $T_a = -20$  to  $+75^\circ\text{C}$ , unless otherwise indicated.

Item	Symbol	Applicable Pins	Test Condition	Values			Unit	Remarks
				Min	Typ	Max		
On-chip oscillator overflow time	$t_{OVF}$			0.2	0.4	—	s	*

Note: \* Shows the time to count from 0 to 255, at which point an internal reset is generated when the internal oscillator is selected.

SCL input low pulse width	$t_{SCLL}$	1200	—	—	ns
SCL, SDA input spike pulse removal time	$t_{SP}$	—	—	50	ns
SDA input bus-free time	$t_{BUF}$	1200	—	—	ns
Start condition input hold time	$t_{STAH}$	600	—	—	ns
Retransmit start condition input setup time	$t_{STAS}$	600	—	—	ns
Stop condition input setup time	$t_{STOS}$	600	—	—	ns
Data input setup time	$t_{SDAS}$	160	—	—	ns
Data input hold time	$t_{SDAH}$	0	—	—	ns
SCL, SDA input fall time	$t_{Sf}$	—	—	300	ns
SDA input rise time	$t_{Sr}$	—	—	300	ns
Data output hold time	$t_{DH}$	50	—	—	ns
SCL, SDA capacitive load	$C_b$	0	—	400	pF
Access time	$t_{AA}$	100	—	900	ns
Cycle time at writing*	$t_{WC}$	—	—	10	ms
Reset release time	$t_{RES}$	—	—	13	ms

Note: \* Cycle time at writing is a time from the stop condition to write completion (internal control).

voltage					
Reset detection voltage 1 <sup>*1</sup>	Vreset1	LVDSSEL = 0	—	2.3	2.7
Reset detection voltage 2 <sup>*2</sup>	Vreset2	LVDSSEL = 1	3.0	3.6	4.2
Lower-limit voltage of LVDR operation <sup>*3</sup>	$V_{LVDRmin}$		1.0	—	—
LVD stabilization time	$t_{LVDRON}$		50	—	—
Current consumption in standby mode	$I_{STBY}$	LVDE = 1, Vcc = 5.0 V, When a 32- kHz crystal resonator is not used	—	—	350

- Notes:
1. This voltage should be used when the falling and rising voltage detection function is used.
  2. Select the low-voltage reset 2 when only the low-voltage detection reset is used.
  3. When the power-supply voltage (Vcc) falls below  $V_{LVDRmin} = 1.0$  V and then rises again, a reset may not occur. Therefore sufficient evaluation is required.

Note: The power supply voltage (Vcc) must fall below  $V_{por} = 100$  mV and then rise. The charge of the RES pin is removed completely. In order to remove charge of the RES pin, it is recommended that the diode be placed in the Vcc side. If the power-supply voltage (Vcc) rises from the point over 100 mV, a power-on reset may not occur.

## 21.4 Operation Timing

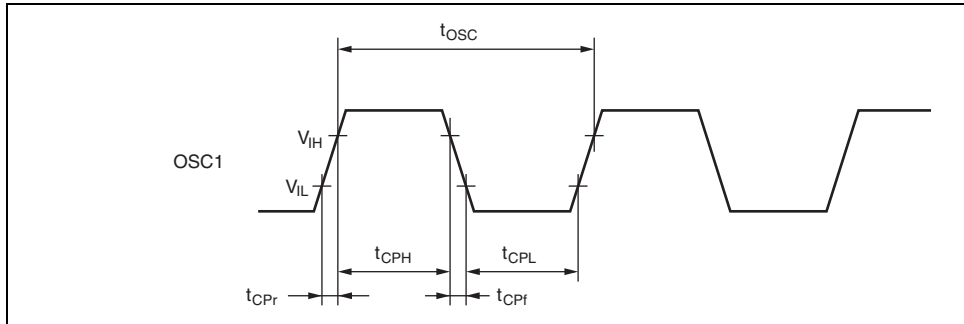


Figure 21.1 System Clock Input Timing

## Figure 21.2 $\overline{\text{RES}}$ Low Width Timing

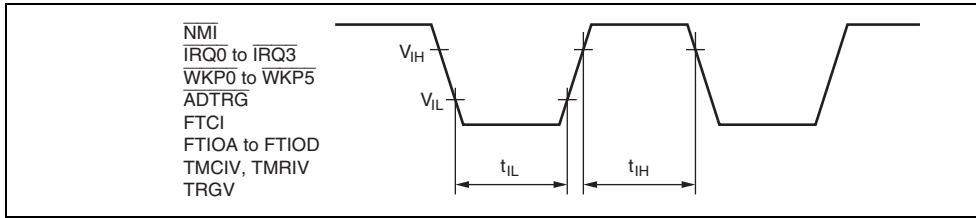


Figure 21.3 Input Timing

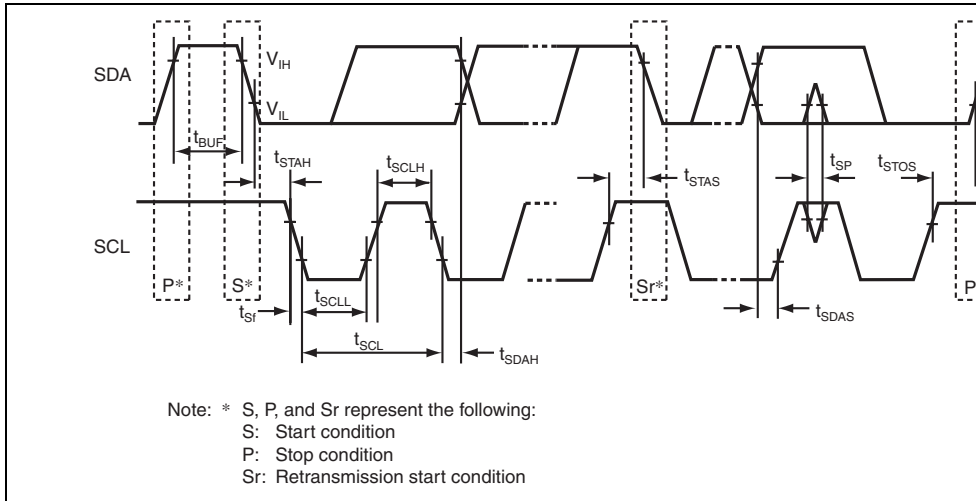
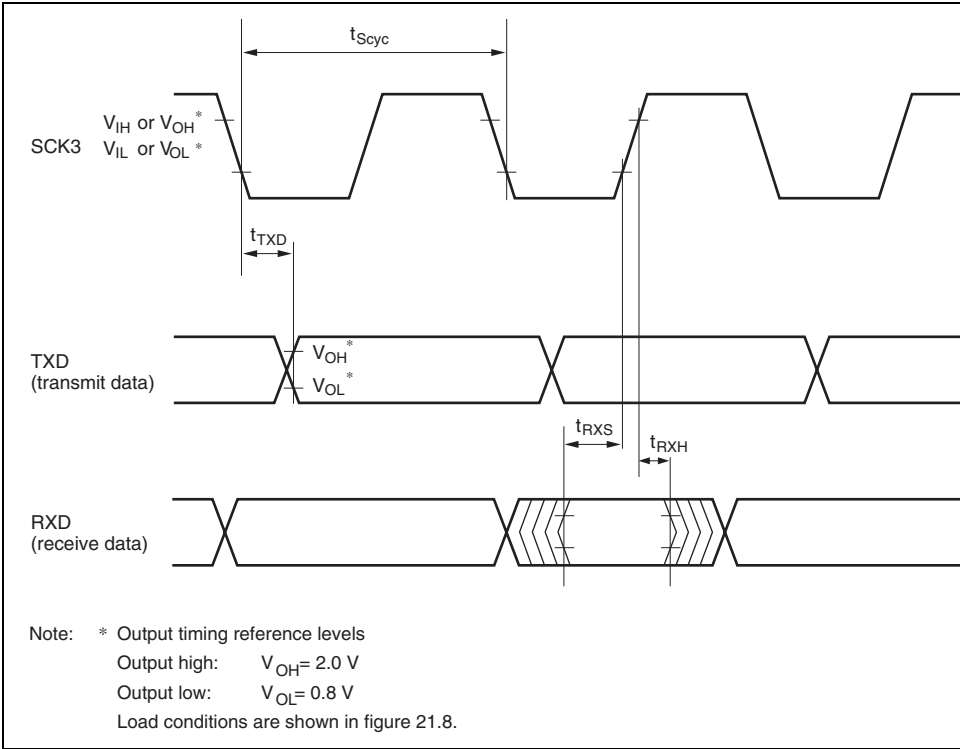
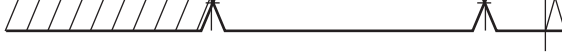


Figure 21.4 I<sup>2</sup>C Bus Interface Input/Output Timing



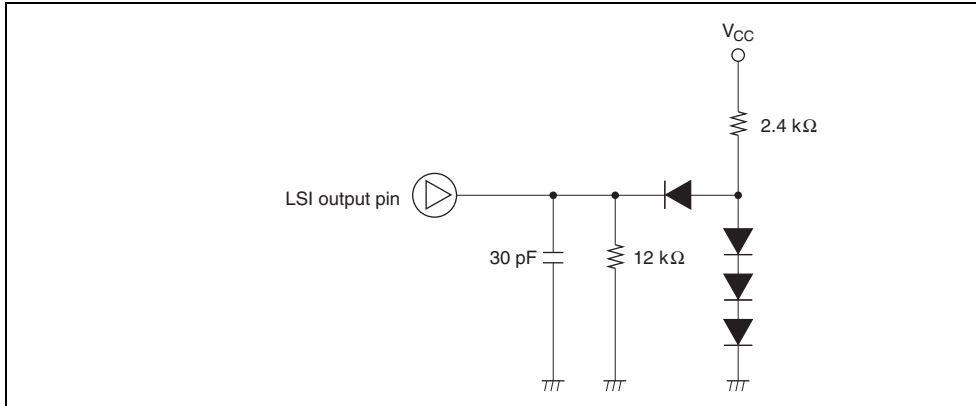
**Figure 21.6 SCI Input/Output Timing in Clocked Synchronous Mode**

(out)



**Figure 21.7 EEPROM Bus Timing**

## 21.5 Output Load Condition



**Figure 21.8 Output Load Circuit**



ERd	General destination register (address register or 32-bit register)
ERs	General source register (address register or 32-bit register)
ERn	General register (32-bit register)
(EAd)	Destination operand
(EAs)	Source operand
PC	Program counter
SP	Stack pointer
CCR	Condition-code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
C	C (carry) flag in CCR
disp	Displacement
→	Transfer from the operand on the left to the operand on the right, or transfer the state on the left to the state on the right
+	Addition of the operands on both sides
−	Subtraction of the operand on the right from the operand on the left
×	Multiplication of the operands on both sides
÷	Division of the operand on the left by the operand on the right
^	Logical AND of the operands on both sides
∨	Logical OR of the operands on both sides
⊕	Logical exclusive OR of the operands on both sides
¬	NOT (logical complement)
( ), < >	Contents of operand

Note: General registers include 8-bit registers (R0H to R7H and R0L to R7L) and 16-bit registers (R0 to R7 and E0 to E7).



MOV.B Rs, Rd	B		2						Rs8 → Rd8	—	—	↓	↓	0
MOV.B @ERs, Rd	B			4					@ERs → Rd8	—	—	↓	↓	0
MOV.B @(d:16, ERs), Rd	B				4				@(d:16, ERs) → Rd8	—	—	↓	↓	0
MOV.B @(d:24, ERs), Rd	B					8			@(d:24, ERs) → Rd8	—	—	↓	↓	0
MOV.B @ERs+, Rd	B						2		@ERs → Rd8 ERs32+1 → ERs32	—	—	↓	↓	0
MOV.B @aa:8, Rd	B						2		@aa:8 → Rd8	—	—	↓	↓	0
MOV.B @aa:16, Rd	B							4	@aa:16 → Rd8	—	—	↓	↓	0
MOV.B @aa:24, Rd	B							6	@aa:24 → Rd8	—	—	↓	↓	0
MOV.B Rs, @ERd	B		2						Rs8 → @ERd	—	—	↓	↓	0
MOV.B Rs, @(d:16, ERd)	B			4					Rs8 → @(d:16, ERd)	—	—	↓	↓	0
MOV.B Rs, @(d:24, ERd)	B				8				Rs8 → @(d:24, ERd)	—	—	↓	↓	0
MOV.B Rs, @-ERd	B					2			ERd32-1 → ERd32 Rs8 → @ERd	—	—	↓	↓	0
MOV.B Rs, @aa:8	B						2		Rs8 → @aa:8	—	—	↓	↓	0
MOV.B Rs, @aa:16	B							4	Rs8 → @aa:16	—	—	↓	↓	0
MOV.B Rs, @aa:24	B							6	Rs8 → @aa:24	—	—	↓	↓	0
MOV.W #xx:16, Rd	W	4							#xx:16 → Rd16	—	—	↓	↓	0
MOV.W Rs, Rd	W		2						Rs16 → Rd16	—	—	↓	↓	0
MOV.W @ERs, Rd	W			2					@ERs → Rd16	—	—	↓	↓	0
MOV.W @(d:16, ERs), Rd	W				4				@(d:16, ERs) → Rd16	—	—	↓	↓	0
MOV.W @(d:24, ERs), Rd	W					8			@(d:24, ERs) → Rd16	—	—	↓	↓	0
MOV.W @ERs+, Rd	W						2		@ERs → Rd16 ERs32+2 → @ERd32	—	—	↓	↓	0
MOV.W @aa:16, Rd	W							4	@aa:16 → Rd16	—	—	↓	↓	0
MOV.W @aa:24, Rd	W							6	@aa:24 → Rd16	—	—	↓	↓	0
MOV.W Rs, @ERd	W		2						Rs16 → @ERd	—	—	↓	↓	0
MOV.W Rs, @(d:16, ERd)	W			4					Rs16 → @(d:16, ERd)	—	—	↓	↓	0
MOV.W Rs, @(d:24, ERd)	W				8				Rs16 → @(d:24, ERd)	—	—	↓	↓	0

	MOV.L @ERs, ERd	L			4				@ERs → ERd32	—	—	↕	↕	0	—
	MOV.L @(d:16, ERs), ERd	L			6				@(d:16, ERs) → ERd32	—	—	↕	↕	0	—
	MOV.L @(d:24, ERs), ERd	L			10				@(d:24, ERs) → ERd32	—	—	↕	↕	0	—
	MOV.L @ERs+, ERd	L			4				@ERs → ERd32 ERs32+4 → ERs32	—	—	↕	↕	0	—
	MOV.L @aa:16, ERd	L			6				@aa:16 → ERd32	—	—	↕	↕	0	—
	MOV.L @aa:24, ERd	L			8				@aa:24 → ERd32	—	—	↕	↕	0	—
	MOV.L ERs, @ERd	L		4					ERs32 → @ERd	—	—	↕	↕	0	—
	MOV.L ERs, @(d:16, ERd)	L			6				ERs32 → @(d:16, ERd)	—	—	↕	↕	0	—
	MOV.L ERs, @(d:24, ERd)	L			10				ERs32 → @(d:24, ERd)	—	—	↕	↕	0	—
	MOV.L ERs, @-ERd	L			4				ERd32-4 → ERd32 ERs32 → @ERd	—	—	↕	↕	0	—
	MOV.L ERs, @aa:16	L			6				ERs32 → @aa:16	—	—	↕	↕	0	—
	MOV.L ERs, @aa:24	L			8				ERs32 → @aa:24	—	—	↕	↕	0	—
POP	POP.W Rn	W						2	@SP → Rn16 SP+2 → SP	—	—	↕	↕	0	—
	POP.L ERn	L						4	@SP → ERn32 SP+4 → SP	—	—	↕	↕	0	—
PUSH	PUSH.W Rn	W						2	SP-2 → SP Rn16 → @SP	—	—	↕	↕	0	—
	PUSH.L ERn	L						4	SP-4 → SP ERn32 → @SP	—	—	↕	↕	0	—
MOVFPE	MOVFPE @aa:16, Rd	B						4	Cannot be used in this LSI	Cannot be used in this LSI					
MOVTPPE	MOVTPPE Rs, @aa:16	B						4	Cannot be used in this LSI	Cannot be used in this LSI					

	ADD.W Rs, Rd	W	2										Rd16+Rs16 → Rd16	—	(1)	↓	↓	↓	↓
	ADD.L #xx:32, ERd	L	6										ERd32+#xx:32 → ERd32	—	(2)	↓	↓	↓	↓
	ADD.L ERs, ERd	L	2										ERd32+ERs32 → ERd32	—	(2)	↓	↓	↓	↓
ADDX	ADDX.B #xx:8, Rd	B	2										Rd8+#xx:8 +C → Rd8	—	↓	↓	↓	(3)	↓
	ADDX.B Rs, Rd	B	2										Rd8+Rs8 +C → Rd8	—	↓	↓	↓	(3)	↓
ADDS	ADDS.L #1, ERd	L	2										ERd32+1 → ERd32	—	—	—	—	—	—
	ADDS.L #2, ERd	L	2										ERd32+2 → ERd32	—	—	—	—	—	—
	ADDS.L #4, ERd	L	2										ERd32+4 → ERd32	—	—	—	—	—	—
INC	INC.B Rd	B	2										Rd8+1 → Rd8	—	—	↓	↓	↓	↓
	INC.W #1, Rd	W	2										Rd16+1 → Rd16	—	—	↓	↓	↓	↓
	INC.W #2, Rd	W	2										Rd16+2 → Rd16	—	—	↓	↓	↓	↓
	INC.L #1, ERd	L	2										ERd32+1 → ERd32	—	—	↓	↓	↓	↓
	INC.L #2, ERd	L	2										ERd32+2 → ERd32	—	—	↓	↓	↓	↓
DAA	DAA Rd	B	2										Rd8 decimal adjust → Rd8	—	*	↓	↓	↓	*
SUB	SUB.B Rs, Rd	B	2										Rd8-Rs8 → Rd8	—	↓	↓	↓	↓	↓
	SUB.W #xx:16, Rd	W	4										Rd16-#xx:16 → Rd16	—	(1)	↓	↓	↓	↓
	SUB.W Rs, Rd	W	2										Rd16-Rs16 → Rd16	—	(1)	↓	↓	↓	↓
	SUB.L #xx:32, ERd	L	6										ERd32-#xx:32 → ERd32	—	(2)	↓	↓	↓	↓
	SUB.L ERs, ERd	L	2										ERd32-ERs32 → ERd32	—	(2)	↓	↓	↓	↓
SUBX	SUBX.B #xx:8, Rd	B	2										Rd8-#xx:8-C → Rd8	—	↓	↓	↓	(3)	↓
	SUBX.B Rs, Rd	B	2										Rd8-Rs8-C → Rd8	—	↓	↓	↓	(3)	↓
SUBS	SUBS.L #1, ERd	L	2										ERd32-1 → ERd32	—	—	—	—	—	—
	SUBS.L #2, ERd	L	2										ERd32-2 → ERd32	—	—	—	—	—	—
	SUBS.L #4, ERd	L	2										ERd32-4 → ERd32	—	—	—	—	—	—
DEC	DEC.B Rd	B	2										Rd8-1 → Rd8	—	—	↓	↓	↓	↓
	DEC.W #1, Rd	W	2										Rd16-1 → Rd16	—	—	↓	↓	↓	↓
	DEC.W #2, Rd	W	2										Rd16-2 → Rd16	—	—	↓	↓	↓	↓

	MULXU. W Rs, ERd	W	2															Rd16 × Rs16 → ERd32 (unsigned multiplication)	—	—	—	—	—	—
MULXS	MULXS. B Rs, Rd	B	4															Rd8 × Rs8 → Rd16 (signed multiplication)	—	—	↕	↕	—	—
	MULXS. W Rs, ERd	W	4															Rd16 × Rs16 → ERd32 (signed multiplication)	—	—	↕	↕	—	—
DIVXU	DIVXU. B Rs, Rd	B	2															Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (unsigned division)	—	—	(6)	(7)	—	—
	DIVXU. W Rs, ERd	W	2															ERd32 ÷ Rs16 → ERd32 (Ed: remainder, Rd: quotient) (unsigned division)	—	—	(6)	(7)	—	—
DIVXS	DIVXS. B Rs, Rd	B	4															Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (signed division)	—	—	(8)	(7)	—	—
	DIVXS. W Rs, ERd	W	4															ERd32 ÷ Rs16 → ERd32 (Ed: remainder, Rd: quotient) (signed division)	—	—	(8)	(7)	—	—
CMP	CMP.B #xx:8, Rd	B	2															Rd8-#xx:8	—	↕	↕	↕	↕	↕
	CMP.B Rs, Rd	B	2															Rd8-Rs8	—	↕	↕	↕	↕	↕
	CMP.W #xx:16, Rd	W	4															Rd16-#xx:16	—	(1)	↕	↕	↕	↕
	CMP.W Rs, Rd	W	2															Rd16-Rs16	—	(1)	↕	↕	↕	↕
	CMP.L #xx:32, ERd	L	6															ERd32-#xx:32	—	(2)	↕	↕	↕	↕
	CMP.L ERs, ERd	L	2															ERd32-ERs32	—	(2)	↕	↕	↕	↕

	EXTS	EXTS.W Rd	W	2										( $\langle$ bit 7 $\rangle$ of Rd16) → ( $\langle$ bits 15 to 8 $\rangle$ of Rd16)	—	—	↕	↕	0
		EXTS.L ERd	L	2										( $\langle$ bit 15 $\rangle$ of ERd32) → ( $\langle$ bits 31 to 16 $\rangle$ of ERd32)	—	—	↕	↕	0

	AND.W Hs, Rd	W	2															Rd16∧Hs16 → Rd16	—	—	↓	↓	0	—
	AND.L #xx:32, ERd	L	6															ERd32∧#xx:32 → ERd32	—	—	↓	↓	0	—
	AND.L ERs, ERd	L	4															ERd32∧ERs32 → ERd32	—	—	↓	↓	0	—
OR	OR.B #xx:8, Rd	B	2															Rd8#xx:8 → Rd8	—	—	↓	↓	0	—
	OR.B Rs, Rd	B	2															Rd8Rs8 → Rd8	—	—	↓	↓	0	—
	OR.W #xx:16, Rd	W	4															Rd16#xx:16 → Rd16	—	—	↓	↓	0	—
	OR.W Rs, Rd	W	2															Rd16Rs16 → Rd16	—	—	↓	↓	0	—
	OR.L #xx:32, ERd	L	6															ERd32#xx:32 → ERd32	—	—	↓	↓	0	—
	OR.L ERs, ERd	L	4															ERd32ERs32 → ERd32	—	—	↓	↓	0	—
XOR	XOR.B #xx:8, Rd	B	2															Rd8⊕#xx:8 → Rd8	—	—	↓	↓	0	—
	XOR.B Rs, Rd	B	2															Rd8⊕Rs8 → Rd8	—	—	↓	↓	0	—
	XOR.W #xx:16, Rd	W	4															Rd16⊕#xx:16 → Rd16	—	—	↓	↓	0	—
	XOR.W Rs, Rd	W	2															Rd16⊕Rs16 → Rd16	—	—	↓	↓	0	—
	XOR.L #xx:32, ERd	L	6															ERd32⊕#xx:32 → ERd32	—	—	↓	↓	0	—
	XOR.L ERs, ERd	L	4															ERd32⊕ERs32 → ERd32	—	—	↓	↓	0	—
NOT	NOT.B Rd	B	2															¬ Rd8 → Rd8	—	—	↓	↓	0	—
	NOT.W Rd	W	2															¬ Rd16 → Rd16	—	—	↓	↓	0	—
	NOT.L ERd	L	2															¬ Rd32 → Rd32	—	—	↓	↓	0	—



SHAR	SHAR.B Rd	B	2										—	—	↓	↓	0
	SHAR.W Rd	W	2										—	—	↓	↓	0
	SHAR.L ERd	L	2										—	—	↓	↓	0
SHLL	SHLL.B Rd	B	2										—	—	↓	↓	0
	SHLL.W Rd	W	2										—	—	↓	↓	0
	SHLL.L ERd	L	2										—	—	↓	↓	0
SHLR	SHLR.B Rd	B	2										—	—	↓	↓	0
	SHLR.W Rd	W	2										—	—	↓	↓	0
	SHLR.L ERd	L	2										—	—	↓	↓	0
ROTXL	ROTXL.B Rd	B	2										—	—	↓	↓	0
	ROTXL.W Rd	W	2										—	—	↓	↓	0
	ROTXL.L ERd	L	2										—	—	↓	↓	0
ROTXR	ROTXR.B Rd	B	2										—	—	↓	↓	0
	ROTXR.W Rd	W	2										—	—	↓	↓	0
	ROTXR.L ERd	L	2										—	—	↓	↓	0
ROTL	ROTL.B Rd	B	2										—	—	↓	↓	0
	ROTL.W Rd	W	2										—	—	↓	↓	0
	ROTL.L ERd	L	2										—	—	↓	↓	0
ROTR	ROTR.B Rd	B	2										—	—	↓	↓	0
	ROTR.W Rd	W	2										—	—	↓	↓	0
	ROTR.L ERd	L	2										—	—	↓	↓	0

	BSET Rn, Rd	B	2					(Rn8 of Rd8) ← 1	—	—	—	—	—	—
	BSET Rn, @ERd	B		4				(Rn8 of @ERd) ← 1	—	—	—	—	—	—
	BSET Rn, @aa:8	B				4		(Rn8 of @aa:8) ← 1	—	—	—	—	—	—
BCLR	BCLR #xx:3, Rd	B	2					(#xx:3 of Rd8) ← 0	—	—	—	—	—	—
	BCLR #xx:3, @ERd	B		4				(#xx:3 of @ERd) ← 0	—	—	—	—	—	—
	BCLR #xx:3, @aa:8	B				4		(#xx:3 of @aa:8) ← 0	—	—	—	—	—	—
	BCLR Rn, Rd	B	2					(Rn8 of Rd8) ← 0	—	—	—	—	—	—
	BCLR Rn, @ERd	B		4				(Rn8 of @ERd) ← 0	—	—	—	—	—	—
	BCLR Rn, @aa:8	B					4	(Rn8 of @aa:8) ← 0	—	—	—	—	—	—
BNOT	BNOT #xx:3, Rd	B	2					(#xx:3 of Rd8) ← ¬ (#xx:3 of Rd8)	—	—	—	—	—	—
	BNOT #xx:3, @ERd	B		4				(#xx:3 of @ERd) ← ¬ (#xx:3 of @ERd)	—	—	—	—	—	—
	BNOT #xx:3, @aa:8	B				4		(#xx:3 of @aa:8) ← ¬ (#xx:3 of @aa:8)	—	—	—	—	—	—
	BNOT Rn, Rd	B	2					(Rn8 of Rd8) ← ¬ (Rn8 of Rd8)	—	—	—	—	—	—
	BNOT Rn, @ERd	B		4				(Rn8 of @ERd) ← ¬ (Rn8 of @ERd)	—	—	—	—	—	—
	BNOT Rn, @aa:8	B					4	(Rn8 of @aa:8) ← ¬ (Rn8 of @aa:8)	—	—	—	—	—	—
BTST	BTST #xx:3, Rd	B	2					¬ (#xx:3 of Rd8) → Z	—	—	—	↑	—	—
	BTST #xx:3, @ERd	B		4				¬ (#xx:3 of @ERd) → Z	—	—	—	↑	—	—
	BTST #xx:3, @aa:8	B				4		¬ (#xx:3 of @aa:8) → Z	—	—	—	↑	—	—
	BTST Rn, Rd	B	2					¬ (Rn8 of @Rd8) → Z	—	—	—	↑	—	—
	BTST Rn, @ERd	B		4				¬ (Rn8 of @ERd) → Z	—	—	—	↑	—	—
	BTST Rn, @aa:8	B					4	¬ (Rn8 of @aa:8) → Z	—	—	—	↑	—	—
BLD	BLD #xx:3, Rd	B	2					(#xx:3 of Rd8) → C	—	—	—	—	—	—

BST	BST #xx:3, Rd	B	4				$C \rightarrow (\#xx:3 \text{ of Rd})$	—	—	—	—
	BST #xx:3, @ERd	B				4	$C \rightarrow (\#xx:3 \text{ of @ERd24})$	—	—	—	—
BIST	BIST #xx:3, Rd	B	2				$\neg C \rightarrow (\#xx:3 \text{ of Rd8})$	—	—	—	—
	BIST #xx:3, @ERd	B				4	$\neg C \rightarrow (\#xx:3 \text{ of @ERd24})$	—	—	—	—
	BIST #xx:3, @aa:8	B				4	$\neg C \rightarrow (\#xx:3 \text{ of @aa:8})$	—	—	—	—
BAND	BAND #xx:3, Rd	B	2				$C \wedge (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BAND #xx:3, @ERd	B				4	$C \wedge (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BAND #xx:3, @aa:8	B				4	$C \wedge (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIAND	BIAND #xx:3, Rd	B	2				$C \wedge \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIAND #xx:3, @ERd	B				4	$C \wedge \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIAND #xx:3, @aa:8	B				4	$C \wedge \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BOR	BOR #xx:3, Rd	B	2				$C \vee (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BOR #xx:3, @ERd	B				4	$C \vee (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BOR #xx:3, @aa:8	B				4	$C \vee (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIOR	BIOR #xx:3, Rd	B	2				$C \vee \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIOR #xx:3, @ERd	B				4	$C \vee \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIOR #xx:3, @aa:8	B				4	$C \vee \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BXOR	BXOR #xx:3, Rd	B	2				$C \oplus (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BXOR #xx:3, @ERd	B				4	$C \oplus (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BXOR #xx:3, @aa:8	B				4	$C \oplus (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIXOR	BIXOR #xx:3, Rd	B	2				$C \oplus \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIXOR #xx:3, @ERd	B				4	$C \oplus \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIXOR #xx:3, @aa:8	B				4	$C \oplus \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—



	JSR @ERn	—							2						PC → @-SP PC ← ERn	—	—	—	—	—
	JSR @aa:24	—								4					PC → @-SP PC ← aa:24	—	—	—	—	—
	JSR @ @aa:8	—											2		PC → @-SP PC ← @aa:8	—	—	—	—	—
RTS	RTS	—												2	PC ← @SP+	—	—	—	—	—

RTE	RTE	—											CCR ← @SP+ PC ← @SP+	↓	↓	↓	↓	↓
SLEEP	SLEEP	—											Transition to power-down state	—	—	—	—	—
LDC	LDC #xx:8, CCR	B	2										#xx:8 → CCR	↑	↓	↑	↓	↑
	LDC Rs, CCR	B	2										Rs8 → CCR	↑	↓	↑	↓	↑
	LDC @ERs, CCR	W		4									@ERs → CCR	↑	↓	↑	↓	↑
	LDC @(d:16, ERs), CCR	W			6								@(d:16, ERs) → CCR	↑	↓	↑	↓	↑
	LDC @(d:24, ERs), CCR	W				10							@(d:24, ERs) → CCR	↑	↓	↑	↓	↑
	LDC @ERs+, CCR	W					4						@ERs → CCR ERs32+2 → ERs32	↑	↓	↑	↓	↑
	LDC @aa:16, CCR	W						6					@aa:16 → CCR	↑	↓	↑	↓	↑
LDC @aa:24, CCR	W							8				@aa:24 → CCR	↑	↓	↑	↓	↑	
STC	STC CCR, Rd	B	2										CCR → Rd8	—	—	—	—	—
	STC CCR, @ERd	W		4									CCR → @ERd	—	—	—	—	—
	STC CCR, @(d:16, ERd)	W			6								CCR → @(d:16, ERd)	—	—	—	—	—
	STC CCR, @(d:24, ERd)	W				10							CCR → @(d:24, ERd)	—	—	—	—	—
	STC CCR, @-ERd	W						4					ERd32-2 → ERd32 CCR → @ERd	—	—	—	—	—
	STC CCR, @aa:16	W							6				CCR → @aa:16	—	—	—	—	—
STC CCR, @aa:24	W								8			CCR → @aa:24	—	—	—	—	—	
ANDC	ANDC #xx:8, CCR	B	2										CCR^#xx:8 → CCR	↑	↓	↑	↓	↑
ORC	ORC #xx:8, CCR	B	2										CCRv#xx:8 → CCR	↑	↓	↑	↓	↑
XORC	XORC #xx:8, CCR	B	2										CCR@#xx:8 → CCR	↑	↓	↑	↓	↑
NOP	NOP	—									2		PC ← PC+2	—	—	—	—	—



Instruction code: 

1st byte		2nd byte	
AH	AL	BH	BL

AL	0	1	2	3	4	5	6	7	8	9	A	B	C
AH	0	1	2	3	4	5	6	7	8	9	A	B	C
	NOP	Table A-2 (2)	STC	LDC	ORC	XORC	ANDC	LDC	ADD		Table A-2 (2)	Table A-2 (2)	Table A-2 (2)
	Table A-2 (2)	Table A-2 (2)	Table A-2 (2)	Table A-2 (2)	OR.B	XOR.B	AND.B	Table A-2 (2)	SUB		Table A-2 (2)	Table A-2 (2)	Table A-2 (2)
2	MOV.B												
3	MOV.B												
4	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI	BGE
5	MULXU	DIVXU	MULXU	DIVXU	RTS	BSR	RTE	TRAPA	Table A-2 (2)		JMP		BSS
6	BSET	BNOT	BCLR	BTST	OR	XOR	AND	BST	BIST	MOV			
7					BOR	BXOR	BAND	BBD	BBD	MOV	Table A-2 (2)	Table A-2 (2)	EEMOV
8	ADD												
9	ADDX												
A	CMP												
B	SUBX												
C	OR												
D	XOR												
E	AND												



Instruction code: 

1st byte	2nd byte
AH AL	BH BL

BH / AH \ AL	0	1	2	3	4	5	6	7	8	9	A	B
01	MOV				LDC/STC				SLEEP			
0A	INC											
0B	ADDS					INC		INC		ADDS		
0F	DAA											
10	SHLL			SHLL						SHAL		SHAL
11	SHLR			SHLR						SHAR		SHAR
12	ROTXL			ROTXL						ROTL		ROTL
13	ROTXR			ROTXR						ROTR		ROTR
17	NOT			NOT				EXTU		NEG		NEG
1A	DEC											
1B	SUBS					DEC		DEC				SUB
1F	DAS											
58	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI
79	MOV	ADD	OMP	SUB	OR	XOR	AND					

Instruction code:

1st byte		2nd byte		3rd byte		4th byte	
AH	AL	BH	BL	CH	CL	DH	DL

Instruction when n = 8:

CL AH ALBH BLCH	0	1	2	3	4	5	6	7	8	9	A	B
	MULXS		DIVXS		OR		XOR		AND			
01406	Instruction when n = 8											
01C05	MULXS		MULXS									
01D05		DIVXS		DIVXS								
01F06					OR	XOR	AND					
7C06*1				BTST								
7C07*1				BTST	BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7D06*1	BSET		BNOT									
7D07*1	BSET		BNOT									
7Eaa6*2				BTST								
7Eaa7*2				BTST	BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7Faa6*2	BSET		BNOT									
7Faa7*2	BSET		BNOT									

Instruction when n = 9:

CL AH ALBH BLCH	0	1	2	3	4	5	6	7	8	9	A	B
	MULXS		DIVXS		OR		XOR		AND		LDC	
01406	Instruction when n = 9											
01C05	MULXS		MULXS									
01D05		DIVXS		DIVXS								
01F06					OR	XOR	AND					
7C06*1				BTST								
7C07*1				BTST	BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7D06*1	BSET		BNOT									
7D07*1	BSET		BNOT									
7Eaa6*2				BTST								
7Eaa7*2				BTST	BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7Faa6*2	BSET		BNOT									
7Faa7*2	BSET		BNOT									

Notes: 1. r is the register designation field.  
 2. aa is the absolute address field.

BSET #0, @FF00

From table A.4:

$$I = L = 2, \quad J = K = M = N = 0$$

From table A.3:

$$S_1 = 2, \quad S_L = 2$$

Number of states required for execution =  $2 \times 2 + 2 \times 2 = 8$

When instruction is fetched from on-chip ROM, branch address is read from on-chip ROM. on-chip RAM is used for stack area.

JSR @@ 30

From table A.4:

$$I = 2, \quad J = K = 1, \quad L = M = N = 0$$

From table A.3:

$$S_1 = S_j = S_k = 2$$

Number of states required for execution =  $2 \times 2 + 1 \times 2 + 1 \times 2 = 8$

Note: \* Depends on which on-chip peripheral module is accessed. See section 20.1, F  
Addresses (Address Order).

ADDS	ADDS #1/2/4, ERd	1	
ADDX	ADDX #xx:8, Rd	1	
	ADDX Rs, Rd	1	
AND	AND.B #xx:8, Rd	1	
	AND.B Rs, Rd	1	
	AND.W #xx:16, Rd	2	
	AND.W Rs, Rd	1	
	AND.L #xx:32, ERd	3	
	AND.L ERs, ERd	2	
ANDC	ANDC #xx:8, CCR	1	
BAND	BAND #xx:3, Rd	1	
	BAND #xx:3, @ERd	2	1
	BAND #xx:3, @aa:8	2	1
Bcc	BRA d:8 (BT d:8)	2	
	BRN d:8 (BF d:8)	2	
	BHI d:8	2	
	BLS d:8	2	
	BCC d:8 (BHS d:8)	2	
	BCS d:8 (BLO d:8)	2	
	BNE d:8	2	
	BEQ d:8	2	
	BVC d:8	2	
	BVS d:8	2	
	BPL d:8	2	
	BMI d:8	2	
	BGE d:8	2	

	BCC d:16(BHS d:16)	2	
	BCS d:16(BLO d:16)	2	
	BNE d:16	2	
	BEQ d:16	2	
	BVC d:16	2	
	BVS d:16	2	
	BPL d:16	2	
	BMI d:16	2	
	BGE d:16	2	
	BLT d:16	2	
	BGT d:16	2	
	BLE d:16	2	
<hr/>			
BCLR	BCLR #xx:3, Rd	1	
	BCLR #xx:3, @ERd	2	2
	BCLR #xx:3, @aa:8	2	2
	BCLR Rn, Rd	1	
	BCLR Rn, @ERd	2	2
	BCLR Rn, @aa:8	2	2
<hr/>			
BIAND	BIAND #xx:3, Rd	1	
	BIAND #xx:3, @ERd	2	1
	BIAND #xx:3, @aa:8	2	1
<hr/>			
BILD	BILD #xx:3, Rd	1	
	BILD #xx:3, @ERd	2	1
	BILD #xx:3, @aa:8	2	1

	BIXOR #xx:3, @ERd	2	1
	BIXOR #xx:3, @aa:8	2	1
BLD	BLD #xx:3, Rd	1	
	BLD #xx:3, @ERd	2	1
	BLD #xx:3, @aa:8	2	1
BNOT	BNOT #xx:3, Rd	1	
	BNOT #xx:3, @ERd	2	2
	BNOT #xx:3, @aa:8	2	2
	BNOT Rn, Rd	1	
	BNOT Rn, @ERd	2	2
	BNOT Rn, @aa:8	2	2
BOR	BOR #xx:3, Rd	1	
	BOR #xx:3, @ERd	2	1
	BOR #xx:3, @aa:8	2	1
BSET	BSET #xx:3, Rd	1	
	BSET #xx:3, @ERd	2	2
	BSET #xx:3, @aa:8	2	2
	BSET Rn, Rd	1	
	BSET Rn, @ERd	2	2
	BSET Rn, @aa:8	2	2
BSR	BSR d:8	2	1
	BSR d:16	2	1
BST	BST #xx:3, Rd	1	
	BST #xx:3, @ERd	2	2
	BST #xx:3, @aa:8	2	2

	BXOR #xx:3, @ERd	2	1
	BXOR #xx:3, @aa:8	2	1
CMP	CMP.B #xx:8, Rd	1	
	CMP.B Rs, Rd	1	
	CMP.W #xx:16, Rd	2	
	CMP.W Rs, Rd	1	
	CMP.L #xx:32, ERd	3	
	CMP.L ERs, ERd	1	
DAA	DAA Rd	1	
DAS	DAS Rd	1	
DEC	DEC.B Rd	1	
	DEC.W #1/2, Rd	1	
	DEC.L #1/2, ERd	1	
DIVXS	DIVXS.B Rs, Rd	2	
	DIVXS.W Rs, ERd	2	
DIVXU	DIVXU.B Rs, Rd	1	
	DIVXU.W Rs, ERd	1	
EEPMOV	EEPMOV.B	2	$2n+2^{*1}$
	EEPMOV.W	2	$2n+2^{*1}$
EXTS	EXTS.W Rd	1	
	EXTS.L ERd	1	
EXTU	EXTU.W Rd	1	
	EXTU.L ERd	1	



	JSR @aa:24	2		1
	JSR @aa:8	2	1	1
LDC	LDC #xx:8, CCR	1		
	LDC Rs, CCR	1		
	LDC@ERs, CCR	2		1
	LDC@(d:16, ERs), CCR	3		1
	LDC@(d:24,ERs), CCR	5		1
	LDC@ERs+, CCR	2		1
	LDC@aa:16, CCR	3		1
	LDC@aa:24, CCR	4		1
MOV	MOV.B #xx:8, Rd	1		
	MOV.B Rs, Rd	1		
	MOV.B @ERs, Rd	1		1
	MOV.B @(d:16, ERs), Rd	2		1
	MOV.B @(d:24, ERs), Rd	4		1
	MOV.B @ERs+, Rd	1		1
	MOV.B @aa:8, Rd	1		1
	MOV.B @aa:16, Rd	2		1
	MOV.B @aa:24, Rd	3		1
	MOV.B Rs, @ERd	1		1
	MOV.B Rs, @(d:16, ERd)	2		1
	MOV.B Rs, @(d:24, ERd)	4		1
	MOV.B Rs, @-ERd	1		1
	MOV.B Rs, @aa:8	1		1

	MOV.W @aa:16, Rd	2	1
	MOV.W @aa:24, Rd	3	1
	MOV.W Rs, @ERd	1	1
	MOV.W Rs, @(d:16,ERd)	2	1
	MOV.W Rs, @(d:24,ERd)	4	1
MOV	MOV.W Rs, @-ERd	1	1
	MOV.W Rs, @aa:16	2	1
	MOV.W Rs, @aa:24	3	1
	MOV.L #xx:32, ERd	3	
	MOV.L ERs, ERd	1	
	MOV.L @ERs, ERd	2	2
	MOV.L @(d:16,ERs), ERd	3	2
	MOV.L @(d:24,ERs), ERd	5	2
	MOV.L @ERs+, ERd	2	2
	MOV.L @aa:16, ERd	3	2
	MOV.L @aa:24, ERd	4	2
	MOV.L ERs, @ERd	2	2
	MOV.L ERs, @(d:16,ERd)	3	2
	MOV.L ERs, @(d:24,ERd)	5	2
	MOV.L ERs, @-ERd	2	2
	MOV.L ERs, @aa:16	3	2
	MOV.L ERs, @aa:24	4	2
MOVFP	MOVFP @aa:16, Rd* <sup>2</sup>	2	1
MOVTP	MOVTP Rs, @aa:16* <sup>2</sup>	2	1

NOP	NOP	1	
NOT	NOT.B Rd	1	
	NOT.W Rd	1	
	NOT.L ERd	1	
OR	OR.B #xx:8, Rd	1	
	OR.B Rs, Rd	1	
	OR.W #xx:16, Rd	2	
	OR.W Rs, Rd	1	
	OR.L #xx:32, ERd	3	
	OR.L ERs, ERd	2	
ORC	ORC #xx:8, CCR	1	
POP	POP.W Rn	1	1
	POP.L ERn	2	2
PUSH	PUSH.W Rn	1	1
	PUSH.L ERn	2	2
ROTL	ROTL.B Rd	1	
	ROTL.W Rd	1	
	ROTL.L ERd	1	
ROTR	ROTR.B Rd	1	
	ROTR.W Rd	1	
	ROTR.L ERd	1	
ROTXL	ROTXL.B Rd	1	
	ROTXL.W Rd	1	
	ROTXL.L ERd	1	

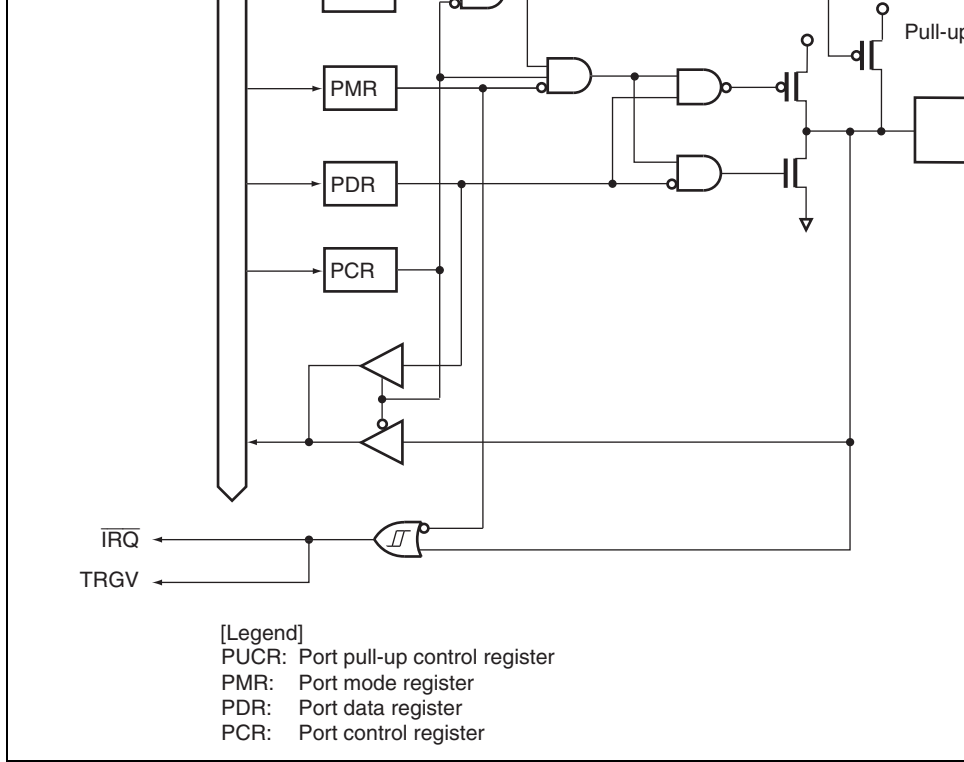
	SHAL.L ERd	1	
SHAR	SHAR.B Rd	1	
	SHAR.W Rd	1	
	SHAR.L ERd	1	
SHLL	SHLL.B Rd	1	
	SHLL.W Rd	1	
	SHLL.L ERd	1	
SHLR	SHLR.B Rd	1	
	SHLR.W Rd	1	
	SHLR.L ERd	1	
SLEEP	SLEEP	1	
STC	STC CCR, Rd	1	
	STC CCR, @ERd	2	1
	STC CCR, @(d:16,ERd)	3	1
	STC CCR, @(d:24,ERd)	5	1
	STC CCR, @-ERd	2	1
	STC CCR, @aa:16	3	1
	STC CCR, @aa:24	4	1
SUB	SUB.B Rs, Rd	1	
	SUB.W #xx:16, Rd	2	
	SUB.W Rs, Rd	1	
	SUB.L #xx:32, ERd	3	
	SUB.L ERs, ERd	1	
SUBS	SUBS #1/2/4, ERd	1	

	XOR.L #xx:32, ERd	3
	XOR.L ERs, ERd	2
XORC	XORC #xx:8, CCR	1

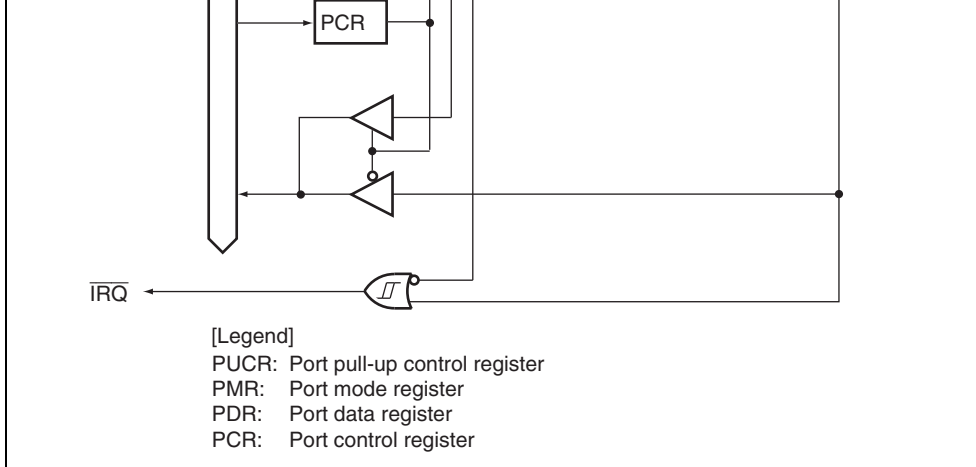
---

- Notes:
1. n: Specified value in R4L. The source and destination operands are accessed n times respectively.
  2. It can not be used in this LSI.

	MOVFPPE, MOVTPPE	—	—	—	—	—	—	—	—	—	—	—	—	—	—
Arithmetic operations	ADD, CMP	BWL	BWL	—	—	—	—	—	—	—	—	—	—	—	—
	SUB	WL	BWL	—	—	—	—	—	—	—	—	—	—	—	—
	ADDX, SUBX	B	B	—	—	—	—	—	—	—	—	—	—	—	—
	ADDS, SUBS	—	L	—	—	—	—	—	—	—	—	—	—	—	—
	INC, DEC	—	BWL	—	—	—	—	—	—	—	—	—	—	—	—
	DAA, DAS	—	B	—	—	—	—	—	—	—	—	—	—	—	—
	MULXU, MULXS, DIVXU, DIVXS	—	BW	—	—	—	—	—	—	—	—	—	—	—	—
	NEG	—	BWL	—	—	—	—	—	—	—	—	—	—	—	—
EXTU, EXTS	—	WL	—	—	—	—	—	—	—	—	—	—	—	—	
Logical operations	AND, OR, XOR	—	BWL	—	—	—	—	—	—	—	—	—	—	—	—
	NOT	—	BWL	—	—	—	—	—	—	—	—	—	—	—	—
Shift operations		—	BWL	—	—	—	—	—	—	—	—	—	—	—	—
Bit manipulations		—	B	B	—	—	—	B	—	—	—	—	—	—	—
Branching instructions	BCC, BSR	—	—	—	—	—	—	—	—	—	—	—	—	—	—
	JMP, JSR	—	—	○	—	—	—	—	—	—	○	○	—	—	—
	RTS	—	—	—	—	—	—	—	—	○	—	—	○	—	—
System control instructions	TRAPA	—	—	—	—	—	—	—	—	—	—	—	—	—	○
	RTE	—	—	—	—	—	—	—	—	—	—	—	—	—	○
	SLEEP	—	—	—	—	—	—	—	—	—	—	—	—	—	○
	LDC	B	B	W	W	W	W	—	W	W	—	—	—	—	○
	STC	—	B	W	W	W	W	—	W	W	—	—	—	—	—
	ANDC, ORC, XORC	B	—	—	—	—	—	—	—	—	—	—	—	—	—
	NOP	—	—	—	—	—	—	—	—	—	—	—	—	—	○
Block data transfer instructions	—	—	—	—	—	—	—	—	—	—	—	—	—	—	BW

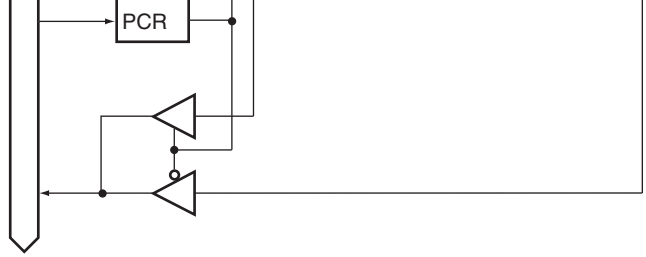


**Figure B.1 Port 1 Block Diagram (P17)**



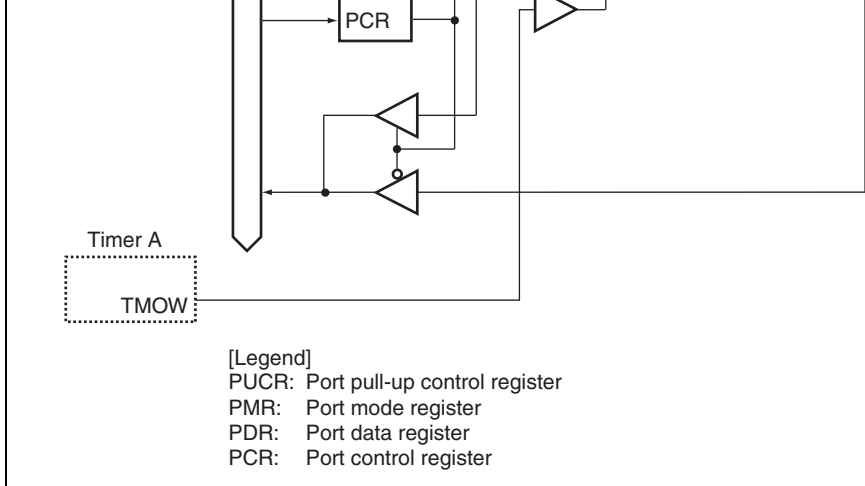
**Figure B.2 Port 1 Block Diagram (P16 to P14)**



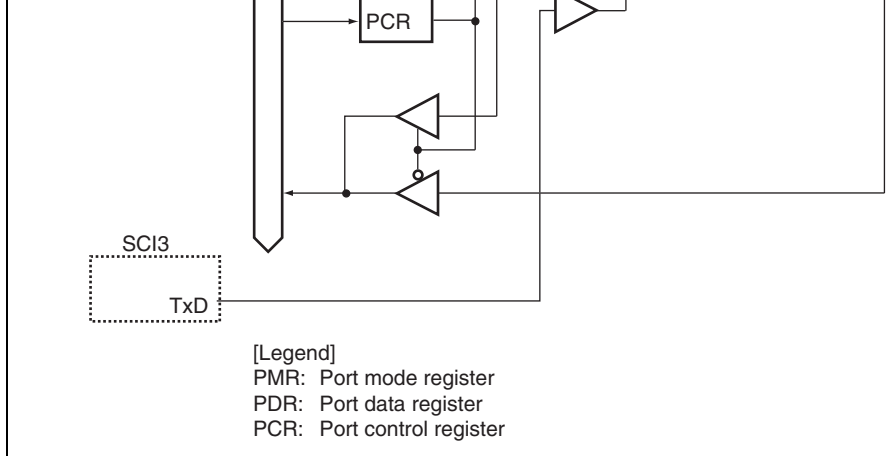


[Legend]  
 PUCR: Port pull-up control register  
 PDR: Port data register  
 PCR: Port control register

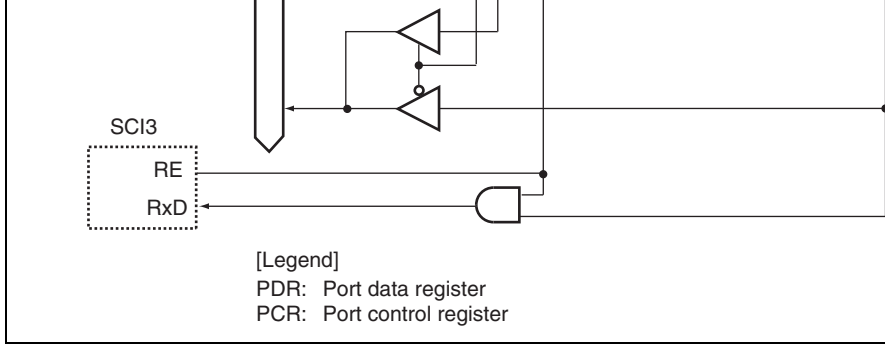
**Figure B.3 Port 1 Block Diagram (P12, P11)**



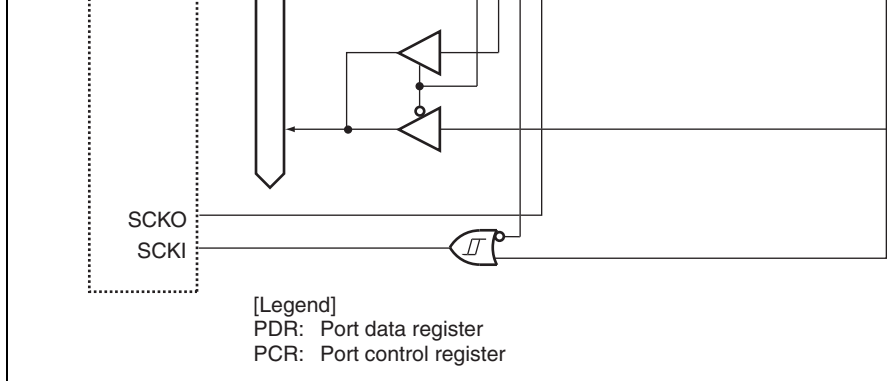
**Figure B.4 Port 1 Block Diagram (P10)**



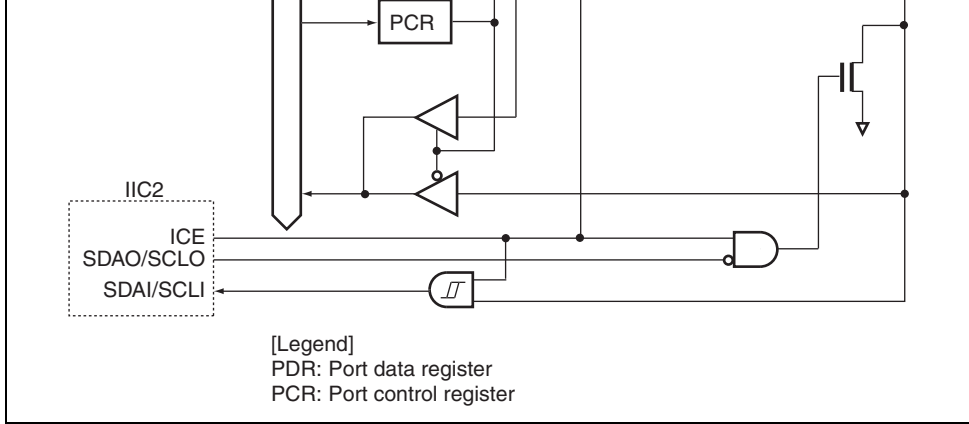
**Figure B.5 Port 2 Block Diagram (P22)**



**Figure B.6 Port 2 Block Diagram (P21)**

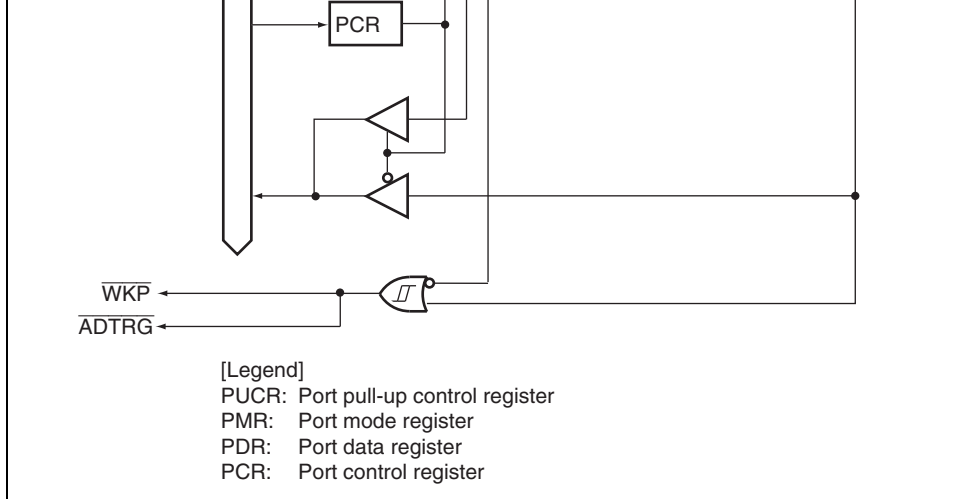


**Figure B.7 Port 2 Block Diagram (P20)**

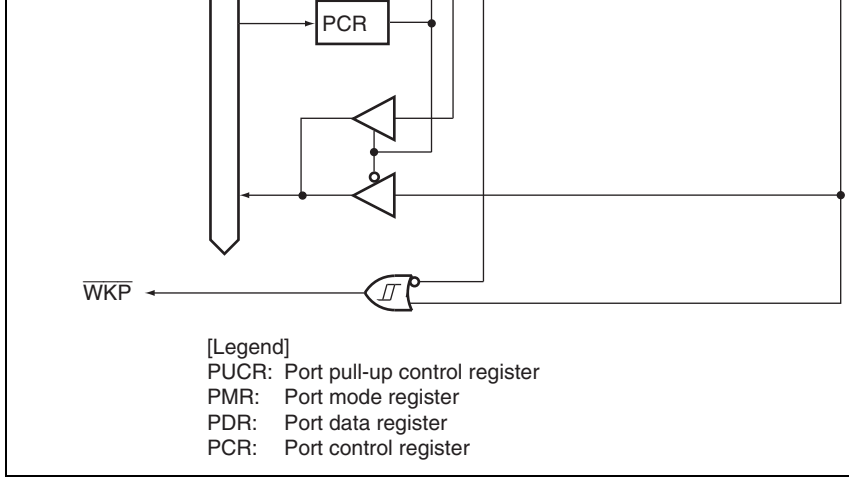


**Figure B.8 Port 5 Block Diagram (P57, P56)\***

Note: \* This diagram is applied to the SCL and SDA pins in the H8/3694N.

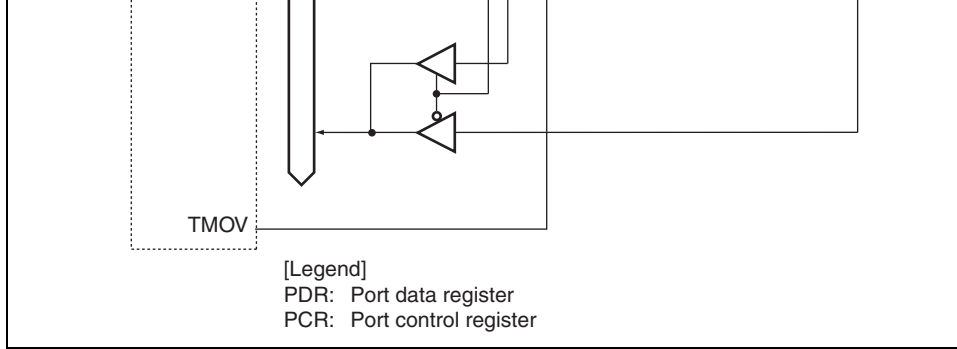


**Figure B.9 Port 5 Block Diagram (P55)**

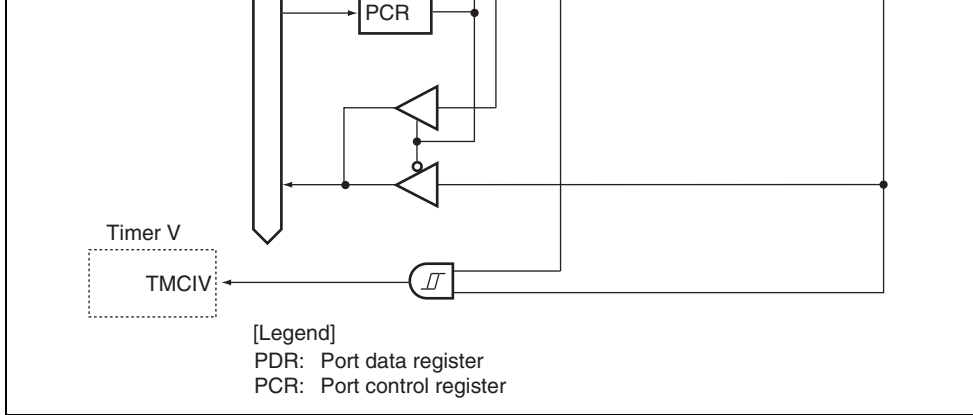


**Figure B.10 Port 5 Block Diagram (P54 to P50)**

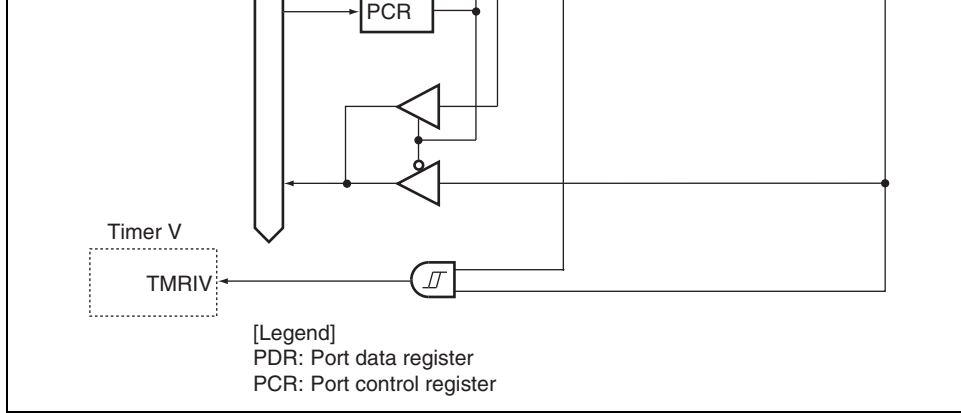




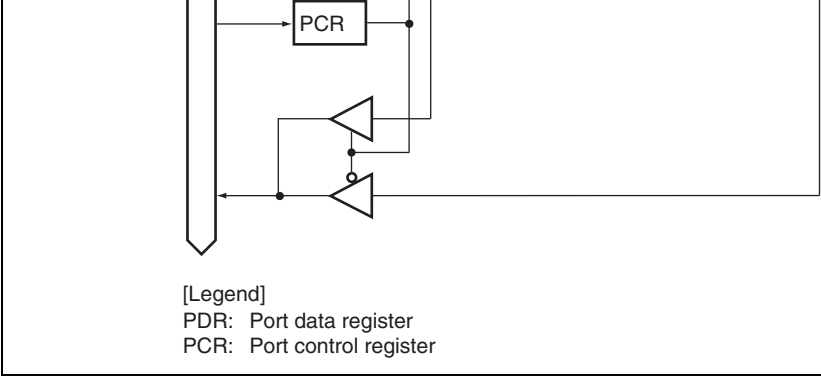
**Figure B.11 Port 7 Block Diagram (P76)**



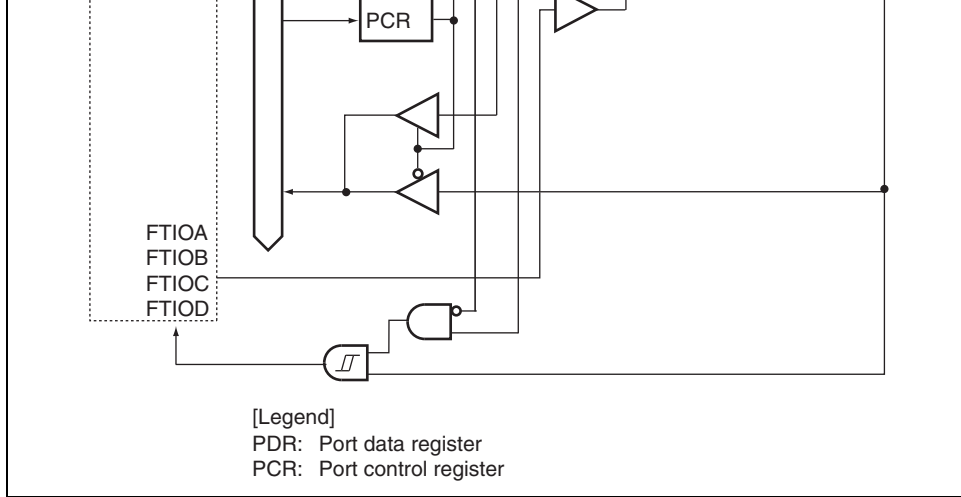
**Figure B.12 Port 7 Block Diagram (P75)**



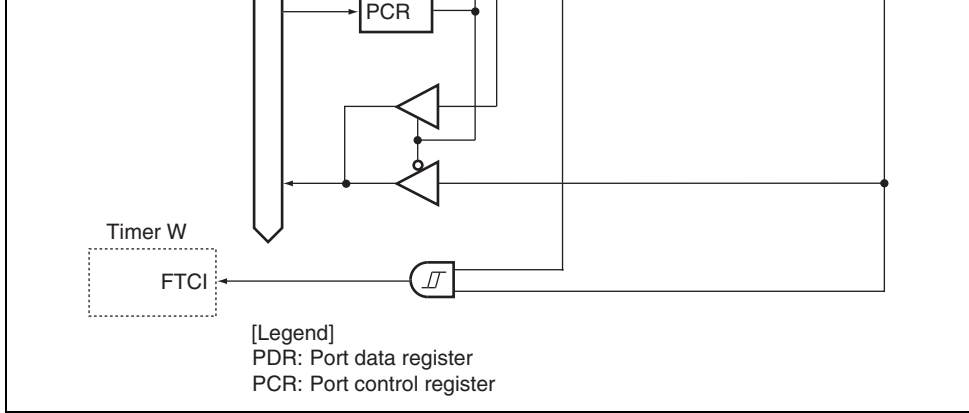
**Figure B.13 Port 7 Block Diagram (P74)**



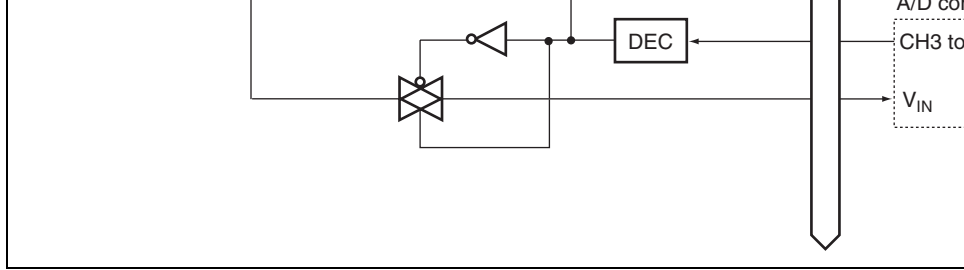
**Figure B.14 Port 8 Block Diagram (P87 to P85)**



**Figure B.15 Port 8 Block Diagram (P84 to P81)**



**Figure B.16 Port 8 Block Diagram (P80)**



**Figure B.17 Port B Block Diagram (PB7 to PB0)**

## B.2 Port States in Each Operating State

Port	Reset	Sleep	Subsleep	Standby	Subactive	Active
P17 to P14, P12 to P10	High impedance	Retained	Retained	High impedance* <sup>1</sup>	Functioning	Functioning
P22 to P20	High impedance	Retained	Retained	High impedance	Functioning	Functioning
P57 to P50* <sup>2</sup>	High impedance	Retained	Retained	High impedance* <sup>1</sup>	Functioning	Functioning
P76 to P74	High impedance	Retained	Retained	High impedance	Functioning	Functioning
P87 to P80	High impedance	Retained	Retained	High impedance	Functioning	Functioning
PB7 to PB0	High impedance	High impedance	High impedance	High impedance	High impedance	High impedance

Notes: 1. High level output when the pull-up MOS is in on state.

2. The P55 to P50 pins are applied to the H8/3694N.

			POR & LVDC			
			HD64F3694GFP	HD64F3694GFP	LQFP-64 (	
			HD64F3694GFX	HD64F3694GFX	LQFP-48 (	
			HD64F3694GFY	HD64F3694GFY	LQFP-48 (	
			HD64F3694GFT	HD64F3694GFT	QFN-48(T	
Mask ROM version	Standard product		HD6433694H	HD6433694(***)H	QFP-64 (F	
			HD6433694FP	HD6433694(***)FP	LQFP-64 (	
			HD6433694FX	HD6433694(***)FX	LQFP-48 (	
			HD6433694FY	HD6433694(***)FY	LQFP-48 (	
			HD6433694FT	HD6433694(***)FT	QFN-48(T	
		Product with POR & LVDC		HD6433694GH	HD6433694G(***)H	QFP-64 (F
			HD6433694GFP	HD6433694G(***)FP	LQFP-64 (	
			HD6433694GFX	HD6433694G(***)FX	LQFP-48 (	
			HD6433694GFY	HD6433694G(***)FY	LQFP-48 (	
			HD6433694GFT	HD6433694G(***)FT	QFN-48(T	
H8/3693	Mask ROM version	Standard product	HD6433693H	HD6433693(***)H	QFP-64 (F	
			HD6433693FP	HD6433693(***)FP	LQFP-64 (	
			HD6433693FX	HD6433693(***)FX	LQFP-48 (	
			HD6433693FY	HD6433693(***)FY	LQFP-48 (	
			HD6433693FT	HD6433693(***)FT	QFN-48(T	
		Product with POR & LVDC		HD6433693GH	HD6433693G(***)H	QFP-64 (F
			HD6433693GFP	HD6433693G(***)FP	LQFP-64 (	
			HD6433693GFX	HD6433693G(***)FX	LQFP-48 (	
			HD6433693GFY	HD6433693G(***)FY	LQFP-48 (	
			HD6433693GFT	HD6433693G(***)FT	QFN-48(T	

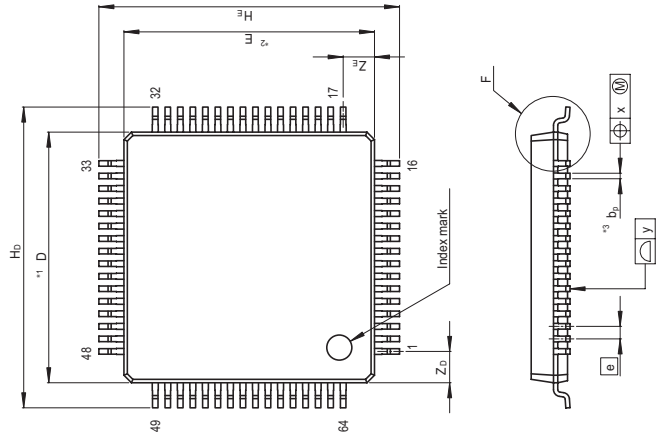


			HD6433692GFY	HD6433692G(***)FY	LQFP-4
			HD6433692GFT	HD6433692G(***)FT	QFN-48
H8/3691	Mask ROM version	Standard product	HD6433691H	HD6433691(***)H	QFP-64
			HD6433691FP	HD6433691(***)FP	LQFP-64
			HD6433691FX	HD6433691(***)FX	LQFP-48
			HD6433691FY	HD6433691(***)FY	LQFP-48
			HD6433691FT	HD6433691(***)FT	QFN-48
		Product with POR & LVDC	HD6433691GH	HD6433691G(***)H	QFP-64
	HD6433691GFP		HD6433691G(***)FP	LQFP-64	
	HD6433691GFX		HD6433691G(***)FX	LQFP-48	
	HD6433691GFY		HD6433691G(***)FY	LQFP-48	
	HD6433691GFT		HD6433691G(***)FT	QFN-48	
H8/3690	Mask ROM version	Standard product	HD6433690H	HD6433690(***)H	QFP-64
			HD6433690FP	HD6433690(***)FP	LQFP-64
			HD6433690FX	HD6433690(***)FX	LQFP-48
			HD6433690FY	HD6433690(***)FY	LQFP-48
			HD6433690FT	HD6433690(***)FT	QFN-48
		Product with POR & LVDC	HD6433690GH	HD6433690G(***)H	QFP-64
	HD6433690GFP		HD6433690G(***)FP	LQFP-64	
	HD6433690GFX		HD6433690G(***)FX	LQFP-48	
	HD6433690GFY		HD6433690G(***)FY	LQFP-48	
	HD6433690GFT		HD6433690G(***)FT	QFN-48	



JEITA Package Code P-LQFP64-10x10-0.50	RENESAS Code P.LQFP064KC-A	Previous Code FP-64E/FP-64EV	MASS [Typ.] 0.4g
---	-------------------------------	---------------------------------	---------------------

NOTE)  
 1. DIMENSIONS\*\*1\*AND\*\*2\*  
 DO NOT INCLUDE MOLD FLASH  
 2. DIMENSION\*\*3\*DOES NOT  
 INCLUDE TRIM OFFSET.



Terminal cross section

Detail F

Reference Symbol	D	E	A <sub>2</sub>	H <sub>0</sub>	H <sub>E</sub>	A	A <sub>1</sub>	b <sub>1</sub>	b <sub>2</sub>	c	c <sub>1</sub>	θ	F	x	y
------------------	---	---	----------------	----------------	----------------	---	----------------	----------------	----------------	---	----------------	---	---	---	---

Figure D.1 FP-64E Package Dimensions

JEITA Package Code P-QFP64-14x14-0.80	RENESAS Code PRQP0064GB-A	Previous Code FP-64A/FP-64AV	MASS[Typ.] 1.2g
--	------------------------------	---------------------------------	--------------------

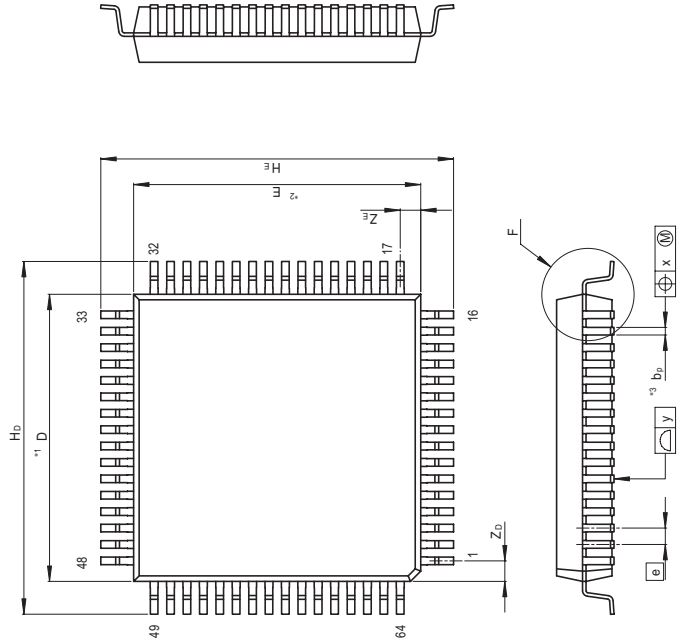


Figure D.2 FP-64A Package Dimensions



JEITA Package Code P-LQFP48-10x10-0.65	RENESAS Code PQFP0048/A-A	Previous Code FP-48F-FP-48FV	MASS[Typ.] 0.4g
---	------------------------------	---------------------------------	--------------------

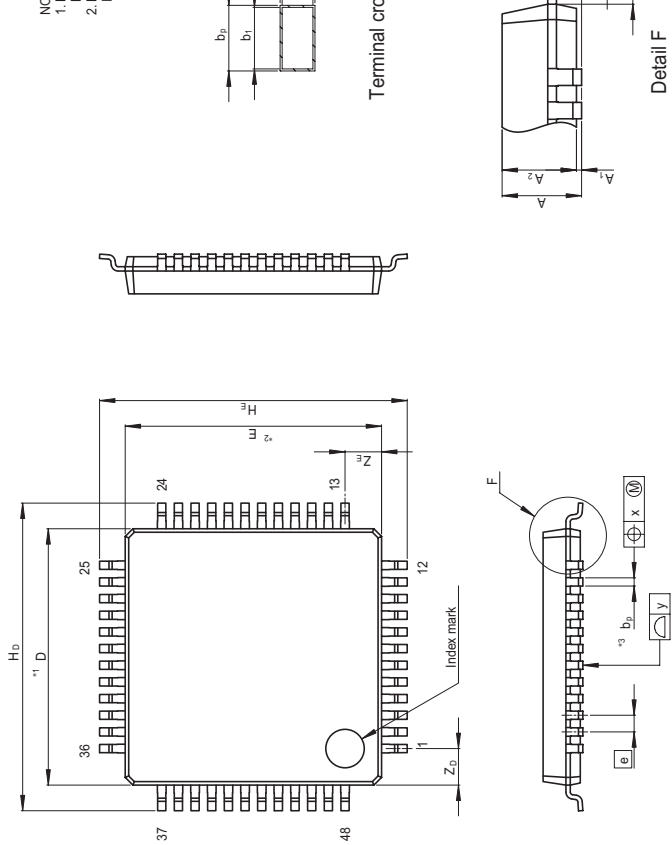
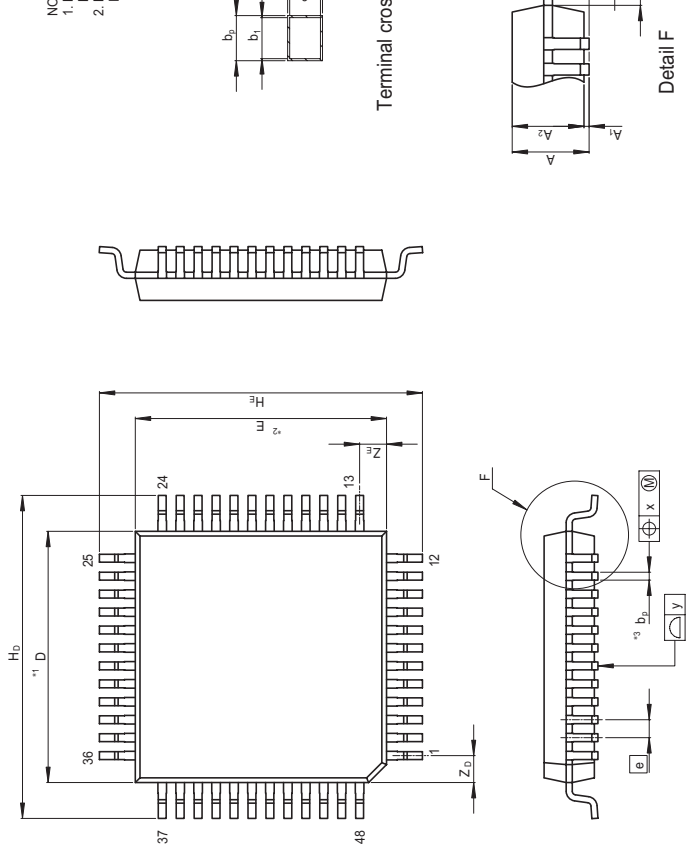


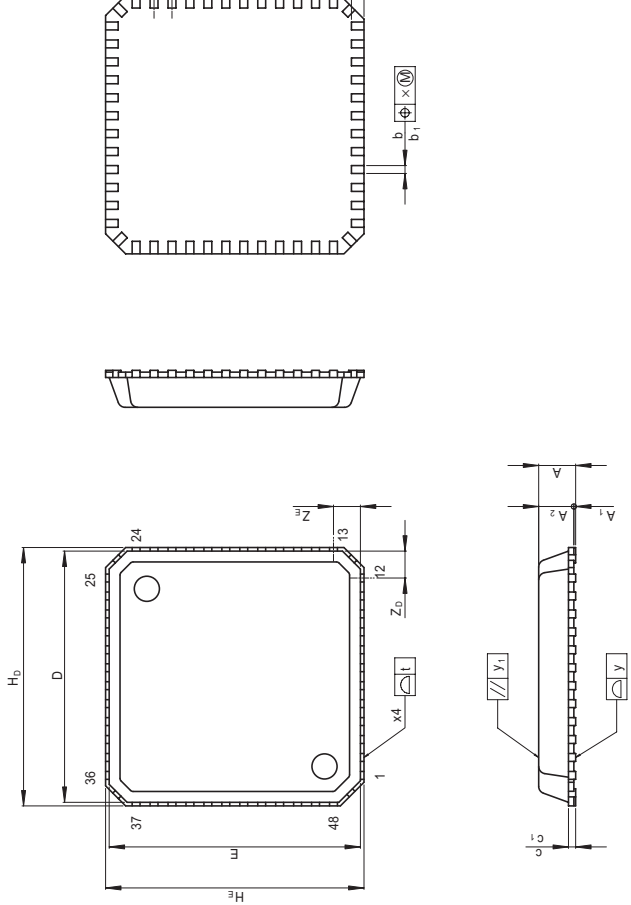
Figure D.3 FP-48F Package Dimensions

JEITA Package Code P-LQFP48-7x7-0.50	RENESAS Code P-LQFP048KC-A	Previous Code FP-48B/FP-48BV	MASS[Typ.] 0.29
---	-------------------------------	---------------------------------	--------------------

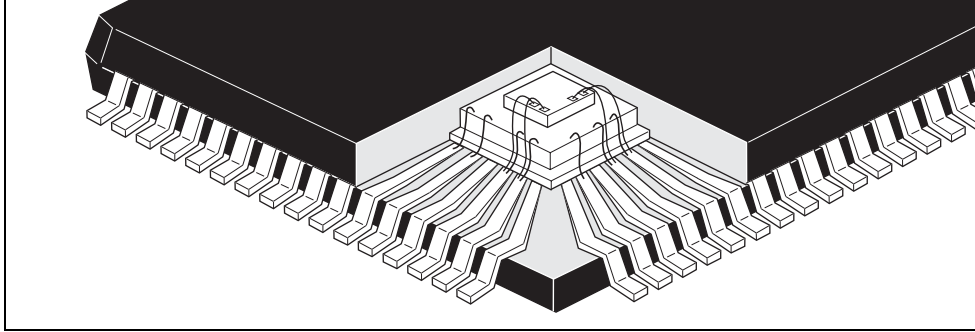


**Figure D.4 FP-48B Package Dimensions**

JETA Package Code P-VQFN48-7X7-0.50	RENESAS Code PVCN0048K0A	Previous Code TNP-48/TNP-48V	MASS[Typ.] 0.1g
--	-----------------------------	---------------------------------	--------------------



**Figure D.5 TNP-48 Package Dimensions**



**Figure E.1 EEPROM Stacked-Structure Cross-Sectional View**



available to the user.

- When the E7 or E8 is used, address breaks can be either available to the user or for use by the E7 or E8. If address breaks are set as being used by the E7 or E8, address break control registers must not be accessed.
- When the E7 or E8 is used,  $\overline{\text{NMI}}$  is an input/output pin (open-drain in output mode), P85 and P87 are input pins and P86 is an output pin.

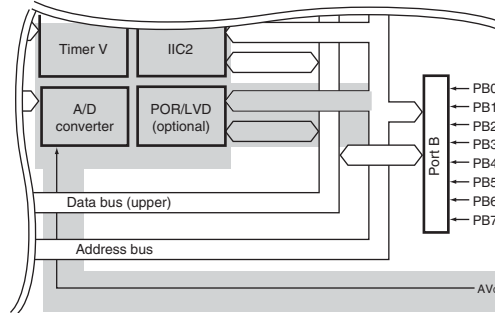
Note has been deleted.

Section 1 Overview

4, 5

Figure 1.1 Internal Block Diagram of H8/3694 Group of F-ZTAT™ and Mask-ROM Versions,

Figure 1.2 Internal Block Diagram of H8/3694N (EEPROM Stacked Version)



Section 6 Power-Down Modes	76			
6.1.1 System Control Register 1 (SYSCR1)		3	NESEL	Noise Elimination Sampling Frequency Select  The subclock pulse generator generates the watch clock signal ( $\phi_w$ ) and the system clock pulse generator generates the oscillator clock ( $\phi_{osc}$ ). This bit selects the sampling frequency of the oscillator clock when the watch clock signal ( $\phi_w$ ) is sampled. When $\phi_{osc} = 4$ to 20 MHz, clear NESEL to 0.
Section 8 RAM	107	Note: * When the E7 or E8 is used, area H'F780 to H'F78F must not be accessed.		
Section 13 Watchdog Timer	184			
13.2.1 Timer Control/Status Register WD (TCSRWD)		4	TCSRWE	Timer Control/Status Register <b>WD</b> Write Enable

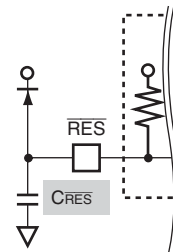
15.7 Usage Notes 264 Added

Section 16 A/D Converter 268  
 16.3.1 A/D Data Registers  
 A to D (ADDRA to  
 ADDR D)

Therefore byte access to ADDR should be done by re-  
 upper byte first then the lower one. Word access is al-  
 possible. ADDR is initialized to H'0000.

Section 18 Power-On  
 Reset and Low-Voltage  
 Detection Circuits  
 (Optional) 290

Figure 18.1 Block  
 Diagram of Power-On  
 Reset Circuit and Low-  
 Voltage Detection Circuit



Section 21 Electrical  
 Characteristics 318  
 Table 21.2 DC  
 Characteristics (1)

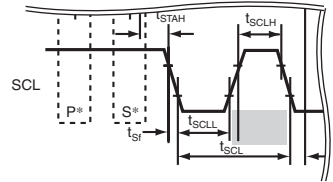
Item	Symbol	Applicable Pins	Test Condition
Input high voltage	$V_{IH}$	PB0 to PB7	$V_{cc} = 4.0$ to $5.5$ V
Input low voltage	$V_{IL}$	RXD,SCL, SDA, P10 to P12, : P80 to P87 PB0 to PB7	$V_{cc} = 4.0$ to $5.5$ V

Item	Symbol	Pins	Test Condition
Input high voltage	$V_{IH}$	PB0 to PB7	$V_{CC} = 4.0$ to $5.5$ V
Input low voltage	$V_{IL}$	RXD, SCL, SDA P10 to P12, : P80 to P87 PB0 to PB7	$V_{CC} = 4.0$ to $5.5$ V

340	Mode	$\overline{RES}$ Pin	Internal State
	Active mode 1	$V_{CC}$	Operates
	Active mode 2		Operates ( $\phi_{OSC}/64$ )
	Sleep mode 1	$V_{CC}$	Only timers oper
	Sleep mode 2		Only timers oper ( $\phi_{OSC}/64$ )

Figure 21.4 I<sup>2</sup>C Bus Interface Input/Output Timing

352



Appendix D Package Dimensions

405 to 409 Swapped with new ones.

Immediate .....	36
Memory indirect .....	37
Program-counter relative .....	36
Register direct.....	35
Register indirect.....	35
Register indirect with displacement.....	35
Register indirect with post-increment...	35
Register indirect with pre-decrement....	36

## C

Clock pulse generators.....	69
Prescaler S .....	73
Prescaler W .....	73
Subclock generator .....	72
System clock generator .....	70
Condition field.....	33
Condition-code register (CCR).....	19
CPU .....	13

## E

EEPROM.....	277
Acknowledge .....	281
Acknowledge polling .....	284
Byte write .....	283
Current address read .....	285
EEPROM interface .....	280
Page write .....	283

Effective address extension.....	
Exception handling .....	
Reset exception handling .....	
Trap instruction.....	

## F

Flash memory .....	
Boot mode.....	
Boot program .....	
Erase/erase-verify .....	
Erasing units .....	
Error protection.....	
Hardware protection.....	
Power-down state.....	
Program/program-verify .....	
Programmer mode.....	
Programming units.....	
Programming/erasing in user program mode .....	
Software protection .....	

## G

General registers .....	
-------------------------	--

## I

I/O ports .....	
-----------------	--

Instruction set .....	24
Arithmetic operations instructions.....	26
Bit Manipulation instructions .....	29
Block data transfer instructions .....	33
Branch instructions .....	31
Data transfer instructions.....	25
Logic operations instructions.....	28
Shift instructions.....	28
System control instructions.....	32
Internal power supply step-down circuit.....	299
Interrupt	
Internal interrupts .....	58
Interrupt response time .....	60
IRQ3 to IRQ0 interrupts .....	57
NMI interrupt.....	57
WKP5 to WKP0 interrupts .....	57
Interrupt mask bit (I).....	19

## L

Large current ports.....	2
Low-voltage detection circuit .....	289
LVDI .....	295
LVDI (interrupt by low voltage detect) circuit.....	295
LVDR .....	294
LVDR (reset by low voltage detect) circuit.....	294

Package .....	
Package dimensions .....	
Pin arrangement .....	
Power-down modes.....	
Sleep mode.....	
Standby mode .....	
Subactive mode.....	
Subsleep mode .....	
Power-on reset .....	
Power-on reset circuit .....	
Product code lineup .....	
Program counter (PC) .....	

## R

### Register

ABRKCR.....	64, 304
ABRKSR .....	65, 304
ADCR .....	270, 304
ADCSR .....	269, 304
ADDRA .....	268, 303
ADDRB .....	268, 304
ADDRC .....	268, 304
ADDRD .....	268, 304
BARH .....	66, 304
BARL.....	66, 304
BDRH .....	66, 304
BDRL.....	66, 304
BRR .....	198, 303

ICCR2.....	236, 302, 307, 311
ICDRR.....	245, 302, 307, 311
ICDRS.....	245
ICDRT.....	245, 302, 307, 311
ICIER.....	239, 302, 307, 311
ICMR.....	237, 302, 307, 311
ICSR.....	241, 302, 307, 311
IEGR1.....	51, 306, 309, 313
IEGR2.....	52, 306, 309, 313
IENR1.....	53, 306, 309, 313
IRR1.....	54, 306, 309, 313
IWPR.....	55, 306, 309, 313
LVDCR.....	290, 302, 307, 311
LVDSR.....	292, 302, 307, 311
MSTCR1.....	79, 306, 309, 313
PCR1.....	111, 305, 309, 313
PCR2.....	115, 305, 309, 313
PCR5.....	119, 305, 309, 313
PCR7.....	124, 305, 309, 313
PCR8.....	126, 305, 309, 313
PDR1.....	111, 305, 309, 312
PDR2.....	115, 305, 309, 312
PDR5.....	119, 305, 309, 312
PDR7.....	124, 305, 309, 312
PDR8.....	127, 305, 309, 312
PDRB.....	130, 305, 309, 312
PMR1.....	110, 305, 309, 313
PMR5.....	118, 305, 309, 313
PUCR1.....	112, 305, 309, 312

TCNTV.....	139, 302
TCORA.....	139, 302
TCORB.....	139, 302
TCRV0.....	140, 302
TCRV1.....	143, 302
TCRW.....	158, 302
TCSR.....	142, 302
TCSRWD.....	184, 302
TCWD.....	185, 302
TDR.....	192, 302
TIERW.....	159, 302
TIOR0.....	161, 302
TIOR1.....	163, 302
TMA.....	133, 302
TMRW.....	157, 302
TMWD.....	186, 302
TSR.....	
TSRW.....	160, 302

Register field.....

**S**

Serial communication interface 3 (SCI3).....	
Asynchronous mode.....	
Bit rate.....	
Break.....	
Clocked synchronous mode.....	
Framing error.....	





---

**Renesas 16-Bit Single-Chip Microcomputer  
Hardware Manual  
H8/3694 Group**

Publication Date: 1st Edition, Jul, 2001

Rev.5.00, Nov. 02, 2005

Published by: Sales Strategic Planning Div.  
Renesas Technology Corp.

Edited by: Customer Support Department  
Global Strategic Communication Div.  
Renesas Solutions Corp.

---

©2005. Renesas Technology Corp. All rights reserved. Printed in Japan.



**RENESAS SALES OFFICES**

<http://www.ren>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

**Renesas Technology America, Inc.**

450 Holger Way, San Jose, CA 95134-1368, U.S.A  
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

**Renesas Technology Europe Limited**

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom  
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

**Renesas Technology (Shanghai) Co., Ltd.**

Unit2807 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China  
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

**Renesas Technology Hong Kong Ltd.**

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong  
Tel: <852> 2265-6688, Fax: <852> 2730-6071

**Renesas Technology Taiwan Co., Ltd.**

10th Floor, No.99, Fushing North Road, Taipei, Taiwan  
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

**Renesas Technology Singapore Pte. Ltd.**

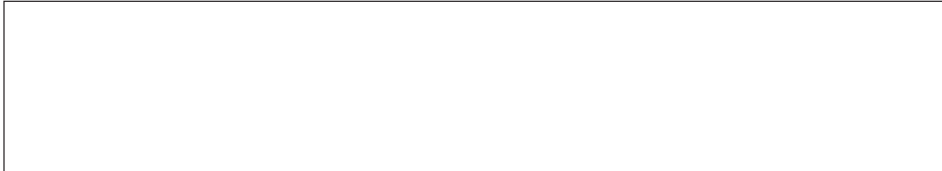
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001

**Renesas Technology Korea Co., Ltd.**

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea  
Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

**Renesas Technology Malaysia Sdn. Bhd.**

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan,  
Tel: <603> 7955-9390, Fax: <603> 7955-9510





# H8/3694Group Hardware Manual



Renesas Electronics Corporation

1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668 Japan

REJ09B0028-0500

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [16-bit Microcontrollers - MCU category](#):*

*Click to view products by [Renesas manufacturer](#):*

Other Similar products are found below :

[MB90F036APMC-GSE1](#) [MB90F342CASPMC-GSE1](#) [MB90F345CESPMC-GE1](#) [MB90F349CAPFR-GSE1](#) [MB90F428GCPFR-GSE1](#)  
[MB90F462APFM-GE1](#) [MB90F462APMC-G-SNE1](#) [MB90F497GPF-GE1](#) [MB90F546GSPFR-GE1](#) [MB90F947APFR-GS-SPE1](#)  
[MB96F346RSBPMC-GS-N2E2](#) [MB96F683RBPMC-GSAE1](#) [R5F11BGEAFB#30](#) [DF3026XBL25V](#) [S912ZVFP64F1VLL](#)  
[R4F24268NVRFQV](#) [R5F107DEGSP#X0](#) [R5F11B7EANA#U0](#) [R5F21172DSP#U0](#) [M30622F8PGP#U3C](#) [MB90092PF-G-BNDE1](#)  
[MB90F335APMC1-G-SPE1](#) [MB90F342CASPF-R-GS-N2E1](#) [MB90F345CAPFR-GSE1](#) [MB90F543GPF-GE1](#) [MB90F546GSPF-GE1](#)  
[MB90F568PMCR-GE1](#) [MB90F594APFR-GE1](#) [MB90F882ASPMC-GE1](#) [MB96F346RSAPQCR-GS-N2E2](#) [MB96F387RSBPMC-GSE2](#)  
[MB96F387RSBPMC-GS-N2E2](#) [MB96F395RSAPMC-GSE2](#) [MB96F623RBPMC1-GSE1](#) [MB96F646RBPMC-GSE1](#)  
[XE167F96F66LACFXUMA1](#) [MB96F696RBPMC-GSAE1](#) [MB96F018RBPMC-GSE1](#) [MB90F962SPMCR-GE1](#) [MB90F867ASPFR-GE1](#)  
[MB90F543GPF-G-FLE1](#) [MB90F345CESPF-GE1](#) [M30290FCHP#U3A](#) [DF2239FA20IV](#) [HD64F3672FPV](#) [R5F104AEASP#V0](#)  
[R5F100BCANA#U0](#) [R5F100BFANA#U0](#) [S9S12H256J2VFVER](#) [R5F100ACASP#V0](#)